

# Service Manual

# LG-P705

---

# Table Of Contents

<b>1. INTRODUCTION.....</b>	<b>3</b>	<b>9. PCB LAYOUT.....</b>	<b>148</b>
1.1 Purpose .....	3	<b>10. CALIBRATION.....</b>	<b>156</b>
1.2 Regulatory Information .....	3	<b>11. HIDDEN MENU.....</b>	<b>176</b>
<b>2. PERFORMANCE.....</b>	<b>5</b>	<b>12. EXPLODED VIEW &amp; REPLACEMENT PART LIST .....</b>	<b>182</b>
2.1 Product Name.....	5	12.1 EXPLODED VIEW .....	182
2.2 Supporting Standard.....	5	12.2 Replacement Parts .....	183
2.3 Main Parts : GSM Solution.....	6	12.3 Accessory .....	221
2.4 HW Features .....	6		
2.5 SW Features .....	8		
2.6 HW SPEC. ....	11		
<b>3. CIC AND SERVICE CENTER .....</b>	<b>19</b>		
3.1 FAQ Questions.....	19		
<b>4. TROUBLE SHOOTING .....</b>	<b>30</b>		
4.1 RF Component .....	30		
4.2 SIGNAL PATH .....	31		
4.3 Checking TCXO Block.....	33		
4.4 Checking GSM TX Module(GSM PAM + FEM) Block.....	35		
4.5 Checking WCDMA Block .....	38		
4.6 Checking GSM Block .....	49		
4.7 GPS/WIFI/BT/FMR RF Component.....	56		
4.8 GPS/WIFI/BT SIGNAL PATH .....	58		
4.9 GPS/WIFI/BT Trouble shooting .....	60		
4.10 Power ON Trouble Shooting.....	67		
4.11 Charging Trouble Shooting .....	72		
4.12 5M Camera Trouble Shooting.....	75		
4.13 VGA Camera Trouble Shooting .....	78		
4.14 Main LCD trouble .....	81		
4.15 Proximity Sensor on/off Trouble Shooting.....	83		
4.16 Motion Sensor on/off Trouble Shooting .....	85		
4.17 Compass Sensor on/off Trouble Shooting .....	87		
4.19 Audio Troble.....	91		
<b>5. DOWNLOAD .....</b>	<b>108</b>		
<b>6.Block diagram .....</b>	<b>128</b>		
<b>7. CIRCUIT DIAGRAM .....</b>	<b>131</b>		
<b>8. BGA PIN MAP .....</b>	<b>142</b>		

# 1. INTRODUCTION

## 1.1 Purpose

This manual provides the information necessary to repair, calibration, description and download the features of this model.

## 1.2 Regulatory Information

### A. Security

Toll fraud, the unauthorized use of telecommunications system by an unauthorized part (for example, persons other than your company's employees, agents, subcontractors, or person working on your company's behalf) can result in substantial additional charges for your telecommunications services. System users are responsible for the security of own system. There are may be risks of toll fraud associated with your telecommunications system. System users are responsible for programming and configuring the equipment to prevent unauthorized use. The manufacturer does not warrant that this product is immune from the above case but will prevent unauthorized use of common carrier telecommunication service of facilities accessed through or connected to it. The manufacturer will not be responsible for any charges that result from such unauthorized use.

### B. Incidence of Harm

If a telephone company determines that the equipment provided to customer is faulty and possibly causing harm or interruption in service to the telephone network, it should disconnect telephone service until repair can be done. A telephone company may temporarily disconnect service as long as repair is not done.

### C. Changes in Service

A local telephone company may make changes in its communications facilities or procedure. If these changes could reasonably be expected to affect the use of the phones or compatibility with the net work, the telephone company is required to give advanced written notice to the user, allowing the user to take appropriate steps to maintain telephone service.

### D. Maintenance Limitations

Maintenance limitations on the phones must be performed only by the manufacturer or its authorized agent. The user may not make any changes and/or repairs expect as specifically noted in this manual. Therefore, note that unauthorized alternations or repair may affect the regulatory status of the system and may void any remaining warranty.

### E. Notice of Radiated Emissions

This model complies with rules regarding radiation and radio frequency emission as defined by local regulatory agencies. In accordance with these agencies, you may be required to provide information such as the following to the end user.

### F. Pictures

The pictures in this manual are for illustrative purposes only; your actual hardware may look slightly different.

### G. Interference and Attenuation

A phone may interfere with sensitive laboratory equipment, medical equipment, etc. Interference from unsuppressed engines or electric motors may cause problems.

### H. Electrostatic Sensitive Devices

## ATTENTION

**Boards, which contain Electrostatic Sensitive Device (ESD), are indicated by the  sign.**

**Following information is ESD handling:**

- Service personnel should ground themselves by using a wrist strap when exchange system boards.
- When repairs are made to a system board, they should spread the floor with anti-static mat which is also grounded.
- Use a suitable, grounded soldering iron.
- Keep sensitive parts in these protective packages until these are used.
- When returning system boards or parts like EEPROM to the factory, use the protective package as described.



## 2. PERFORMANCE

### 2.1 Product Name

P705 : WCDMA900/2100+EGSM/GSM850/DCS/PCS

(HSDPA 7.2Mbps GPRS Class 12 / EDGE Class 12)

### 2.2 Supporting Standard

Item	Feature	Comment
Supporting Standard	WCDMA(FDD1,8)/EGSM/GSM850/DCS1800/PCS1900 Phase 2+(include AMR) SIM Toolkit: Class 1, 2, 3, C(Partially Support)	
Frequency Range	WCDMA(FDD1) TX : 1920 – 1980 MHz WCDMA(FDD1) RX : 2110 – 2170 MHz WCDMA(FDD8) TX : 880~915 MHz WCDMA(FDD8) RX : 925~960 MHz EGSM TX: 880 – 915 MHz EGSM RX: 925 – 960 MHz GSM850 TX: 824 – 849 MHz GSM850 RX: 869 – 894 MHz DCS1800 TX : 1710 – 1785 MHz DCS1800 RX: 1805 – 1880 MHz PCS1900 TX: 1850 – 1910 MHz PCS1900 RX: 1930 – 1990 MHz	
Application Standard	Android Browser (Webkit 533.1)	

### 2.3 Main Parts : GSM Solution

Item	Part Name	Comment
Digital Baseband	MSM7227A: Qualcomm	
Analog Baseband	PM8029 : Qualcomm	
RF Chip	RTR6285A : Qualcomm	

### 2.4 HW Features

Item		Feature	Comment
Form Factor		DOP type	
Battery		1) Capacity Standard : Li-Ion , 1700mAh	
		2) Packing Type : Soft Pack	
Size		Standard : 125.5 x 67 x 8.8 mm	
Weight		122g	With Battery
Volume		73994.8cc	
PCB		L1F2 10 Layers , 0.8T	
Stand by time		2G Up to 600 hrs 3G Up to 720 hrs	@ Paging Period 5 (2G) @ DRX 7 (3G)
Charging time		Under 4 hrs	@ Power Off / 1700mAh
Talk time		2G Up to 350mins 3G Up to 350mins	@ Power Level Max (2G) @ Tx = 12dBm LPM (3G)
RX sensitivity		WCDMA(FDD1) : -106.7 dBm WCDMA(FDD8) : -104.7 dBm EGSM : -105 dBm GSM850 : -105 dBm DCS 1800 : -105 dBm PCS 1900 : -105 dBm	
TX output power	WCDMA/ GSM/ GPRS	WCDMA : 24dBm/3.84MHz,+1/-3dBm EGSM : 33dBm GSM850 : 33 dBm DCS 1800 : 30 dBm PCS 1900 : 30 dBm	Class3 (WCDMA) Class4 (EGSM) Class4 (GSM850) Class1 (PCS) Class1 (DCS)
	EDGE	Half EDGE (RX Only)	
GPRS compatibility		GPRS Class 12	
EDGE compatibility		EDGE Class 12	
SIM card type		Plug-In SIM 3V /1.8V	
Display		TFT Main LCD(4.3' , WVGA 800 x 480)	

## 2. PERFORMANCE

Built-in Camera	5M AF	
Status Indicator	No	
Keypad	Function key : 1 Side Key : 2 Power key : 1	Function Key: Home, Back, Menu, Side Key : Volume up/down
ANT	Main : Internal Fixed Type	LDS type
System connector	5 Pin	
Ear Phone Jack	3.5Phi, 4 Pole, Stereo	
PC synchronization	Yes	
Memory	eMMC : 4GByte DRAM : 4Gbit	
Speech coding	FR, EFR, HR, AMR	
Data & Fax	Built in Data & Fax support	
Vibrator	Built in Vibrator	
Blue Tooth	V3.0	
MIDI(for Buzzer Function)	SW Decoded 64Poly	
Music Player	MP3/ WMA/AAC/HE- AAC/EAAC+/OGG/FLAC	
Video Player	MPEG4, H.263, H.264/DivX/Xvid/VP8	
Camcorder	MPEG4, H.263, H.264	
Voice Recording	Yes	
Speaker Phone Mode Support	Yes	
Travel Adapter	Yes	
CDROM	No	
Stereo Headset	Yes	Inbox
Data Cable	Yes	
T-Flash (External Memory)	Yes	Not inbox

### 2.5 SW Features

Item	Feature	Comment
RSSI	0 ~ 4 Levels	
Battery Charging	0 ~ 20 Levels	
Key Volume	0 ~ 7 Level	
Audio Volume	0 ~ 7 Level	
Time / Date Display	Yes	
Multi-Language	Yes	
Quick Access Mode	Dialing/ Contact / Menu / Message	
PC Sync	Yes	
Speed Dial	Yes	
Profile	Yes	
CLIP / CLIR	Yes	
Phone Book	Name / Number / Email / Website/Postal addresses/Organizations/Gro ups/ Birthday / Ringtone	
Last Dial Number	Yes	
Last Received Number	Yes	
Last Missed Number	Yes	
Search by Number / Name	Yes	
Group	Yes	
Fixed Dial Number	Yes	
Service Dial Number	No	
Own Number	Yes	
Voice Memo	Yes	

## 2. PERFORMANCE

Call Reminder	No	
Network Selection	Automatic	
Mute	Yes	
Call Divert	Yes	
Call Barring	Yes	
Call Charge (AoC)	Yes	
Call Duration	Yes	
SMS (EMS)	There is no limitation on the number of items. It depends on available memory amount.	EMS does not support.
SMS Over GPRS	No	
EMS Melody / Picture	No	
Send / Receive / Save	No	EMS send / Receive / Save
MMS MPEG4 Send / Receive / Save	Yes	
Long Message	MAX 2000 characters	
Cell Broadcast	Yes	
Download	Over the Web	
Game	No	
Calendar	Yes	
Memo	Yes	
World Clock	Yes	
Unit Convert	No	
Stop Watch	Yes	
Wall Paper	Yes	
WAP Browser	No	Support only web browser based on webkit. WAP stack and wml are not supported.
Download Melody / Wallpaper	Yes	Over web browser
SIM Lock	Yes	Operator Dependent
SIM Toolkit	Class 1, 2, 3	Class C - "Browsing status

## 2. PERFORMANCE

	Partially support Class C	event" is not supported
MMS	Yes	
EONS	No	
CPHS	Yes	V4.2
ENS	No	
Camera	Yes	- 5MP AF + VGA VT - VGA recording
JAVA	No	
Voice Dial	No	
IrDa	No	
Bluetooth	Yes	Ver. 3.0
FM radio	Yes	
GPRS	Yes	Class 12
EDGE	Yes	Class 12
Hold / Retrieve	Yes	
Conference Call	Yes	Max. 6
DTMF	Yes	
Memo pad	Yes	
TTY	No	
AMR	Yes	
SyncML	Yes	
IM	No	
Email	Yes	

### 2.6 HW SPEC.

#### 1) GSM transceiver specification

Item	Specification
Phase Error	Rms : 5° Peak : 20 °
Frequency Error	GSM : 0.1 ppm DCS/PCS : 0.1 ppm
EMC(Radiated Spurious Emission Disturbance)	GSM/DCS : < -28dBm
Transmitter Output power and Burst Timing	GSM : 5dBm – 33dBm ± 3dB DCS/PCS : 0dBm – 30dBm ± 3dB
Burst Timing	<3.69us
Spectrum due to modulation out to less than 1800kHz offset	200kHz : -36dBm 600kHz : -51dBm/-56dBm
Spectrum due to modulation out to larger than 1800kHz offset to the edge of the transmit band	GSM : 1800-3000kHz : < -63dBc(-46dBm) 3000kHz-6000kHz : < -65dBc(-46dBm) 6000kHz < : < -71dBc(-46dBm) DCS : 1800-3000kHz : < -65dBc(-51dBm) 6000kHz < : < -73dBc(-51dBm)
Spectrum due to switching transient	400kHz : -19dBm/-22dBm(5/0), -23dBm 600kHz : -21dBm/-24dBm(5/0), -26dBm
Reference Sensitivity – TCH/FS	Class II(RBER) : -105dBm(2.439%)
Usable receiver input level range	0.012(-15 - -40dBm)
Intermodulation rejection – Speech channels	± 800kHz, ± 1600kHz : -98dBm/-96dBm (2.439%)
AM Suppression – GSM : -31dBm – DCS : -29dBm	-98dBm/-96dBm (2.439%)
Timing Advance	± 0.5T

### 2) WCDMA transmitter specification

Item	Specification
Transmit Frequency	Band1 : 1920 MHz ~ 1980 MHz Band8 : 880MHz ~ 915MHz
Maximum Output Power	+24 dBm / 3.84 MHz, +1 / -3 dB
Frequency Error	within $\pm 0.1$ PPM
Open Loop Power Control	Normal Conditions : within $\pm 9$ dB, Extreme Conditions : within $\pm 12$ dB
Minimum Transmit Power	< -50 dBm / 3.84 MHz
Occupied Bandwidth	< 5 MHz at 3.84 Mcps (99% of power)
Adjacent Channel Leakage Power Ratio (ACLR)	> 33 dB @ $\pm 5$ MHz, > 43 dB @ $\pm 10$ MHz
Spurious Emissions $ f-f_c  > 12.5$ MHz	< -36 dBm / 1 kHz RW @ $9 \text{ kHz} \leq f < 150 \text{ kHz}$ < -36 dBm / 10 kHz RW @ $150 \text{ kHz} \leq f < 30 \text{ MHz}$ < -36 dBm / 100 kHz RW @ $30 \text{ MHz} \leq f < 1 \text{ GHz}$ < -30 dBm / 1 MHz RW @ $1 \text{ GHz} \leq f < 12.75 \text{ GHz}$ < -60 dBm / 3.84 MHz RW @ $869 \text{ MHz} \leq f \leq 894 \text{ MHz}$ < -60 dBm / 3.84 MHz RW @ $1930 \text{ MHz} \leq f \leq 1900 \text{ MHz}$ < -60 dBm / 3.84 MHz RW @ $2110 \text{ MHz} \leq f \leq 2155 \text{ MHz}$ < -67 dBm / 100 kHz RW @ $925 \text{ MHz} \leq f \leq 935 \text{ MHz}$ < -79 dBm / 100 kHz RW @ $935 \text{ MHz} < f \leq 960 \text{ GHz}$ < -71 dBm / 100 kHz RW @ $1805 \text{ MHz} \leq f \leq 1880 \text{ MHz}$ < -41 dBm / 300 kHz RW @ $1884.5 \text{ MHz} < f < 1919.6 \text{ MHz}$
Transmit Intermodulation	< -31 dBc @ 5 MHz & < -41 dBc @ 10 MHz when Interference CW Signal Level = -40 dBc
Error Vector Magnitude	< 17.5 %, when Pout $\geq$ -20 dBm
Peak Code Domain Error	< -15 dB at Pout $\geq$ -20 dBm



### 3) WCDMA receiver specification

Item	Specification																			
Receive Frequency	Band1 : 2110 ~ 2170 MHz Band8 : 925~960MHz																			
Reference Sensitivity Level	Band1 : BER < 0.001 when $\hat{I}_{or}$ = -106.7 dBm / 3.84 MHz Band8 : BER < 0.001 when $\hat{I}_{or}$ = -103.7 dBm / 3.84 MHz																			
Maximum Input Level	BER < 0.001 when $\hat{I}_{or}$ = -25 dBm / 3.84 MHz																			
Adjacent Channel Selectivity (ACS)	ACS > 33 dB where BER < 0.001 when $\hat{I}_{or}$ = -92.7dBm / 3.84 MHz & loac = -52 dBm / 3.84 MHz @ $\pm 5$ MHz(Band1) $\hat{I}_{or}$ = -89.7dBm / 3.84 MHz & loac = -52 dBm / 3.84 MHz @ $\pm 5$ MHz(Band8)																			
Blocking Characteristic	BER < 0.001 when $\hat{I}_{or}$ = -103.7 dBm / 3.84 MHz & lblocking = -56 dBm / 3.84 MHz @ Fuw(offset) = $\pm 10$ MHz or lblocking = -44 dBm / 3.84 MHz @ Fuw(offset) = $\pm 15$ MHz																			
Spurious Response	BER < 0.001 when $\hat{I}_{or}$ = -103.7 dBm / 3.84 MHz & lblocking = -44 dBm																			
Intermodulation	BER < 0.001 when $\hat{I}_{or}$ = -103.7 dBm / 3.84 MHz, $\hat{I}_{or}$ = -100.7 dBm/ 3.84 MHz(Band8) & louw1 = -46 dBm @ Fuw1(offset) = $\pm 10$ MHz & louw2 = -46 dBm / 3.84 MHz @ Fuw2(offset) = $\pm 20$ MHz																			
Spurious Emissions	< -57 dBm / 100 kHz BW @ $9\text{ kHz} \leq f < 1\text{ GHz}$ < -47 dBm / 1 MHz BW @ $1\text{ GHz} \leq f \leq 12.75\text{ GHz}$																			
Inner Loop Power Control In Uplink	Adjust output(TPC command) <table><tr><td>cmd</td><td>1dB</td><td>2dB</td><td>3dB</td></tr><tr><td>+1</td><td>+0.5/1.5</td><td>+1/3</td><td>+1.5/4</td></tr><tr><td>0</td><td>-0.5/+0.5</td><td>-0.5/+0.5</td><td>-0.5/+0.5</td></tr><tr><td>-1</td><td>-0.5/-1.5</td><td>-1/-3</td><td>-1.5/-4</td></tr></table> group(10equal command group) <table><tr><td>+1</td><td>+8/+12</td><td>+16/+24</td></tr></table>	cmd	1dB	2dB	3dB	+1	+0.5/1.5	+1/3	+1.5/4	0	-0.5/+0.5	-0.5/+0.5	-0.5/+0.5	-1	-0.5/-1.5	-1/-3	-1.5/-4	+1	+8/+12	+16/+24
cmd	1dB	2dB	3dB																	
+1	+0.5/1.5	+1/3	+1.5/4																	
0	-0.5/+0.5	-0.5/+0.5	-0.5/+0.5																	
-1	-0.5/-1.5	-1/-3	-1.5/-4																	
+1	+8/+12	+16/+24																		

### 4) HSDPA transmitter specification

Item	Specification				
Transmit Frequency	Band1 : 1920 MHz ~ 1980 MHz Band8 : 880MHz ~ 915MHz				
Maximum Output Power	Sub-Test 1=1/15,            2=12/15                            21~25dBm / 3.84 MHz 3=13/15    4=15/8                            20~25dBm / 3.84 MHz 5=15/7        6=15/0                            19~25dBm / 3.84 MHz				
HS-DPCCH	Sub-test in table C.10.1.4	Power step	Power step slot boundary	Power step size, P [dB]	Transmitter power step tolerance [dB]
	5	1	Start of Ack/Nack	6	+/- 2.3
		2	Start of CQI	1	+/- 0.6
		3	Middle of CQI	0	+/- 0.6
		4	End of CQI	5	+/- 2.3
Spectrum Emission Mask	Sub-Test : 1=1/15,    2=12/15, 3=13/15, 4=15/8, 5=15/7,    6=15/0				
	Frequency offset from carrier $\Delta f$		Minimum requirement		Measurement Bandwidth
	2.5 ~ 3.5 MHz		-35-15 $\times(\Delta f-2.5)$ dBc		30 kHz
	3.5 ~ 7.5 MHz		-35-1 $\times(\Delta f-3.5)$ dBc		1 MHz
	7.5 ~ 8.5 MHz		-35-10 $\times(\Delta f-7.5)$ dBc		1 MHz
	8.5 ~ 12.5 MHz		-49dBc		1 MHz
Adjacent Channel Leakage Power Ratio (ACLR)	Sub-Test : 1=1/15,    2=12/15, 3=13/15, 4=15/8, 5=15/7,    6=15/0  > 33 dB @ $\pm 5$ MHz > 43 dB @ $\pm 10$ MHz				
Error Vector Magnitude	< 17.5 %, when Pout $\geq$ -20 dBm				

**5) HSDPA receiver specification**

Item	Specification
Receive Frequency	Band1 : 2110 MHz ~ 2170 MHz Band8 : 925 MHz ~ 960 MHz
Maximum Input Level (BLER or R), 16QAM Only	Sub-Test : 1=1/15, 2=12/15, 3=13/15, 4=15/8, 5=15/7, 6=15/0 BLER < 10% or R >= 700kbps

**6) WLAN 802.11b transceiver specification**

Item	Specification
Transmit Frequency	2400 MHz ~ 2483.5 MHz ( CH1~CH13 )
Tx Power Level	≤ 20dBm under (Europe), ≤ 30dBm under (USA)
Frequency Tolerance	within ±25 PPM
Chip clock Frequency Tolerance	within ±25 PPM
Spectrum Mask	≤ -30 @ $f_c - 22\text{MHz} < f < f_c + 11\text{MHz}$ and $f_c + 11\text{MHz} < f < f_c + 22\text{MHz}$ ≤ -50 @ $f < f_c - 22\text{MHz}$ and $f > f_c + 22\text{MHz}$
Power ramp on/off time	≤ 2us
Carrier Suppression	≤ -15dB
Modulation Accuracy (Peak EVM)	≤ 35%
Spurious Emissions	< -36 dBm @ 30MHz ~ 1GHz < -30 dBm above @ 1GHz ~ 12.75GHz < -47 dBm @ 1.8GHz ~ 1.9GHz < -47 dBm @ 5.15GHz ~ 5.3GHz
Rx Min input Sensitivity	≤ -76dBm(1Mbps,2Mbps,5.5Mbps,11Mbps) @ FER ≤ 8%
Rx Max input Sensitivity	≥ -10dBm(1Mbps,2Mbps,5.5Mbps,11Mbps) @ FER ≤ 8%
Rx Adjacent Channel Rejection	≥ 35dB @ FER ≤ 8%, interference input signal -70dBm@ $f_c \pm 25\text{MHz}$ (11Mbps)

### 7) WLAN 802.11g transceiver specification

Item	Specification
Transmit Frequency	2400 MHz ~ 2483.5 MHz ( CH1~CH13 )
Tx Power Level	≤ 20dBm under (Europe), ≤ 30dBm under (USA)
Frequency Tolerance	within ±25 PPM
Chip clock Frequency Tolerance	within ±25 PPM
Spectrum Mask	≤ -20 @ ±11MHz offset (9Mhz ~ 11MHz) ≤ -28 @ ±20MHz offset (11MHz ~ 20Mhz) ≤ -40 @ ±30MHz offset (20MHz ~ 30Mhz)
Transmitter constellation error (rms EVM)	≤ -5dB@6Mbps, -8dB@9Mbps, -10dB@12Mbps, -13dB@18Mbps, -16dB@24Mbps, -19dB@36Mbps, -22dB@48Mbps, -25dB@54Mbps
Spurious Emissions	< -36 dBm @ 30MHz ~ 1GHz < -30 dBm above @ 1GHz ~ 12.75GHz < -47 dBm @ 1.8GHz ~ 1.9GHz < -47 dBm @ 5.15GHz ~ 5.3GHz
Rx Min input Sensitivity	PER ≤ 10% -82dBm@6Mbps, -81dBm@9Mbps, -79dBm@12Mbps -77dBm@18Mbps, -74dBm@24Mbps, -70dBm@36Mbps -66dBm@48Mbps, -65dBm@54Mbps
Rx Max input Sensitivity	≥ -20dBm(6,9,12,18,24,36,48,54Mbps) @ PER ≤ 10%
Rx Adjacent Channel Rejection	PER ≤ 10%, ACR ≥ 16dB@6Mbps, ACR ≥ 15dB@9Mbps, ACR ≥ 13dB@12Mbps, ACR ≥ 11dB@18Mbps, ACR ≥ 8dB@24Mbps, ACR ≥ 4dB@36Mbps ACR ≥ 0dB@48Mbps, ACR ≥ -1dB@54Mbps ※ ACR shall be measured by setting the desired signal's strength 3 dB above the rate-dependent sensitivity specified in min input sensitivity

### 8) WLAN 802.11n transceiver specification

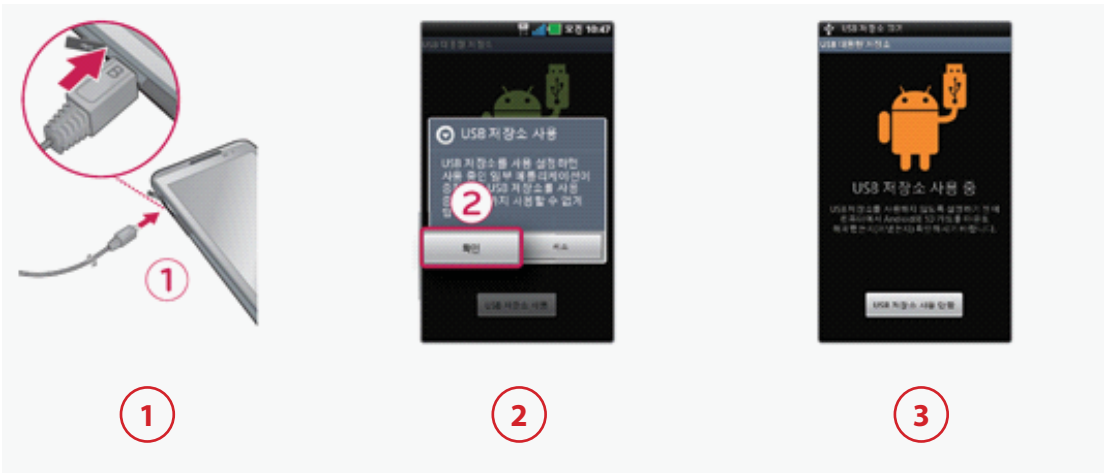
Item	Specification
Transmit Frequency	2400 MHz ~ 2483.5 MHz ( CH1~CH13 )
Tx Power Level	≤ 20dBm under (Europe), ≤ 30dBm under (USA)
Frequency Tolerance	within ±25 PPM
Chip clock Frequency Tolerance	within ±25 PPM
Spectrum Mask	≤ -20 @ ±11MHz offset (9Mhz ~ 11MHz) ≤ -28 @ ±20MHz offset (11MHz ~ 20Mhz) ≤ -45 @ ±30MHz offset (20MHz ~ 30Mhz)
Transmitter constellation error (rms EVM)	≤ -5dB@6.5Mbps, -10dB@13Mbps, -13dB@19.5Mbps, -16dB@26Mbps, -19dB@39Mbps, -22dB@52Mbps, -25dB@58.5Mbps, -28dB@65Mbps
Spurious Emissions	< -36 dBm @ 30MHz ~ 1GHz < -30 dBm above @ 1GHz ~ 12.75GHz < -47 dBm @ 1.8GHz ~ 1.9GHz < -47 dBm @ 5.15GHz ~ 5.3GHz
Rx Min input Sensitivity	PER ≤ 10% -82dBm@6.5Mbps, -79dBm@13Mbps, -77dBm@19.5Mbps -74dBm@26Mbps, -70dBm@39Mbps, -66dBm@52Mbps -65dBm@58.5Mbps, -64dBm@65Mbps
Rx Max input Sensitivity	≥ -20dBm(6.5,13,19.5,26,39,52,58.5,65Mbps) @ PER ≤ 10%
Rx Adjacent Channel Rejection	PER ≤ 10%, ACR ≥ 16dB@6.5Mbps, ACR ≥ 13dB@13Mbps, ACR ≥ 11dB@19.5Mbps, ACR ≥ 8dB@26Mbps, ACR ≥ 4dB@39Mbps, ACR ≥ 0dB@52Mbps ACR ≥ -1dB@58.5Mbps, ACR ≥ -2dB@65Mbps ※ ACR shall be measured by setting the desired signal's strength 3 dB above the rate-dependent sensitivity specified in min input sensitivity

### 10) GPS receiver specification

Item	Specification
Receive Frequency	1574.42 MHz ~ 1576.42 MHz
Minimum Sensitivity	1 satellite $\geq -142\text{dBm}$ , 7 satellites $\geq -147\text{dBm}$ at coarse time aiding


## 3. CIC AND SERVICE CENTER

### 3.1 FAQ Questions

No	FAQ	Q&A
1	<b>Q</b>	I can't remember the PhoneLock password.
	<b>A</b>	<ol style="list-style-type: none"> <li>1. When you forget the pattern (password), and enter wrong patterns five times on Android phones, you can create a new pattern by logging in on your Gmail account as long as the account is activated on your phone. Unless your Gmail account is not activated, you can visit the service center to get the factory reset for the pattern (password).</li> <li>2. TBD</li> <li>3. 3845#*705# -&gt; WCDMA Only -&gt; Factory Reset -&gt; Factory Reset ( !!Do not disclose!! )</li> </ol>
	Development requests	<ol style="list-style-type: none"> <li>1. How to disable Pattern Lock, Password and PIN.</li> <li>2. Request to check out if it is specified in the user manual.</li> <li>3. Description on HW Factory Reset Key combination and how to do it.</li> </ol>
2	<b>Q</b>	How do I put in and take out files from the SD card?
	<b>A</b>	 <p>On the 'USB in Use' screen as above, go to My Computer&gt;p705F&gt;select SD Card</p>
	Development requests	<ol style="list-style-type: none"> <li>1.PC&lt;-&gt; SD CARD</li> <li>2.PHONE&lt;-&gt; SD CARD</li> </ol>

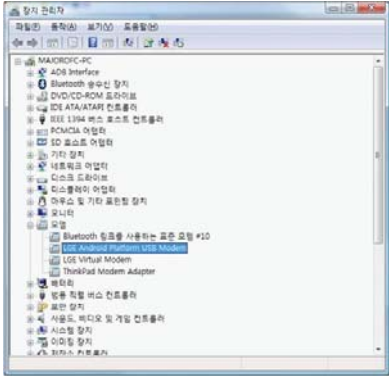
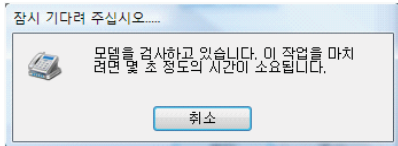
No	FAQ	Q&A
3	<b>Q</b> I use it abroad, but 3G connection doesn't work.	<p><b>A</b></p> <ol style="list-style-type: none"> <li>1. Press the Menu, go to the SetUp, and press More on Wireless and Network</li> <li>2. Press Mobile Network under the Wireless and Network, and press the Network Administrator.</li> <li>3. Press the Network Search, browse available networks, select a network you are to use and connect the network.</li> </ol>
Development requests	ex) 1. Europe<->Europe 2. Europe<->Continents(North America, Asia etc)	
4	<b>Q</b> The GPS location isn't right, what should I do?	<p>1. Make sure GPS, Wi-Fi and 3G networks are ticked off (or checked) for availability.</p> <div data-bbox="308 1137 1361 1552" data-label="Image"> </div> <p><b>A</b></p> <ul style="list-style-type: none"> <li>* Select the Wireless Network, GPS Satellite and GPS Help (allowing access to the GPS Help server). GPS(outdoors), WiFi and 3G Network(indoors/outdoors) are all available indoors and outdoors. You should select the GPS Satellite for precise positioning.</li> <li>* Select the GPS Satellite together with the GPS Help(allowing access to GPS Help server).</li> </ul> <p>(The GPS Help feature is automatically chosen upon your selecting the GPS Satellite on 2X and higher products.) The satellite information is downloaded to the phone via the server, which guarantees more precise and faster display of positioning information.</p>



No	FAQ	Q&A
5	<b>Q</b> The downloaded application isn't compatible?	<p>You need to check out if the application is interoperable with the current OS version on your smartphone.</p> <p>Go to SetUp&gt;check out the Android version in use on the smartphone under the Phone Info. Check out the OS version supported on the Download Page for apps downloaded.</p> <p>Download the version interoperable with the OS.</p> <p>Some applications may not be interoperable due to resolution issues, e.g. Pad/ Optimus View.</p>
6	<b>Q</b> How do I make an e-mail account?	<p><b>A</b></p>  <p>Depending on models, menus may differ from the screen above.</p>
7	<b>Q</b> E-mail registration doesn't work.	<p><b>A</b></p> <p>Make sure you've entered correct ID and Password.</p> <p>Check out if the internet connection is properly done via 3G/WiFi.</p>

No	FAQ	Q&A
8	<b>Q</b>	Unused application shows up as a using program even though it is all killed. What should I do?
	<b>A</b>	<p>On Android OS system, default apps keep working automatically in the background in favor of OS stability and better system performance. Such apps are displayed in the process list even after the user ends apps with the Task Killer.</p> <ol style="list-style-type: none"> <li>1. Task Killer will end an application.</li> <li>2. Services necessary for phone operation are run automatically in the background and displayed on the list, although the applications are not run (i.e. applications that need keep running).</li> <li>3. When you run any functions on the phone, the service internally called will in turn call relevant process, which will be displayed on the list (i.e. applications called along for fast driving and safe program running).</li> <li>4. A particular operation will automatically call relevant processes, which are showed on the list. The processes vary depending on applications. Some apps needed for background tasks will be displayed on the list even when they are ended.</li> </ol> <p>When you set the Task Killer to Auto Kill the entire items, functions necessary for daily use (e.g. Kakao Talk) will be forcefully ended, causing trouble.</p>

No	FAQ	Q&A
9	<b>Q</b>	Wifi connection doesn't work well.
	<b>A</b>	<p>Internet connection speed may vary depending on wireless internet line, speed spec, the number of users connected and signal cancellation.</p> <p>1) Internet line(wireless internet). Wireless routers generating Wi-Fi signals are connected to internet lines or wireless internet. Depending on the lines connected to the internet, maximal Wi-Fi speeds may have limits.</p> <p>* Check out if the wireless router supports normal data speed.</p> <p>* Benchbee app can measure WiFi and 3G speeds.</p> <p>2) Speed spec. Wi-Fi protocols have developed in the order of 802.11b-&gt;g-&gt;a-&gt;n. 802.11n provides the best speed, which cannot be used to the full if either the wireless router sending the signal or the smartphone receiving it does not support the protocol.</p> <p>3) Number of users connected: Speed may drop when a number of users are connected to an AP.</p> <p>4) Signal cancellation: Prevailing Wi-Fi signals around city centers cause crosstalks and fading, leading to disconnection or aborted connection.</p>
10	<b>Q</b>	How do you install the PC Sync Program?
	<b>A</b>	Connect the phone to USB-> 'USB Connection Type' screen appears->select PC Software->Screen for LG PC Suite Installation Guide appears>download and install.
11	<b>Q</b>	How do you install the Phone driver?
	<b>A</b>	Go to <a href="http://www.lgmobile.co.kr">www.lgmobile.co.kr</a> . Download Center at the top->search the Model Name->download the Driver.

No	FAQ	Q&A
12	<b>Q</b>	How to connect internet/data network
	<b>A</b>	<ol style="list-style-type: none"> <li>1.Press the Menu and go to Setup.</li> <li>2.Press More on Wireless and Network</li> <li>3. Select Mobile Network</li> <li>4. Tick off the Data Connection Allowed.</li> </ol>
13	<b>Q</b>	What should I do to connect PC Sync program with the phone?
	<b>A</b>	<p>My Computer-&gt;click right side for Attributes-&gt;Hardware-&gt;run 'Device Manager'</p> <p>In Win 7, Control Panel-&gt;System-&gt;run 'Device Manager'</p> <p>Click Modem under the Device Manager and see the Tree.</p>  <p>Check out if LGE Android Platform USB Modem is there as in the blue section above. Or, if there is one, check out if the icon has a yellow exclamation mark(!).</p> <p>Unless the modem above is there, or if the icon has the ! mark, disconnect the cable and reconnect it. If it still does not work, turn the phone off and turn it on.</p> <p>If the modem abovementioned is there, or unless the yellow ! is seen, click the right side on the modem and go to Attribute Menu-&gt;click the Diagnosis tab in the popup window-&gt;click the Modem Query</p>  <p>If the test window as above stays for over 1 min, or when any error messages pop up, try #5 and reconnect or reboot the phone.</p>

No	FAQ	Q&A
14	<b>Q</b>	Can language be changed?
	<b>A</b>	For language setting, try the right button at the bottom->System Setup->Language and Input->Language Or, select the Setup App in the Menu and set the language at the Language and Input
15	<b>Q</b>	How do you Reset and Factory Reset?
	<b>A</b>	Select Setup App in the Menu. Then, Backup and Factory Reset->Factory Reset->select Factory Reset for the phone
16	<b>Q</b>	I want to change the bell sound.
	<b>A</b>	Select the Setup App from the Menu. Then, select Sound->Bell Sound
17	<b>Q</b>	Is it compatible with other devices?
	<b>A</b>	1. Bluetooth 2. Wifi-direct
Development requests		ex) 1. Bluetooth 2. other
18	<b>Q</b>	How do you use HDMI?
	<b>A</b>	The model does not support the function.

No	FAQ	Q&A
19	<b>Q</b>	HDMI error occurs.
	<b>A</b>	The model does not support the function.
20	<b>Q</b>	How do you use Smart Share?
	<b>A</b>	<p>Your phone can share the media content on the network with other players.</p> <ol style="list-style-type: none"> <li>1. Press Menu -&gt; select SmartShare. <ul style="list-style-type: none"> <li>- Wi-Fi network connection should work. If not, a screen for Wi-Fi connection will appear.</li> </ul> </li> <li>2. At 'From,' set up the library to view the content list. <ul style="list-style-type: none"> <li>- The content list on the device will be displayed, if any devices were connected previously.</li> </ul> </li> <li>3. Set up a content player at 'To.' <ul style="list-style-type: none"> <li>- Only applicable devices (e.g. DLNA-supported TV, PC etc.) can be set up.</li> </ul> </li> <li>4. Select the item from the content list and play it. <ul style="list-style-type: none"> <li>- Press the content long to play it or view detailed information</li> <li>- Press Menu button and run Play, Upload/Download, Setup and Help features right away.</li> </ul> </li> <li>5. Upload or download to and from the content list. <ul style="list-style-type: none"> <li>- You can upload the content from your phone to other devices.</li> <li>- You can download and save the content from external libraries to your phone.</li> <li>- You can see the download/upload status at the notification bar.</li> <li>- Downloaded/uploaded items are saved in the SmartShare folder.</li> </ul> </li> <li>6. You can set up DMS in the Setup Menu. <ul style="list-style-type: none"> <li>- Search and Browse – Other DLNA-supported devices can search your phone.</li> <li>- Device Name – Set up names and icons to be displayed on other devices.</li> <li>- Auto Connection – Automatically accept requests for sharing from other devices.</li> <li>- File Reception – Allow other devices to upload files to your phone.</li> <li>- My Media – You can share only the media type that you want to share.</li> </ul> </li> </ol>

### 3.CIC AND SERVICE CENTER

---

No	FAQ	Q&A
21	<b>Q</b>	Smart Share error occurs.
	<b>A</b>	Wi-Fi connection is a must for the feature. Double check the Wi-Fi connection.

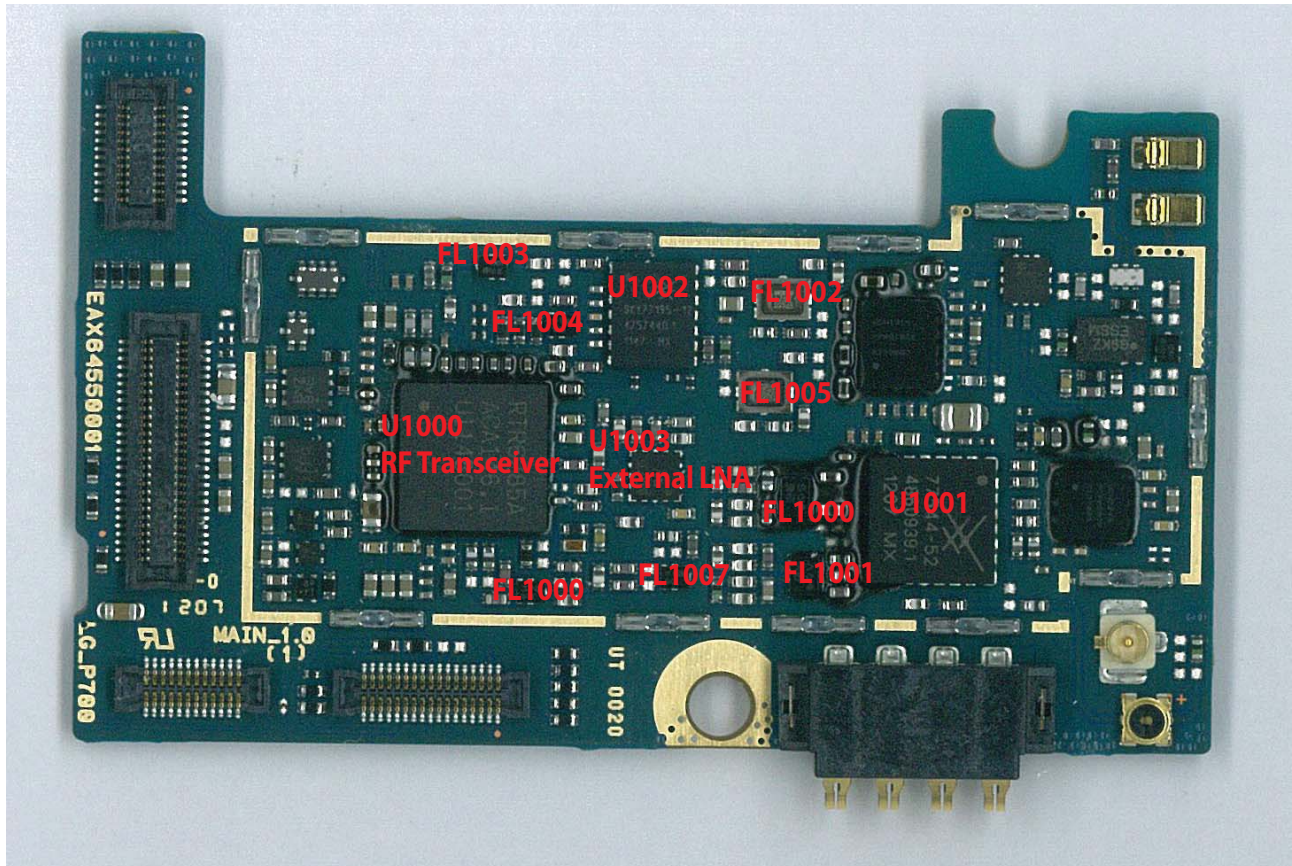
No	FAQ	Q&A
22	<b>Q</b>	Battery consumption is too fast.
	<b>A</b>	<p>* Checklist for battery use</p> <ol style="list-style-type: none"> <li>1) Where few antenna bars are displayed(shadow zones), the phone is considered to be located far from the network. To send and receive the phone's positioning information, more power is needed. Thus, batter power is consumed faster.</li> <li>2) When the screen(LCD Back Light) is turned on, battery power runs out faster. For example, when the electric current of the LCD Back Light is 100mA/h, a 1500-mA battery can last for 15 hours with the LCD being turned on. The longer the screen timeout is set, the faster the battery runs out. So, shorter duration of screen timeout is advisable.</li> <li>3) Even when ending an app by pressing the Home key, the app keeps running in the background, consuming battery power. You are advised to end apps using the Clear/Back key.</li> <li>4) Rooting leads to a Super User Authority in Android system domain, which may cause data modification over the battery control domain, consuming the battery power faster. .</li> <li>5) Apps subject to regular data updates, e.g. Dodol Phone, NateOn, Kakao Talk and Stock/ Weather Widgets may consume the battery power faster, if the update cycle is short.</li> <li>6) On Android phones, cancelling real-time synchronization will save the battery power. Unless you need real-time mail checks or contact synchronization, you are advised to undo the Auto Sync item in the Setup Menu. Then, you can use the synchronization only when you want it, and thus extend the battery power use.</li> <li>7) To install multiple apps at one time, you may as well reboot the system. Many widget apps on the wallpaper may accelerate battery power consumption.</li> <li>8) Battery lasts less on live screen background than on ordinary background screen.</li> <li>9) When Wi-Fi is turned on, the smartphone automatically seeks any Wi-Fi routers or zones around, which consumes the battery power. Turn on Wi-Fi only when you are in any Wi-Fi-available zones and turn it off when it is not necessary. It would be better to cancel the Internet phone 070, which browses Wi-Fi constantly.</li> <li>10) It is advisable to turn off Bluetooth when it is not in use. Once it is turned on, it looks for devices preparing for automatic operation, which may consume the battery power faster.</li> <li>11) Power Control widget will help you manage battery power consumption effectively. You can set or block screen brightness and block Bluetooth in the Main Setup Menu. Android smartphones are basically fitted with the 'Power Control' widget, which guarantees viewing at a glance and easier control over each power-consuming item based on the status of use.</li> <li>12) You can lessen the battery power consumption by setting up battery-saving display modes with 25% of screen brightness, minimizing screen timeout and unsetting animation and illuminance sensor.</li> </ol>



No	FAQ	Q&A
23	<b>Q</b>	How is the distribution schedule of OS or SW new version known?
	<b>A</b>	Refer to the announcement under the Customer Support on <a href="http://www.lgmobile.co.kr">www.lgmobile.co.kr</a> .
24	<b>Q</b>	How do you update the SW?
	<b>A</b>	<ol style="list-style-type: none"> <li>1. Press the Menu and select the Software Update button</li> <li>2. Select the item you want</li> </ol> <ul style="list-style-type: none"> <li>- Update Check: Check new software updates and update software items.</li> <li>- Last Update Date: View the latest date of software updates.</li> <li>- Update Auto Check: Set/unset the automatic update feature. Once set, it automatically checks on a regular basis any new software updates.</li> <li>- Next Update Schedule: Tell the time for automatic update checks.</li> </ul>
25	<b>Q</b>	Until when is it guaranteed after purchase? What is the warranty limit?
	<b>A</b>	<p>"The warranty period of LG home appliances except seasonal products is one year. 1-year warranty is applied to mobile phones as well. However, extra fees may be charged for accessories, consumables and any failure due to consumer's negligence. The same warranty is applied in general to parts.</p>
26	<b>Q</b>	What kinds of phone accessories are there?
	<b>A</b>	TA, data cable, ear mic, manual
27	<b>Q</b>	Please ask and answer 3 expected questions regarding the new product and new features.
	<b>A</b>	ICS OS

## 4. TROUBLE SHOOTING

### 4.1 RF Component

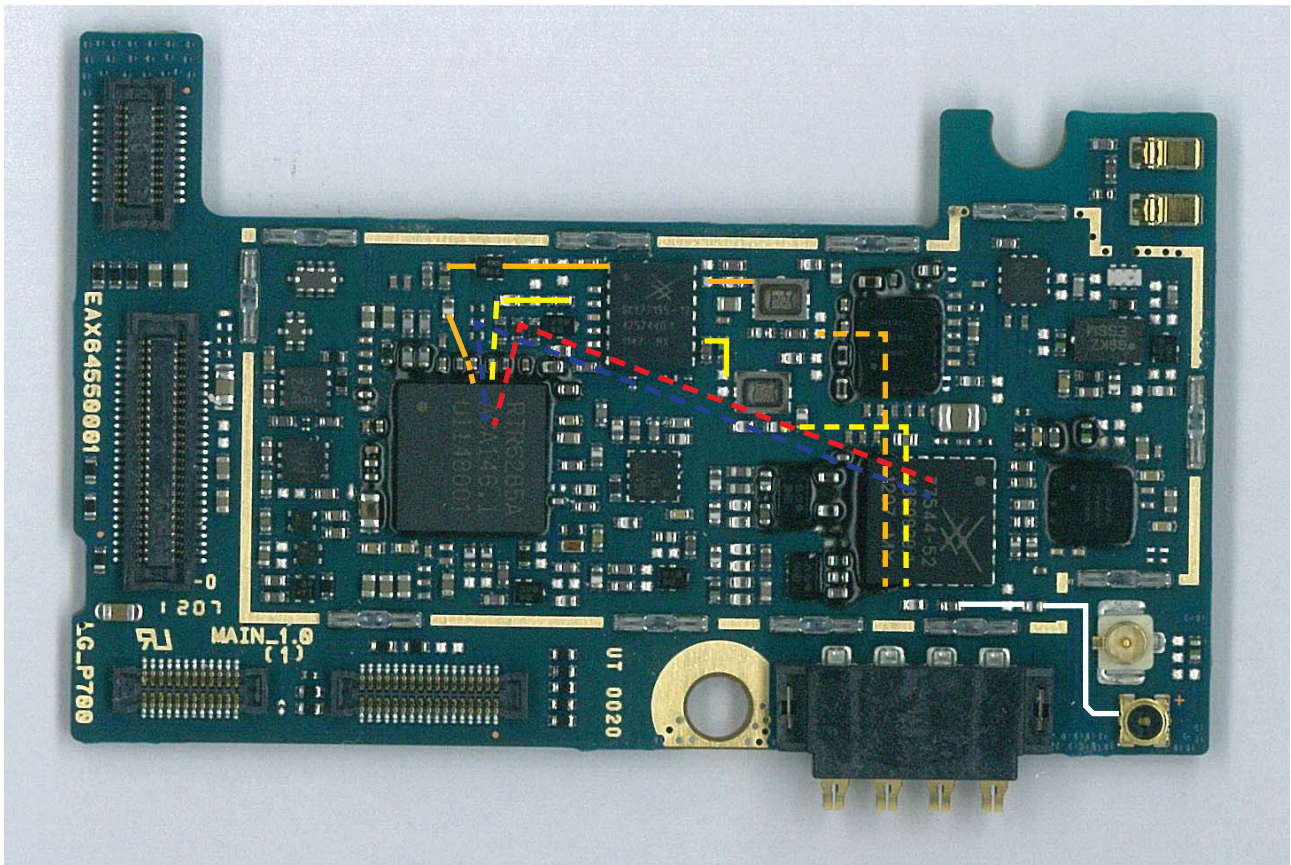


RF component (WCDMA / GSM)

Reference	Description	Reference	Description
U1000	TRT6285A(Transceiver)	FL1002	W900 Duplexer
U1001	FEM + GSM PAM Module	FL1003	W900 RX SAW Filter
U1002	WCDMA Dual (I,VIII) PAM	FL1004	W2100 RX SAW Filter
U1003	WCDMA External LNA	FL1005	W2100 Duplexer
FL1000	GSM L/B SAW Filter	FL1006	W2100 RX SAW Filter
FL1001	GSM H/B SAW Filter	FL1007	W900 RX SAW Filter

### 4.2 SIGNAL PATH

#### WCDMA / GSM Tx PATH



WCDMA 2100 TX PATH

WCDMA 900 TX PATH

GSM Low Band Tx PATH

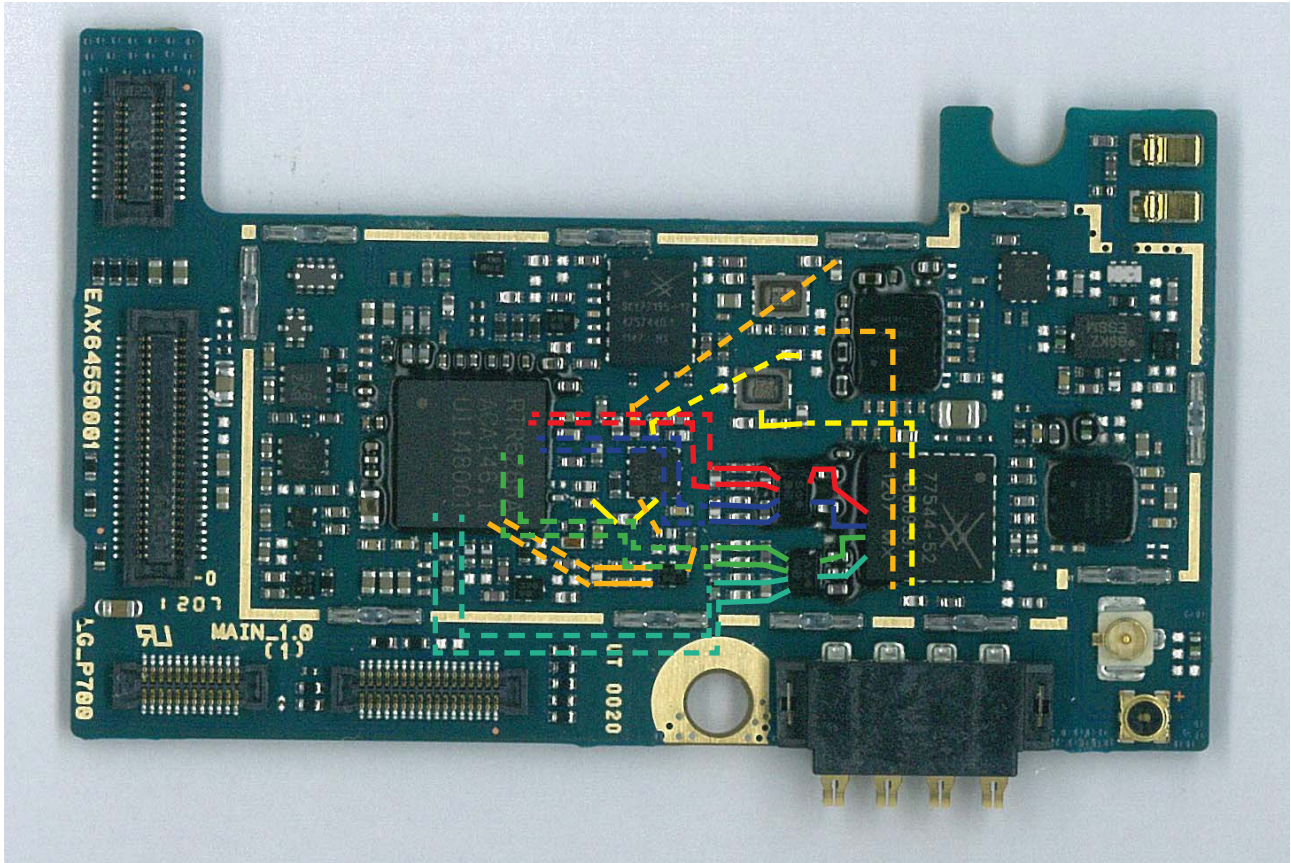
GSM High Band Tx PATH

Common Rx/Tx PATH



## 4. TROUBLE SHOOTING

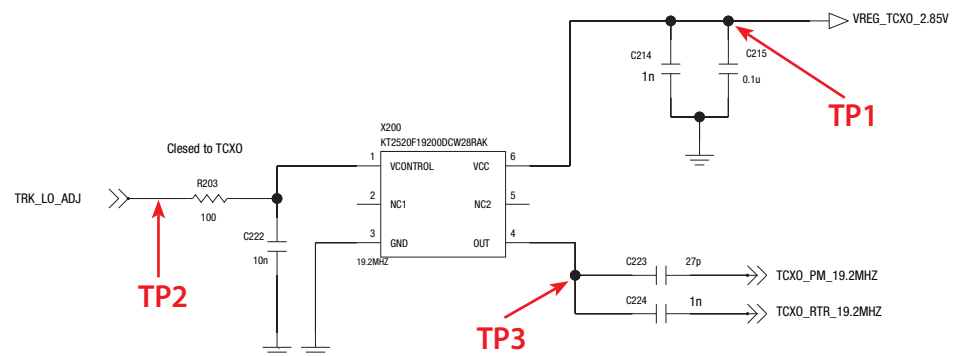
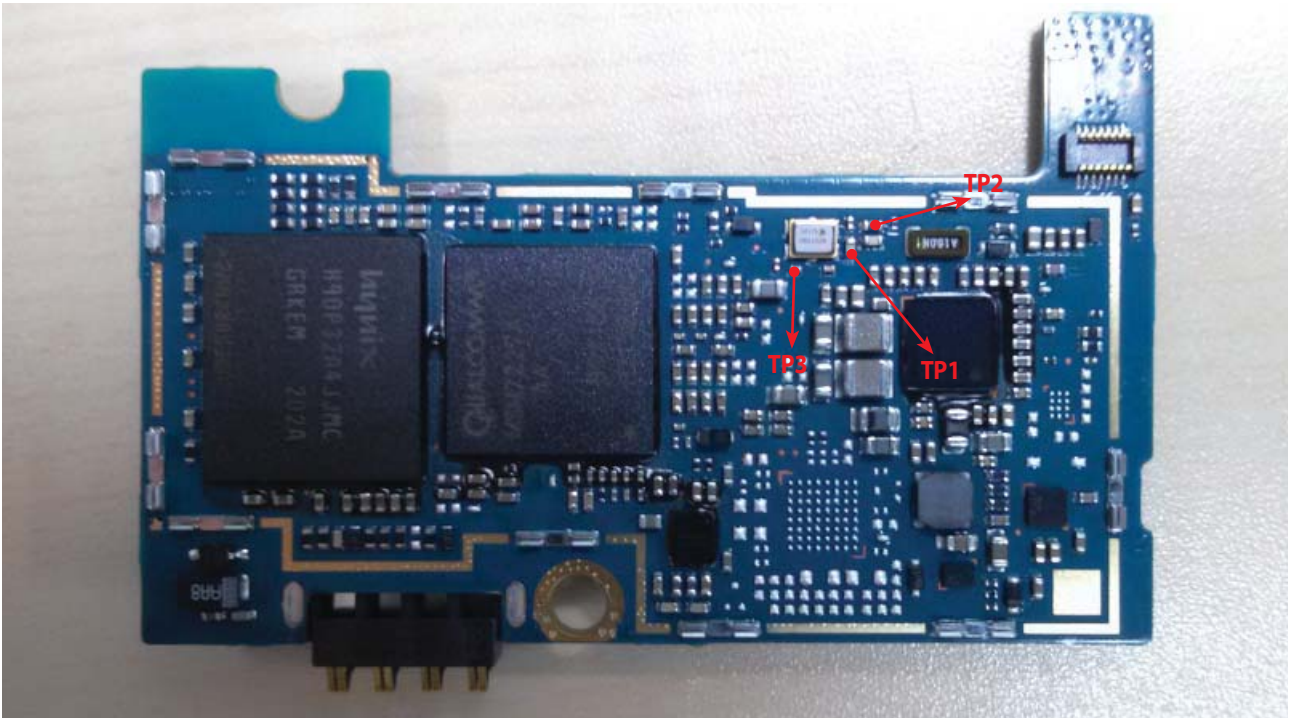
### WCDMA / GSM Rx PATH



- WCDMA 2100 RX PATH
- WCDMA 900/EGSM TX PATH
- EGSM Band RX PATH
- GSM 850 Band Rx PATH
- Common Rx/Tx PATH
- DCS Band Rx PATH
- PCS Band Rx PATH

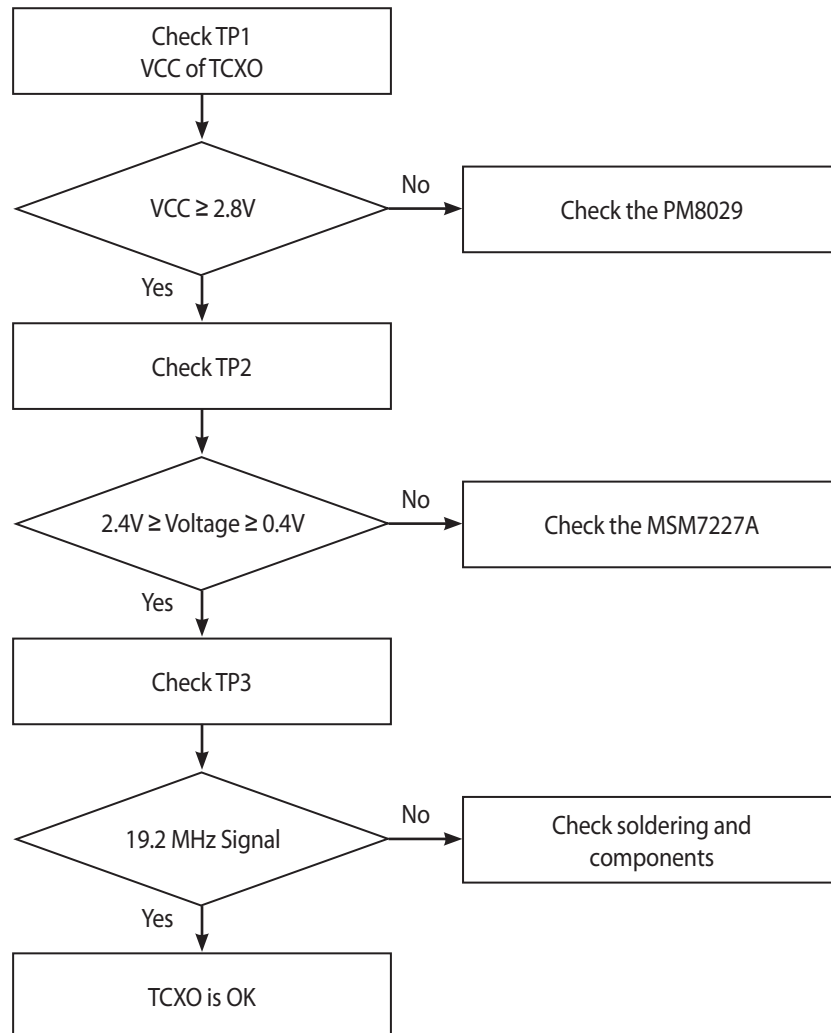
### 4.3 Checking TCXO Block

The output frequency (19.2MHz) of TCXO (X2001) is used as the reference one of RTR6285 and PM7540 internal VCO.



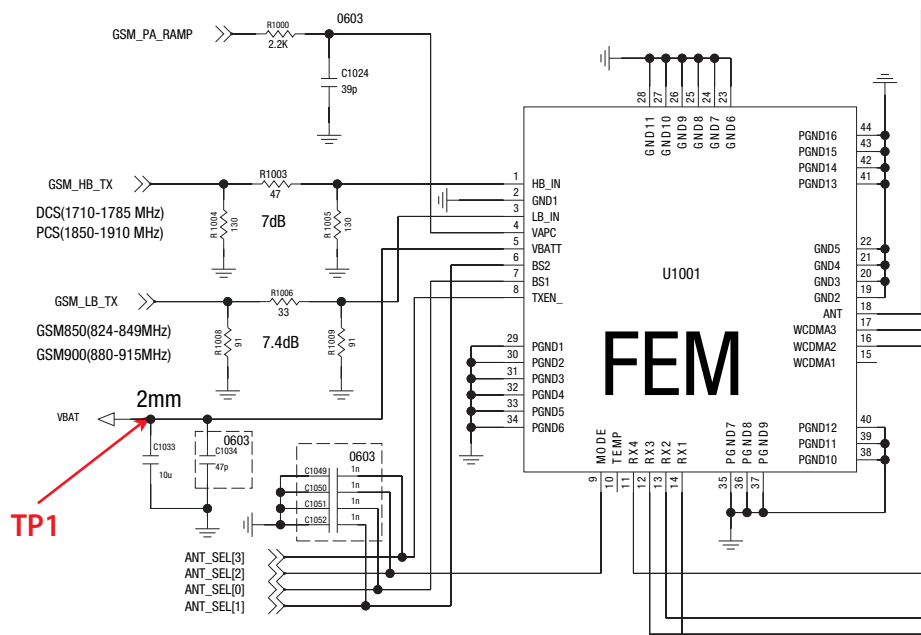
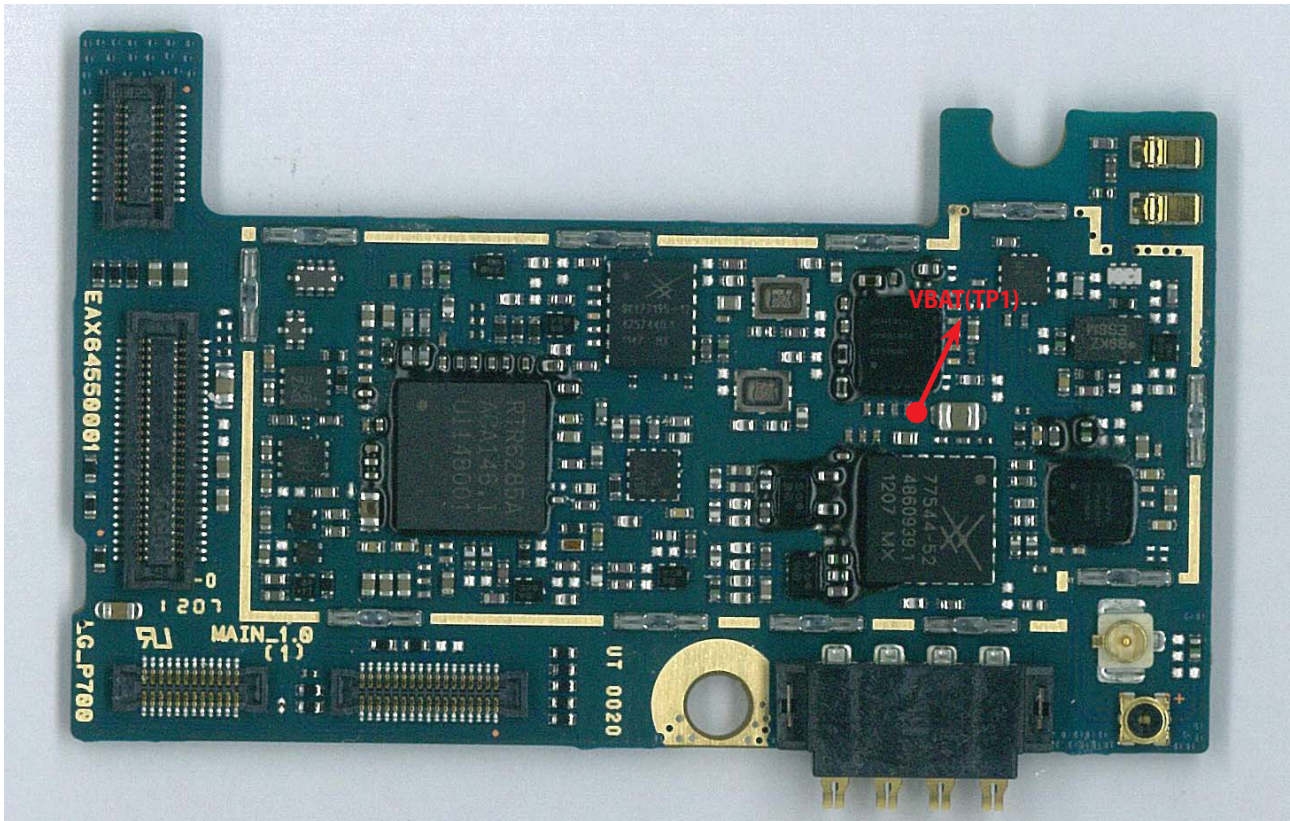
Schematic of the Crystal Part (19.2MHz)

## 4. TROUBLE SHOOTING





### 4.4 Checking GSM TX Module(GSM PAM + FEM) Block



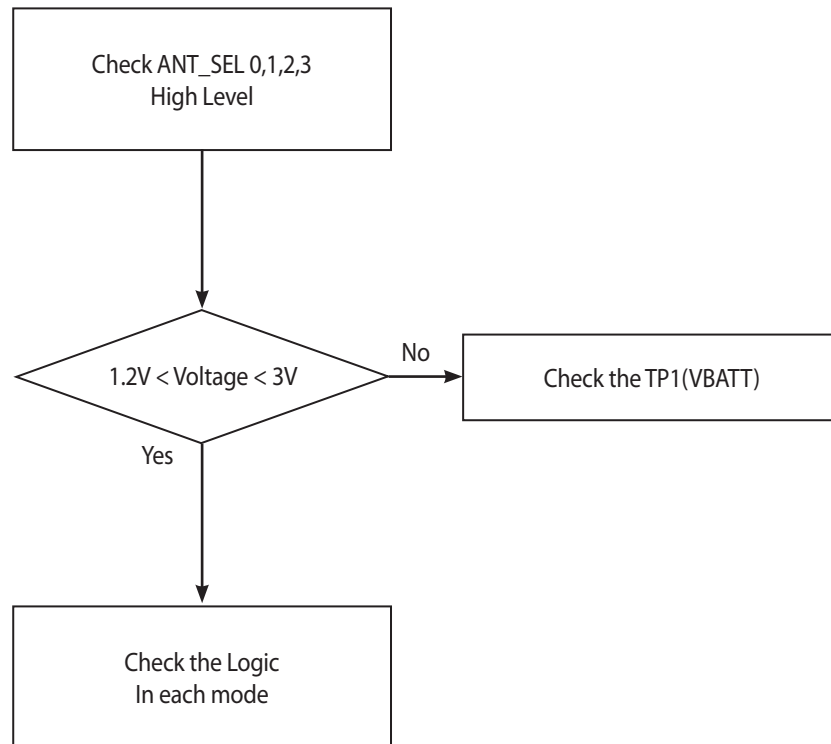
Schematic of the TX Module

### ANTENNA SWITCH MODULE LOGIC(SKY77544)

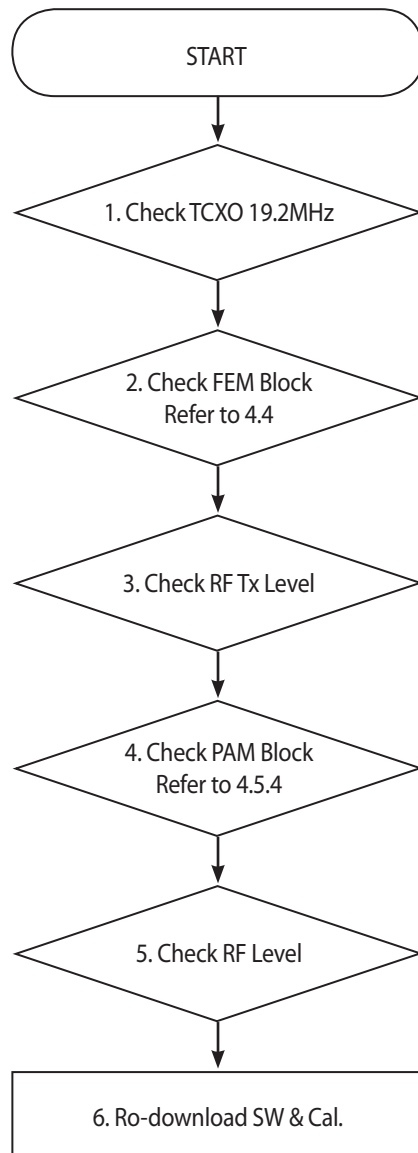
	ANT_SEL0	ANT_SEL1	ANT_SEL2	ANT_SEL3
GSM850/GSM900 TX	LOW	HIGH	LOW	LOW
DCS1800/PCS1900 TX	HIGH	HIGH	LOW	LOW
PCS1900 RX	LOW	LOW	LOW (X)	HIGH
DCS1800 RX	LOW	HIGH	LOW (X)	HIGH
GSM900 RX	HIGH	HIGH	LOW (X)	HIGH
GSM850 RX	HIGH	LOW	LOW (X)	HIGH
W1700	HIGH	LOW	LOW	LOW
W900(W850)	LOW	LOW	HIGH	LOW
W2100	HIGH	LOW	HIGH	LOW



### Checking Switch Block Power Source



### 4.5 Checking WCDMA Block



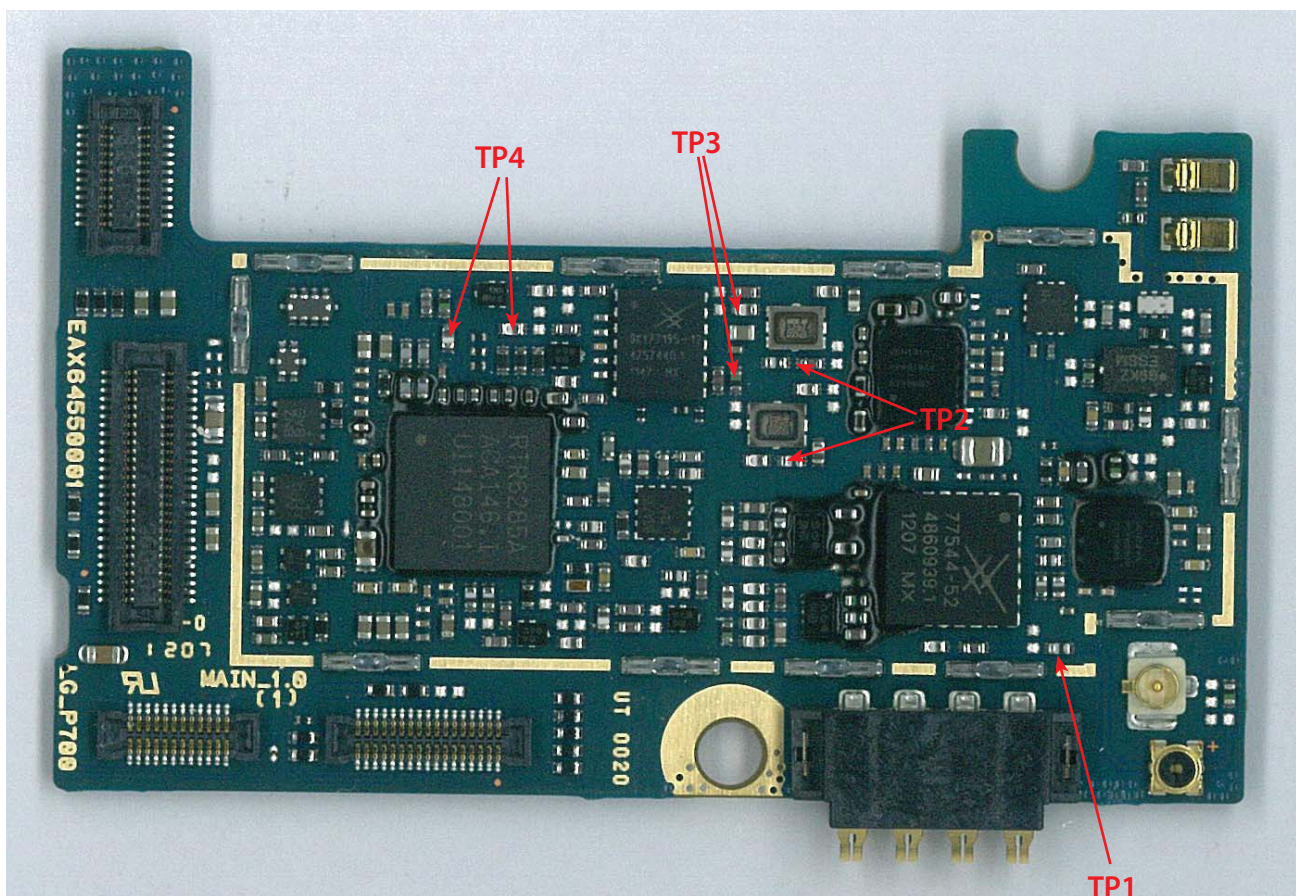
### 4.5.1 Checking TCXO Block

Refer to 4.3

### 4.5.2. Checking FEM Block

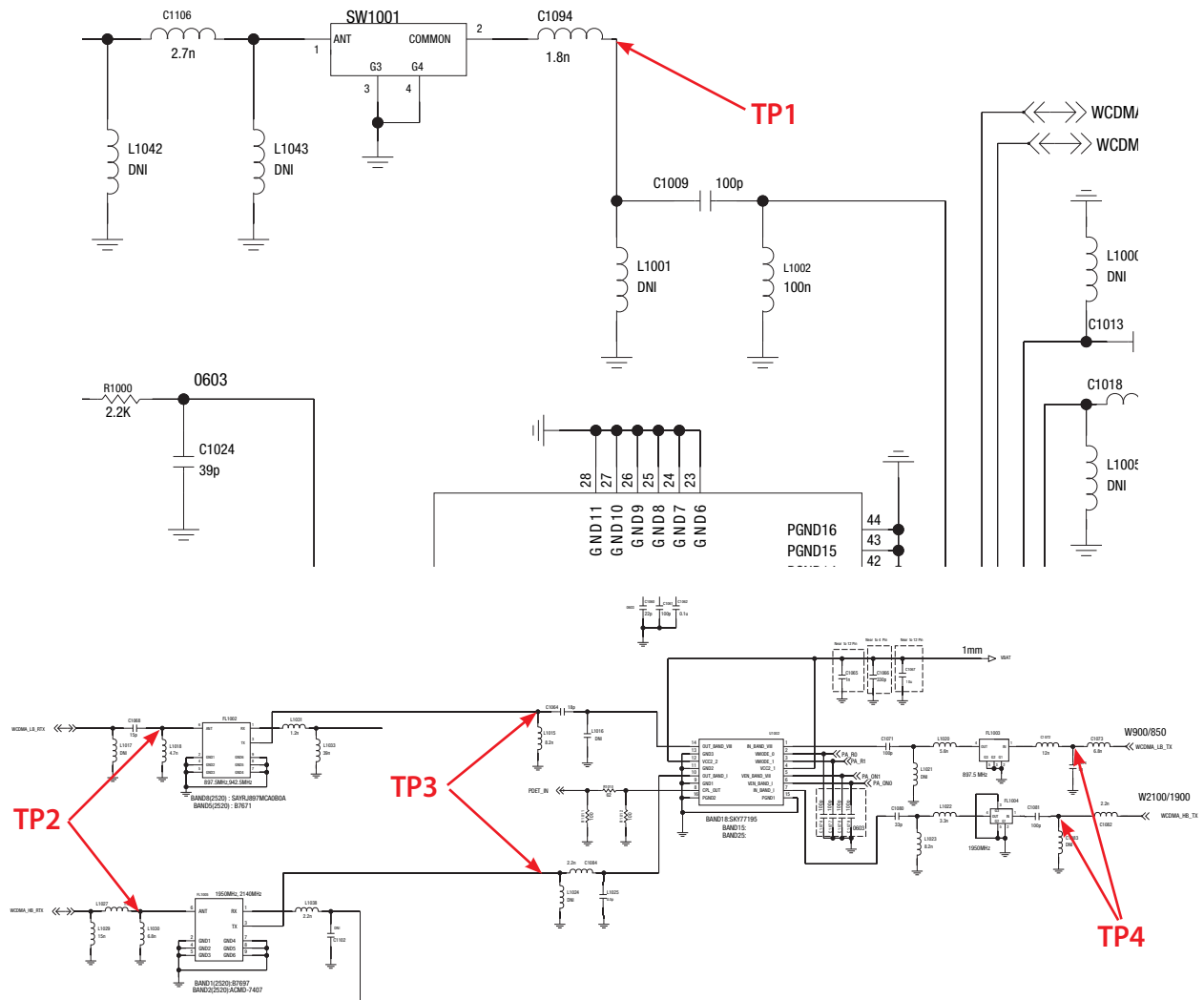
### 4.5.3. Checking RF TX Level

Refer to 4.4



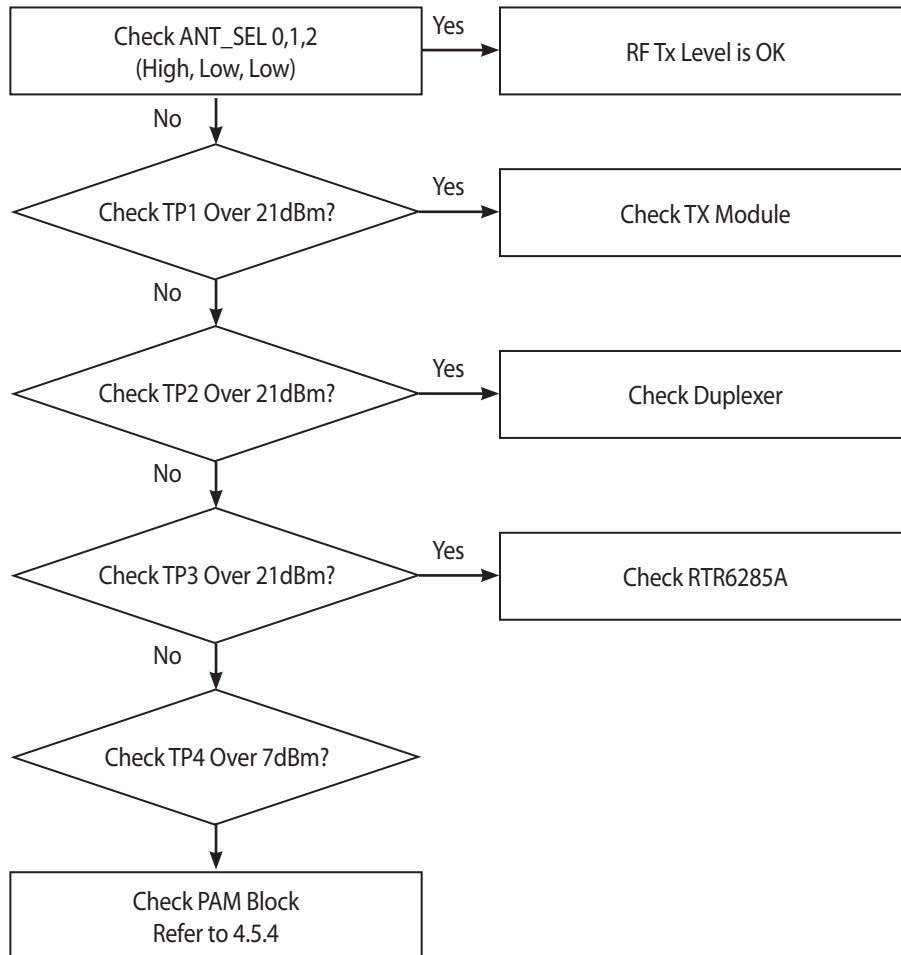
Test Point (TX Level)

## 4. TROUBLE SHOOTING



For testing, Max power output is needed.

## 4. TROUBLE SHOOTING



RTR6285 Maximum output Power = 7 dBm  
RTR6285 minimum output Power = -80 dBm  
PAM(ACPM-5281) = Maximum input Power = 10 dBm



### 4.5.4. Checking PAM Block

#### PAM control signal

PA\_ON0 (C1079), PA\_ON1(C1078) : PAM Enable

PA\_R0: PAM Gain Control

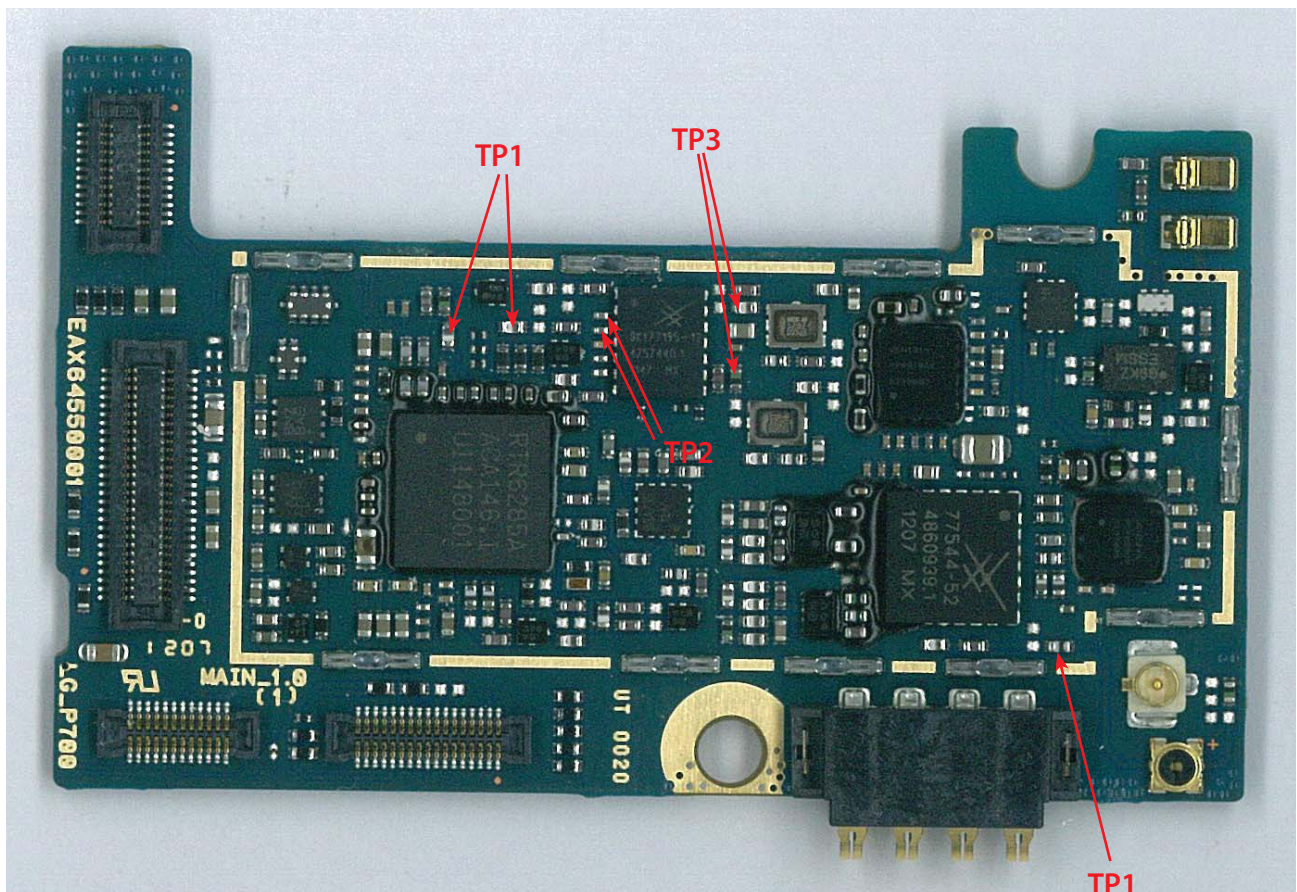
PA\_ON must be HIGH (over 2.6V)

#### PAM IN/OUT Signal

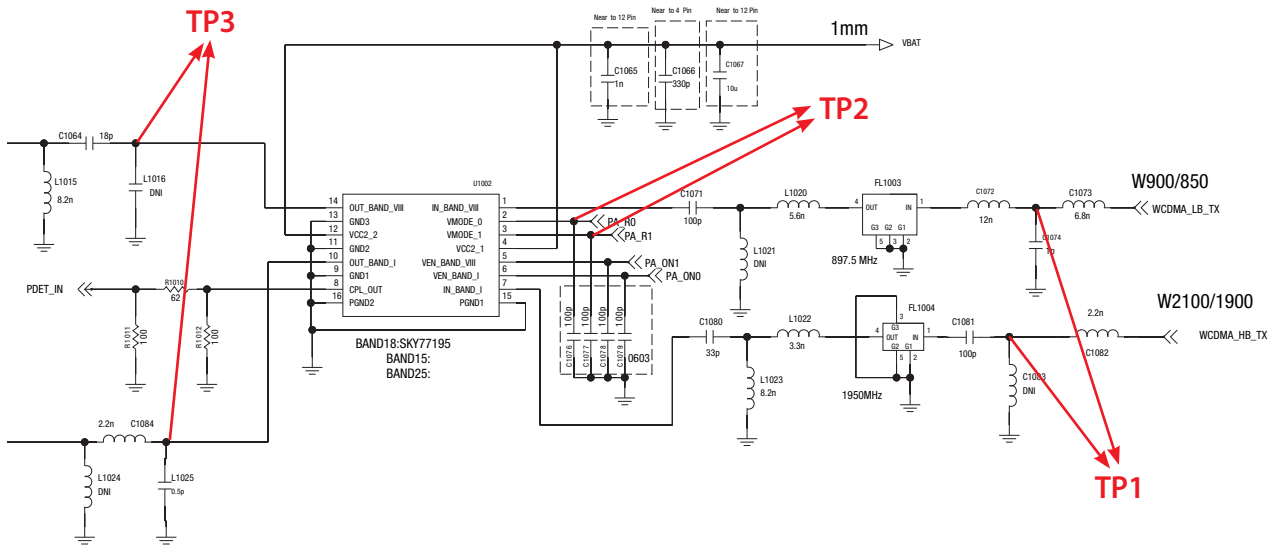
When PAM is under the operation of high power mode (PA\_R0(C1076) : Low),

PAM OUT power must be over 21 dBm

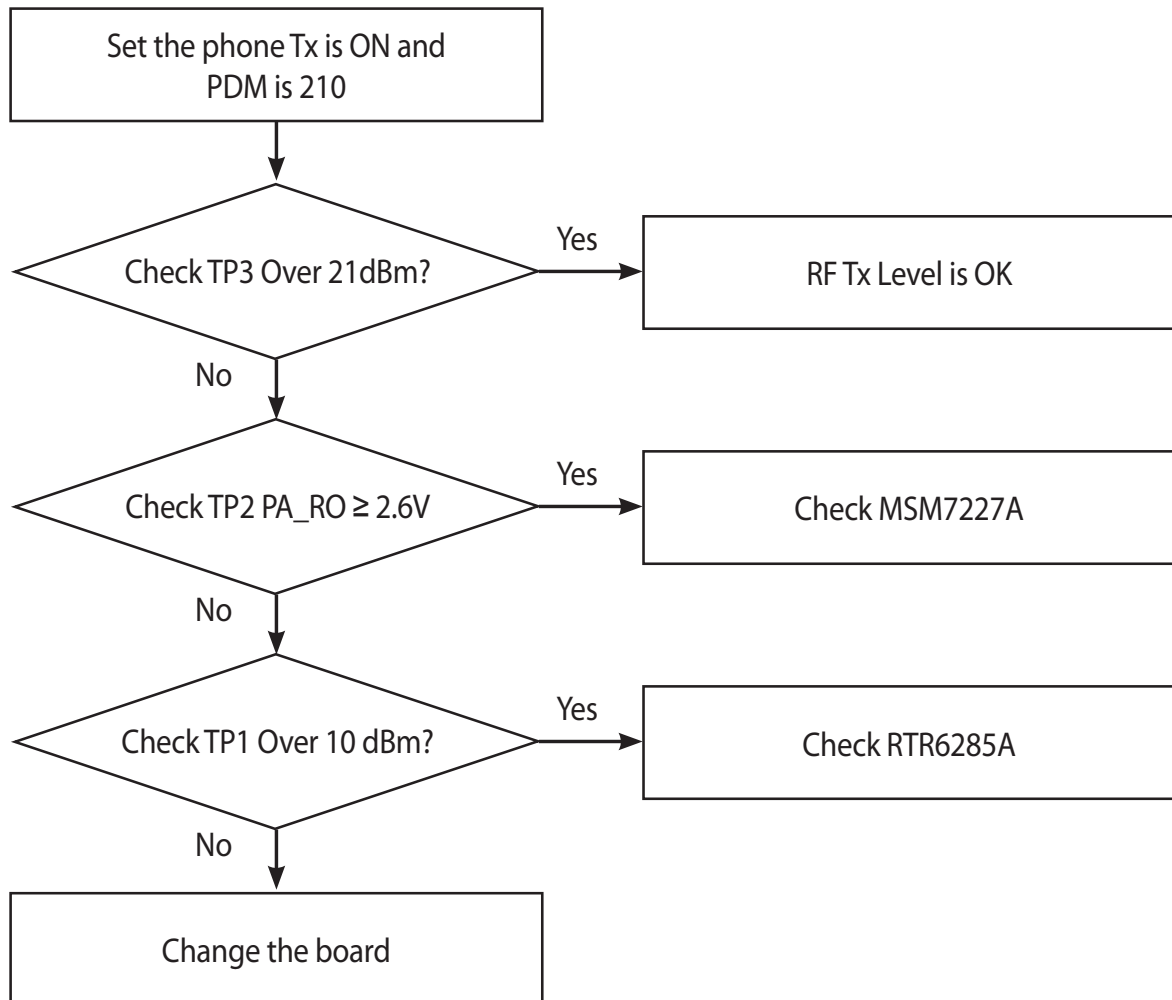
PAM IN power must be under 10 dBm



## 4. TROUBLE SHOOTING

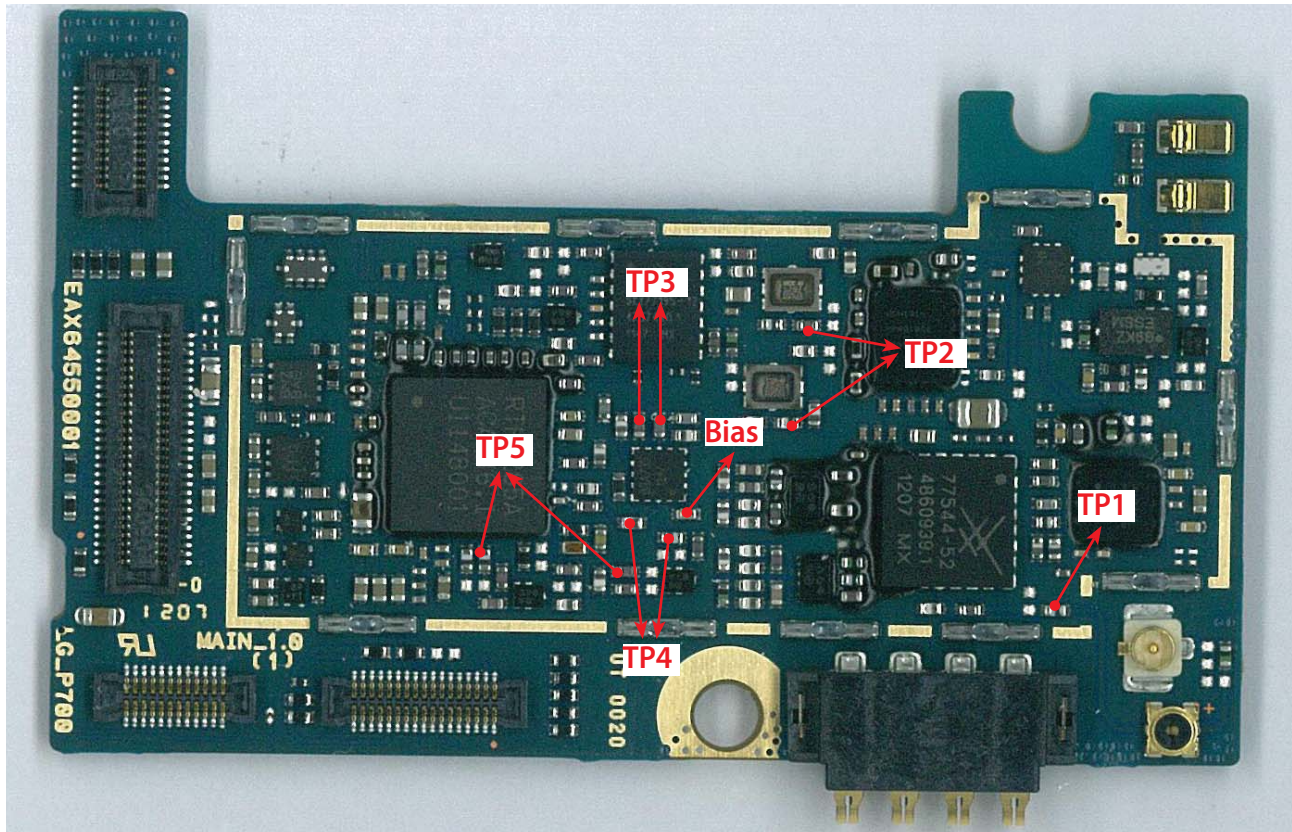


## 4. TROUBLE SHOOTING

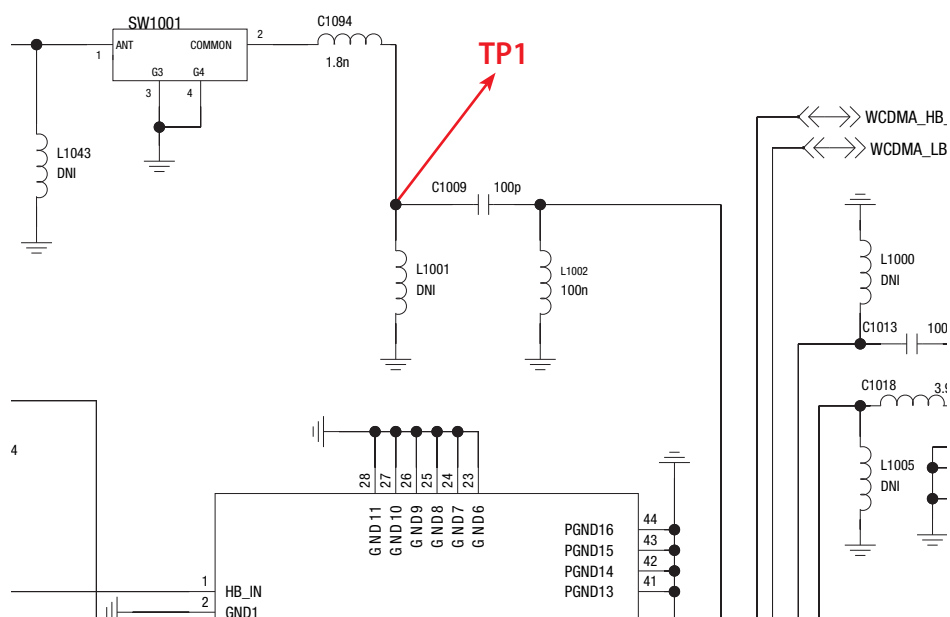




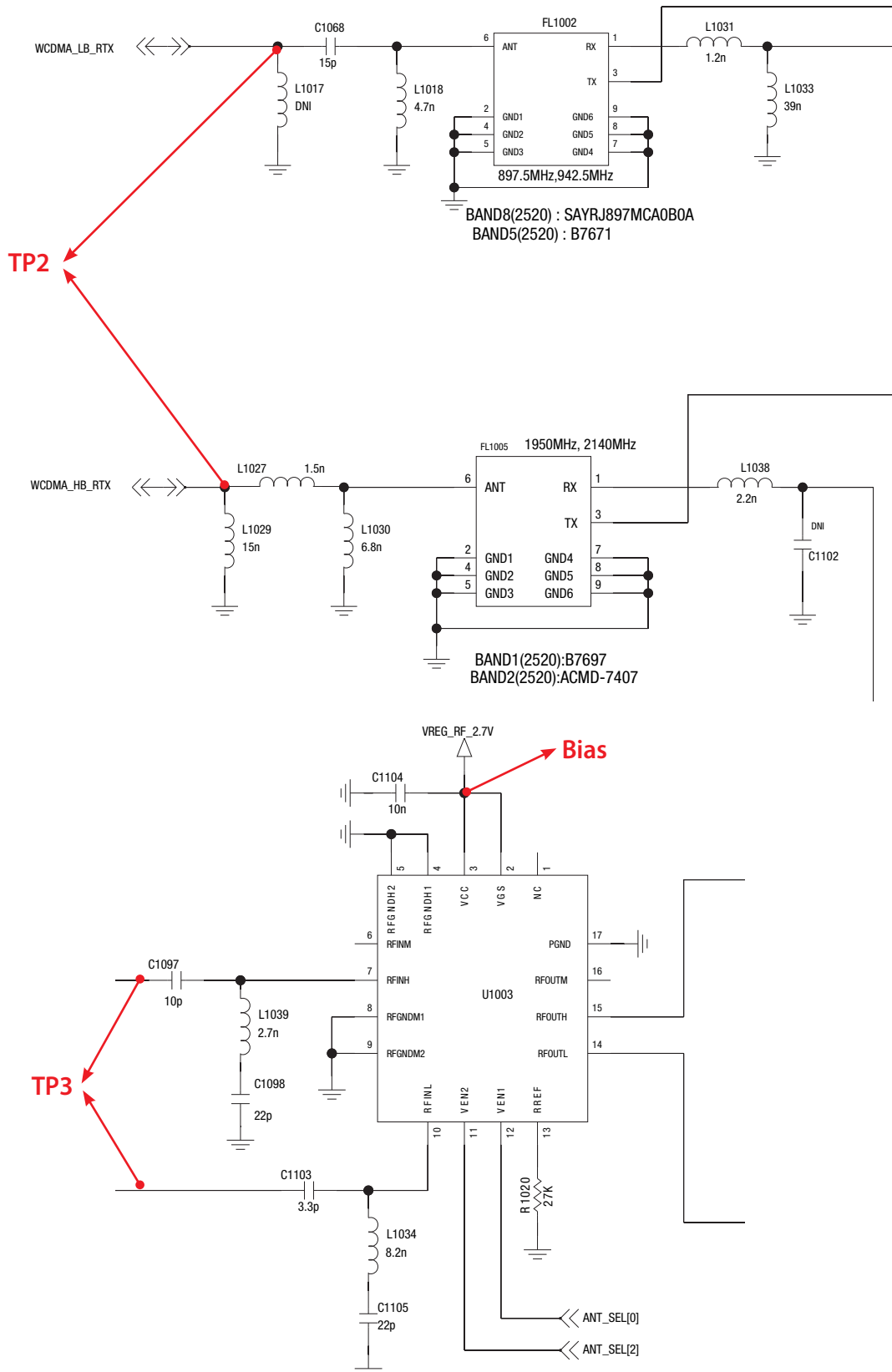
### 4.5.5. Checking RF Rx Level



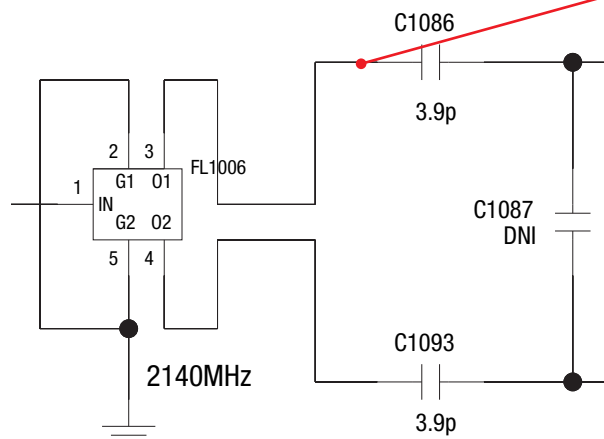
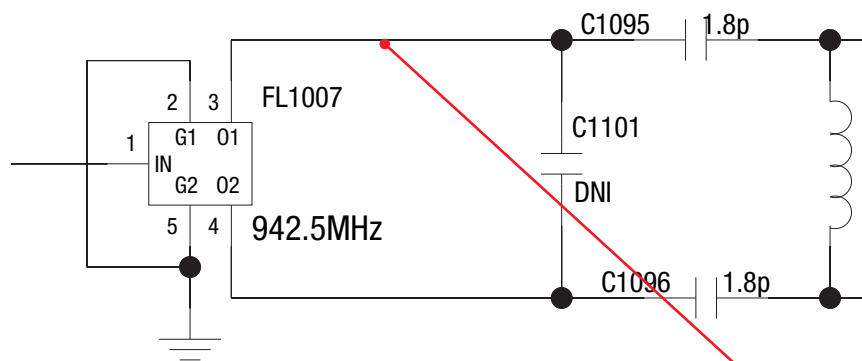
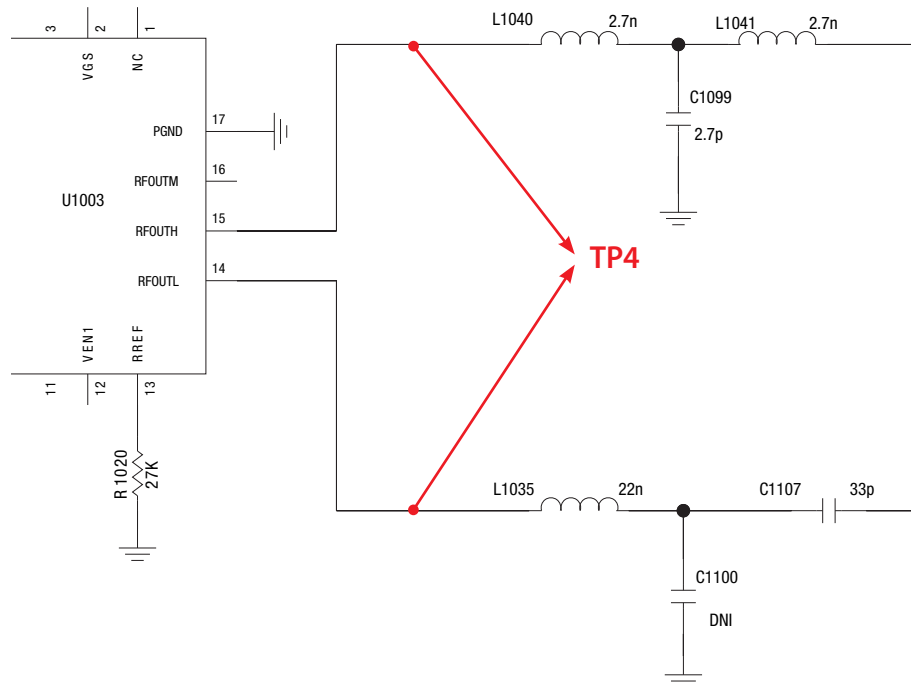
Test Point (RF Rx Level)



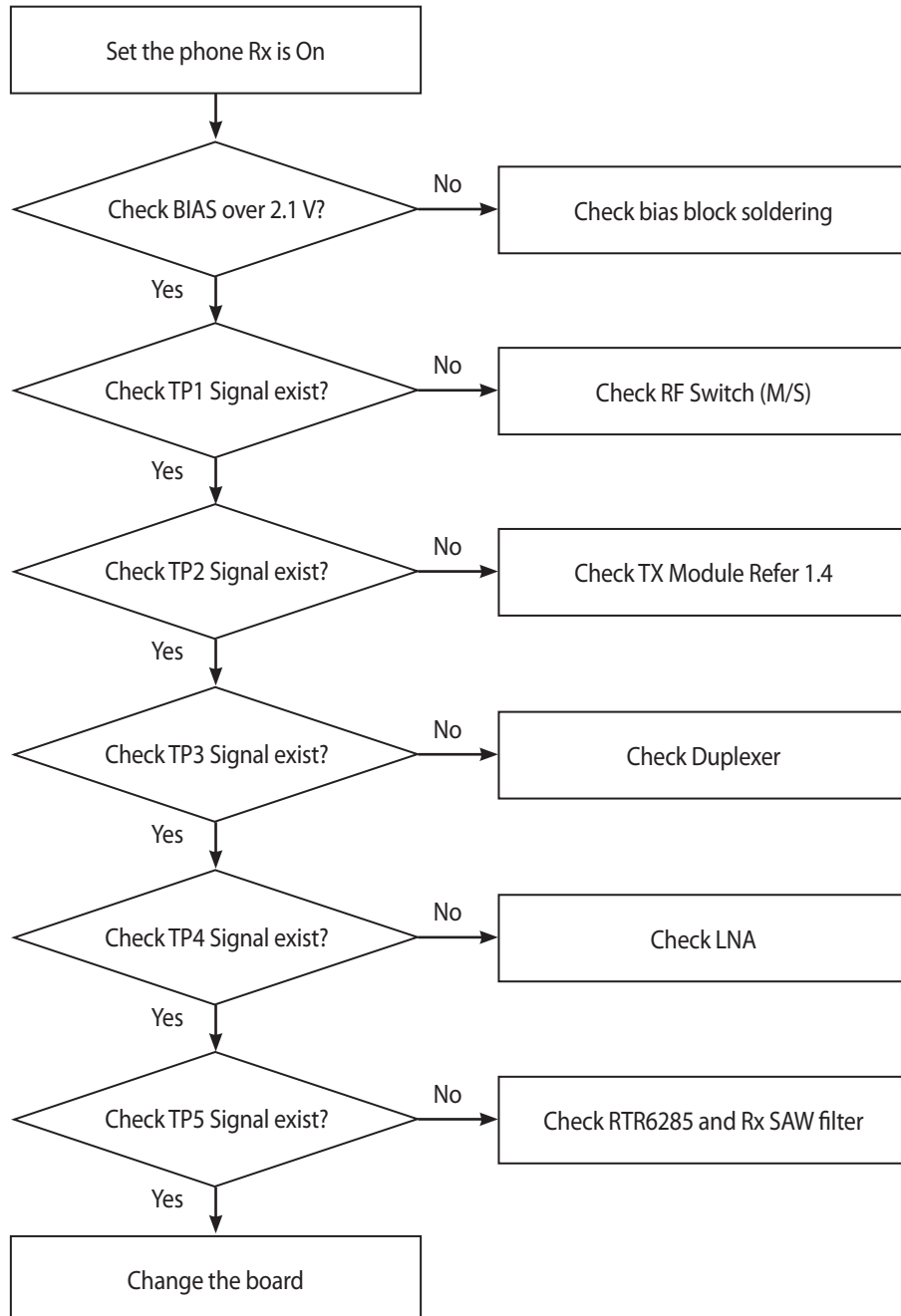
## 4. TROUBLE SHOOTING



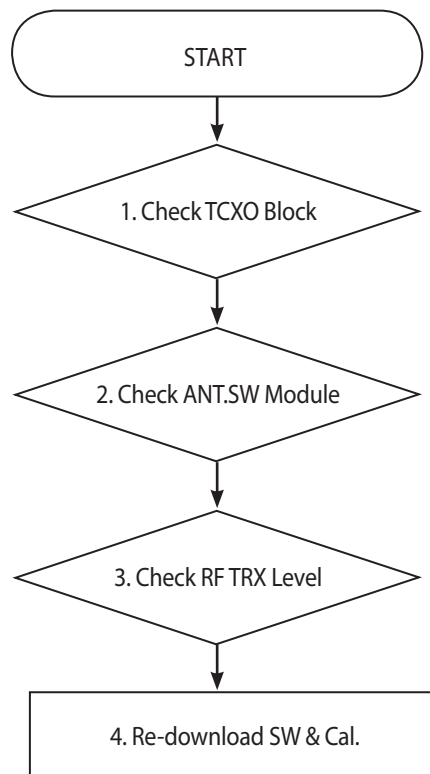
## 4. TROUBLE SHOOTING



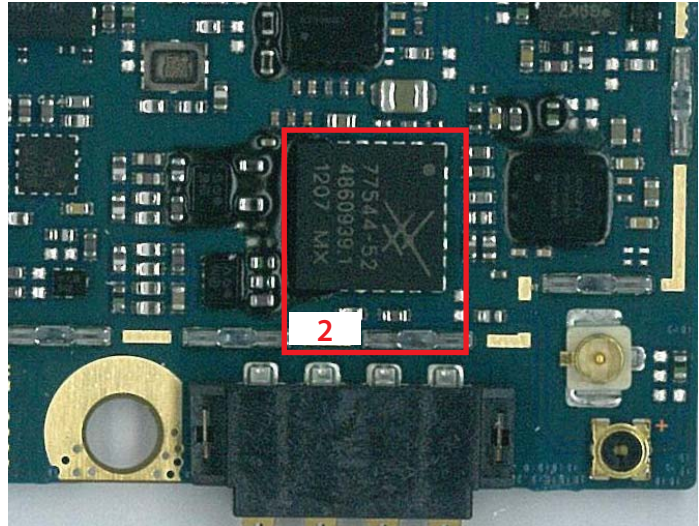
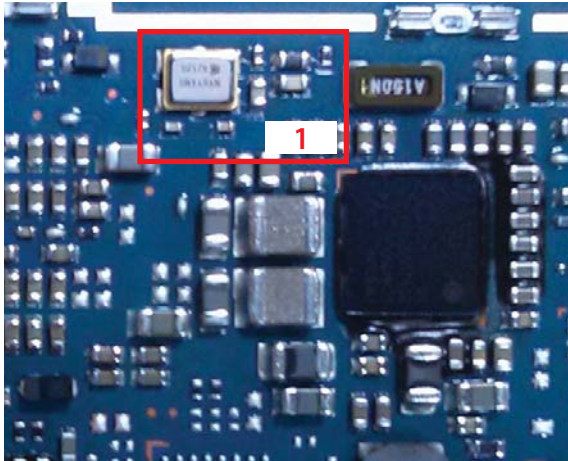
## 4. TROUBLE SHOOTING



### 4.6 Checking GSM Block







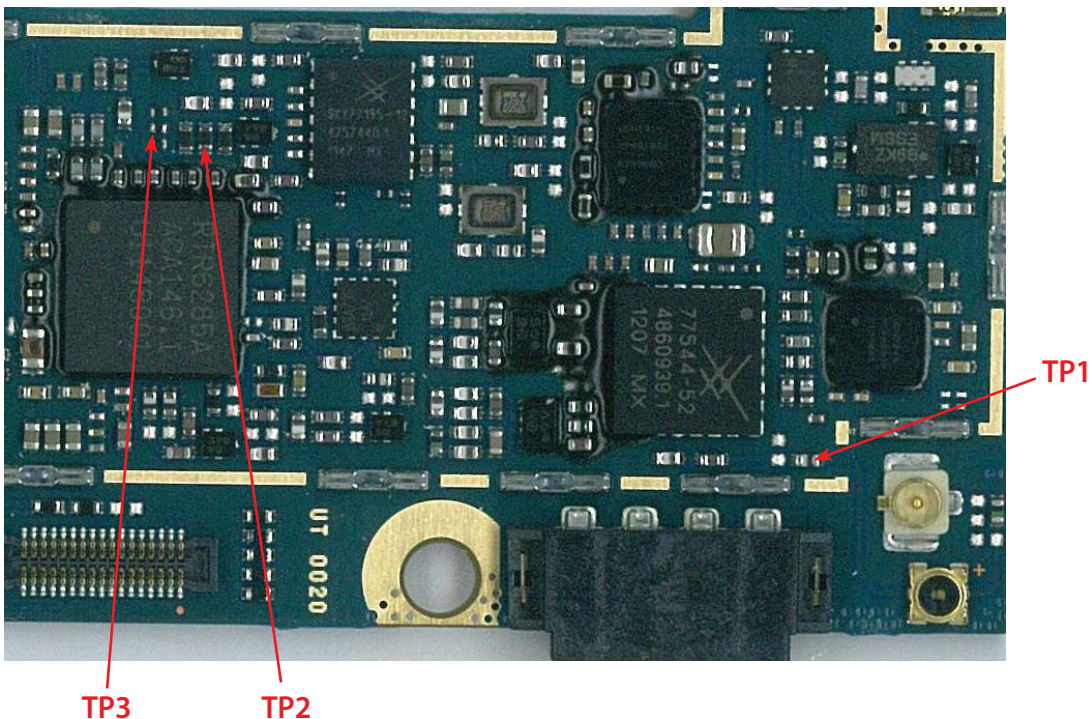
### 4.6.1 Checking TCXO Block

Refer to 4.3

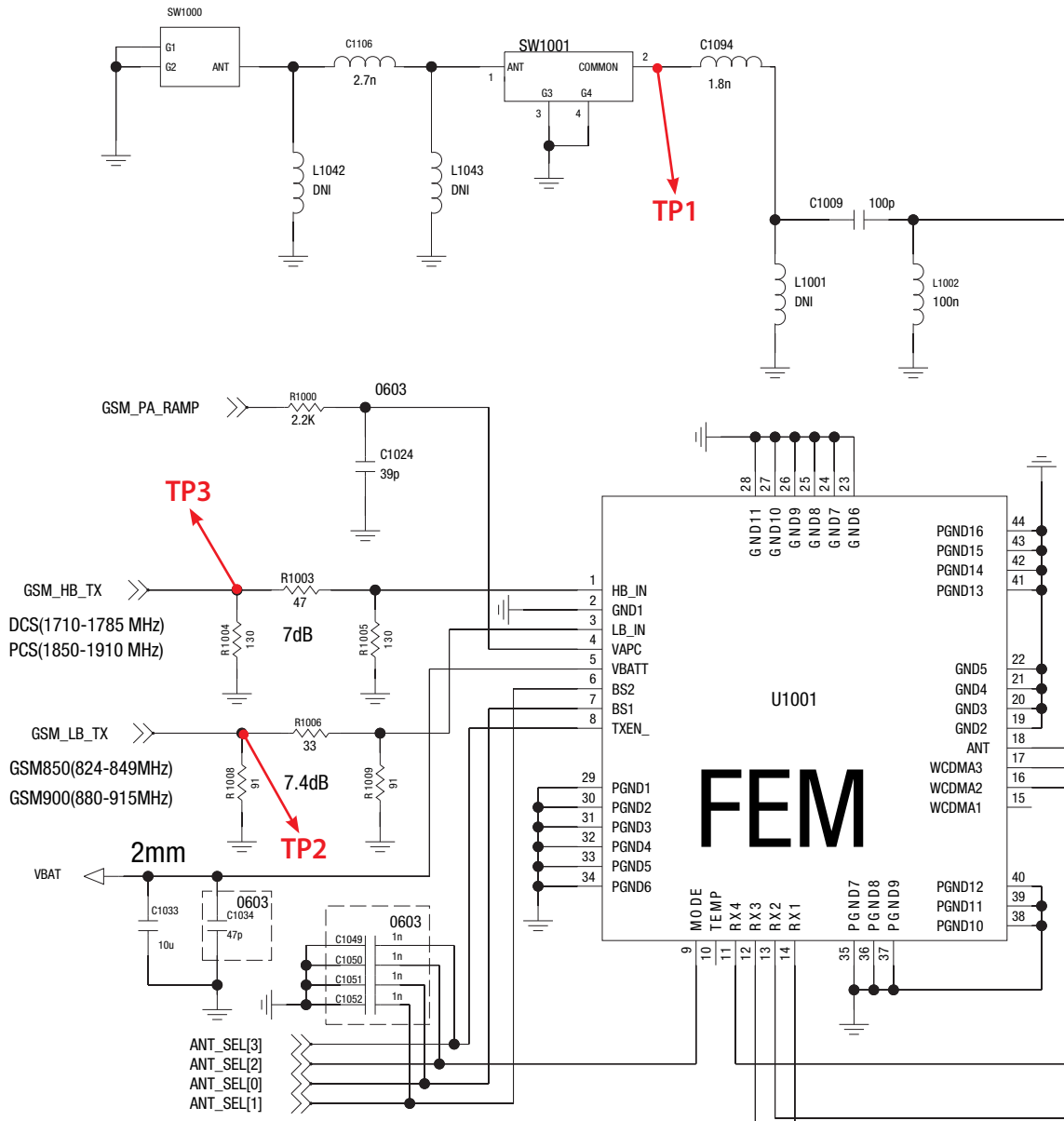
### 4.6.2 Checking FEM Block

Refer to 4.4

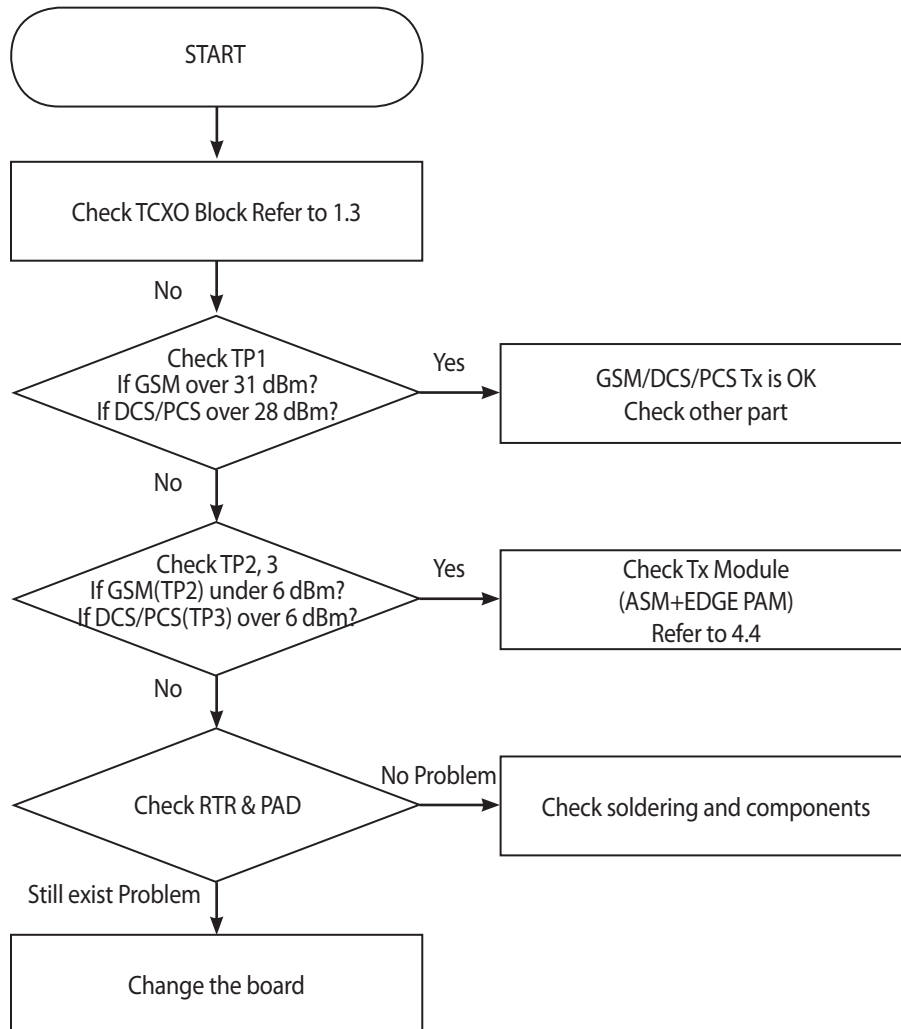
### 4.6.3 Checking RF TX level



## 4. TROUBLE SHOOTING

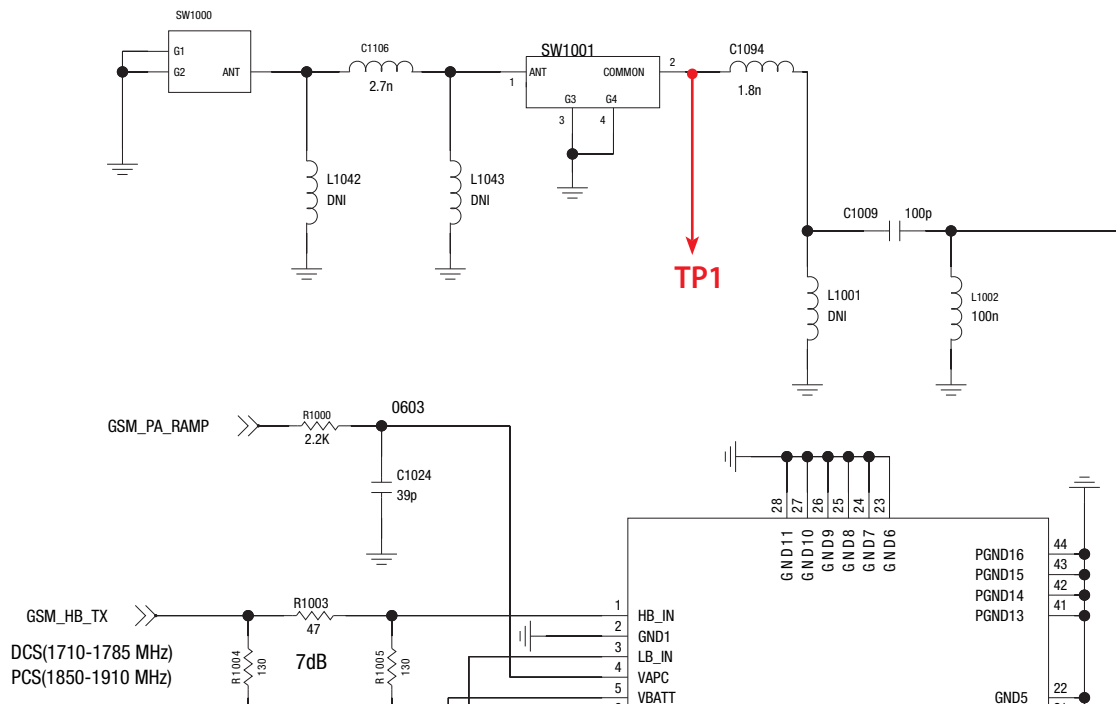
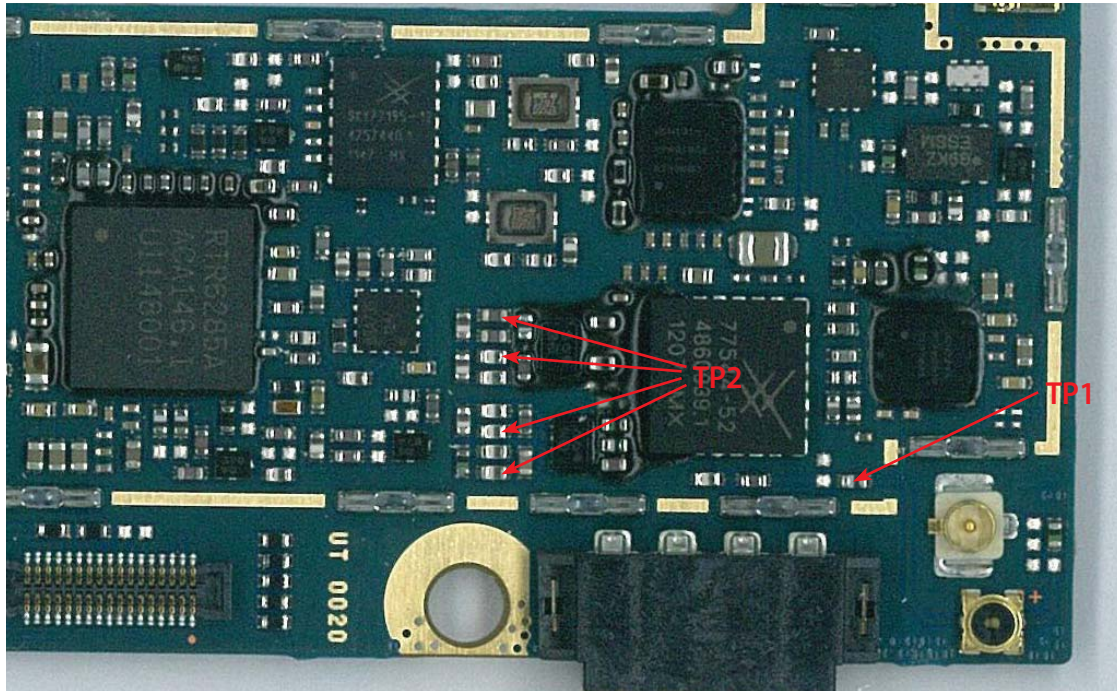


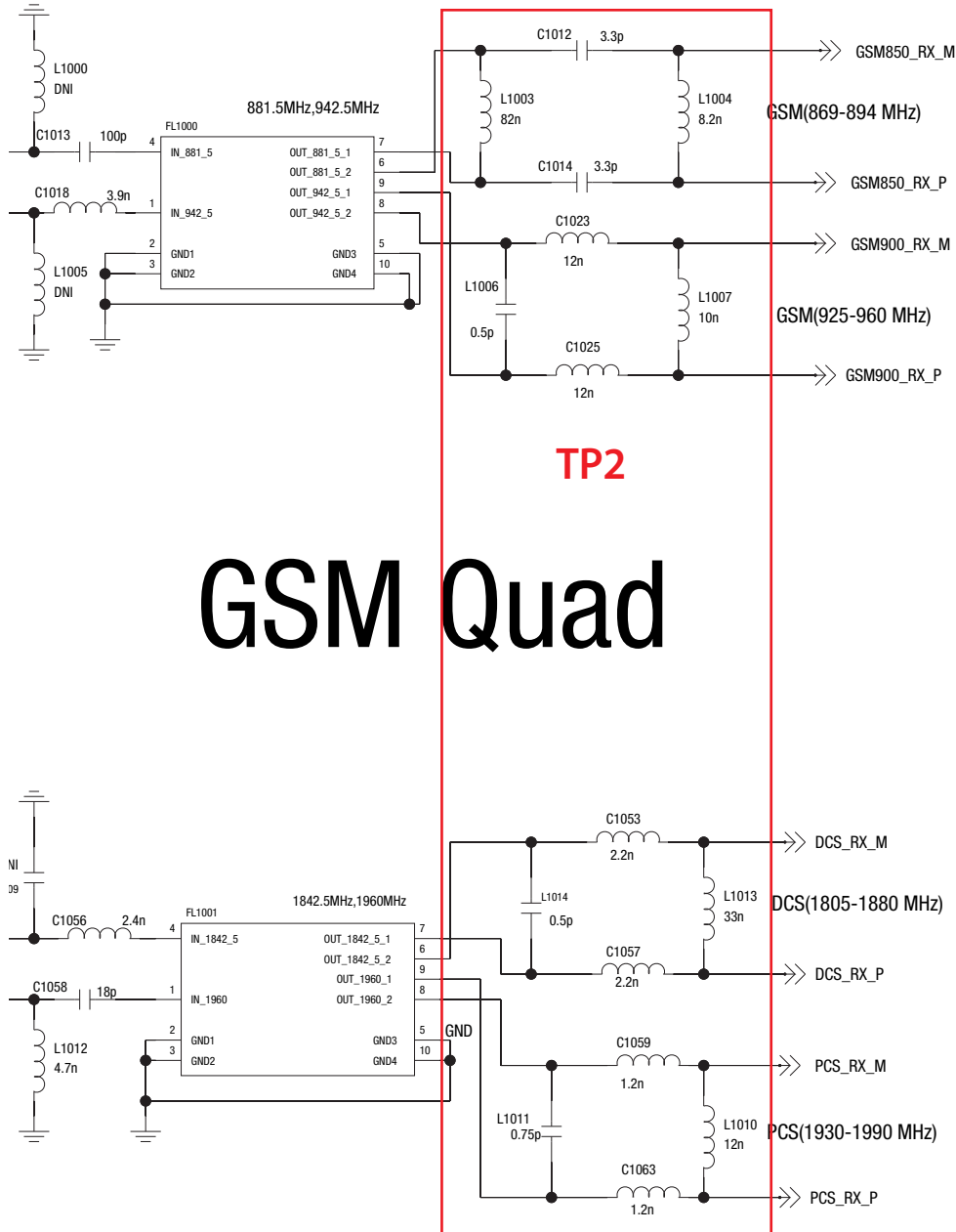
### Schematic of GSM/DCS/PCS Tx Block



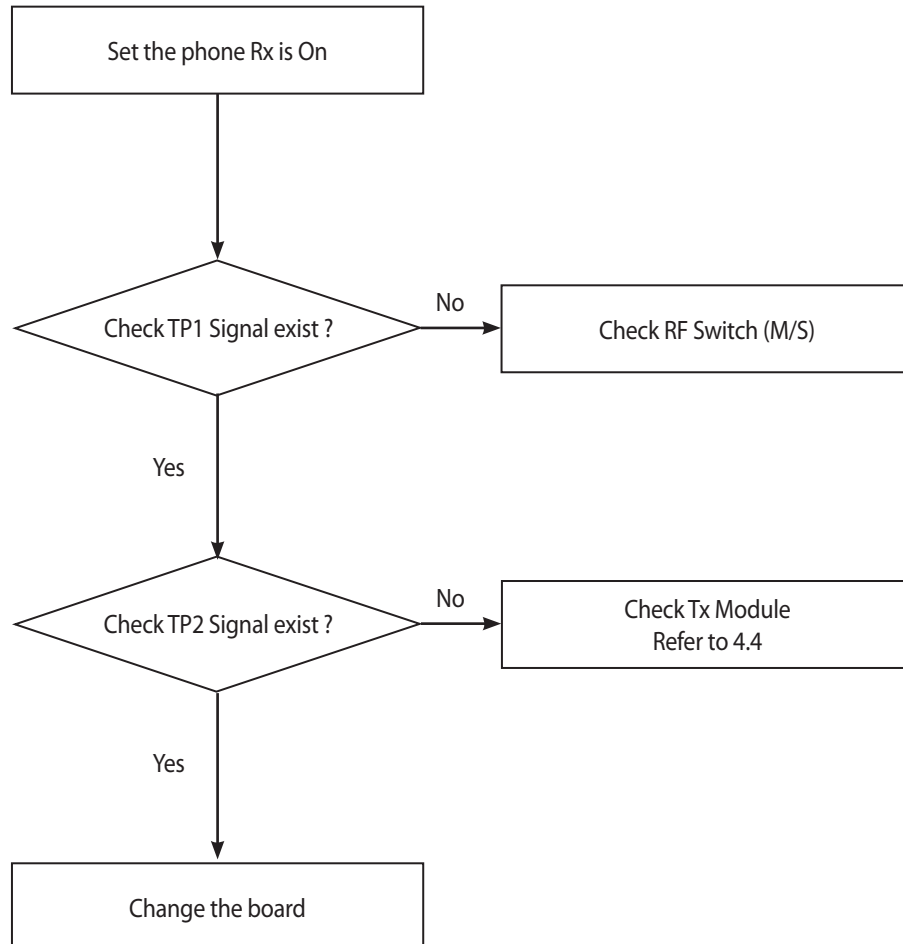


### 4.6.4 Checking RF Rx Block

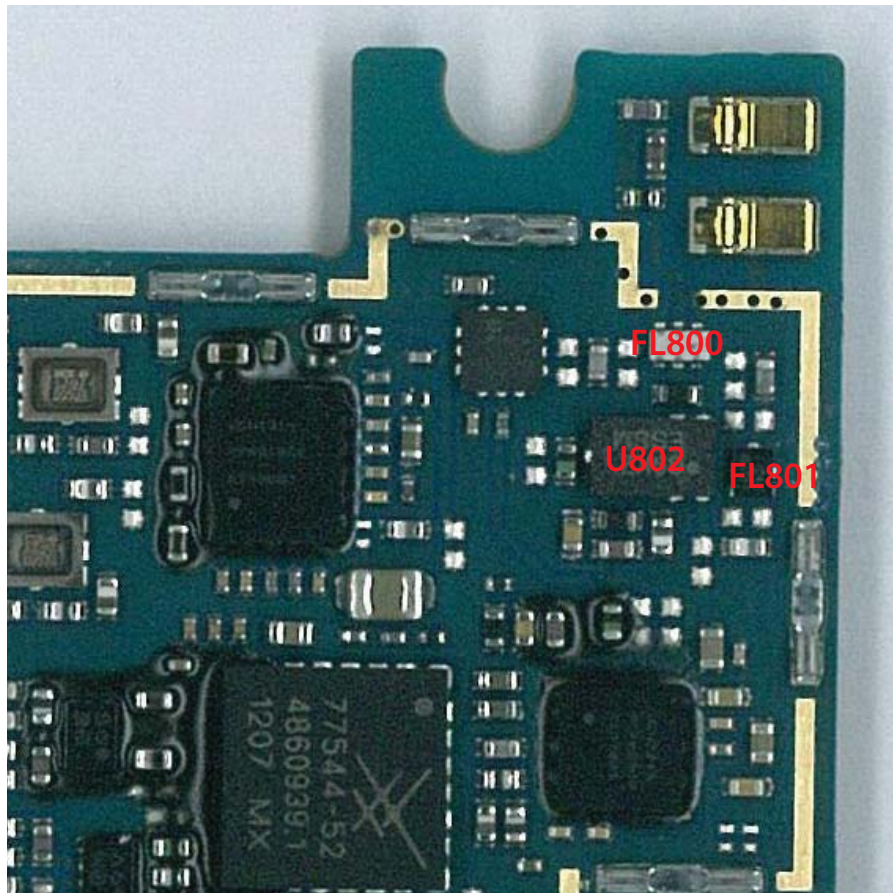




**Schematic of GSM/DCS/PCS Tx Block**



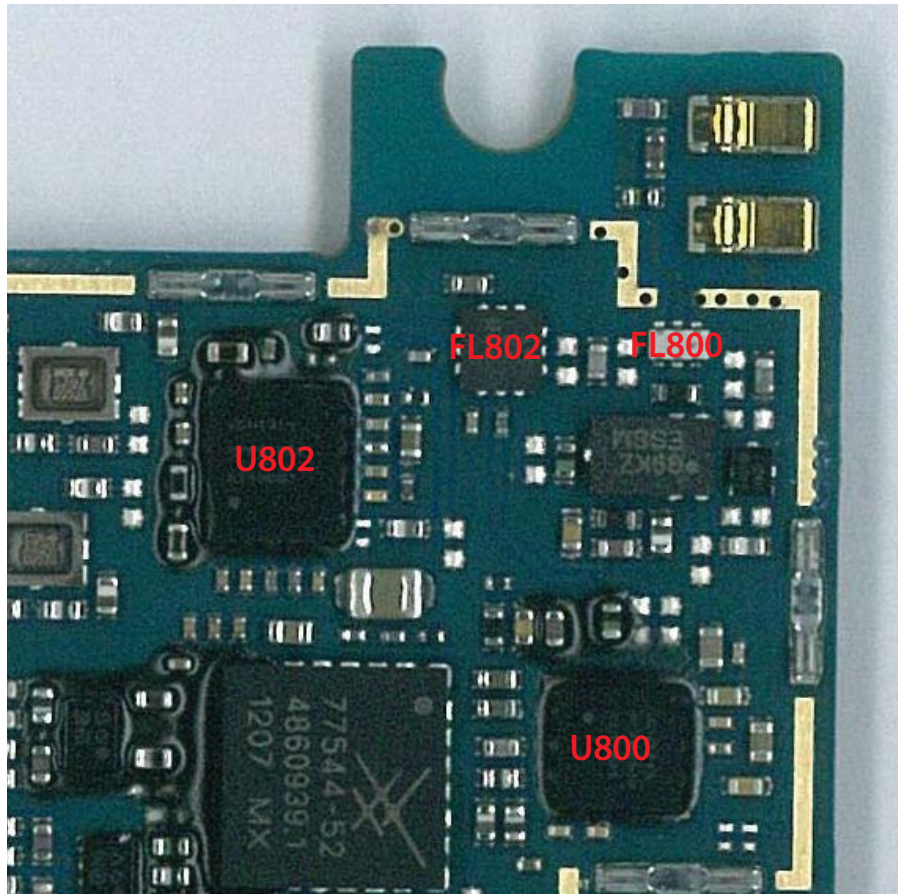
### 4.7 GPS/WIFI/BT/FMR RF Component



**RF Component(GPS)**

Reference	Description
U802	GPS LNA
FL801	GPS SAW Filter
FL800	BT/WIFI/GPS diplexer

## 4. TROUBLE SHOOTING

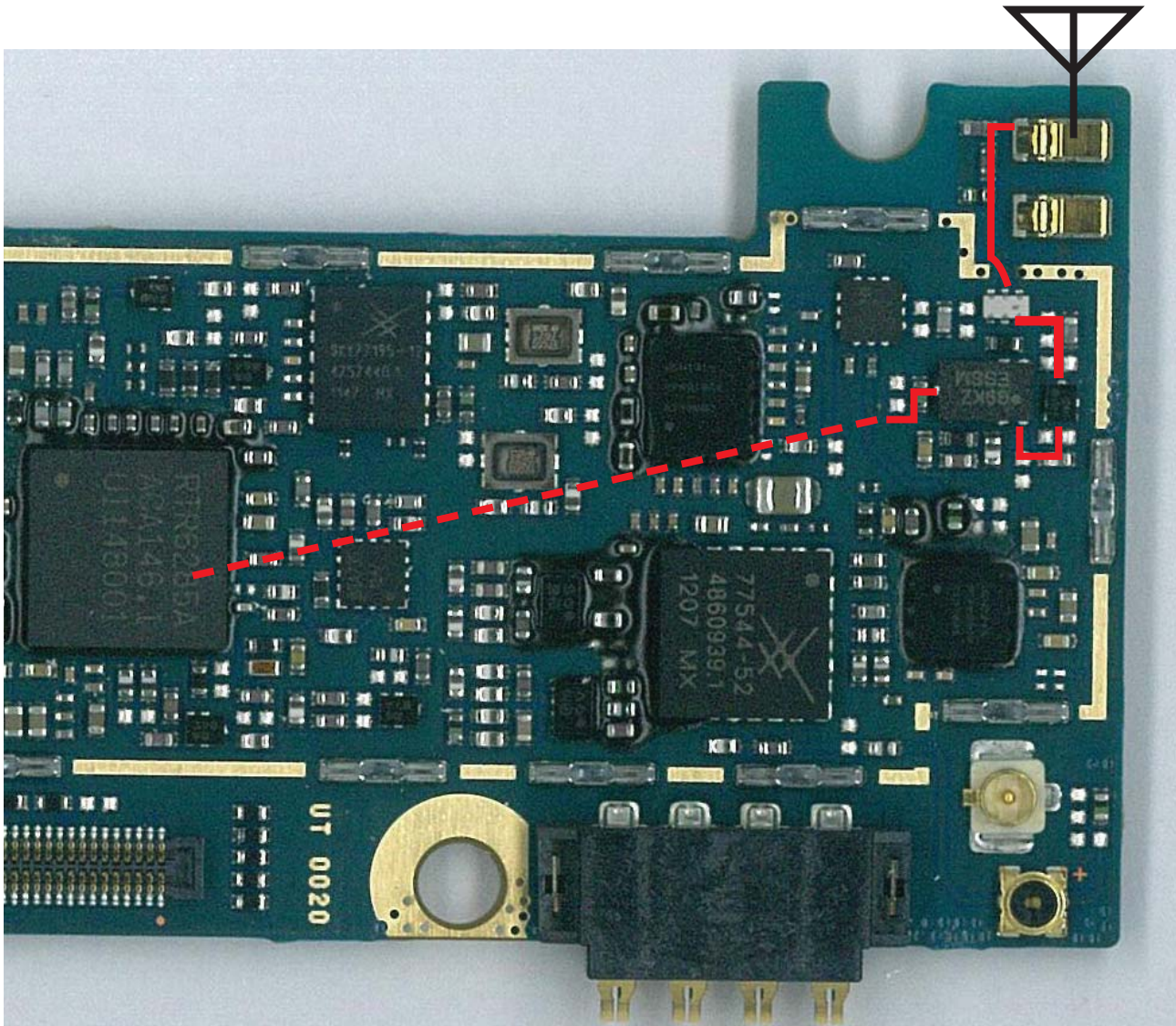


**RF Component(BT/WiFi/FMR)**

Reference	Description
U800	BT/FMR Chip (WCN2243)
U802	WIFI Chip (WCN1314)
FL800	BT/WIFI/GPS diplexer
FL802	BT/WIFI FEM



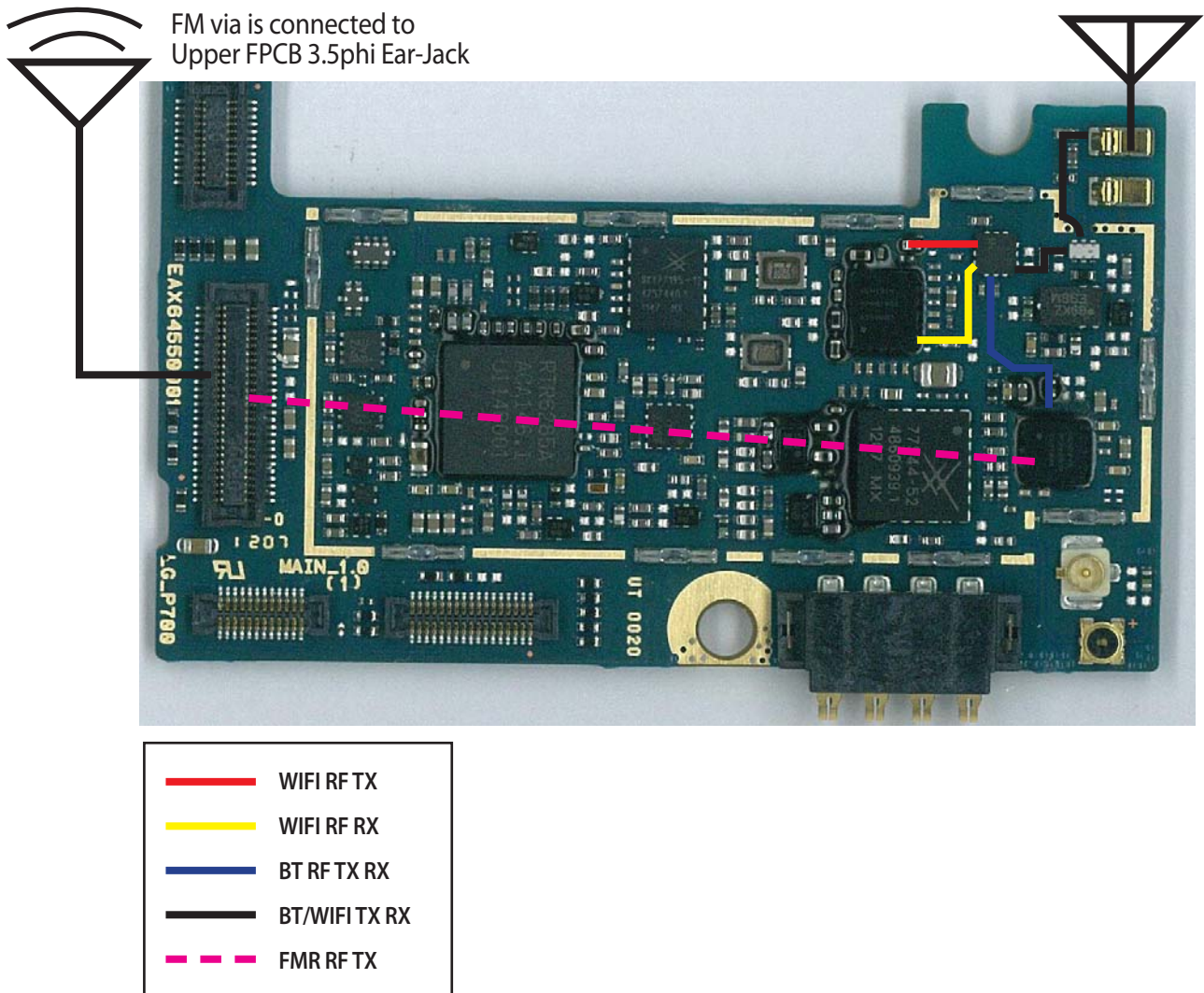
### 4.8 GPS/WIFI/BT SIGNAL PATH



GPS Signal PATH (main board bottom)

GPS Rx PATH

## 4. TROUBLE SHOOTING

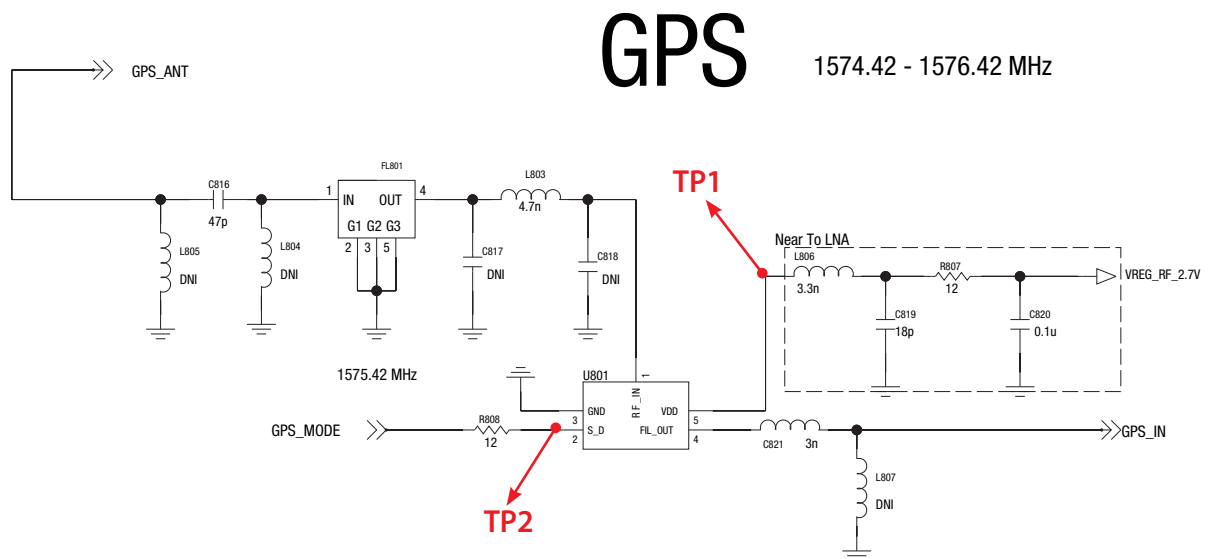
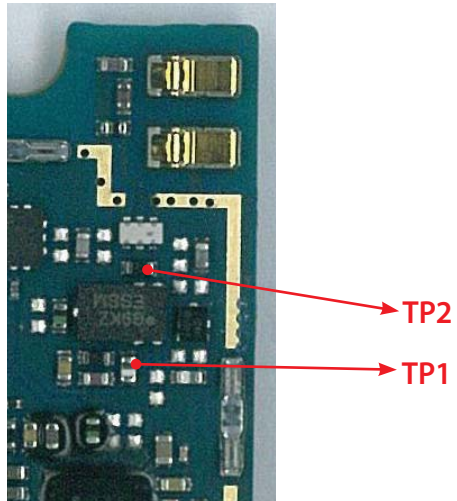


WiFi / BT / FMR Signal PATH

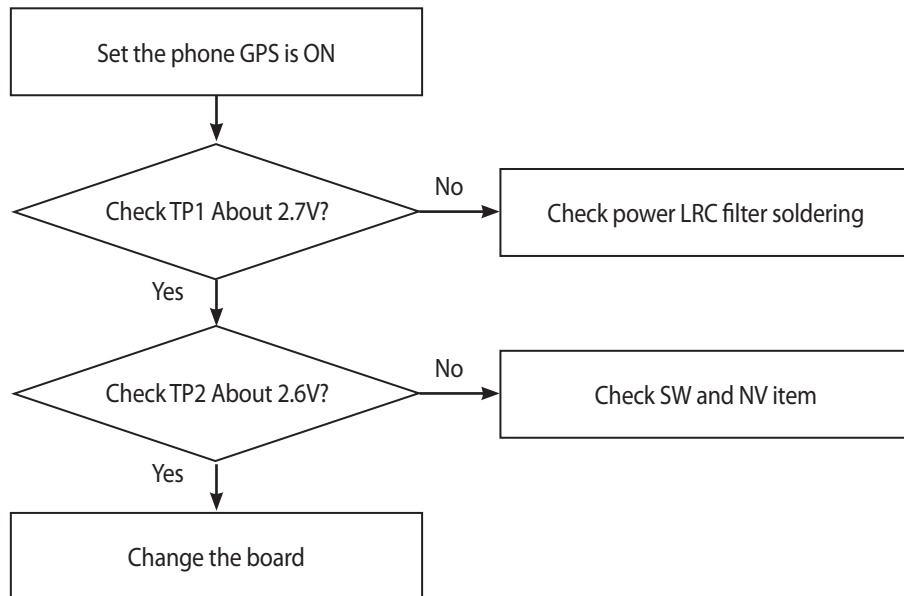
WiFi / BT Tx and Rx PATH

### 4.9 GPS/WIFI/BT Trouble shooting

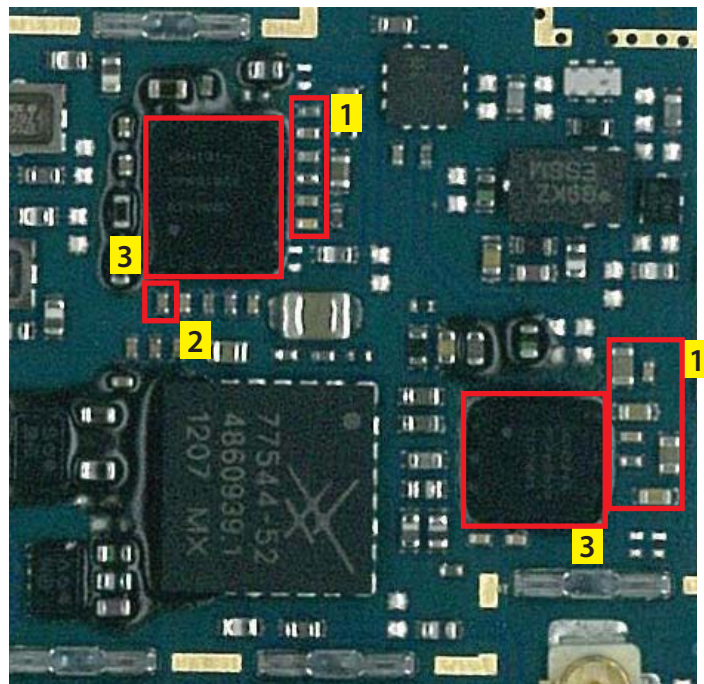
#### 4.9.1 A-GPS Block

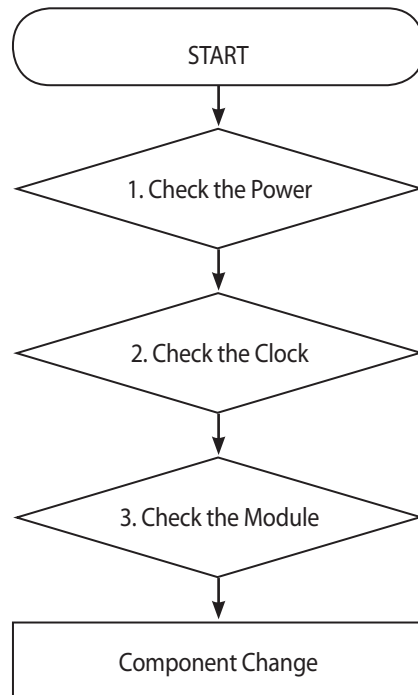






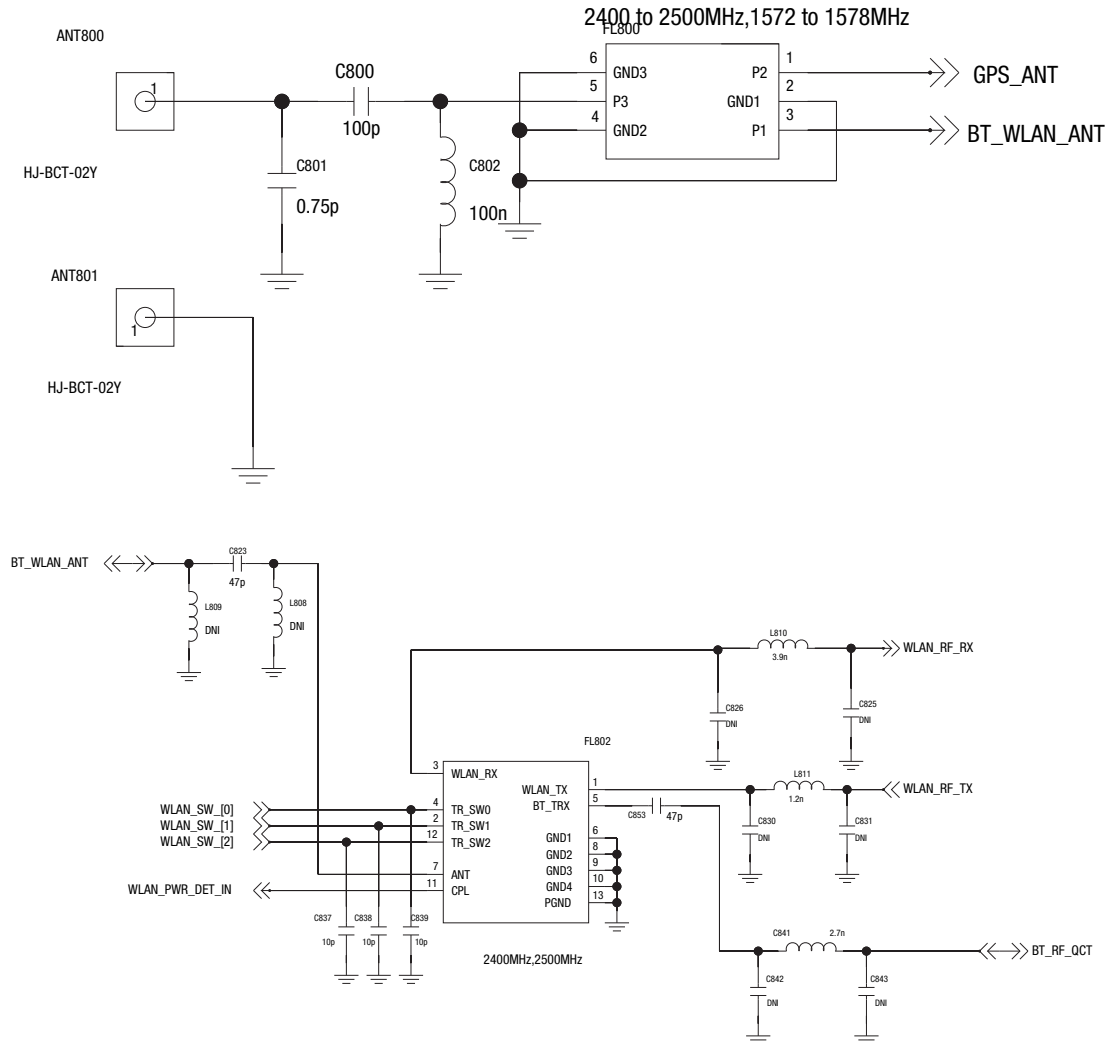
### 4.9.2 WLAN/BT/FM Block





## 4. TROUBLE SHOOTING

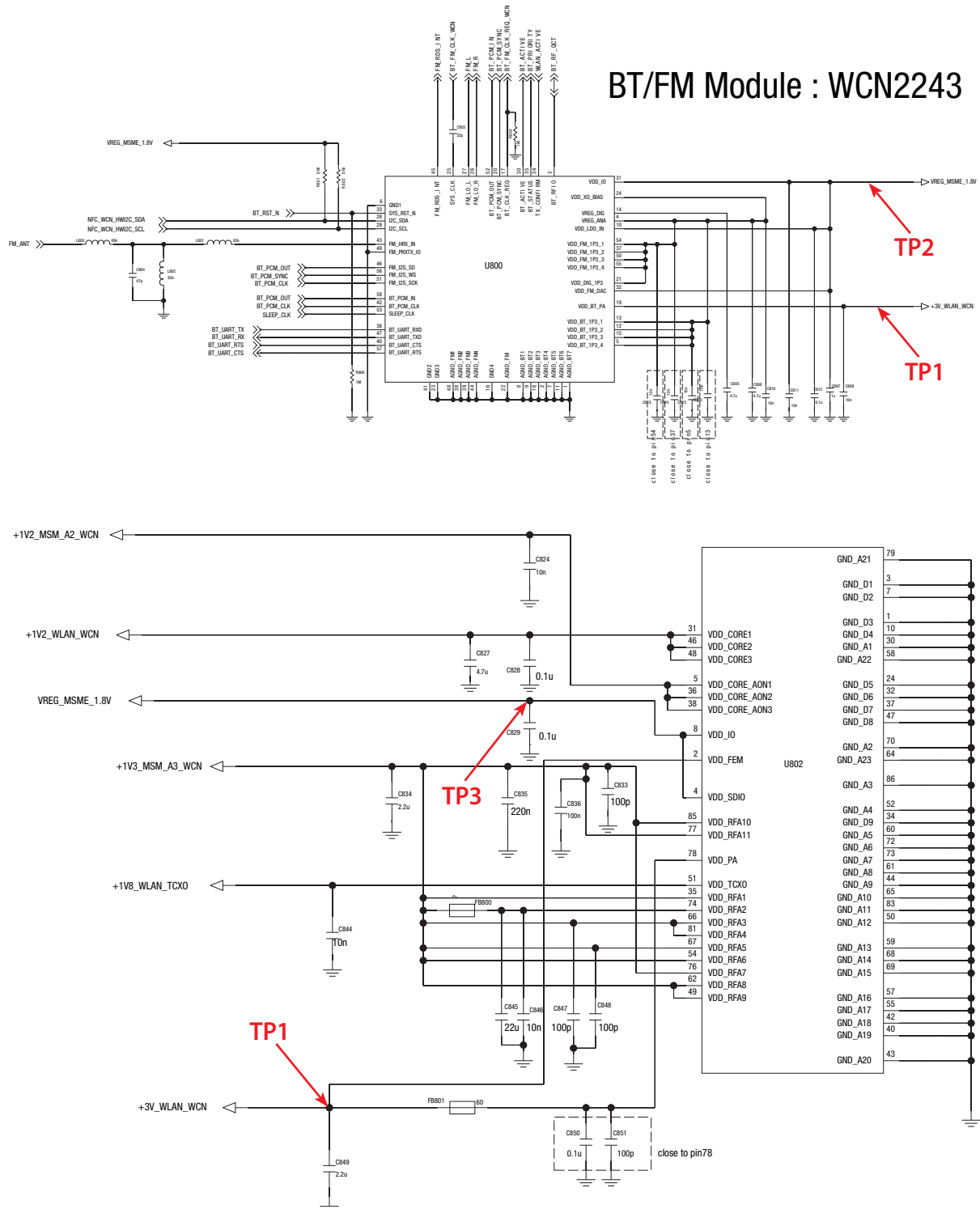
### Module part



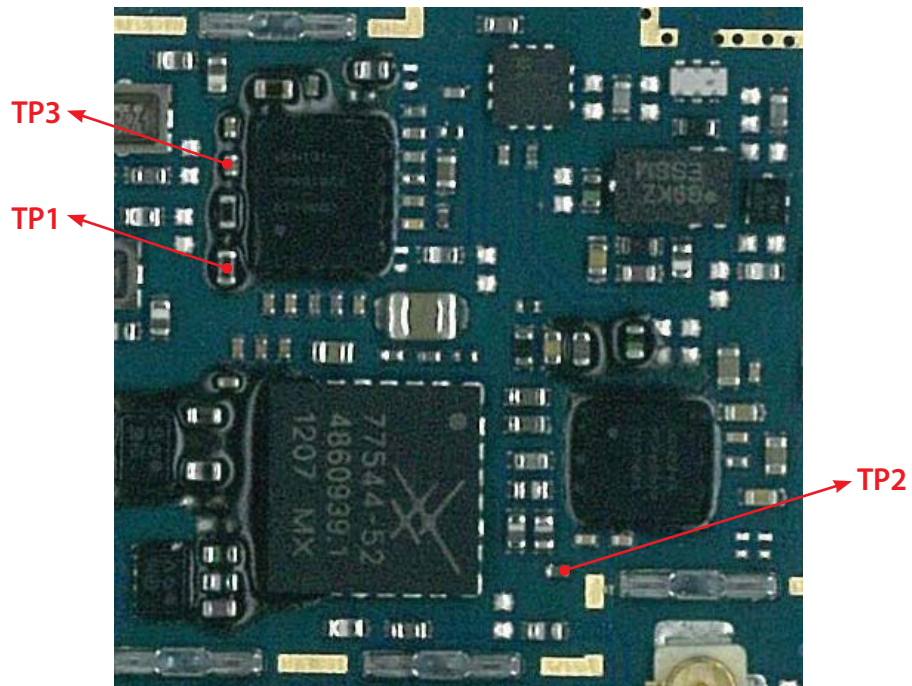
### ANTENNA SWITCH MODULE LOGIC

	SW0	SW1	SW2
WIFI RX-ANT	HIGH	LOW	LOW
WIFI TX-ANT	LOW	HIGH	LOW
BT-ANT	LOW	LOW	HIGH

BT/FM Module : WCN2243



[Figure] Schematic of WiFi/BT module

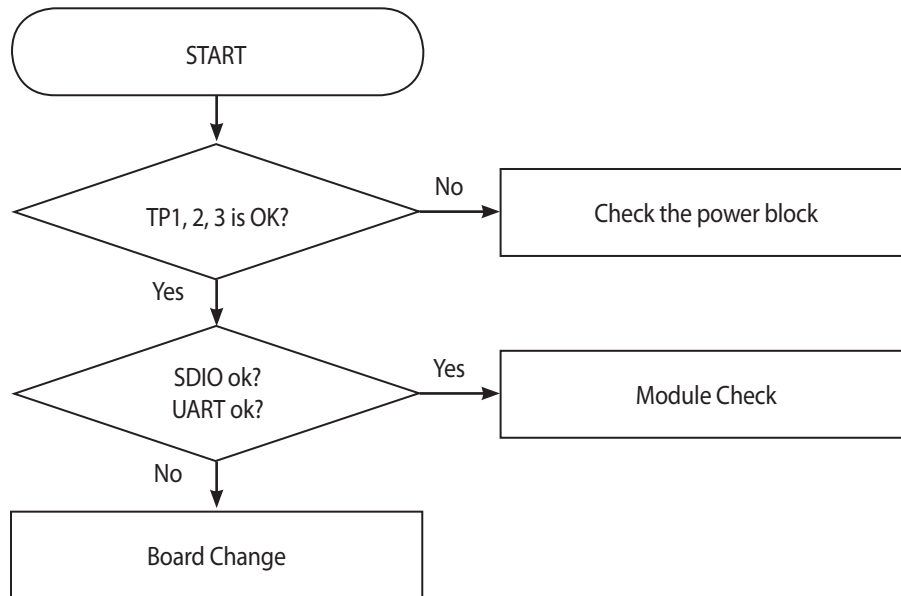


### Test point Description

Test point	Net name	Description
TP1	+3V_WLAN_WCN	Power for BT/WiFi BB core and WiFi power Amp. (V Batt)
TP2	VREG_MSME_1.8V	Power for BT power Amp. (1.8V)
TP3	VREG_MSME_1.8V	Power for host interface (1.8V)

## 4. TROUBLE SHOOTING

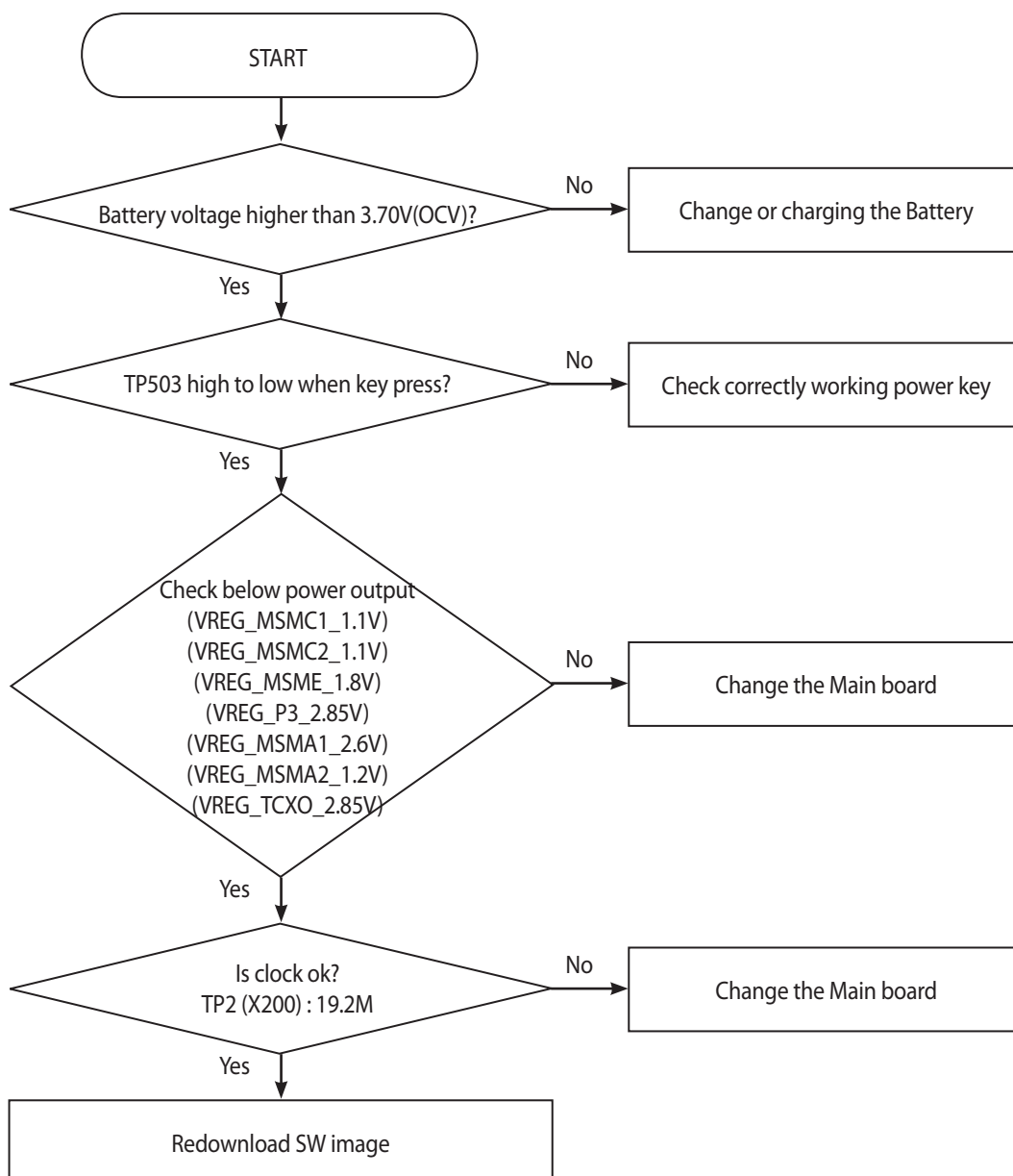
---



### 4.10 Power ON Trouble Shooting

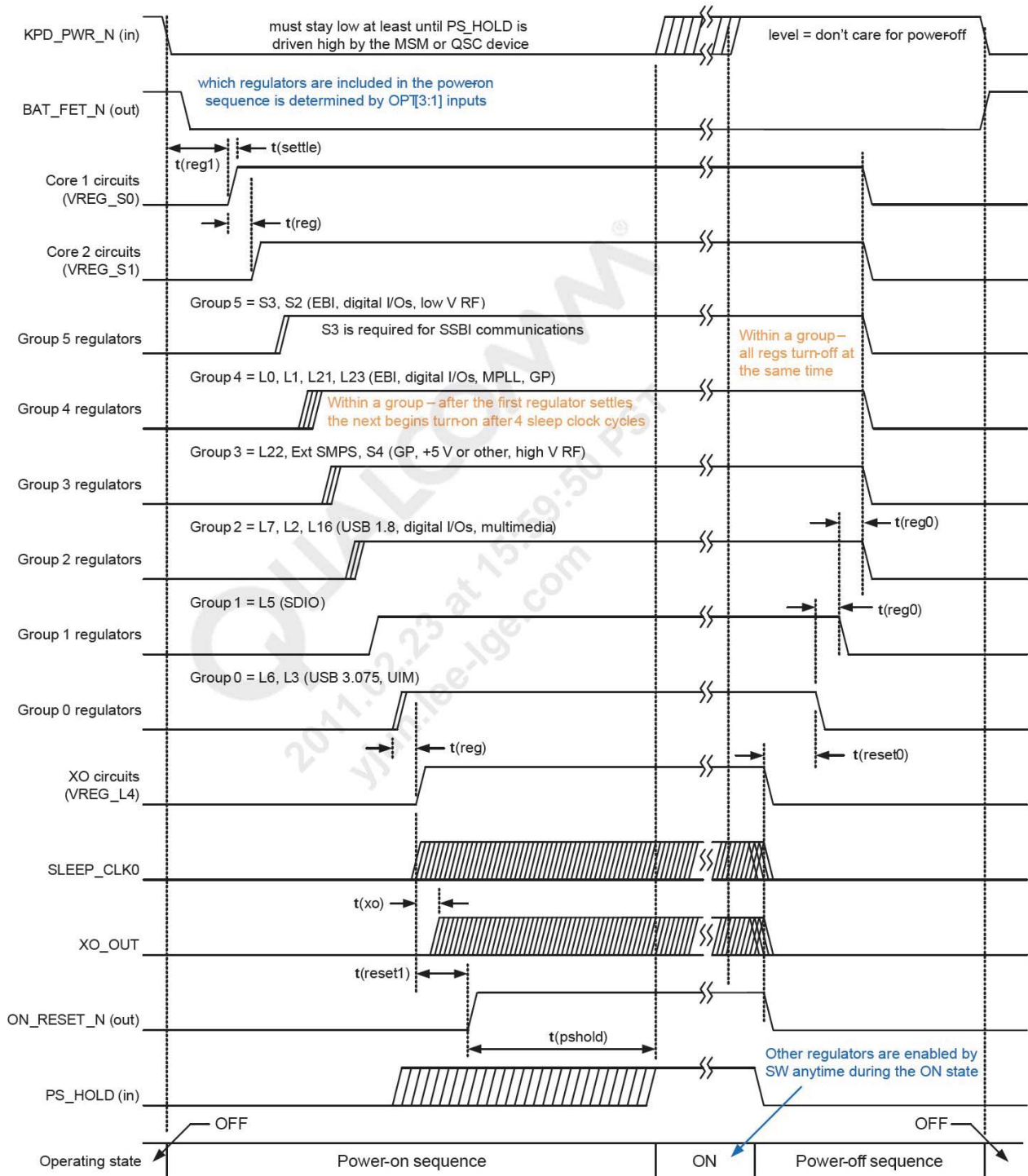
Power On sequence of P705 is :

Power key press -> KPD\_PWR\_N go to low -> PM8029 Power Up -> VREG\_MSMC1\_1.1V (L500), VREG\_MSMC2\_1.1V (L501), VREG\_MSME\_1.8V (L502), VREG\_P3\_2.85V (C541), VREG\_MSMA1\_2.6V (C536), VREG\_MSMA2\_1.2V (C532) VREG\_TCXO\_2.85V (C537) power ON -> Phone booting and PS\_HOLD(D502) go to High

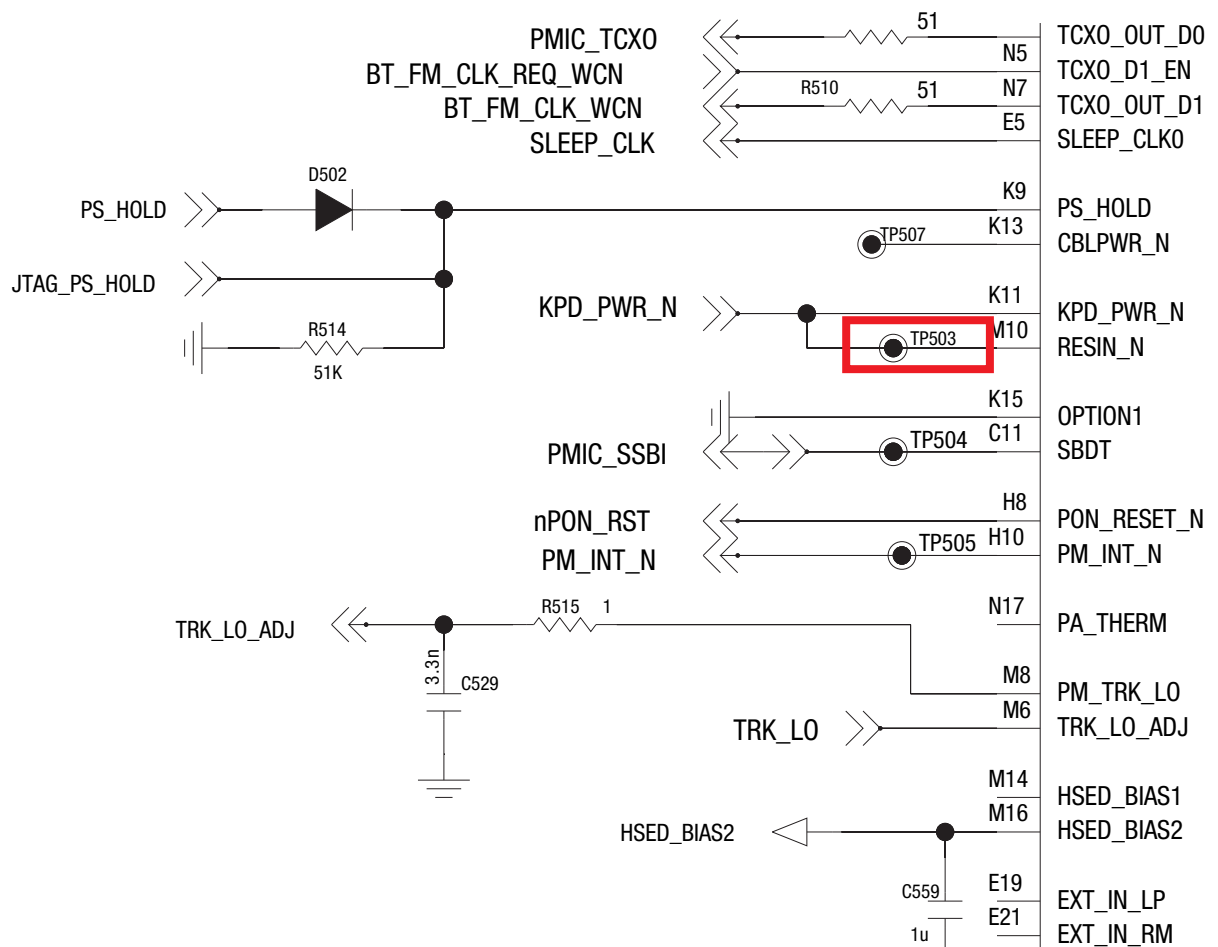
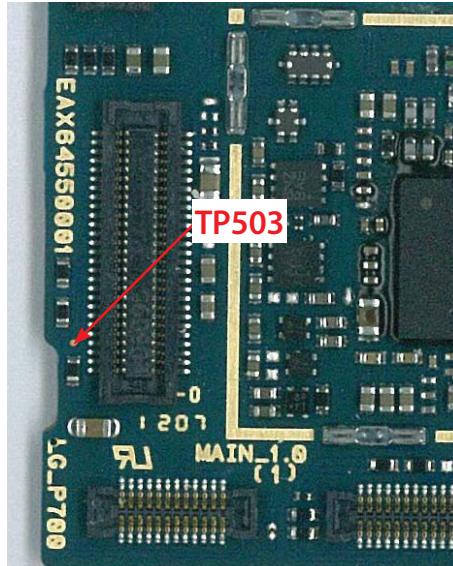




## 4. TROUBLE SHOOTING

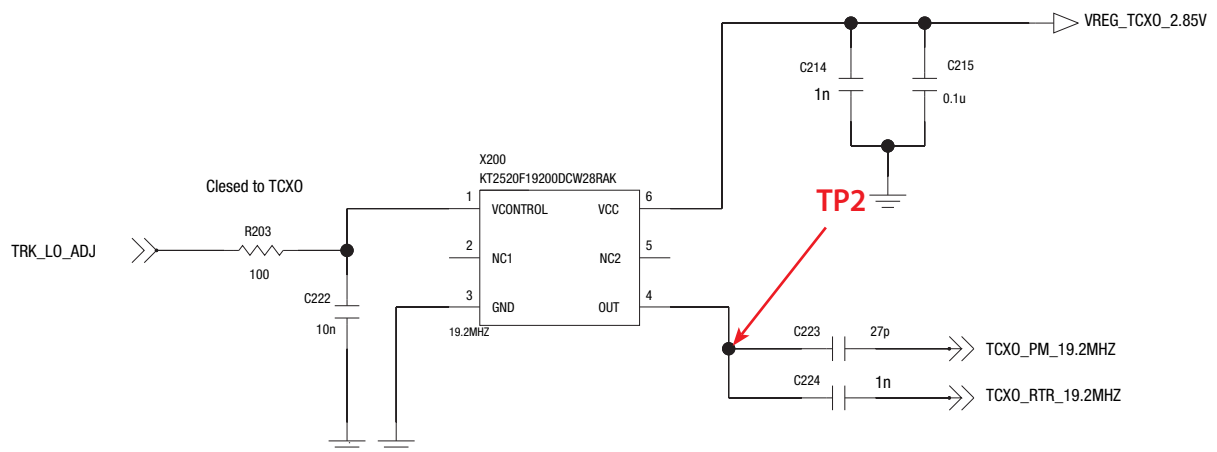
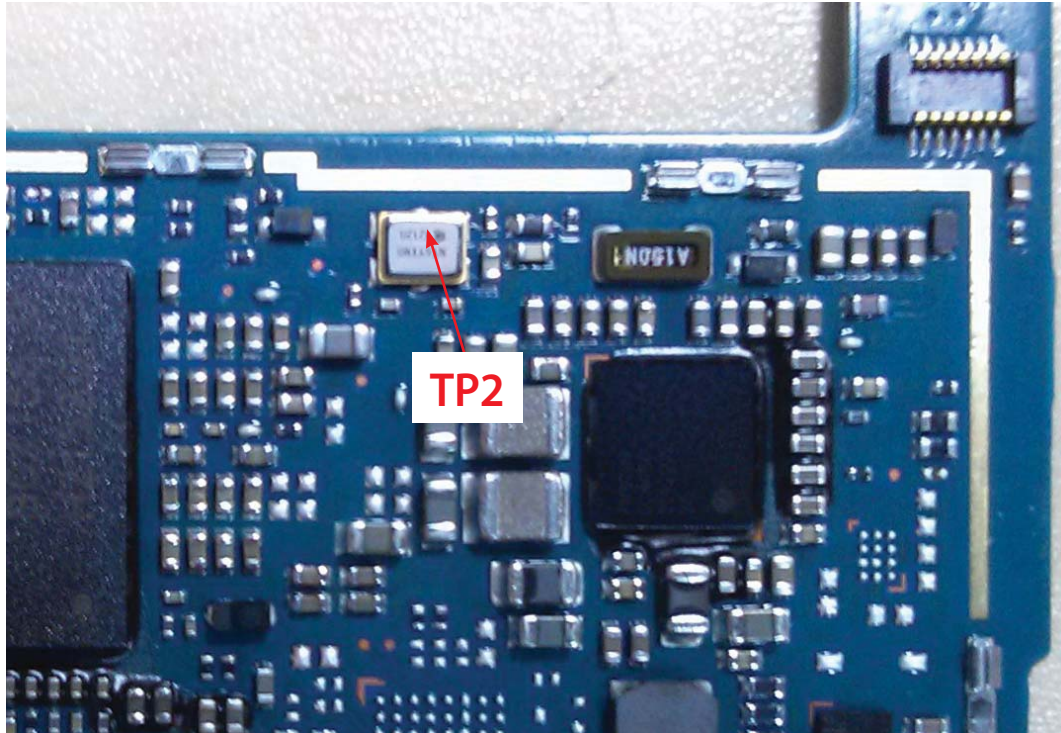


## 4. TROUBLE SHOOTING

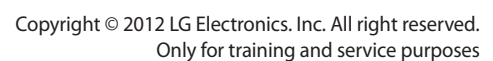




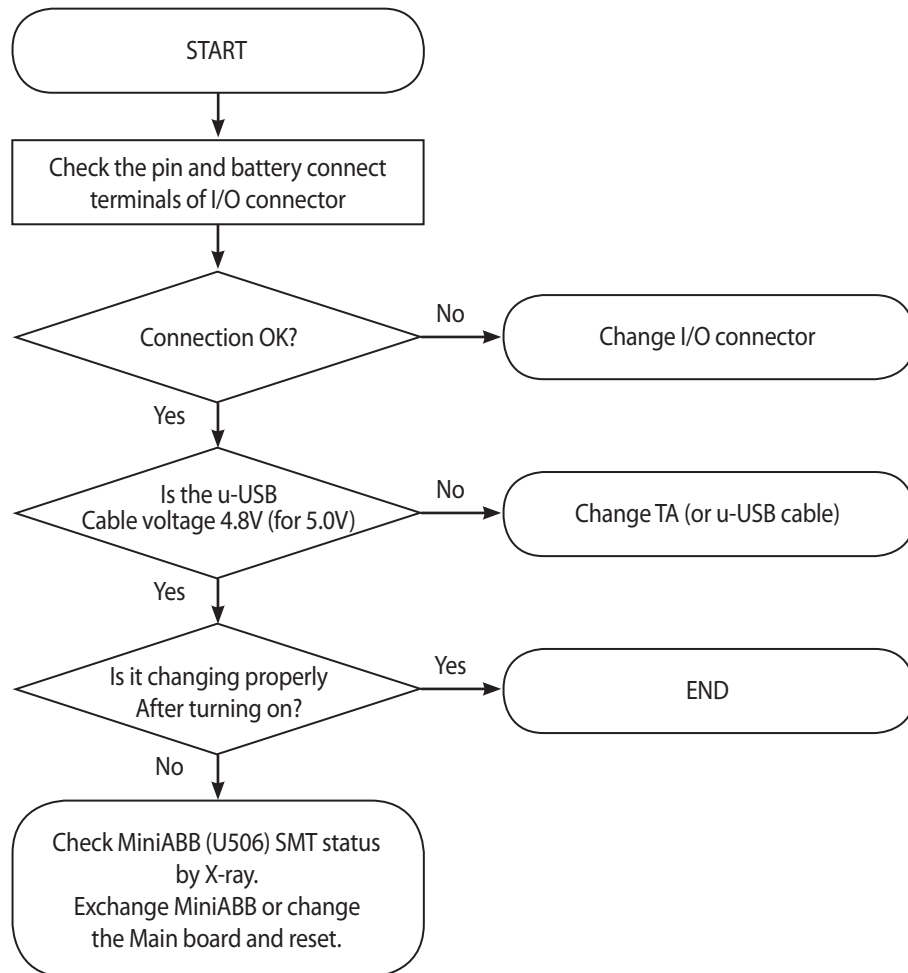
## 4. TROUBLE SHOOTING



## MICRO USB IO



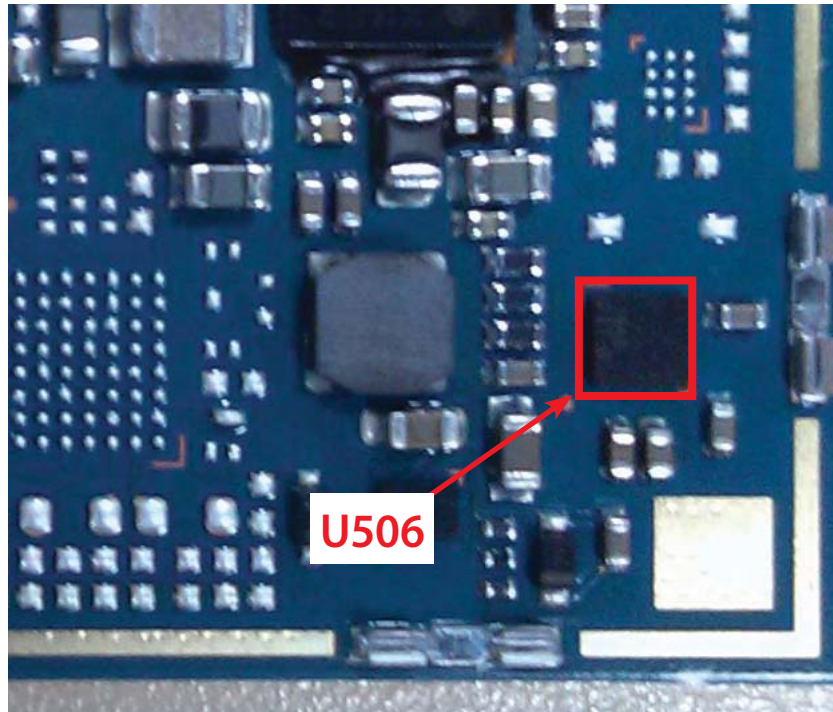




**Charger Troubleshoot Flow**

## 4. TROUBLE SHOOTING

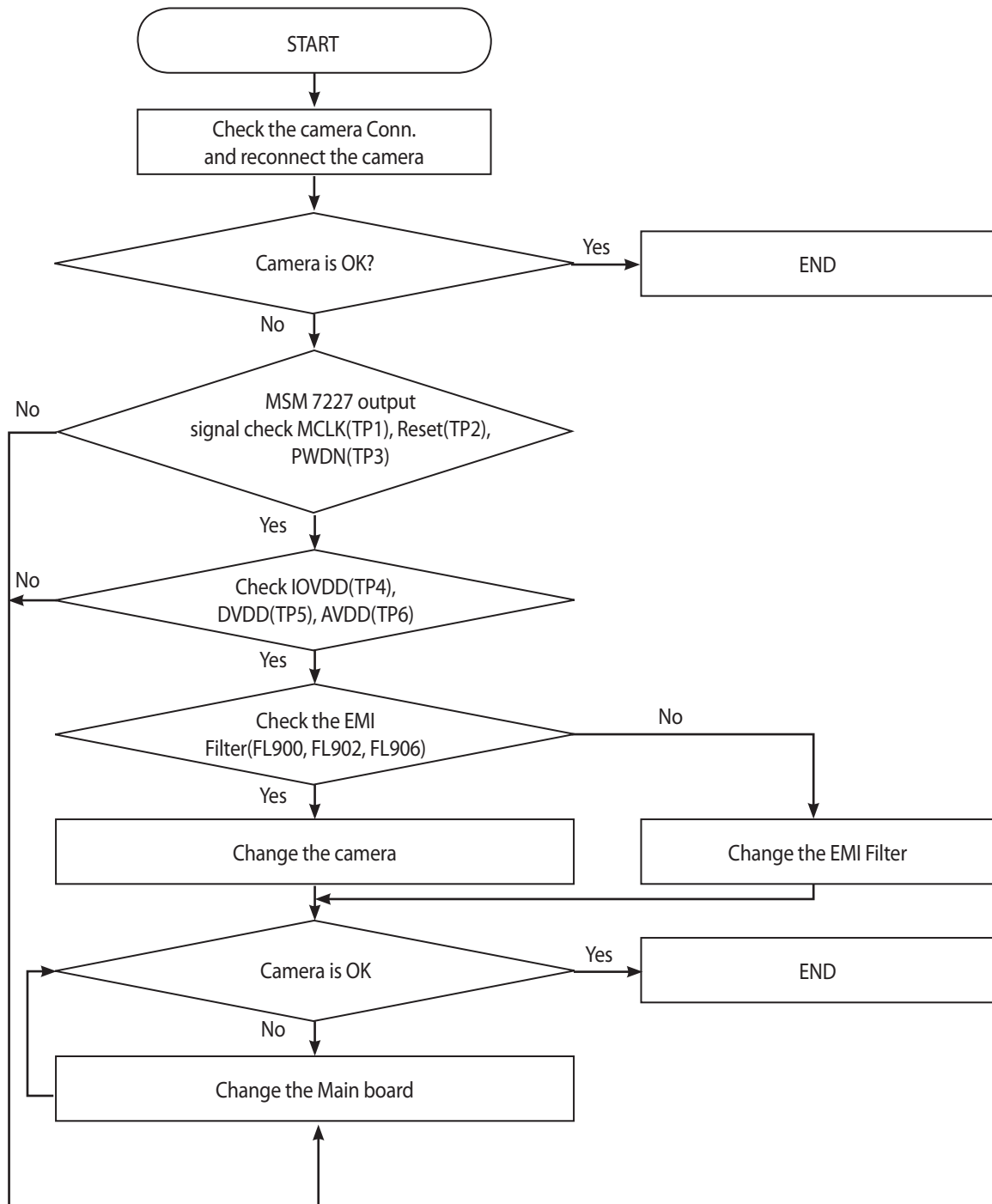
---



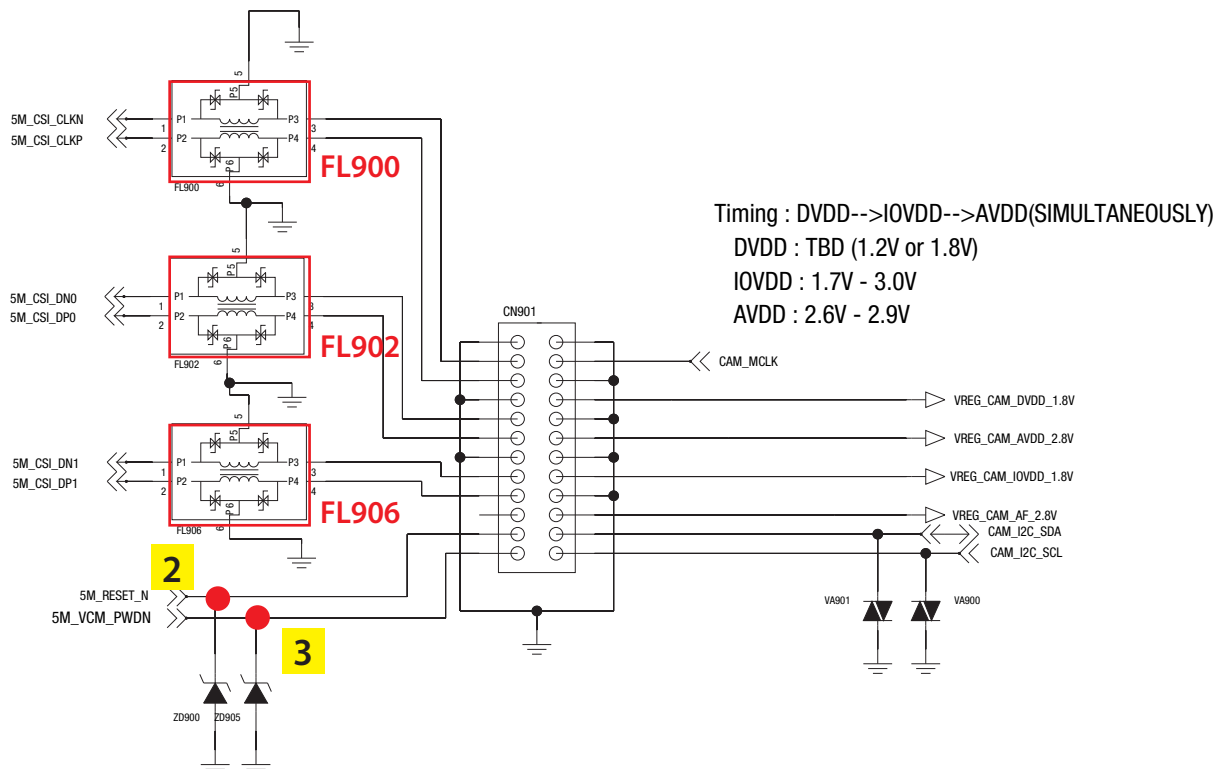
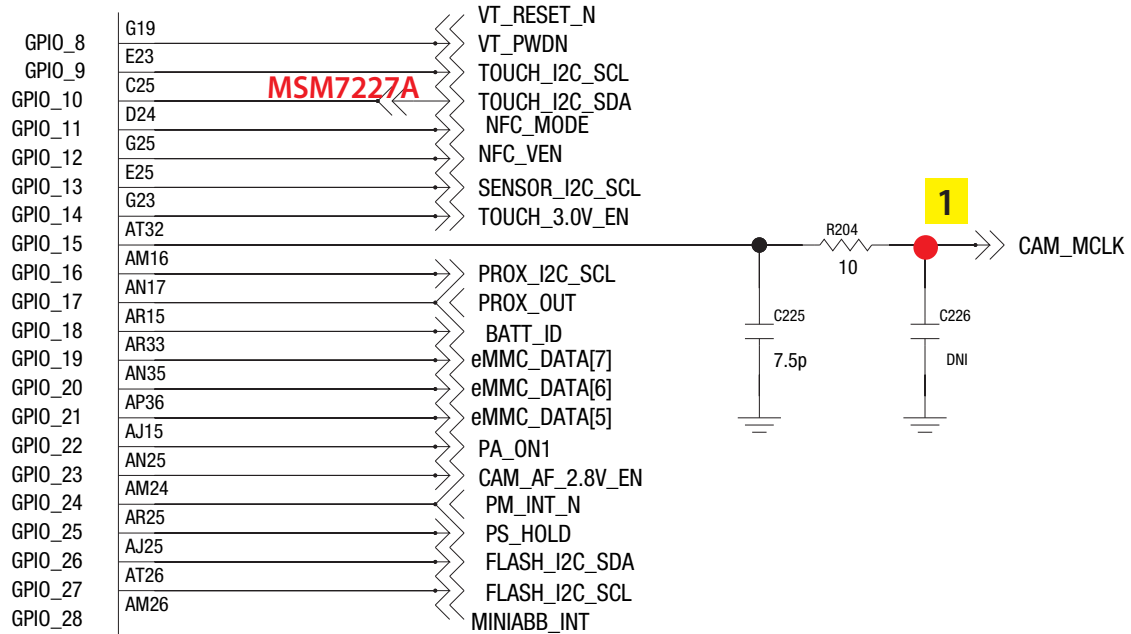


### 4.12 5M Camera Trouble Shooting

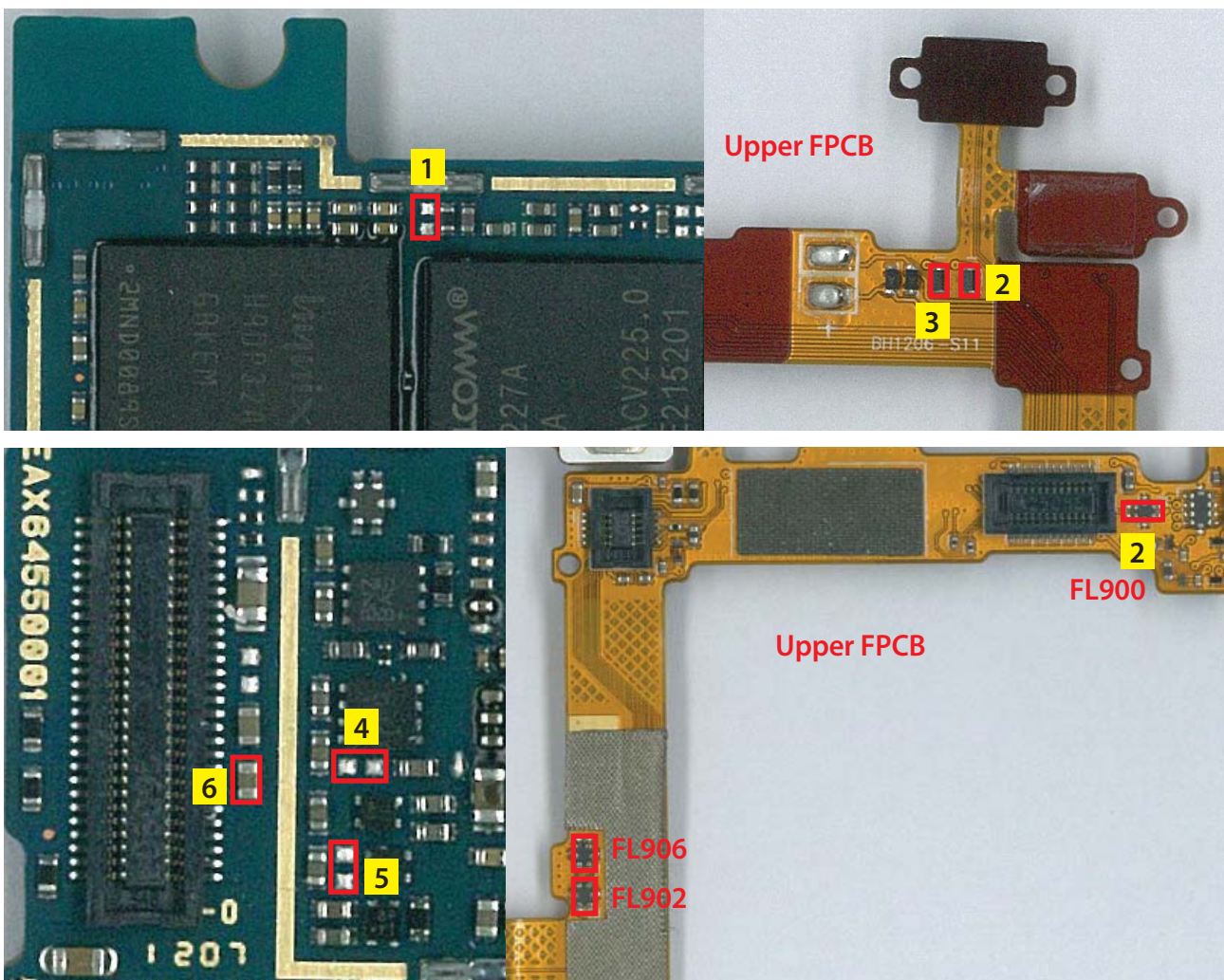
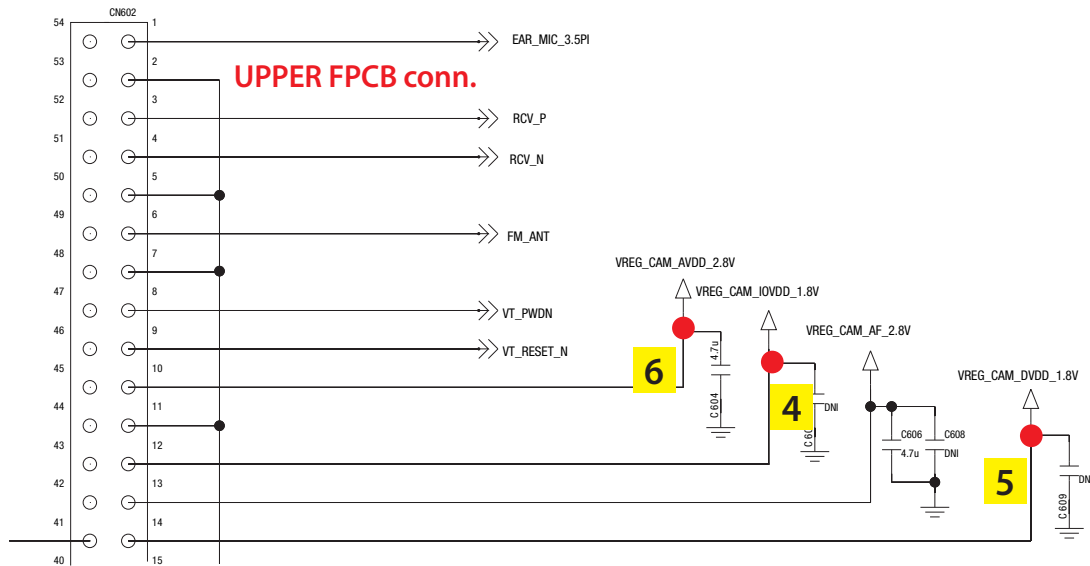
5M camera control signals are generated by MSM7227A.



## 4. TROUBLE SHOOTING

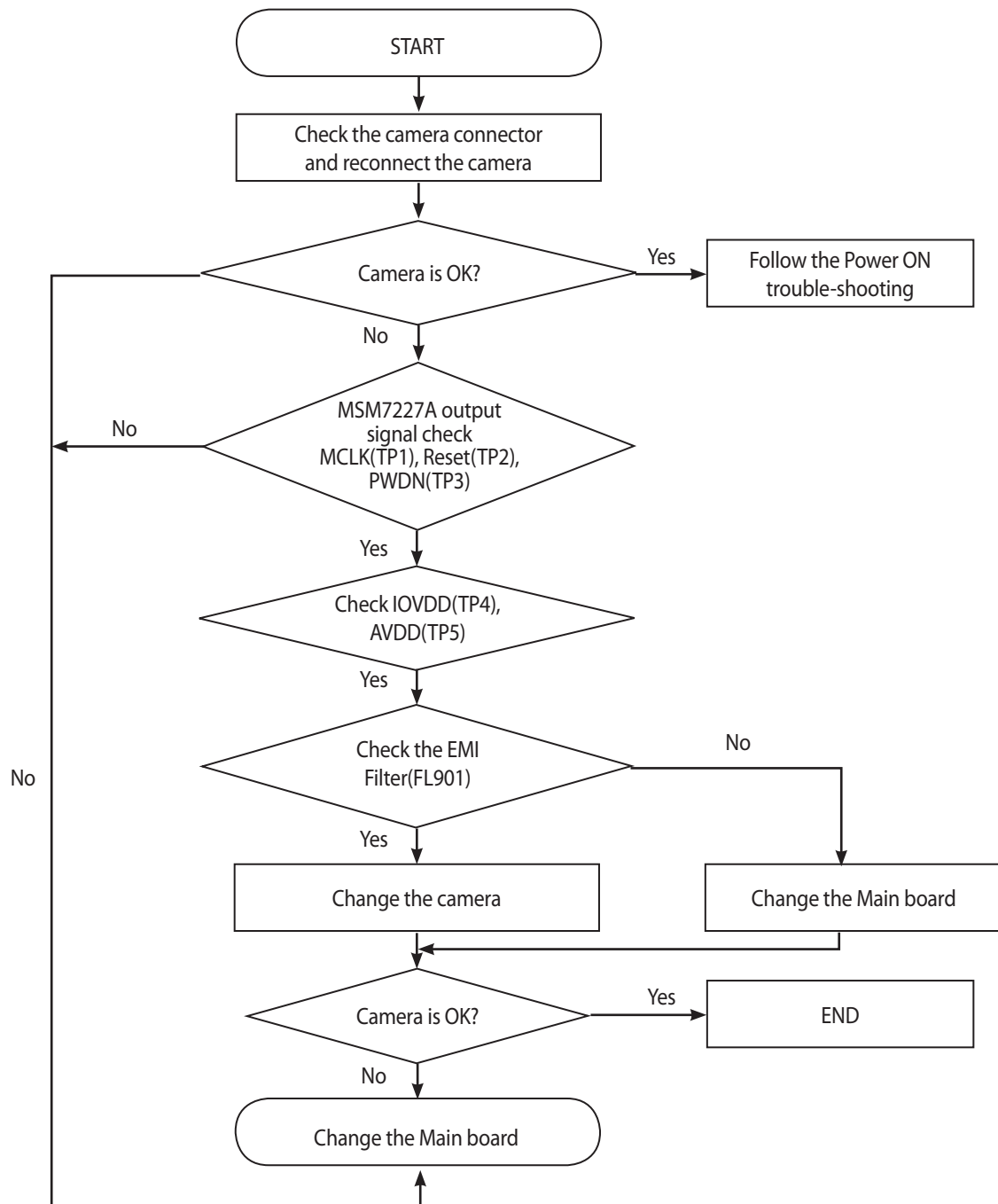


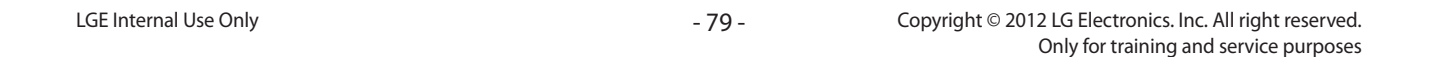
## 4. TROUBLE SHOOTING



### 4.13 VGA Camera Trouble Shooting

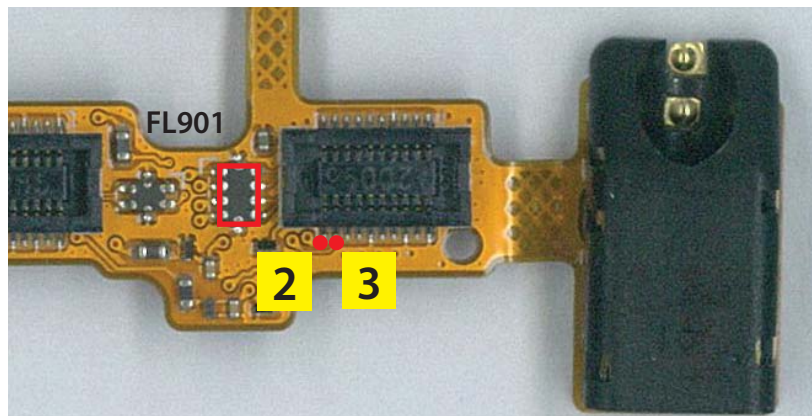
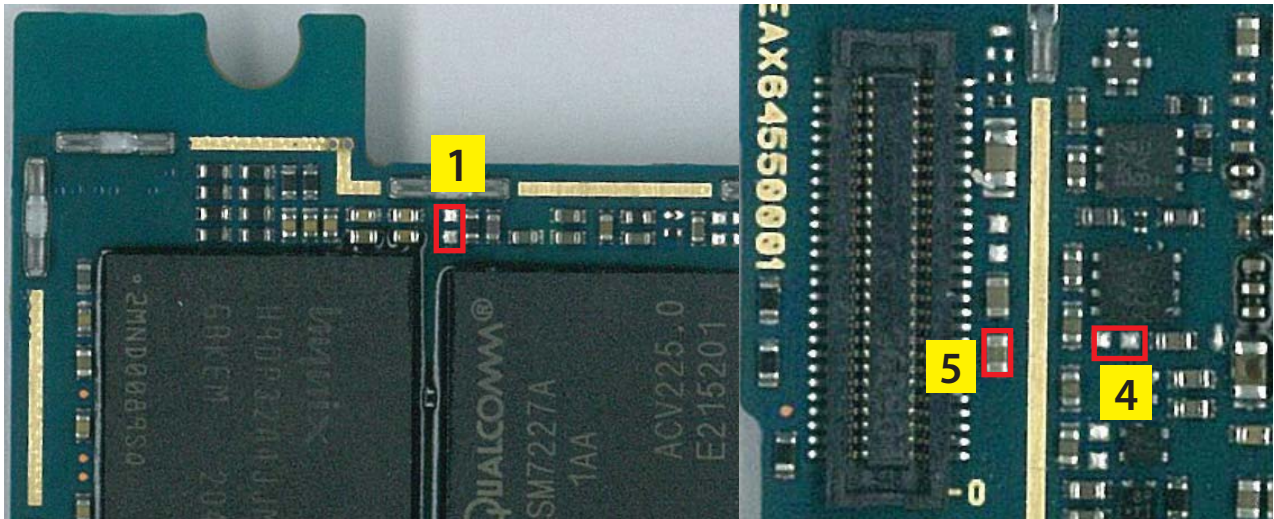
VGA camera control signals are generated by MSM7227A.







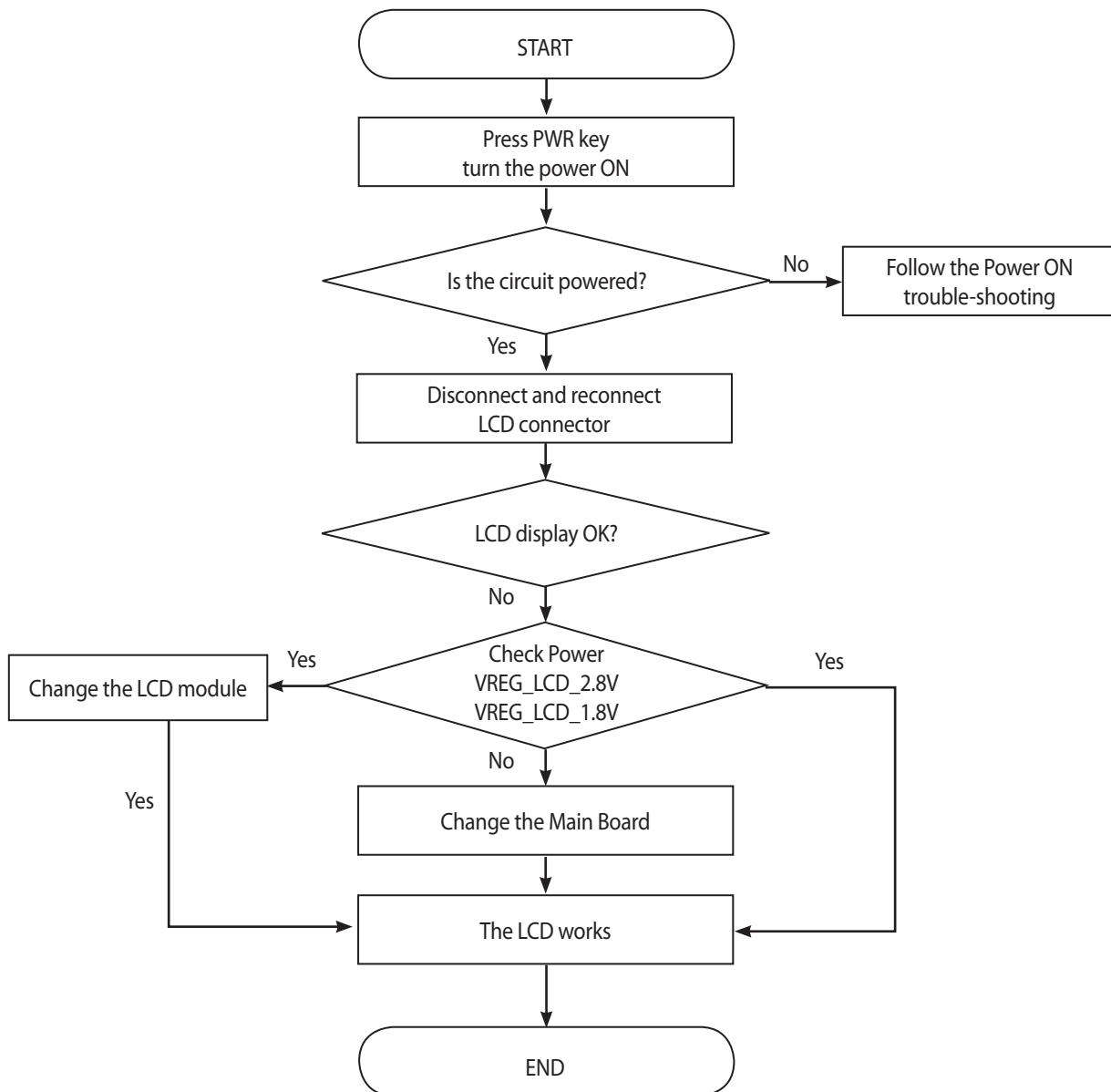
## 4. TROUBLE SHOOTING



### 4.14 Main LCD trouble

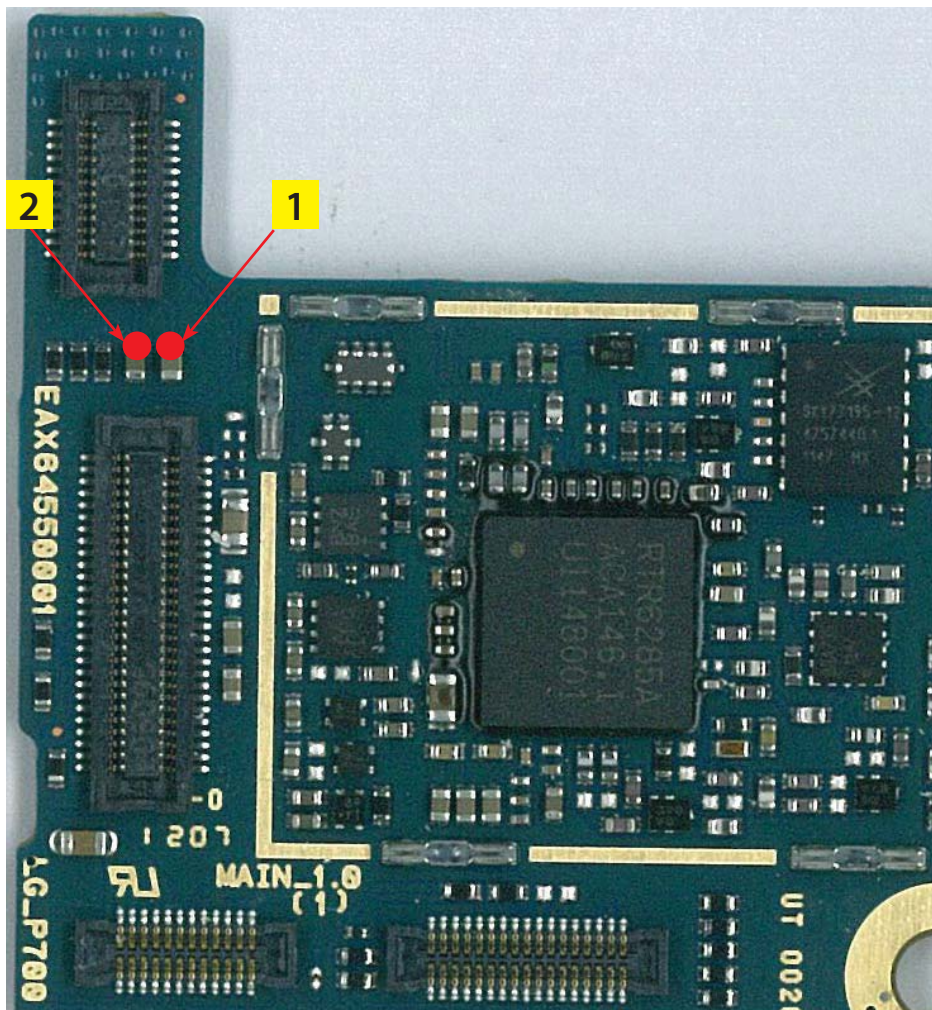
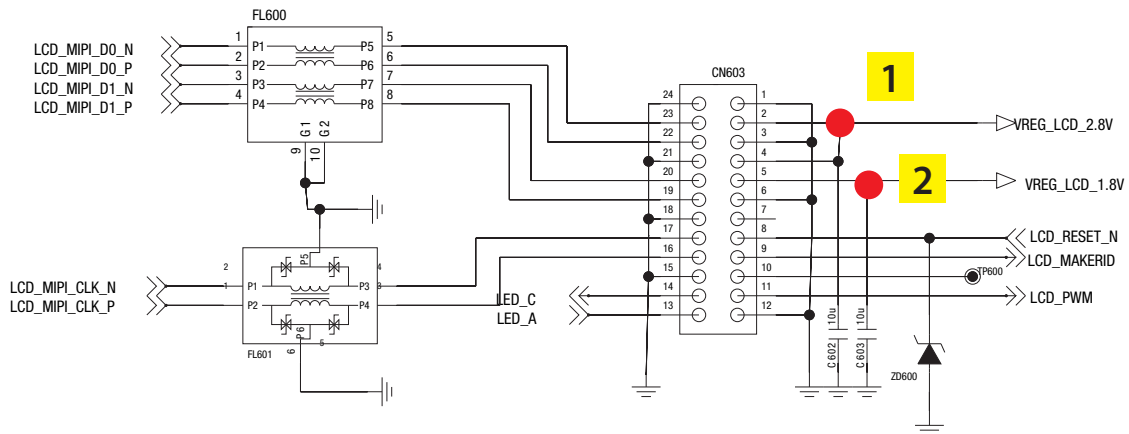
Main LCD control signals are generated by MSM7227A. Those signal's path are :

MSM7227A-> LCD Module





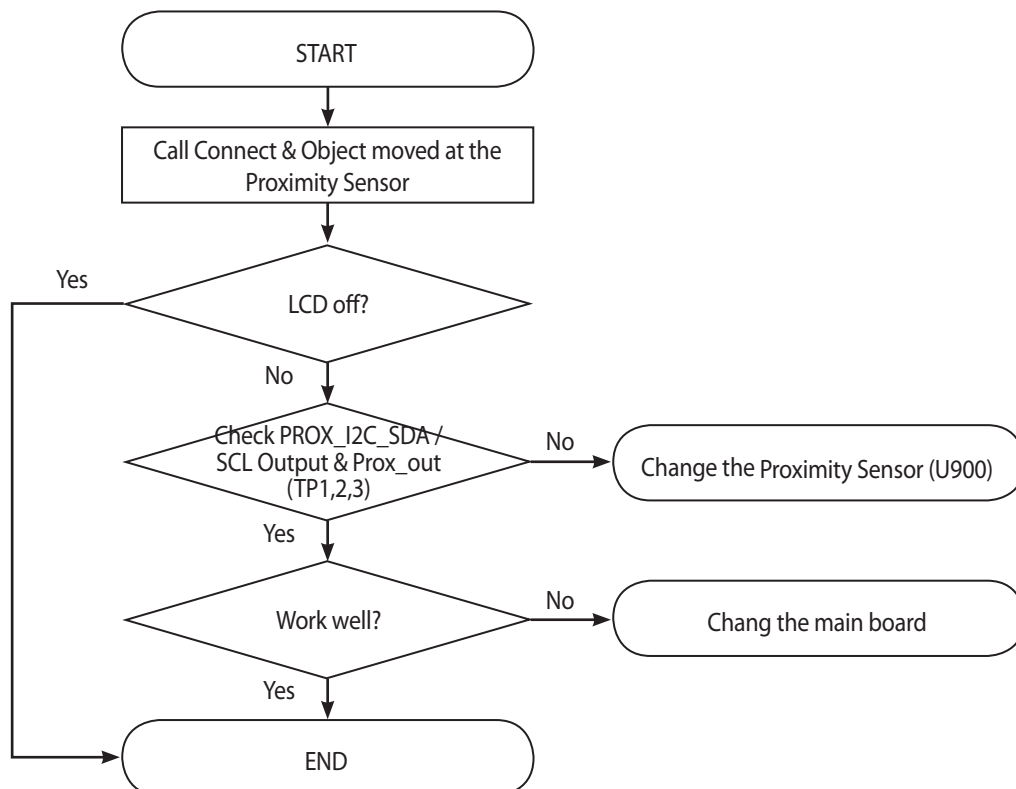
# 4.3" WVGA MIPI 2Lane



### 4.15 Proximity Sensor on/off Trouble Shooting

Proximity Sensor is worked as below :

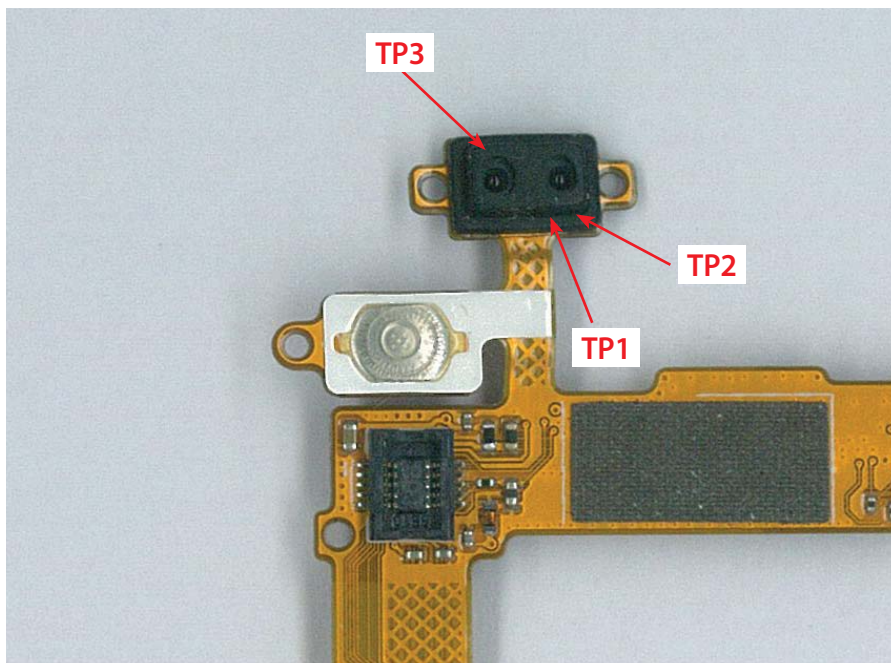
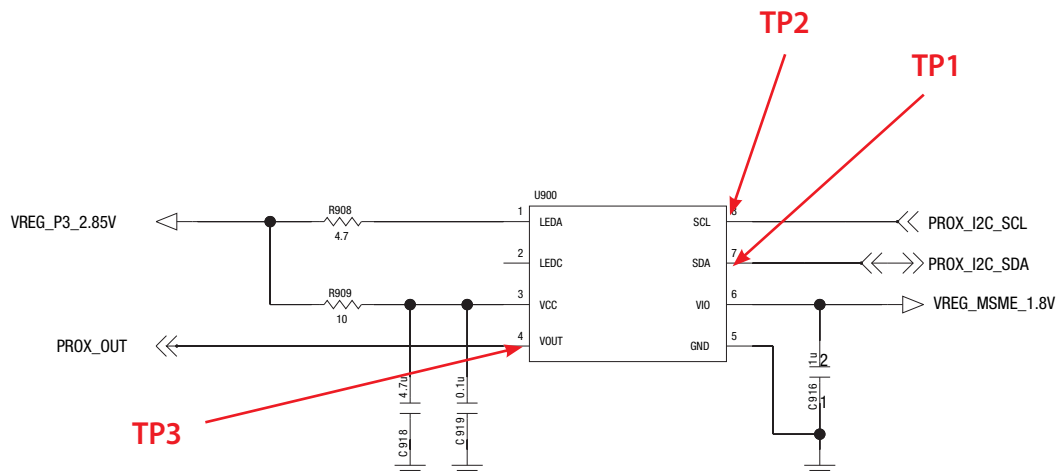
Call connected -> Object moved at the sensor -> Control the screen's on/off operation automatically



#### Measurement

VREG\_MSME\_1.8V  
VREG\_P3\_2.85V  
PROX\_OUT  
PROX\_I2C\_SCL / SDA

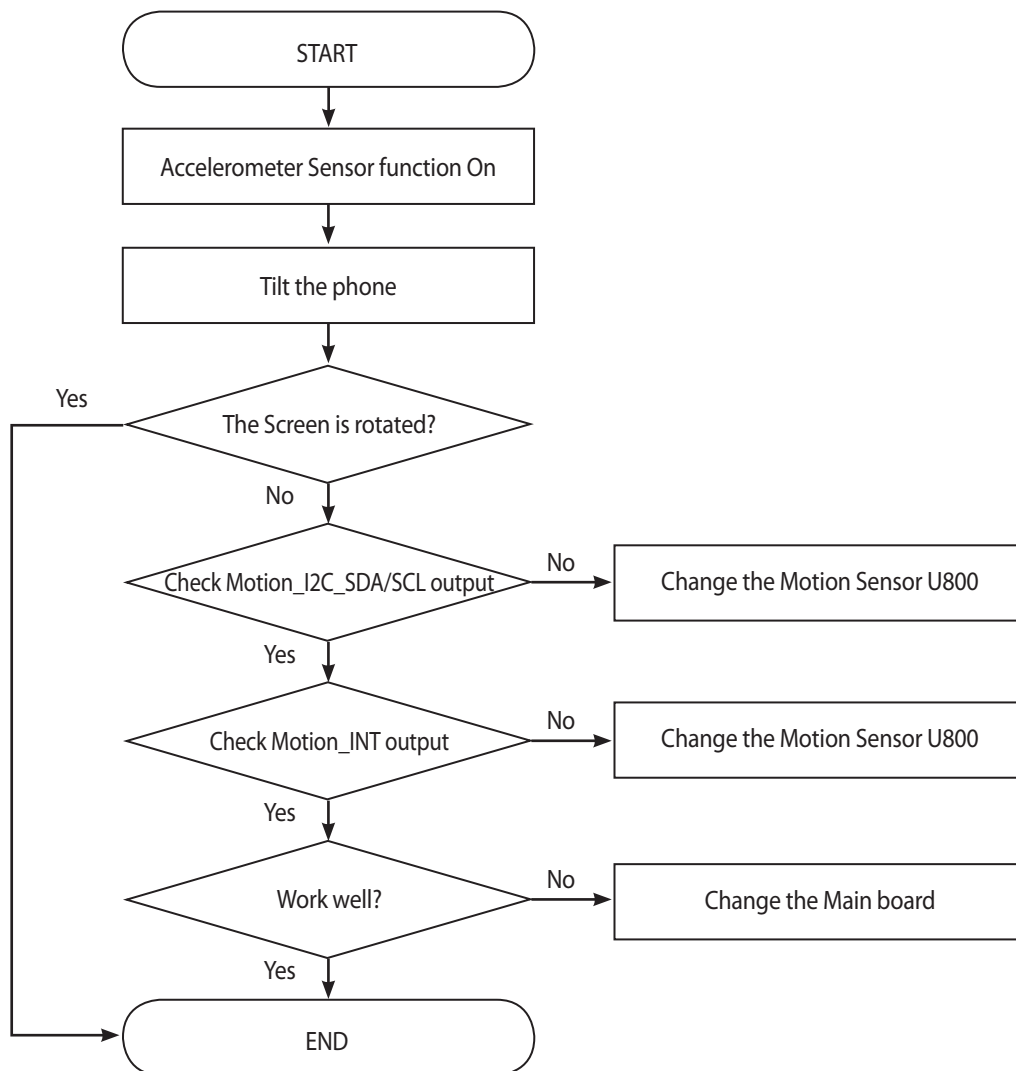
# Proximity Sensor



### 4.16 Motion Sensor on/off Trouble Shooting

Motion Sensor is worked as below :

Accelerometer Sensor function On → Tilt the phone (90°) → The screen is had rotated automatic



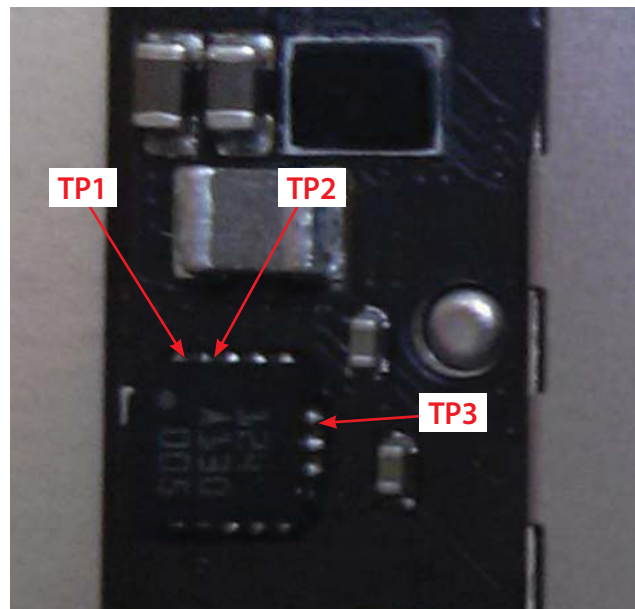
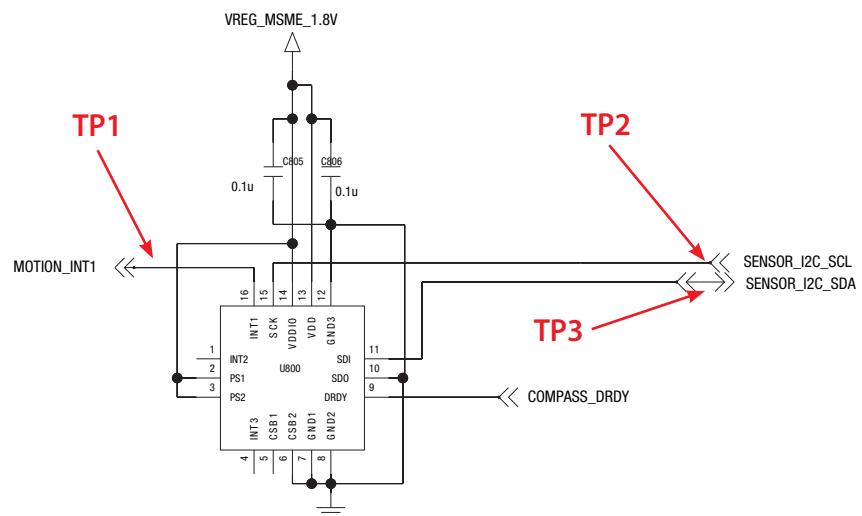
#### Measurement

VREG\_MSME\_1.8V

MOTION\_INT

SENSOR\_I2C\_SDA / SCL

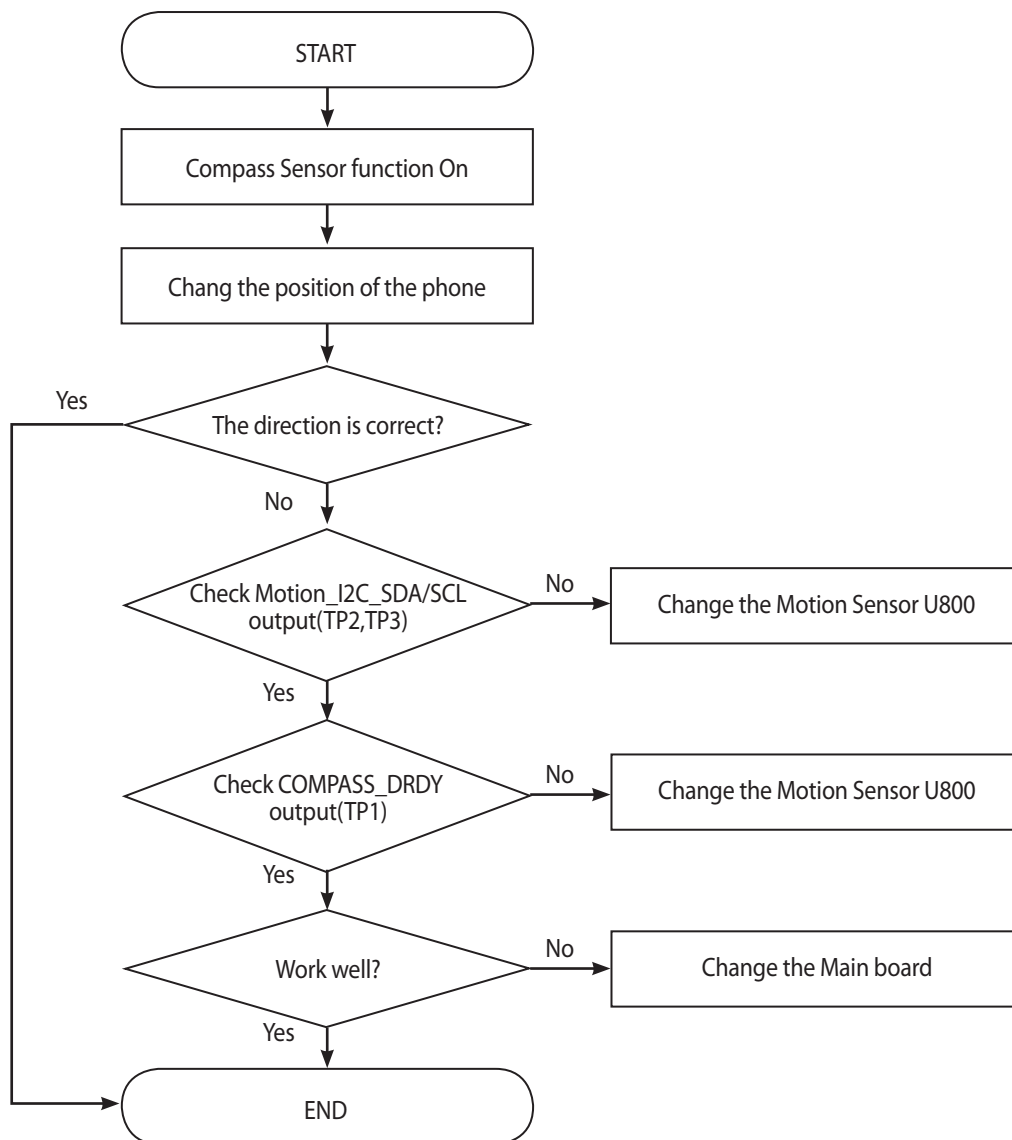
# Digital Compass + Accelerometer sensor



### 4.17 Compass Sensor on/off Trouble Shooting

Compass Sensor is worked as below :

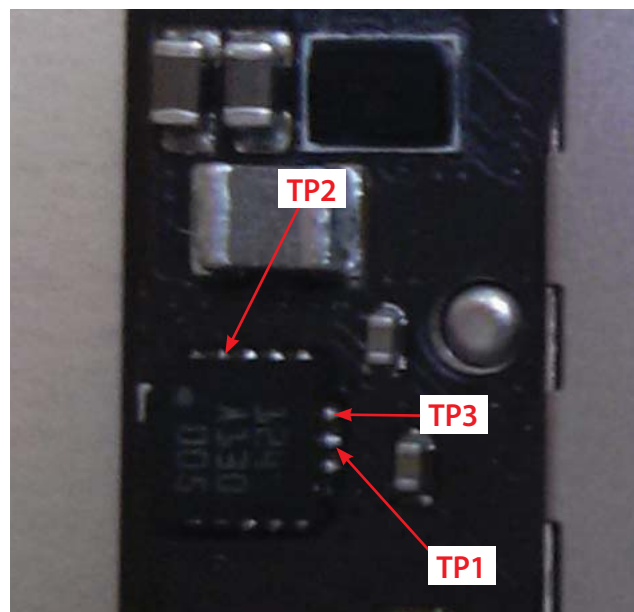
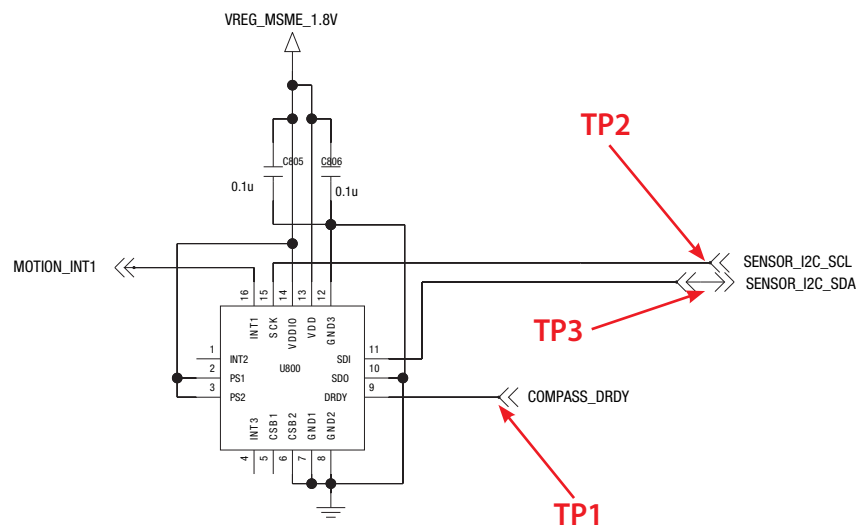
Compass Sensor function On



#### Measurement

VREG\_MSME\_1.8V  
 SENSOR\_I2C\_SCL / SDA  
 COMPASS\_DRDY

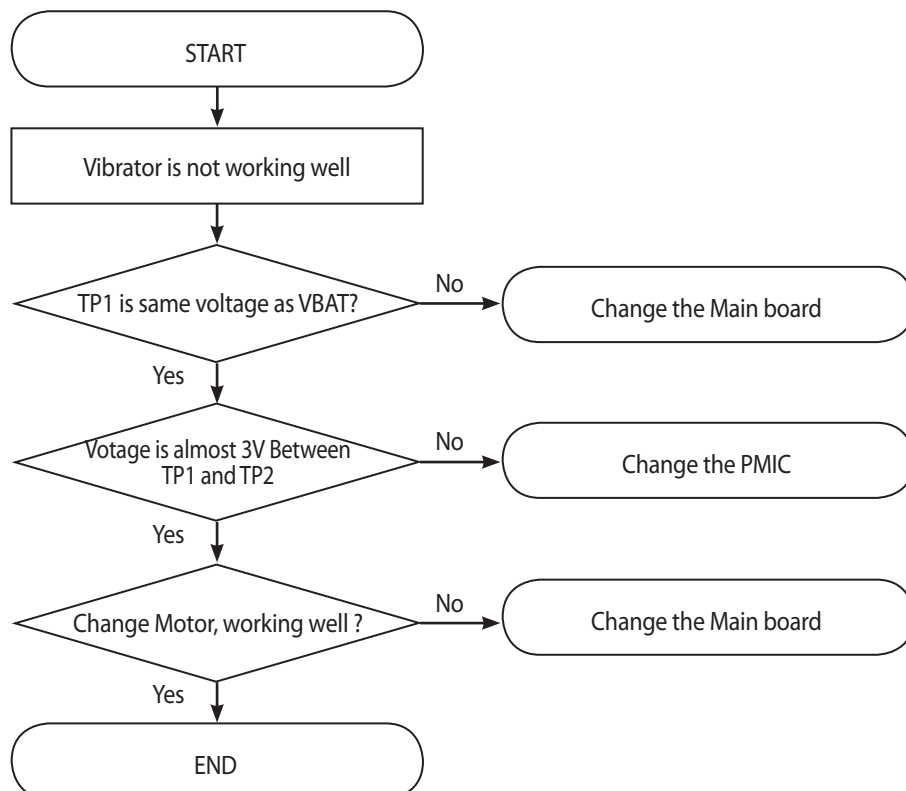
# Digital Compass + Accelerometer sensor





## 4.18 DC Motor Trouble Shooting

Vibrator is worked as below

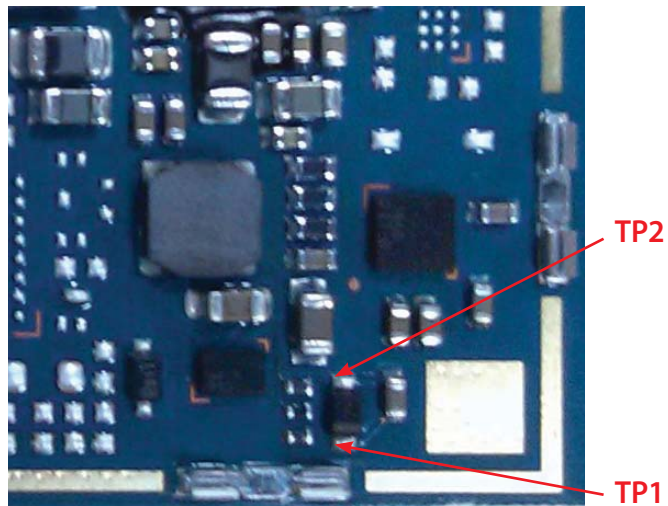
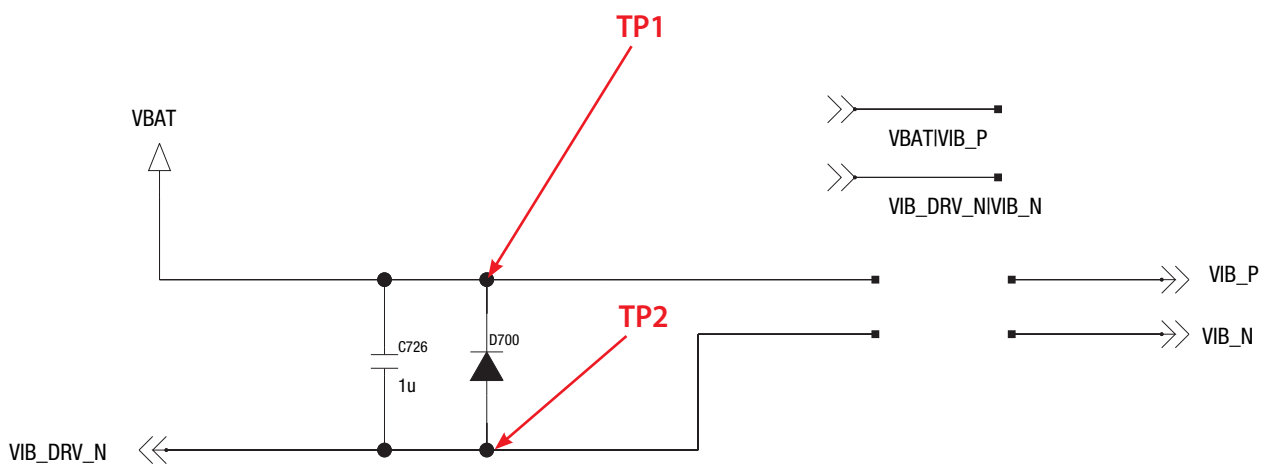


### Measurement

VBAT

VIB\_DRV\_N

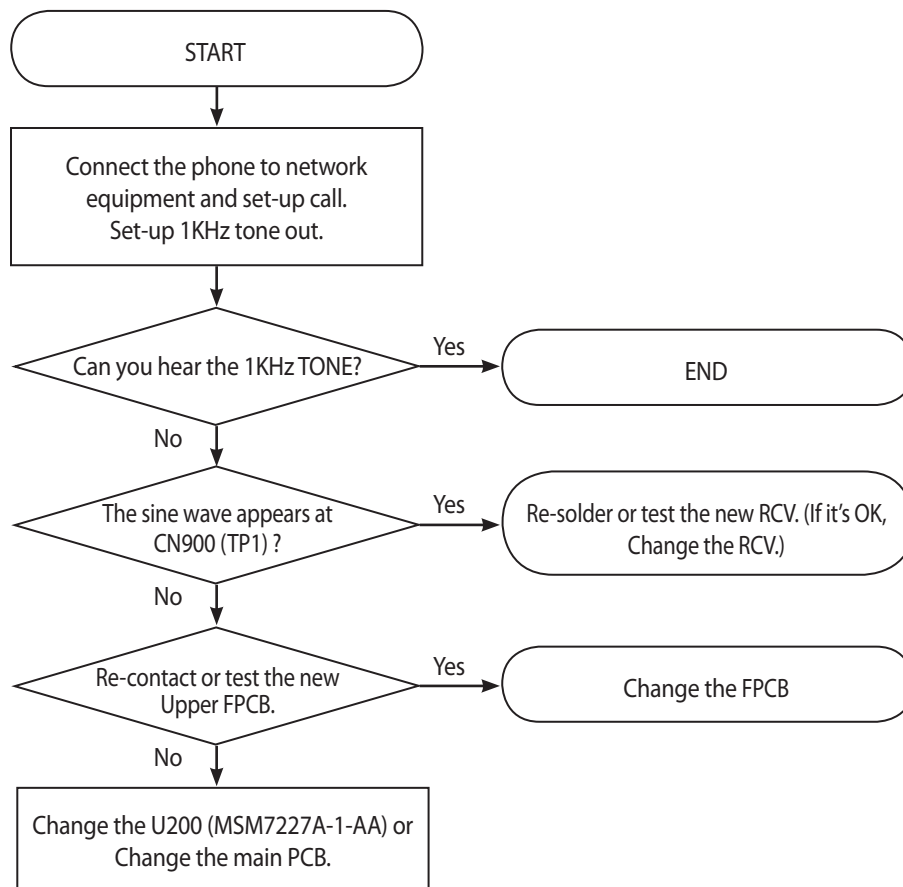
## MOTOR



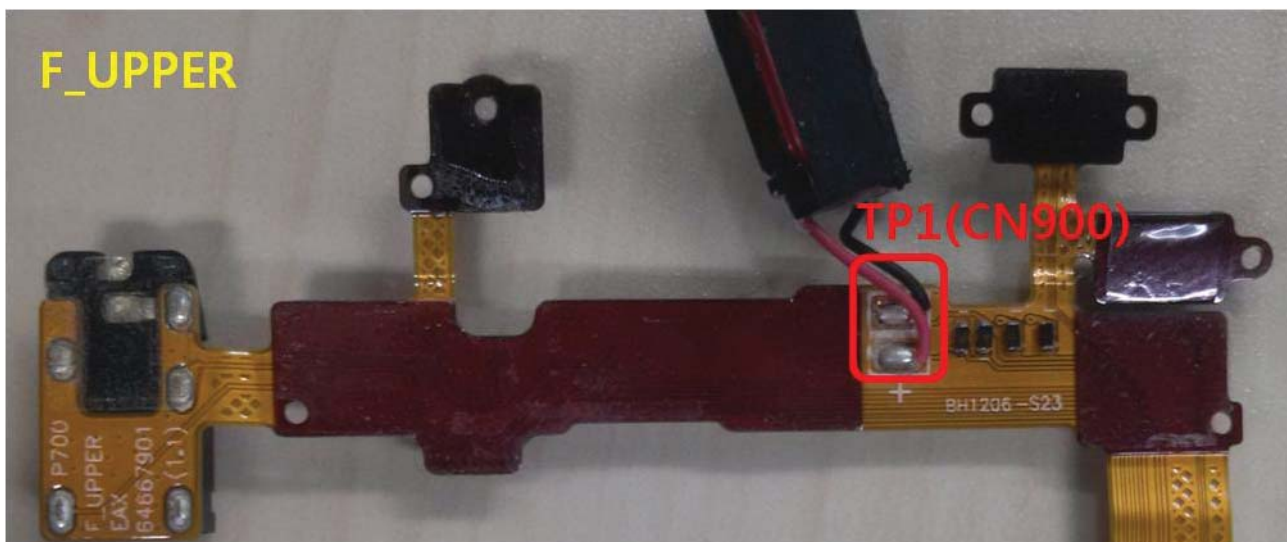
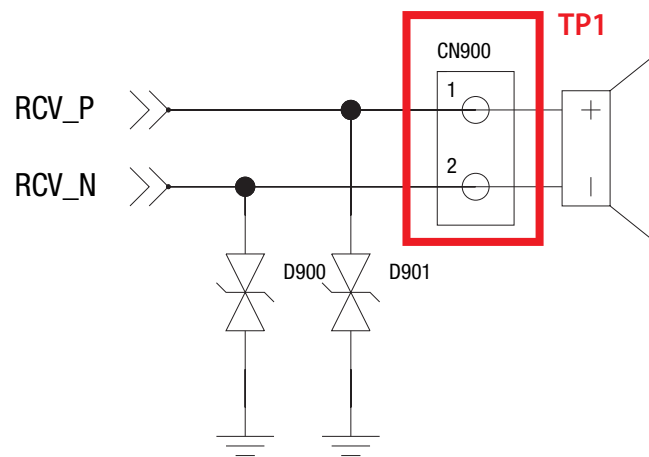
### 4.19 Audio Trouble

#### 4.19.1 Receiver Path

MSM7227A-1-AA RCV\_N / RCV\_P -> CN900 (TP1) (RCV pad)

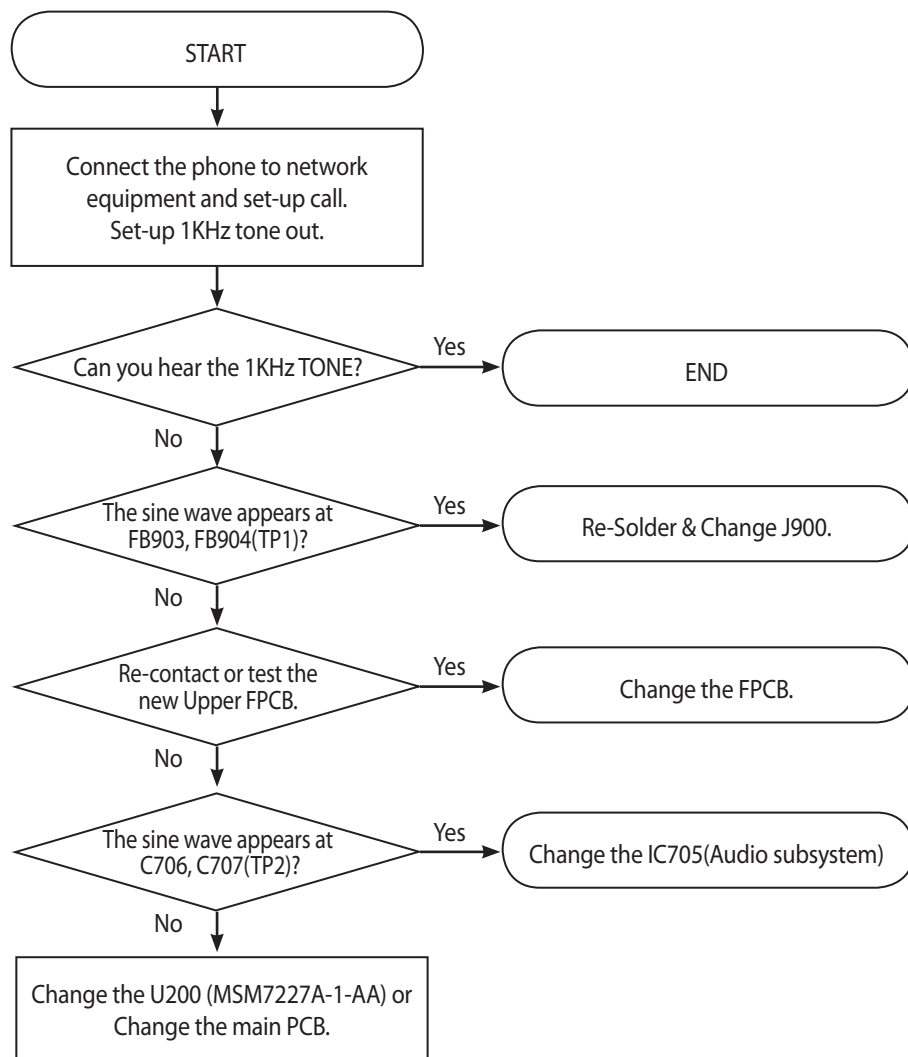


# RECEIVER

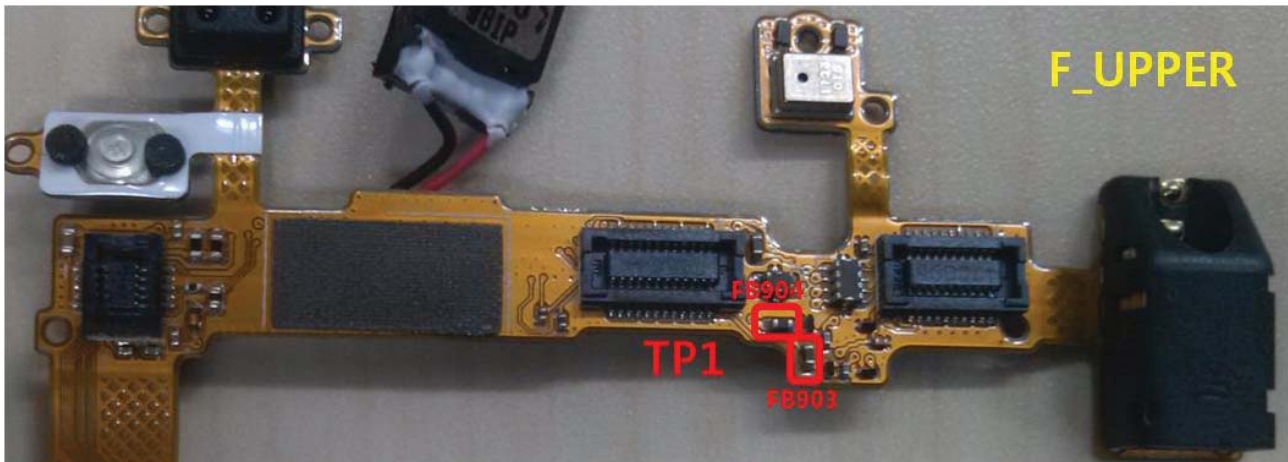
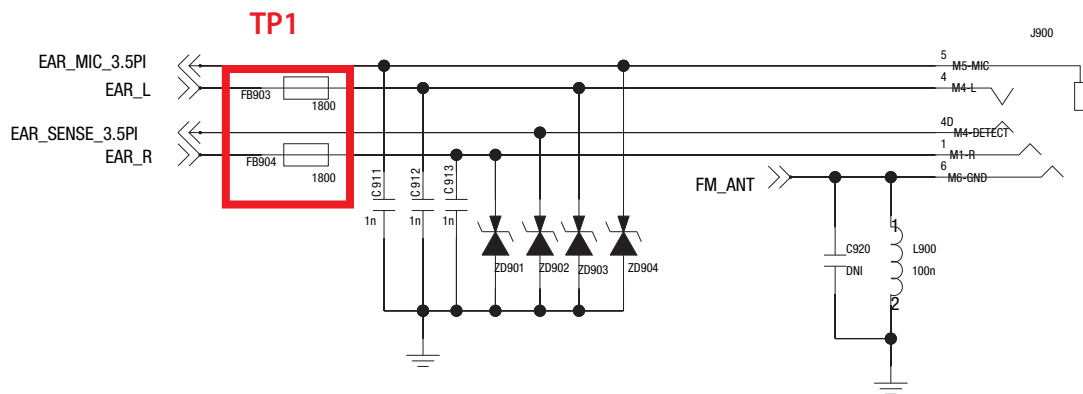


### 4.19.2 Headset path

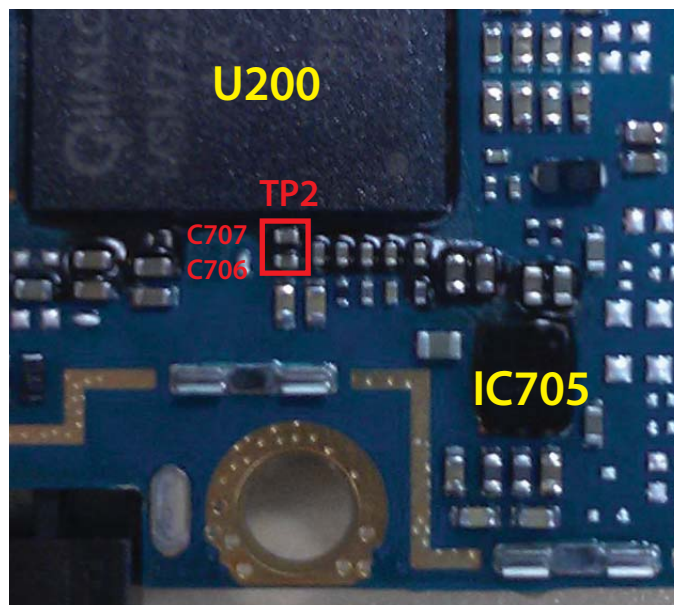
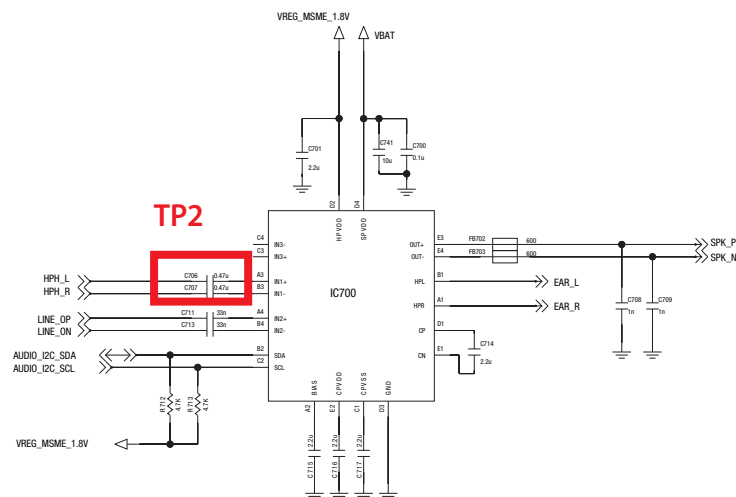
MSM7227A-1-AA HPH\_L / HPH\_R -> C706, C707(TP2) -> IC705 (TPA2055D3:Audio Subsystem) -> R710, R711 -> FB903, FB904(TP1) -> J900 (3.5pi Ear-jack)



## 3.5pi Ear Jack Connector



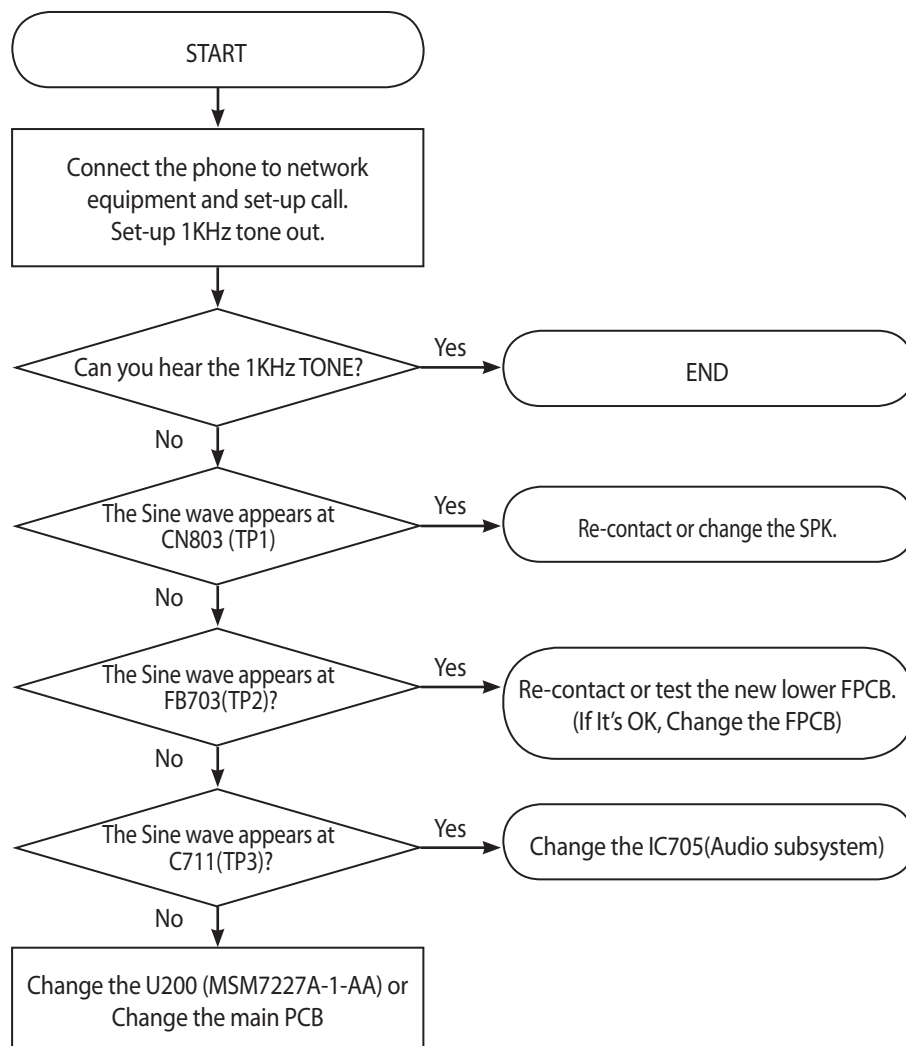
# Audio Sub System



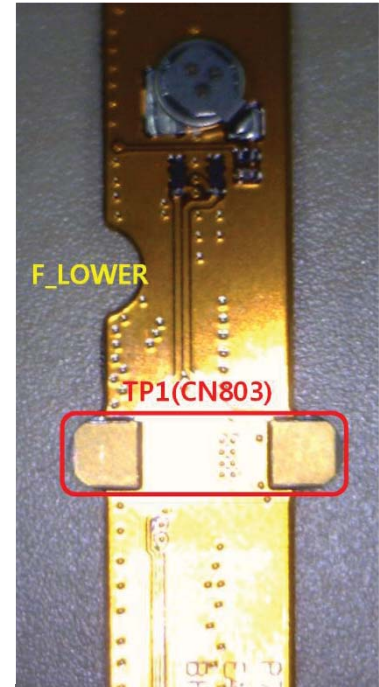
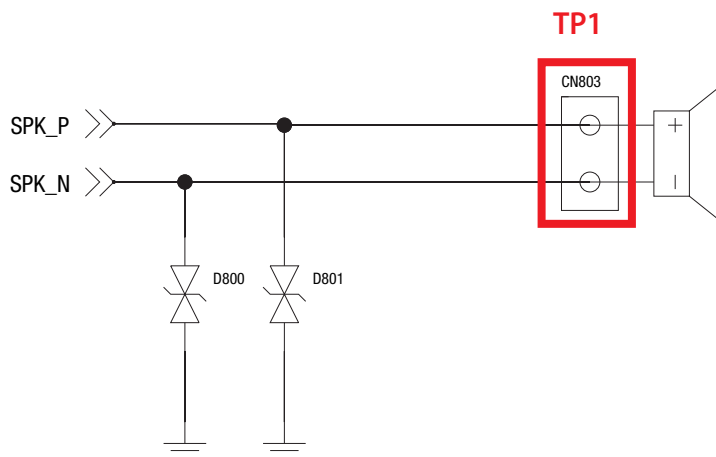


### 4.19.3 Speaker/Speaker Phone path

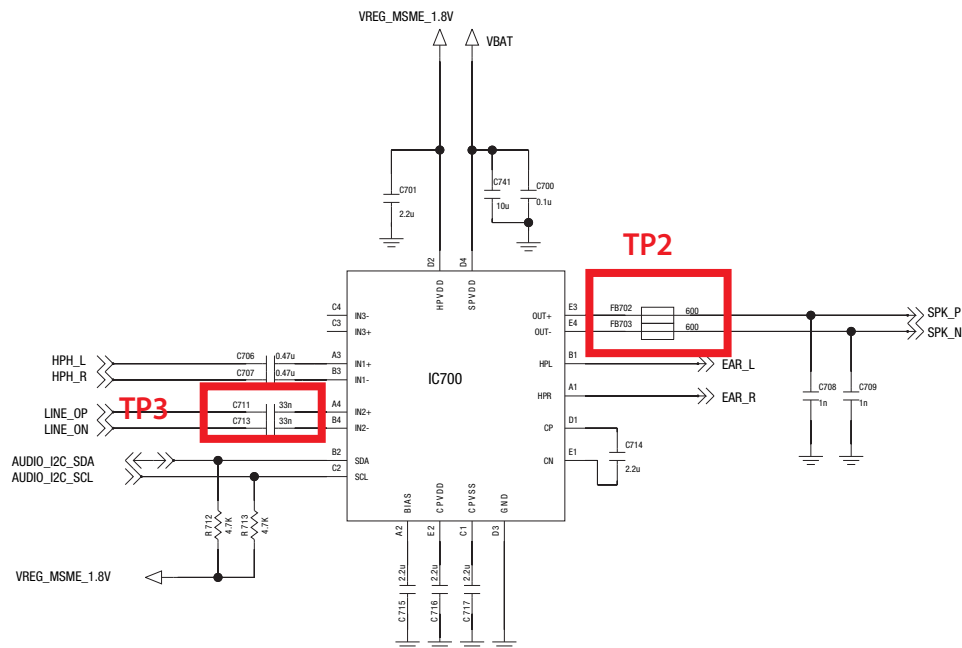
MSM7227A-1-AA LINE\_OP, LINE\_ON -> C711, C713(TP3) -> IC705 (TPA2055D3: Audio Subsystem) -> FB702, FB703(TP2)  
-> CN803(TP1)(SPK pad)

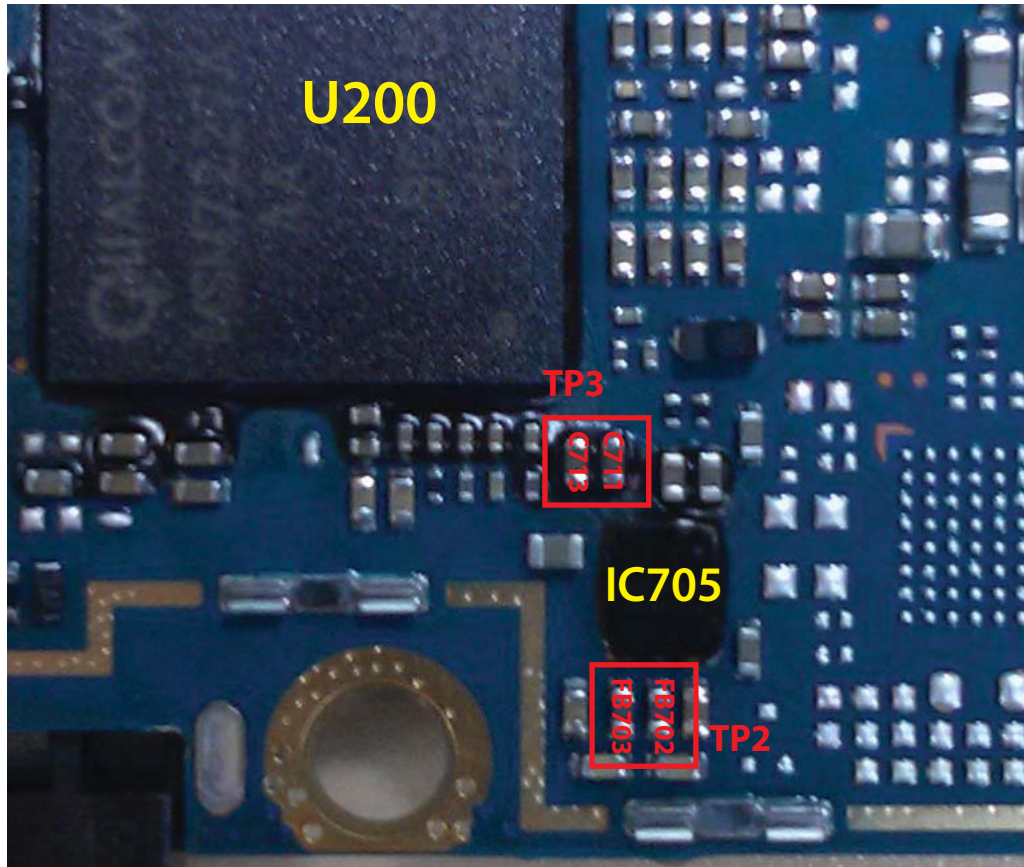


# SPEAKER



## Audio Sub System

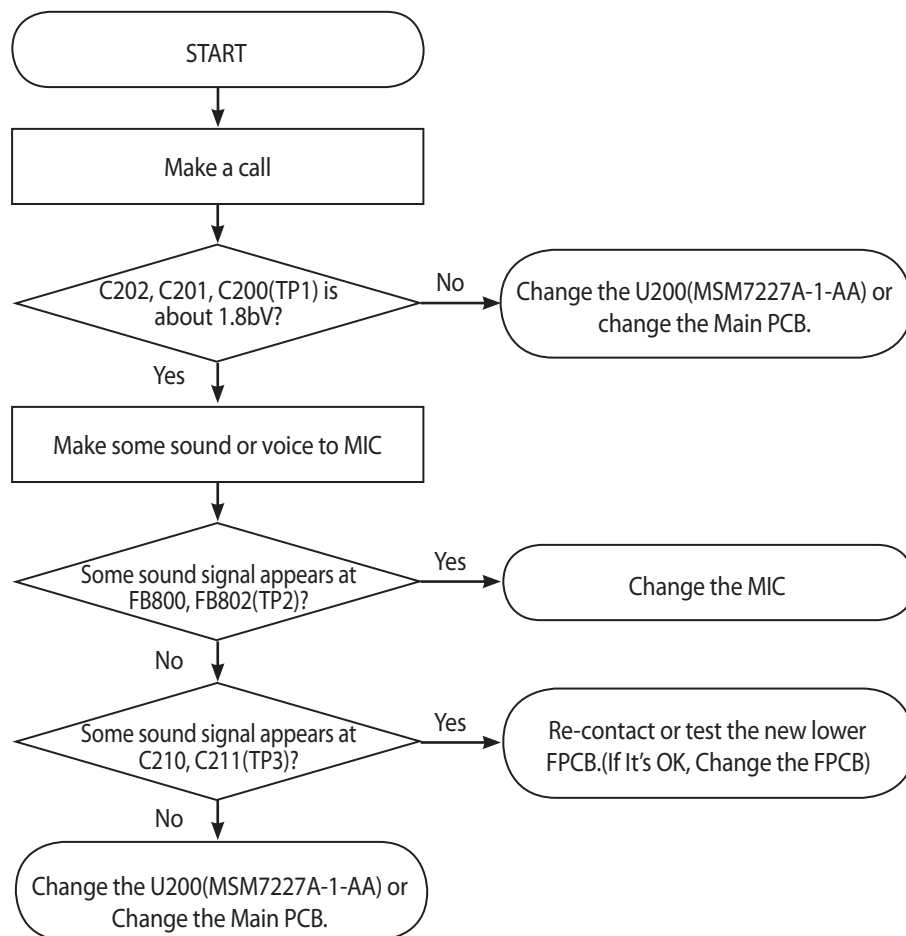


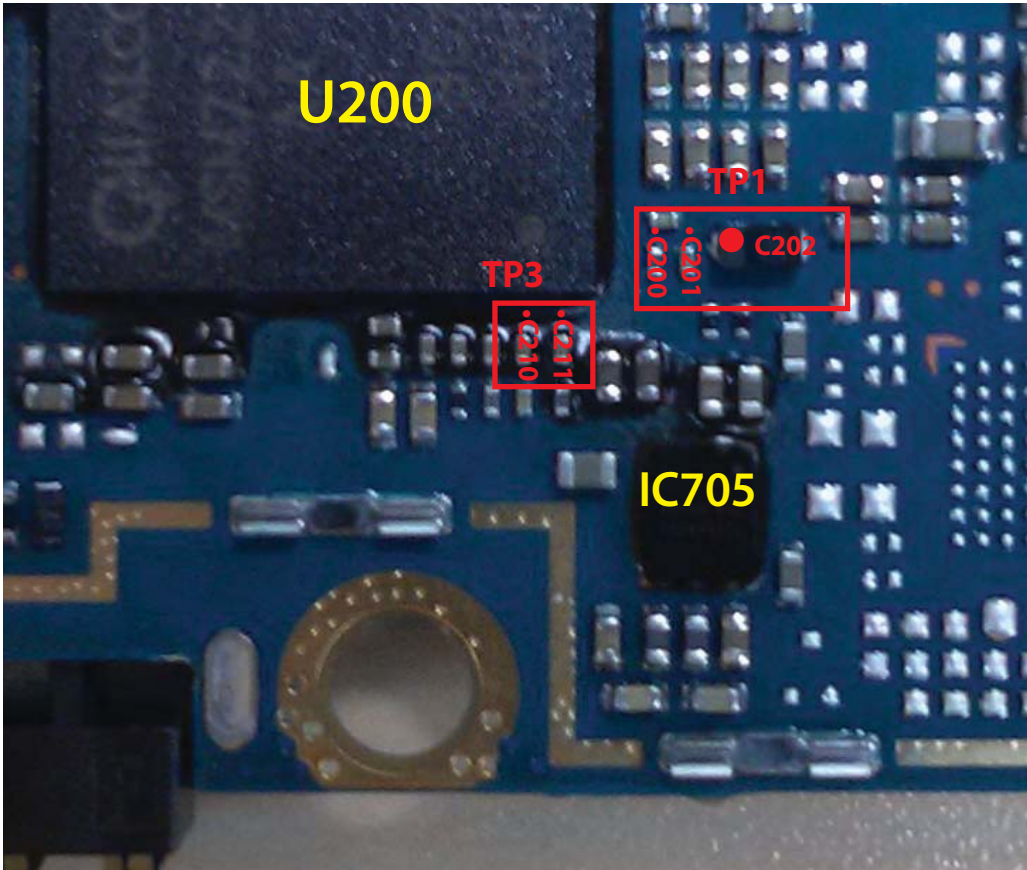


### 4.19.4 Main Microphone

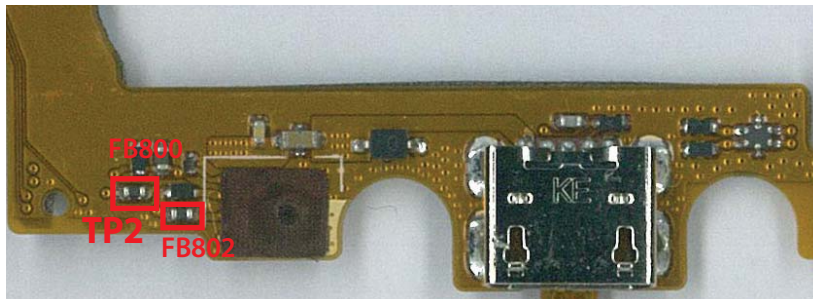
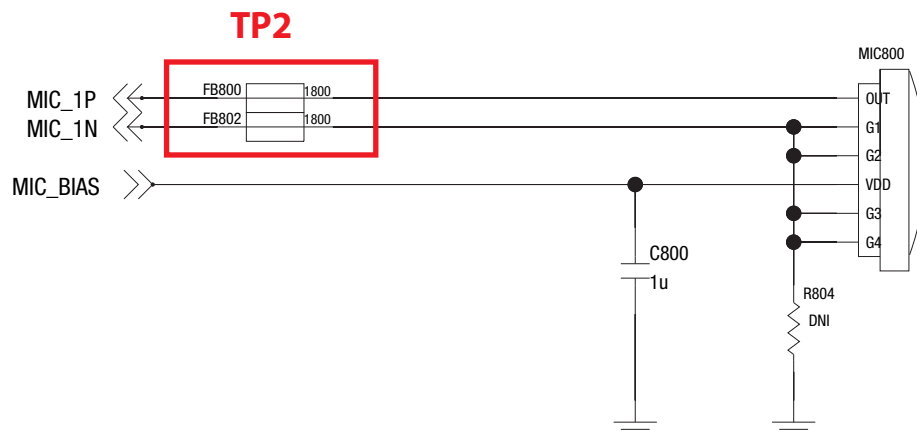
MIC Signal: MIC800 -> FB800, FB802(TP2) -> C211(TP3) MIC\_1P of MSM7227A-1-AA

MIC Bias: MSM7227A-1-AA MIC\_BIAS -> MIC800





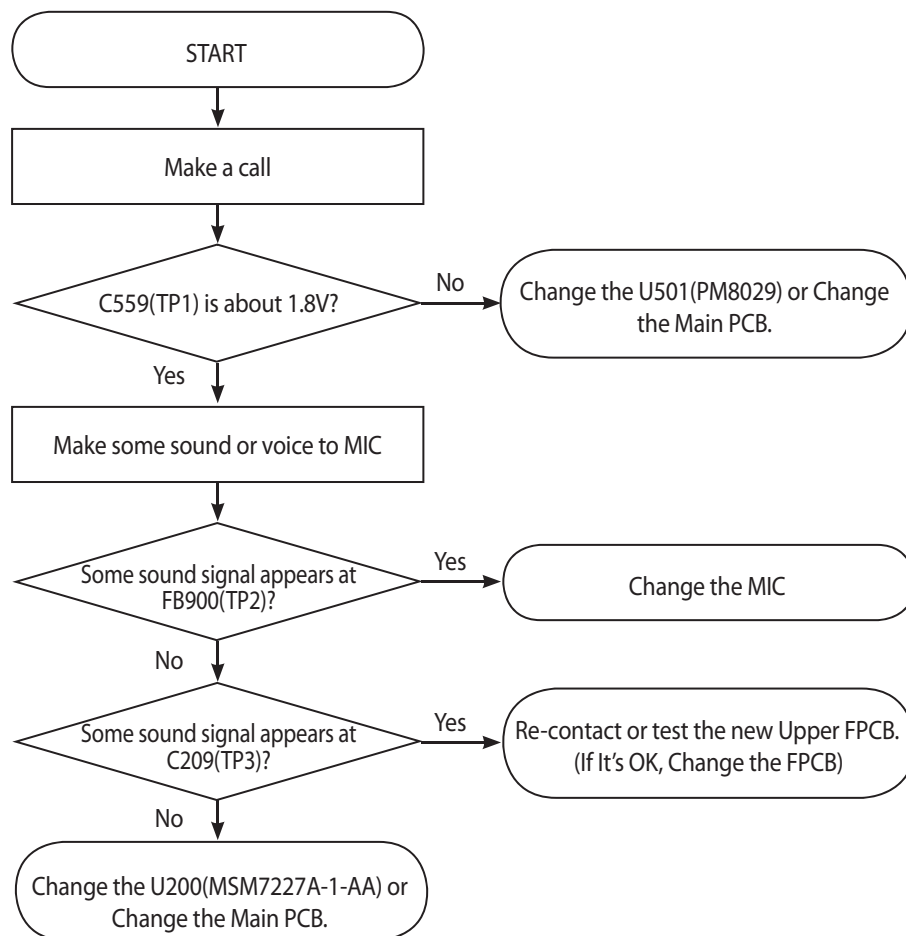
# MAIN MIC



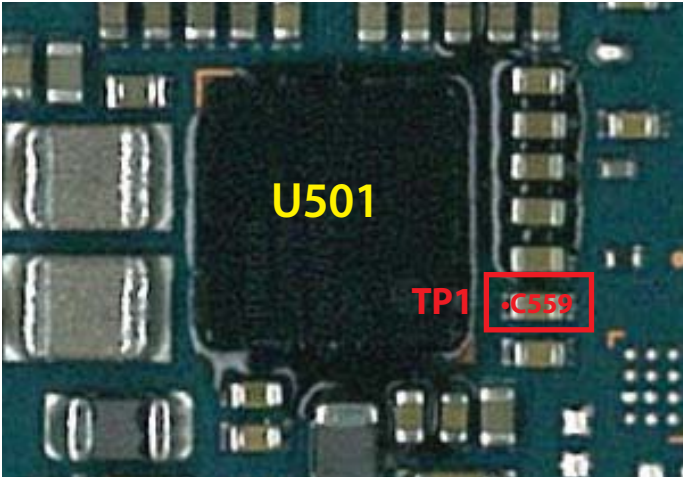
### 4.19.5 2nd Microphone

MIC Signal: MIC900 -> FB900, FB802(TP2) -> C209(TP3) MIC\_2P(AUXIP) of MSM7227A-1-AA

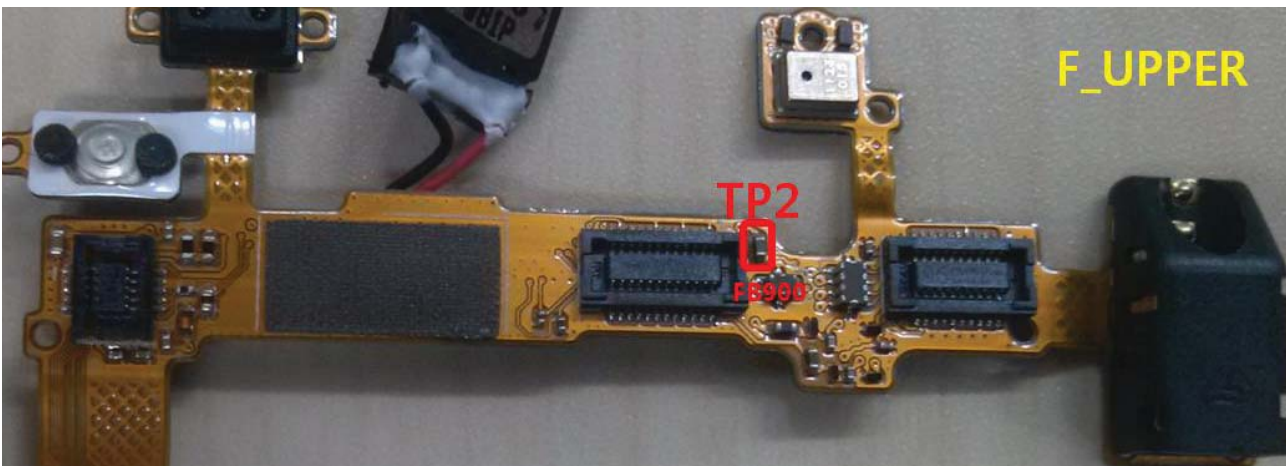
MIC Bias: PM8029 HSED\_BIAS2 -> MIC900

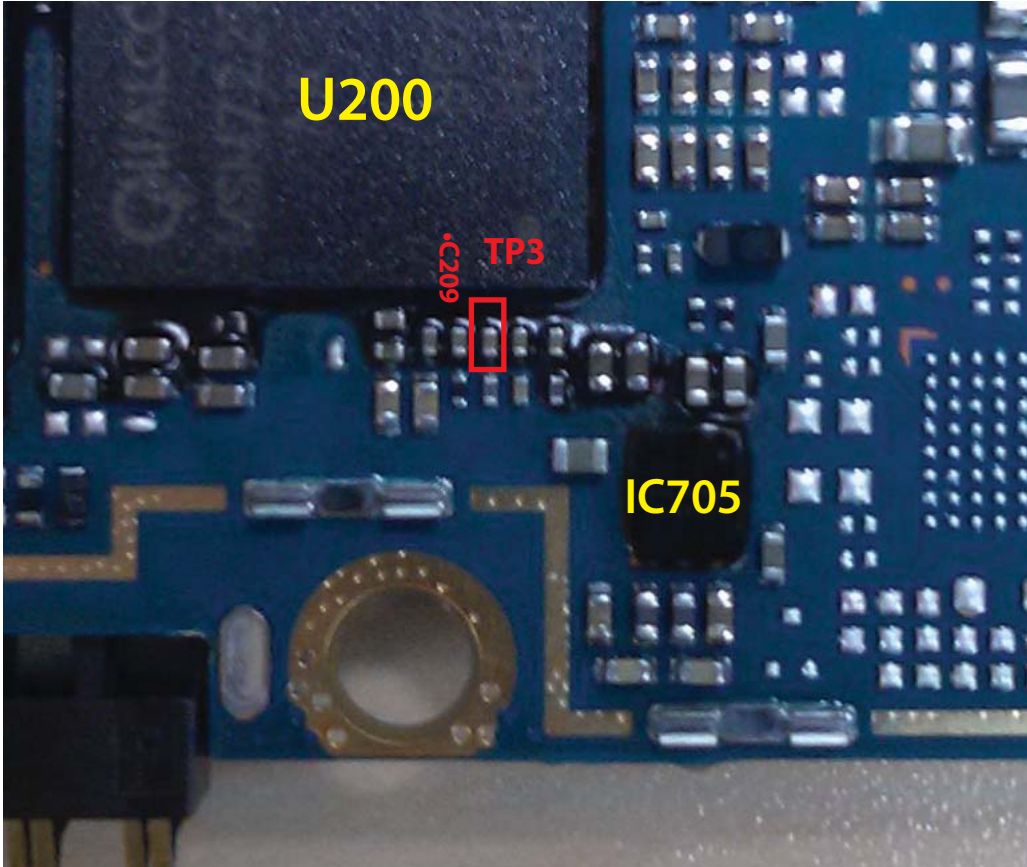






## 2nd MIC



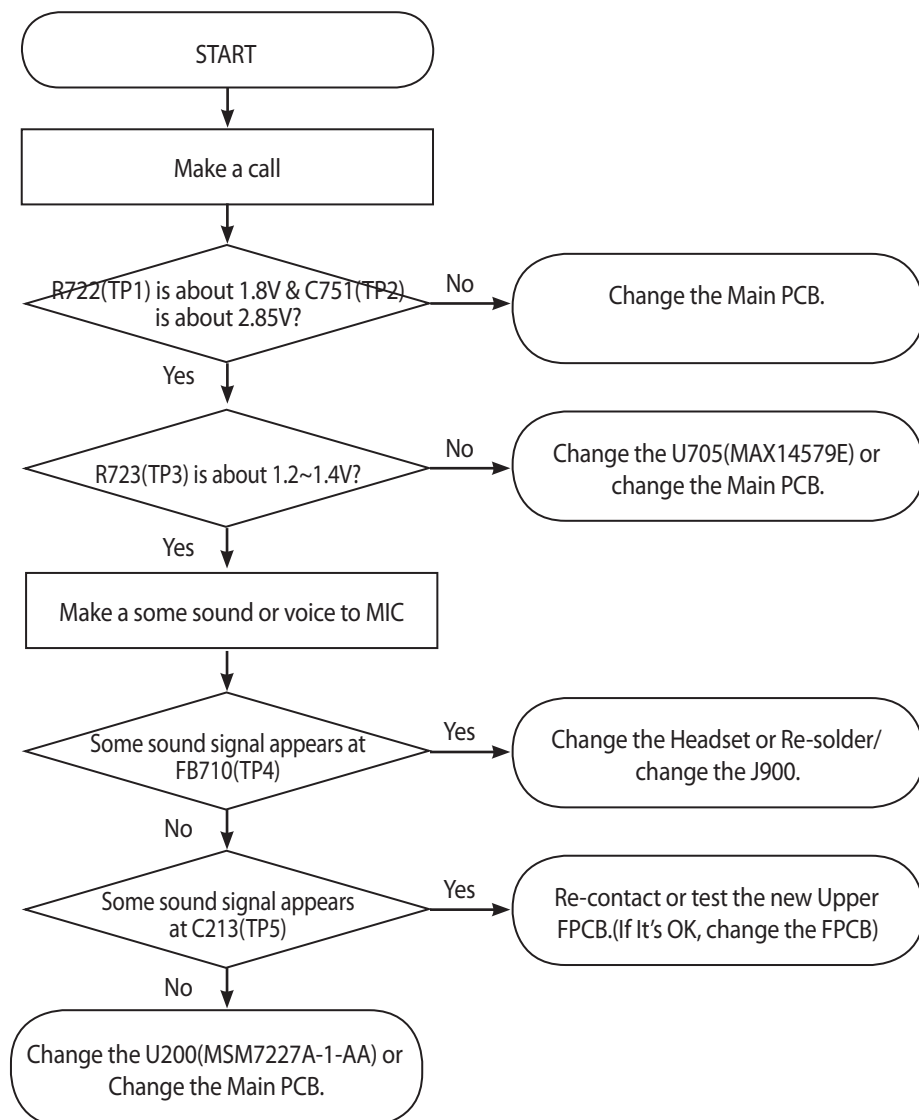


### 4.19.6 Headset mic ophone

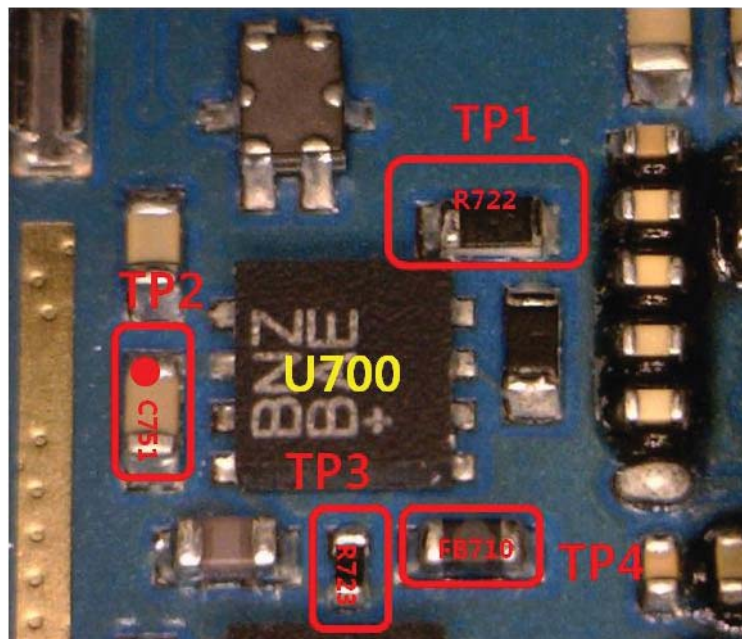
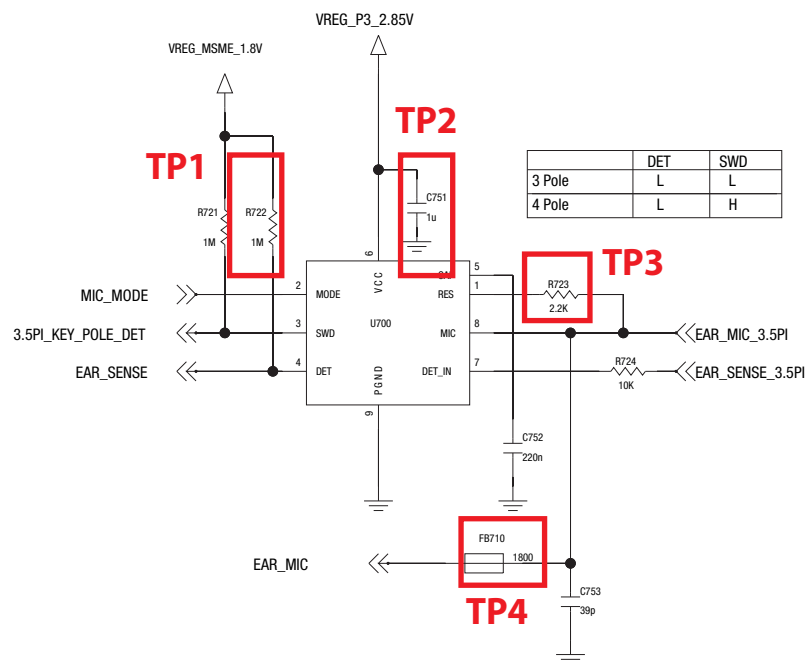
MIC Signal: 3.5 pi Headset (J900) → FB710(TP4) → C213(TP4) EAR\_MIC(MIC2P) of MSM7227A-1-AA

MIC Bias : VREG\_MSME\_1.8V → R722 (**TP1**) (DET) → R723(TP3)(RES) -> Headset MIC

HS Detect IC Bias: VREG\_P3\_2.85V



# HEADSET\_DETECT

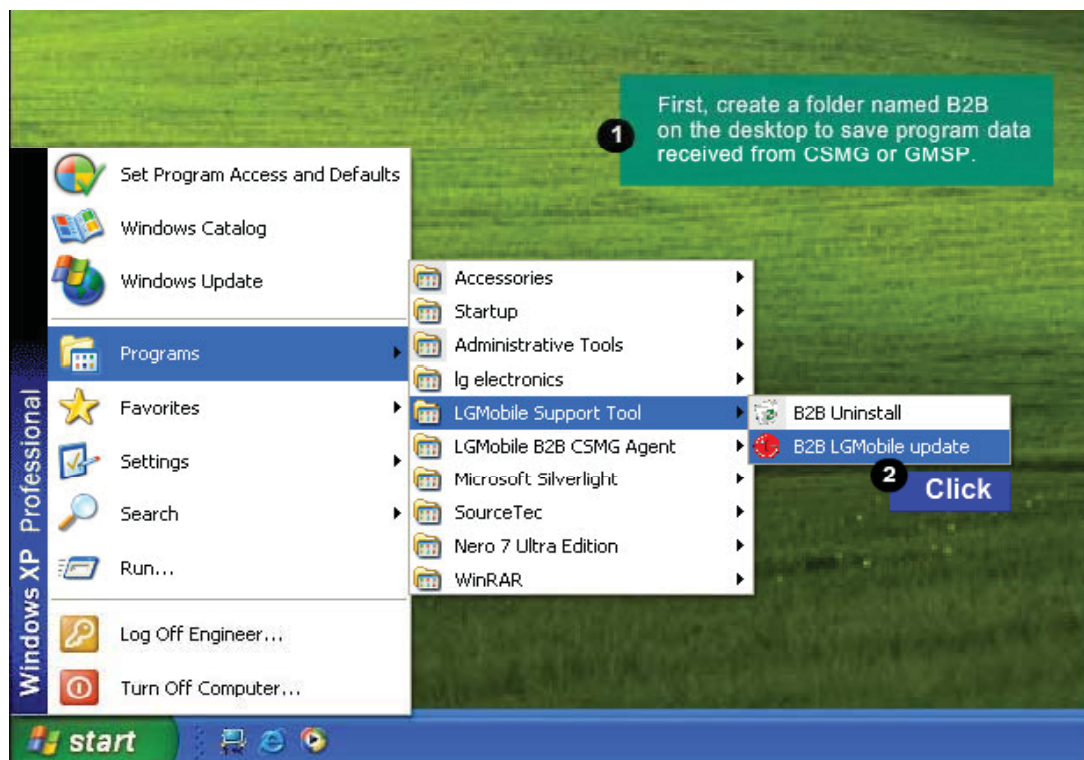




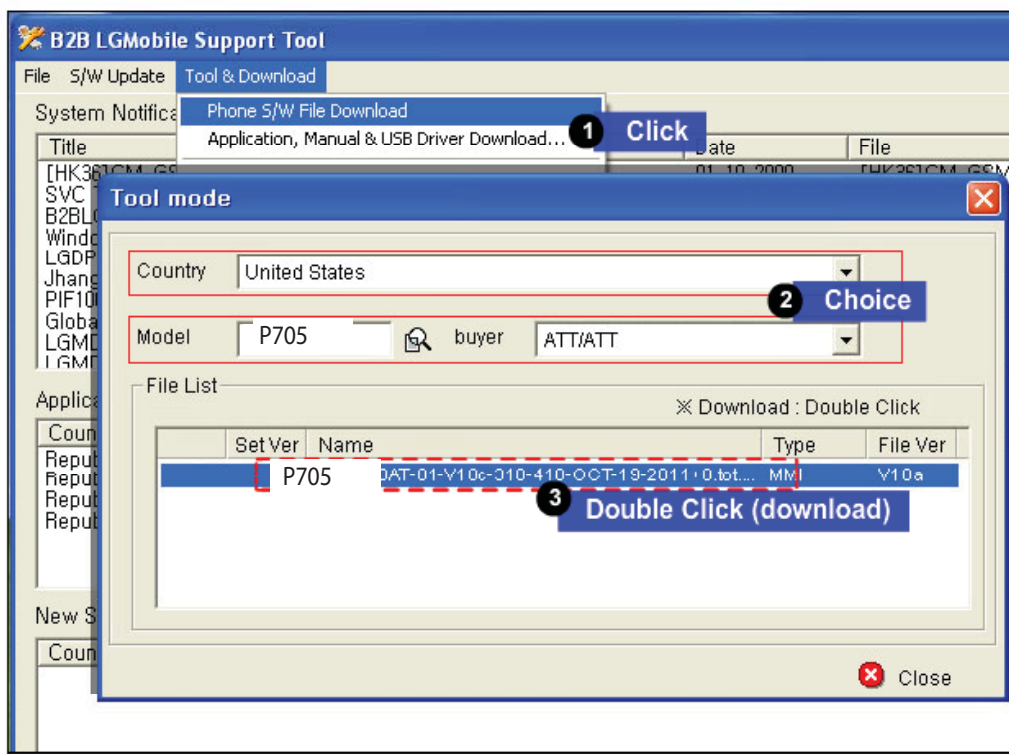
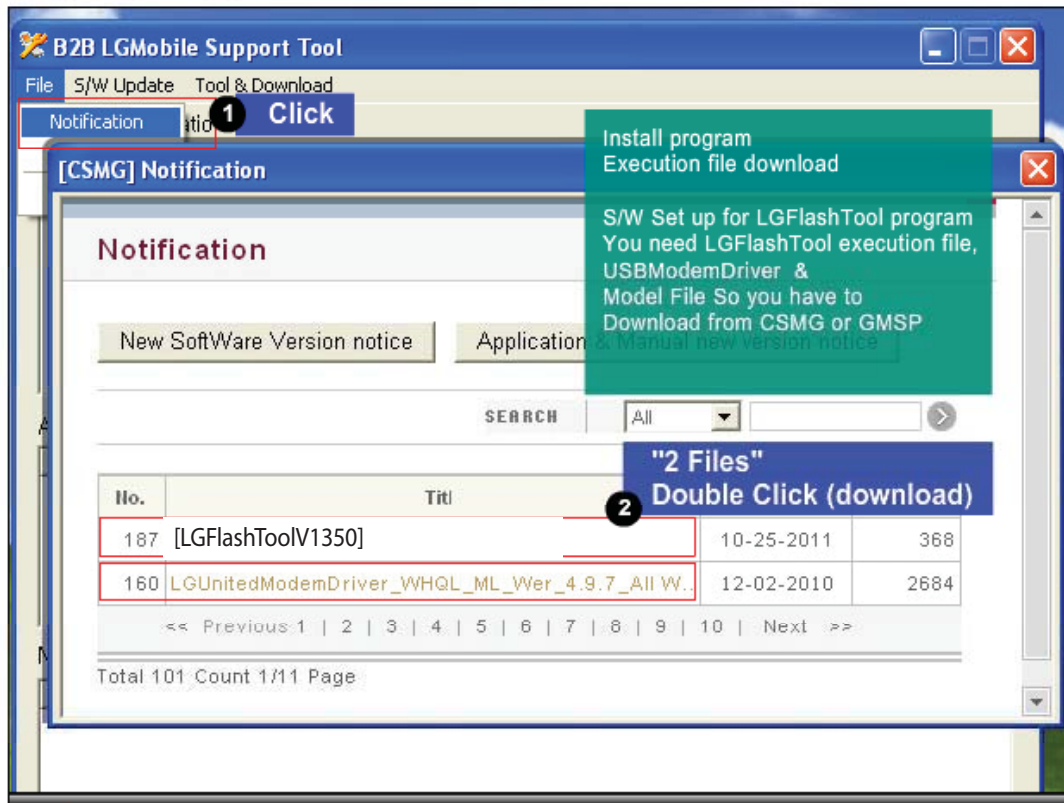


## 5. DOWNLOAD

TOOL INFORMATION		
TOOL VERSION	DLL NAME	USB DRIVER
[LGFlashToolV1350]	[LGFlashToolV1350]LGP705_120413_ Download	LG United Mobile Driver Version 3.6 Package Release 2011.11.01
Please check the final version to "B2B"		
H/W		
	Name	Part No.
D/L Cable	Micro 5P (56-open-910K) USB DLC	RAD32167835

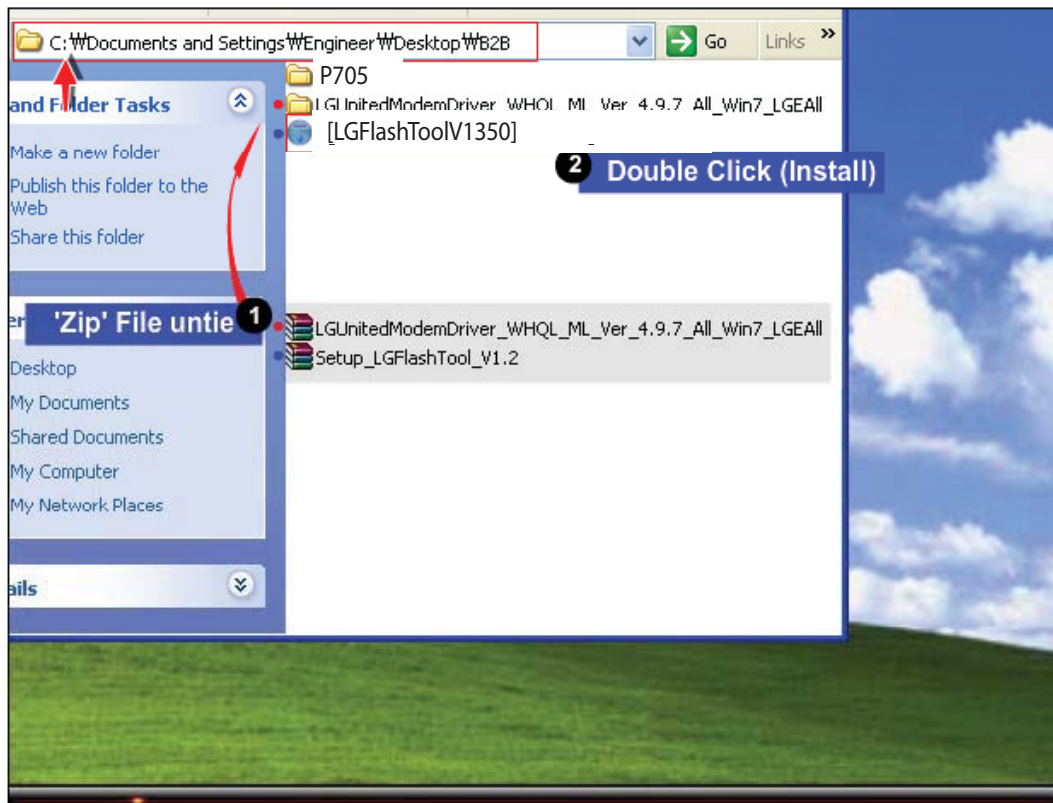
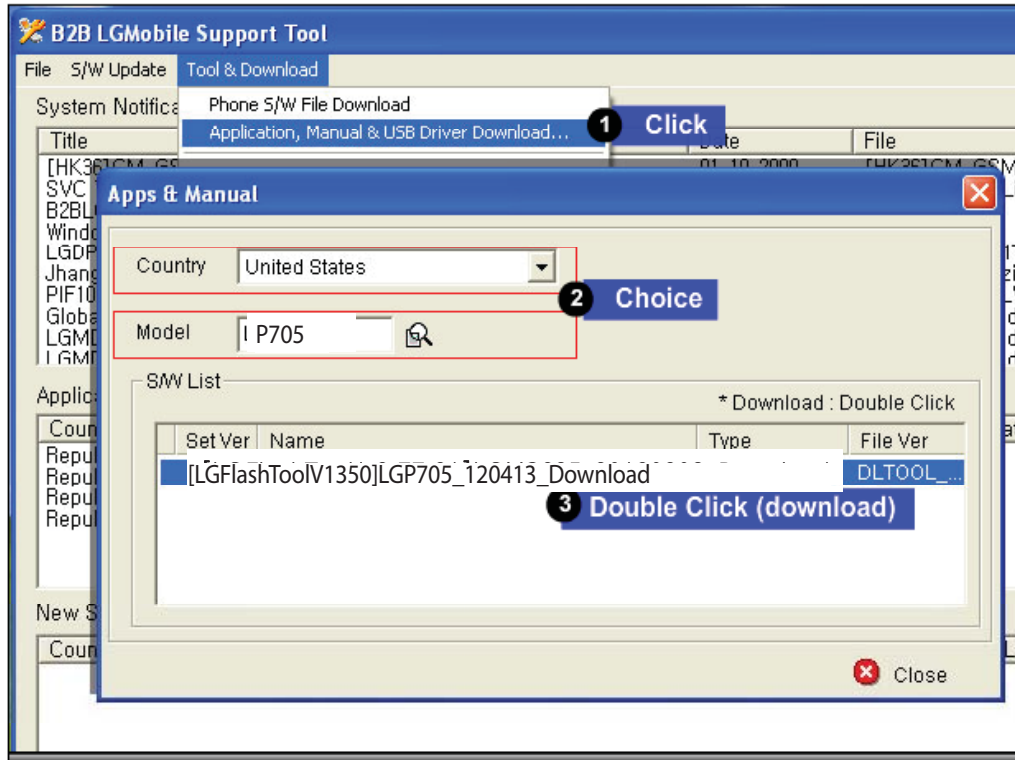


## 5. DOWNLOAD

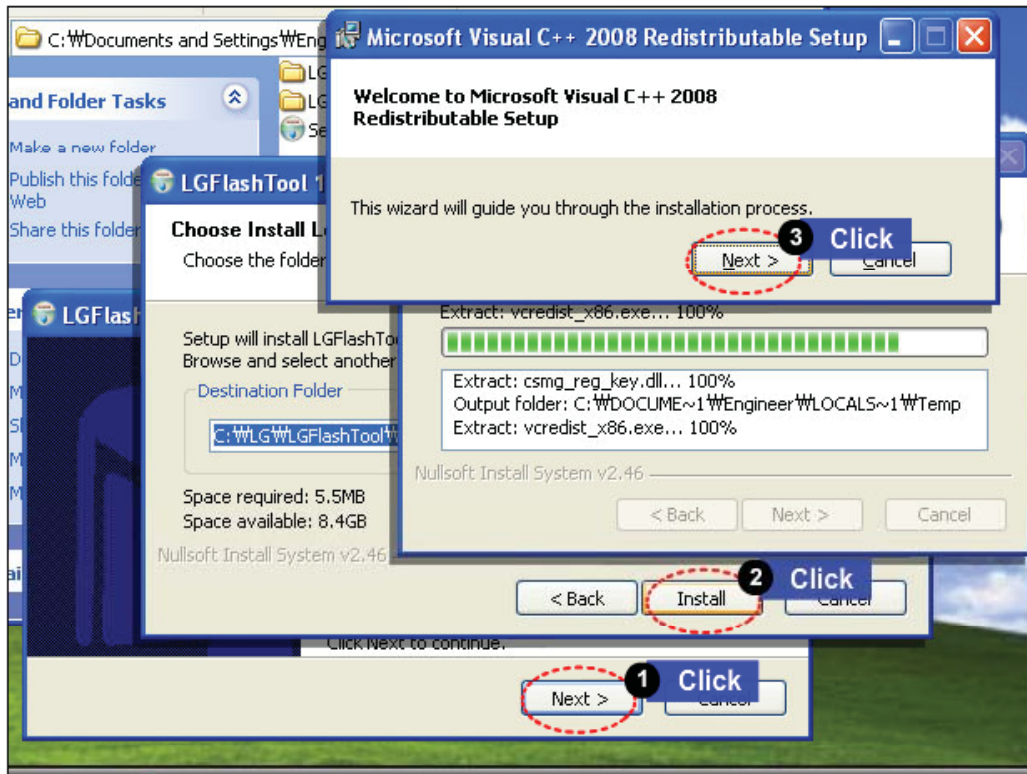




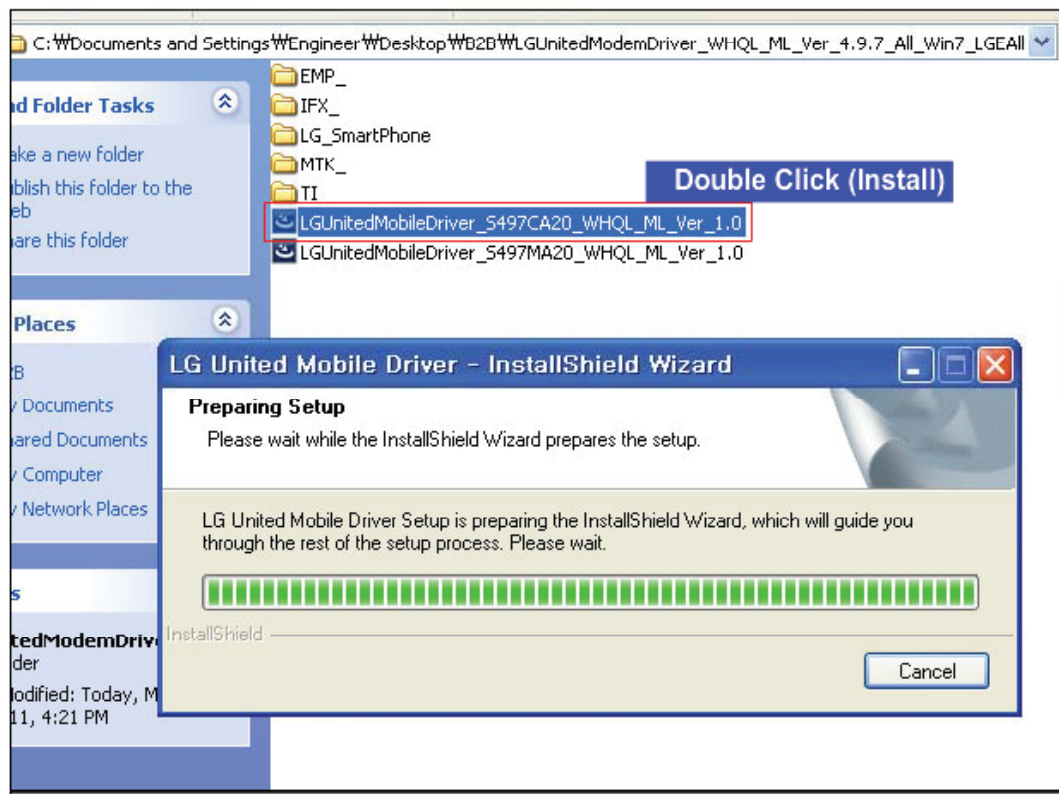
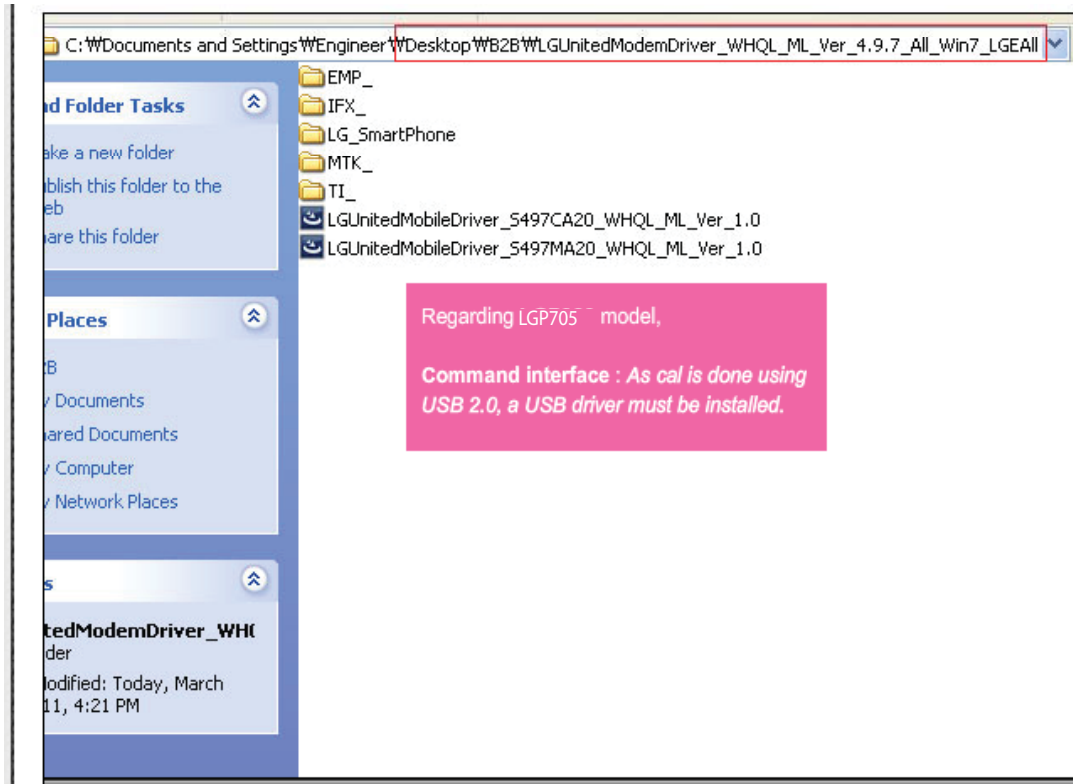
## 5. DOWNLOAD

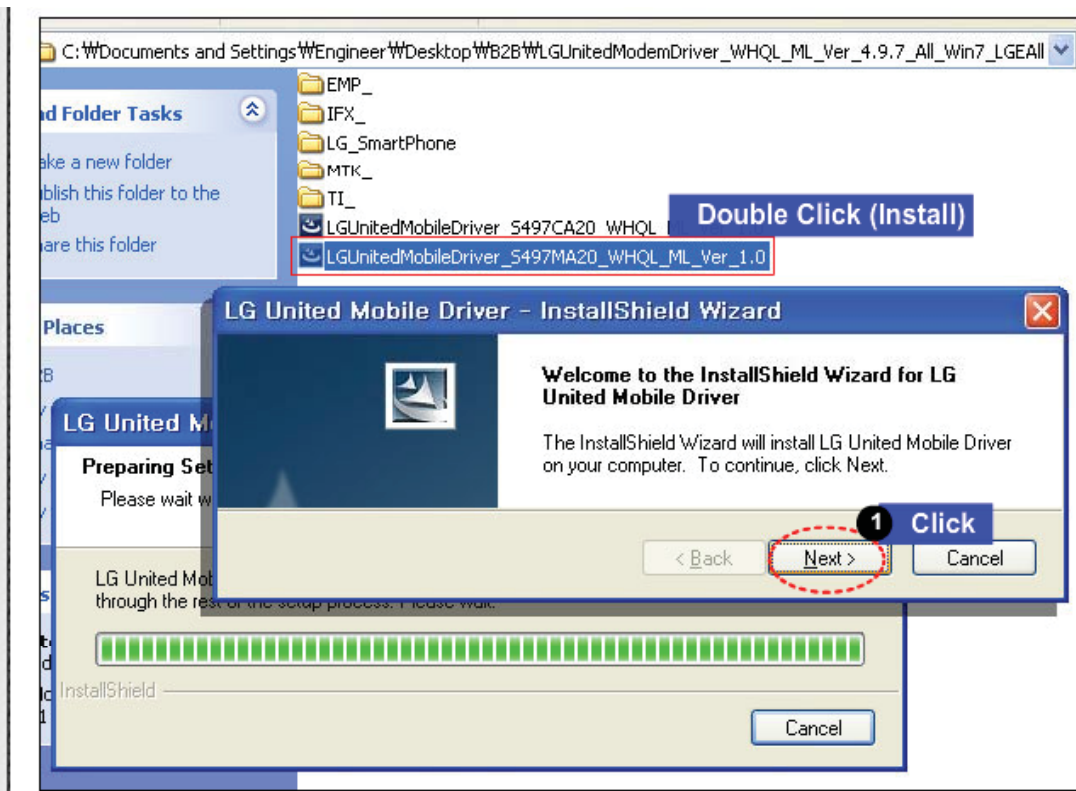
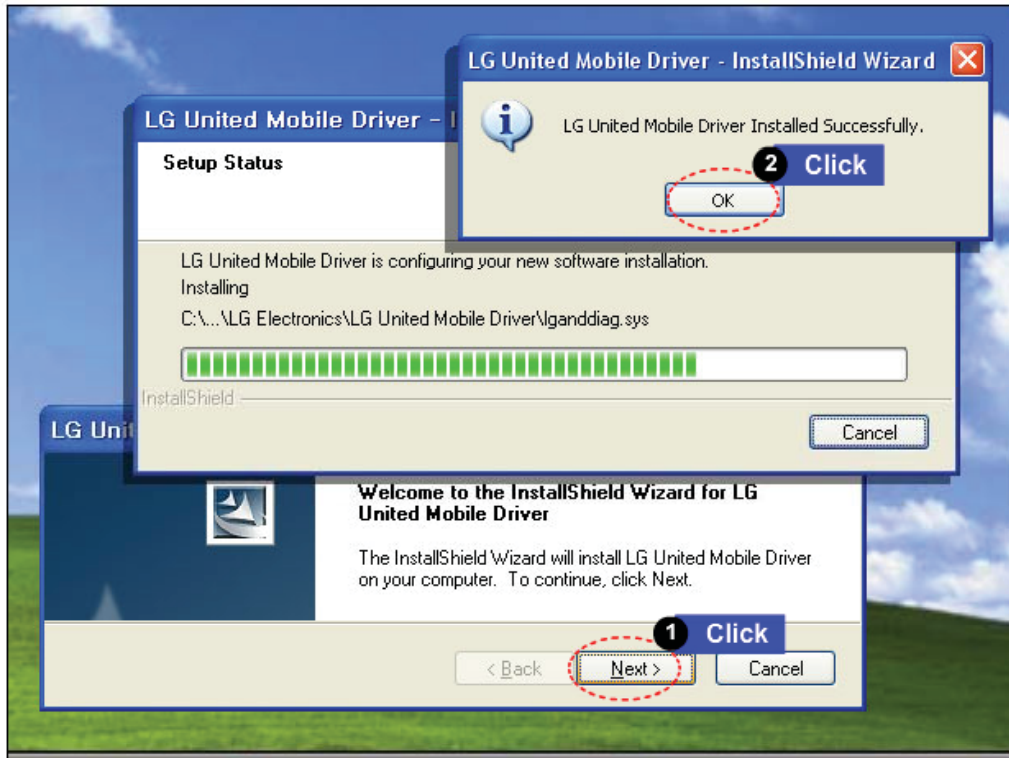


## 5. DOWNLOAD

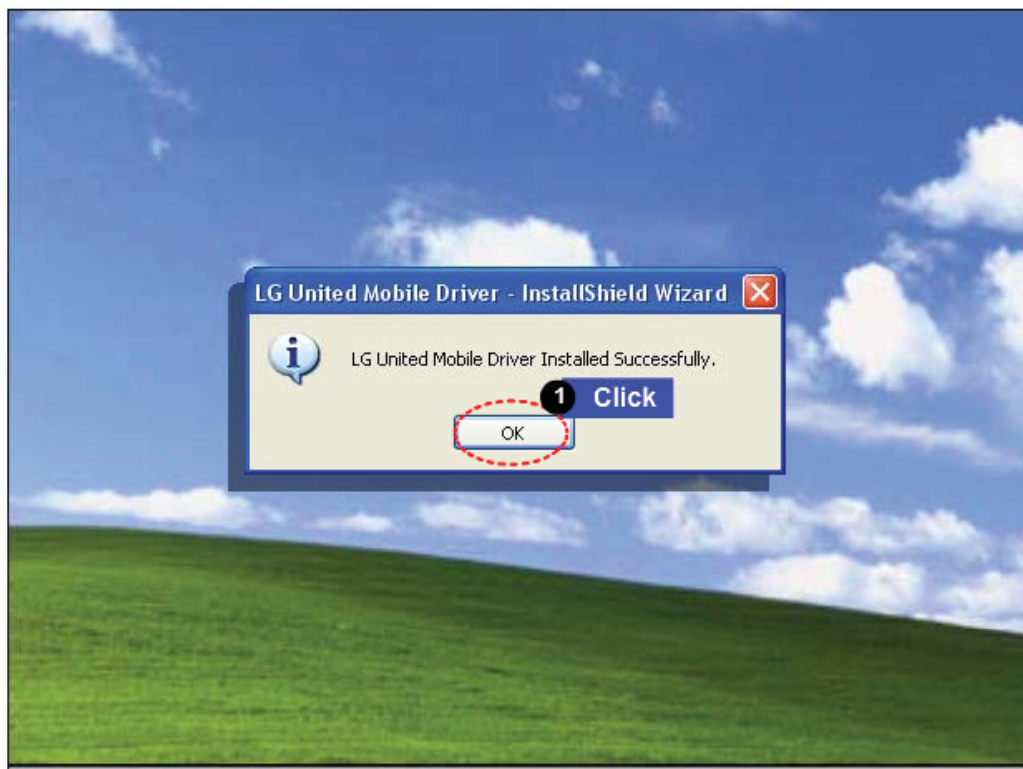
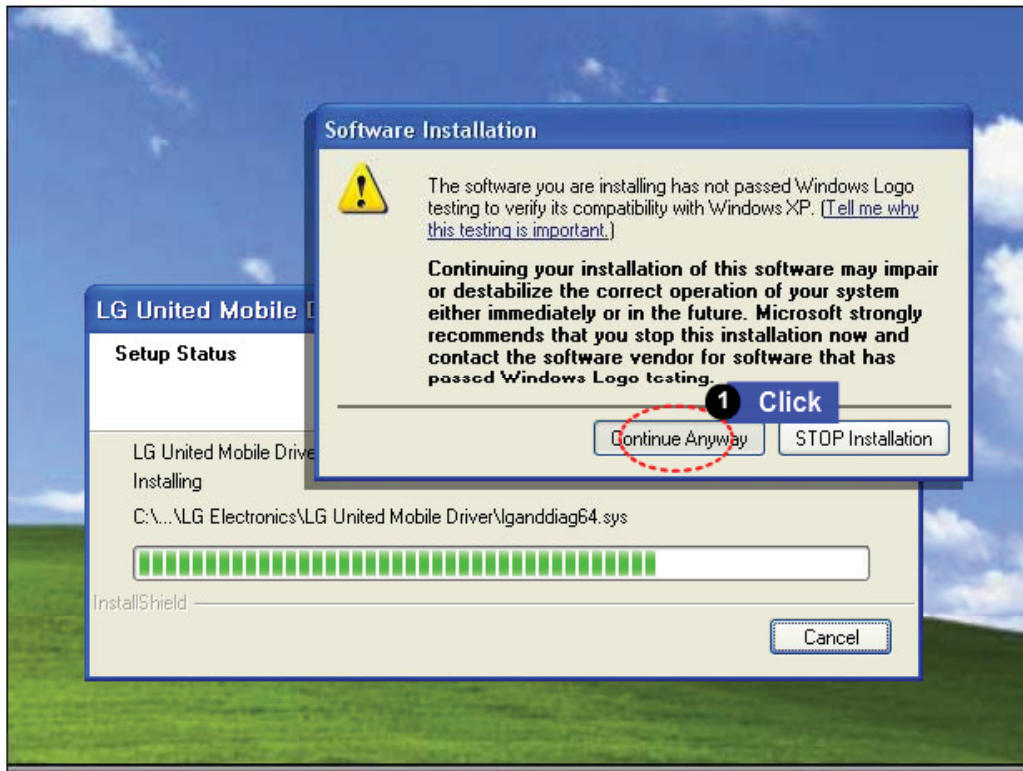


## 5. DOWNLOAD

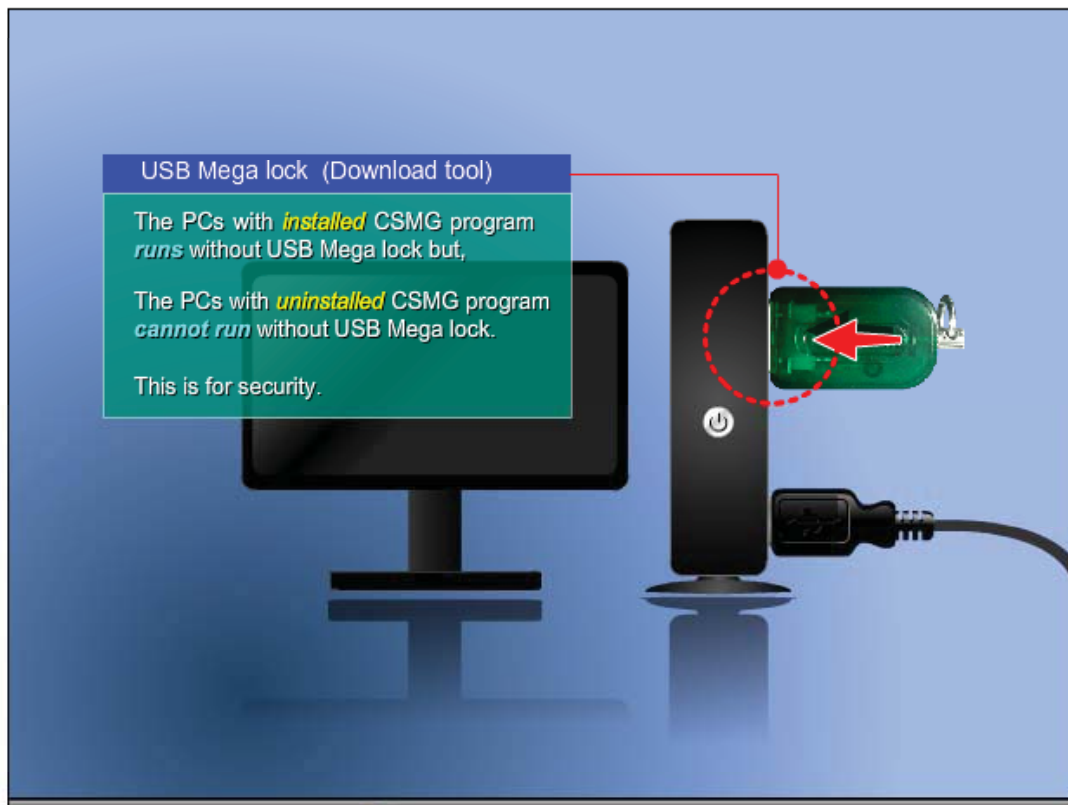
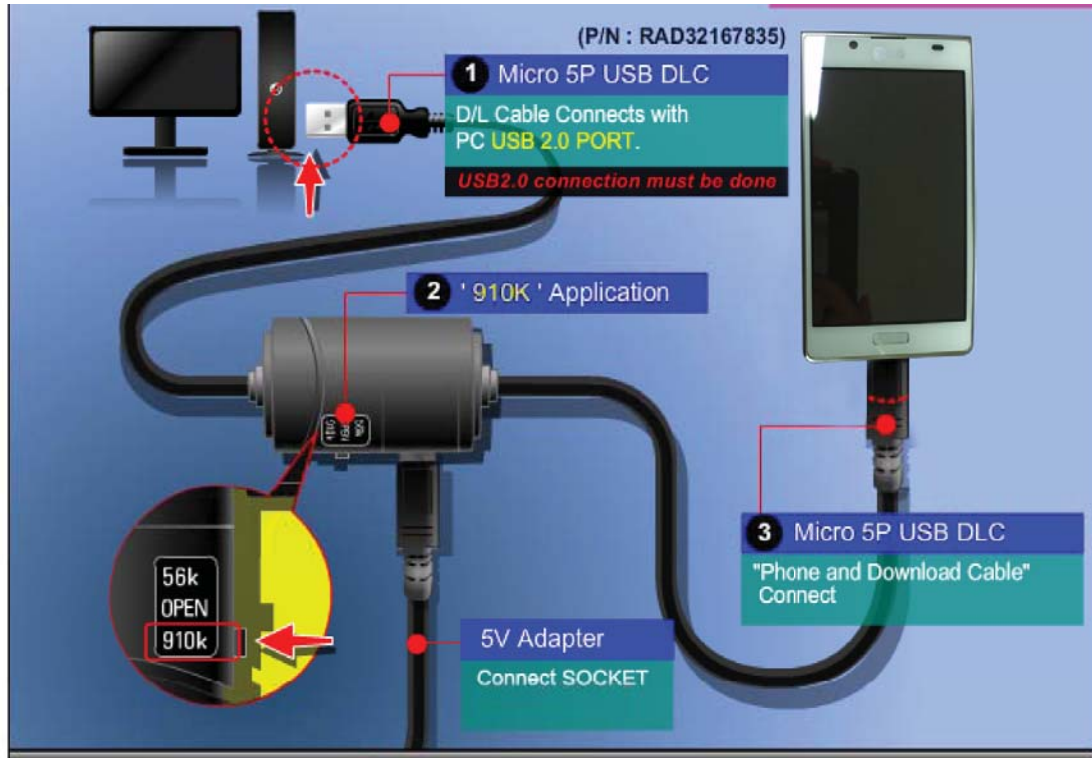


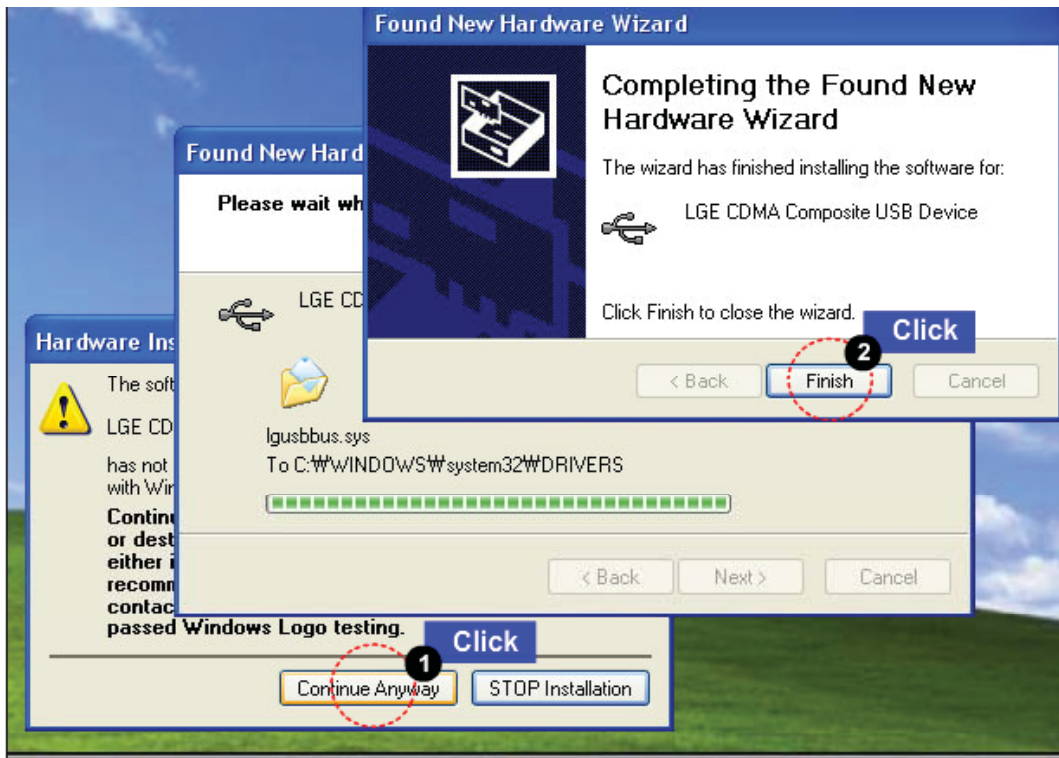
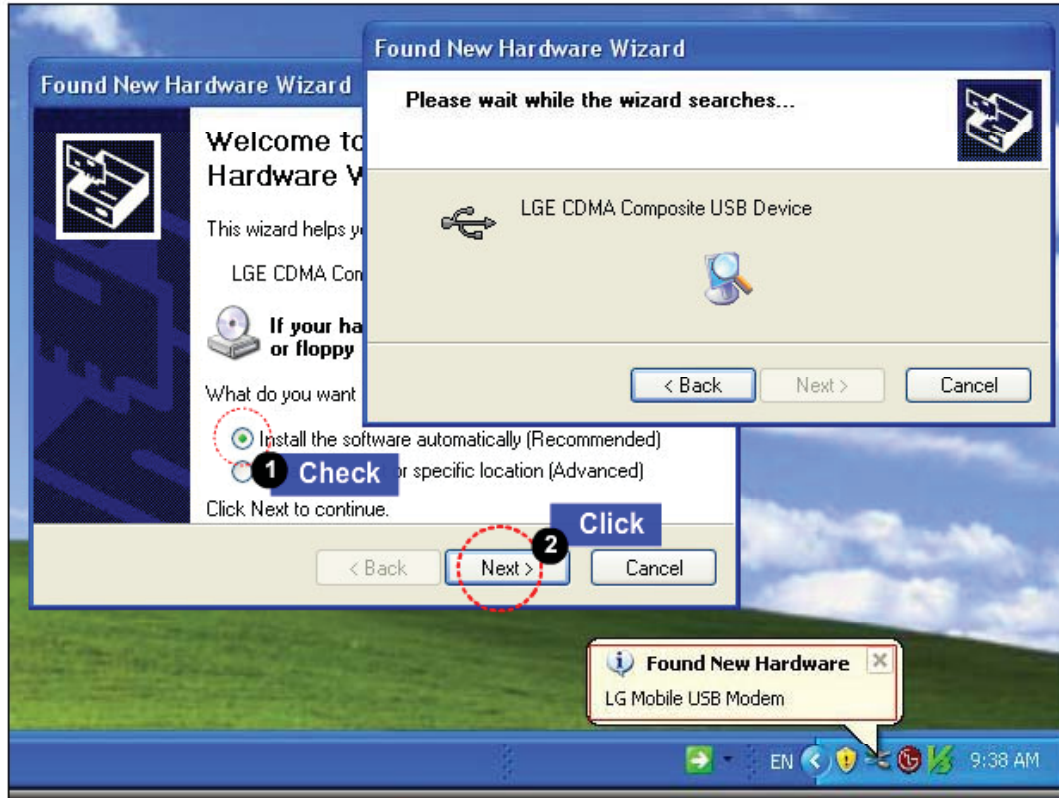






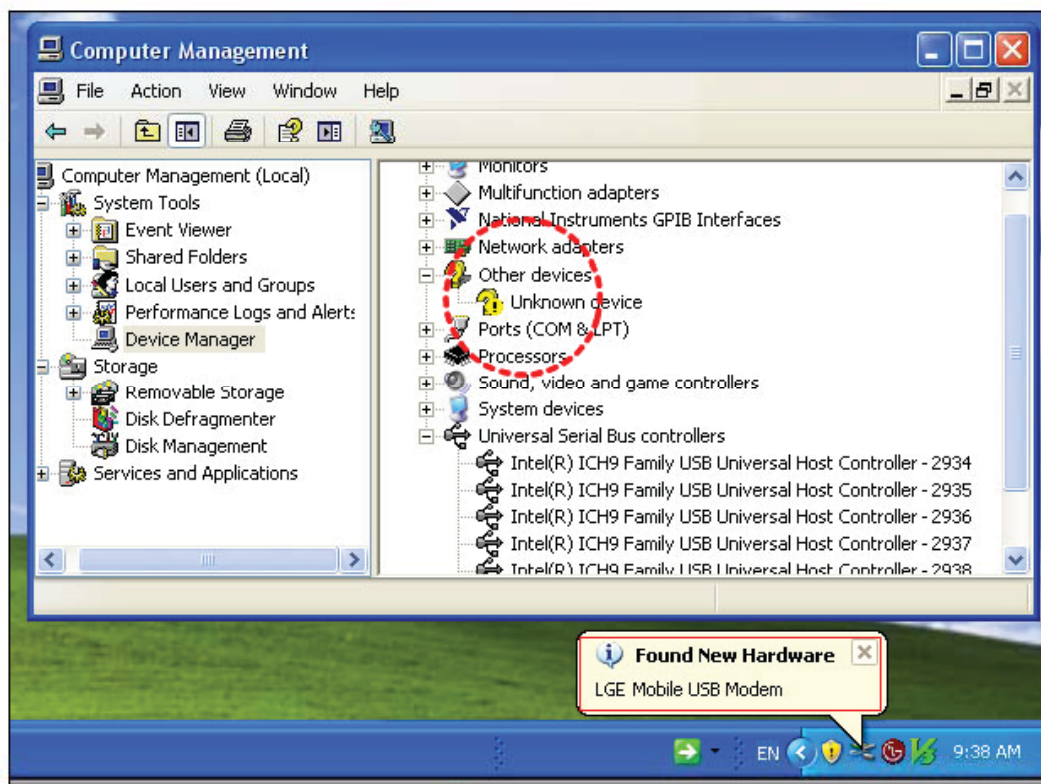
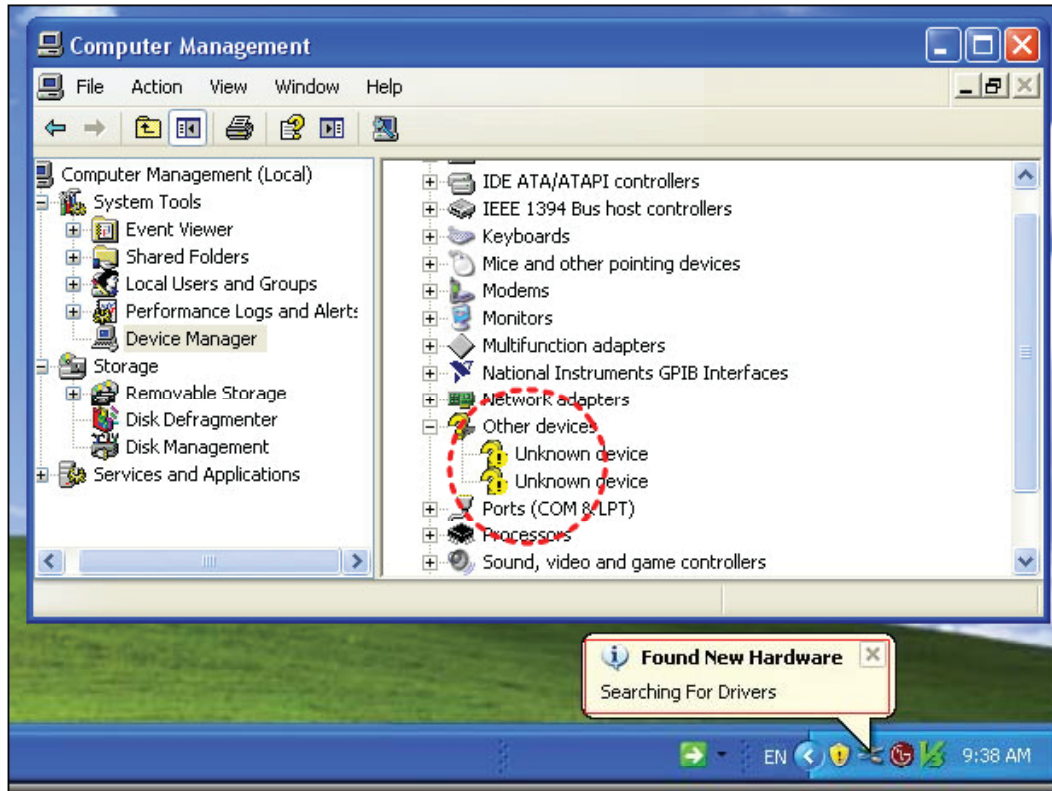
## 5. DOWNLOAD

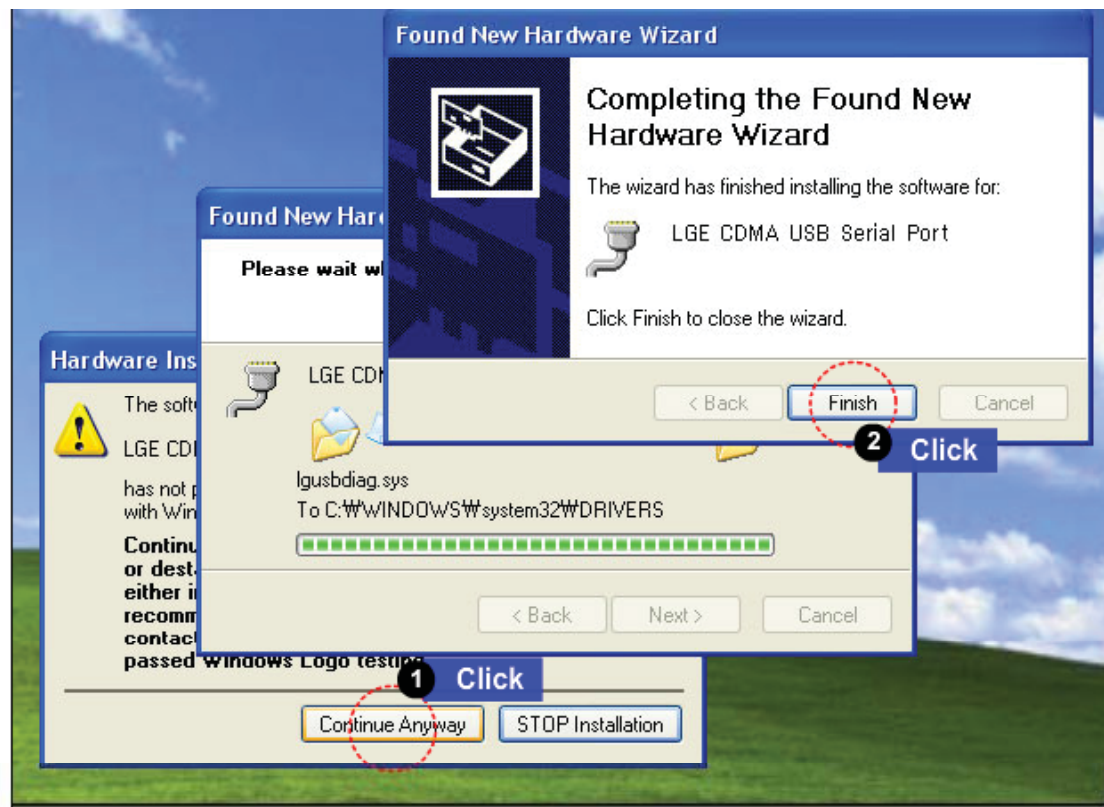
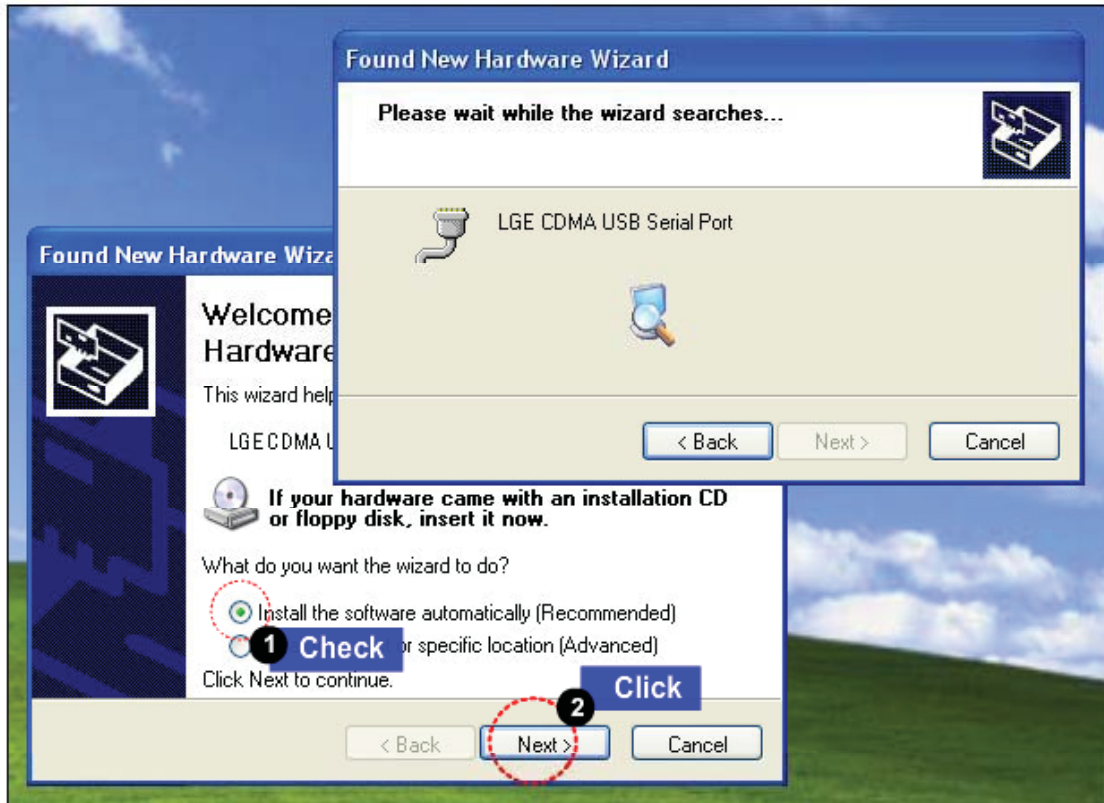




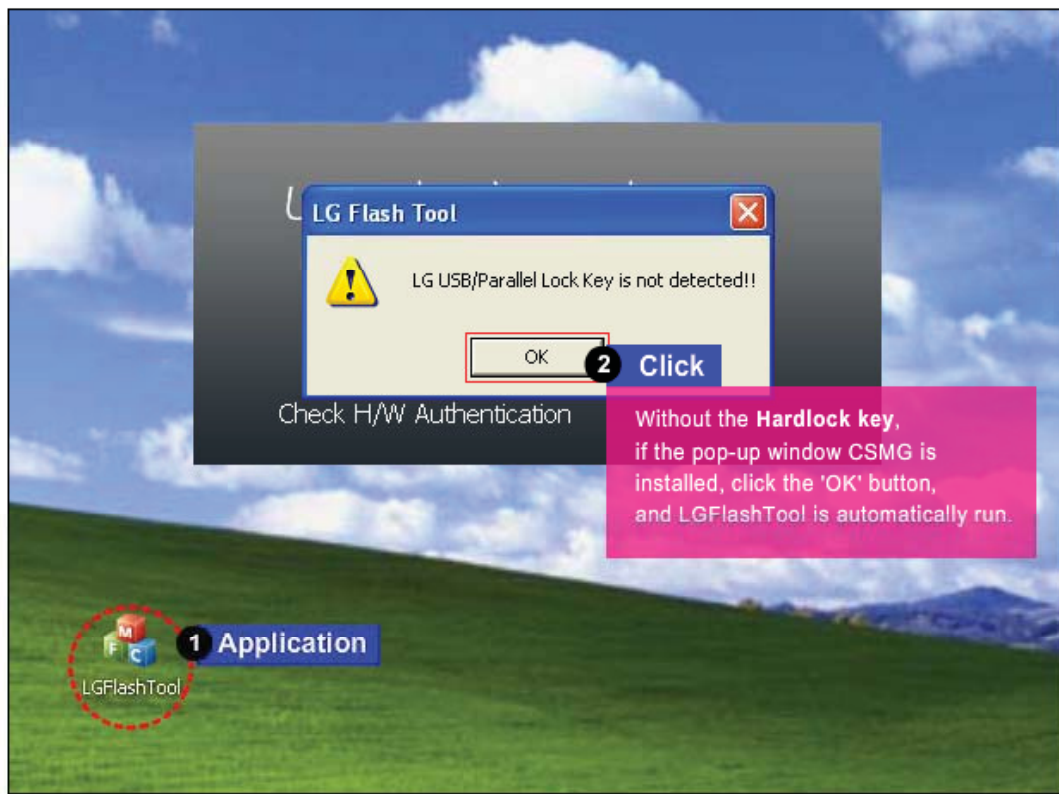
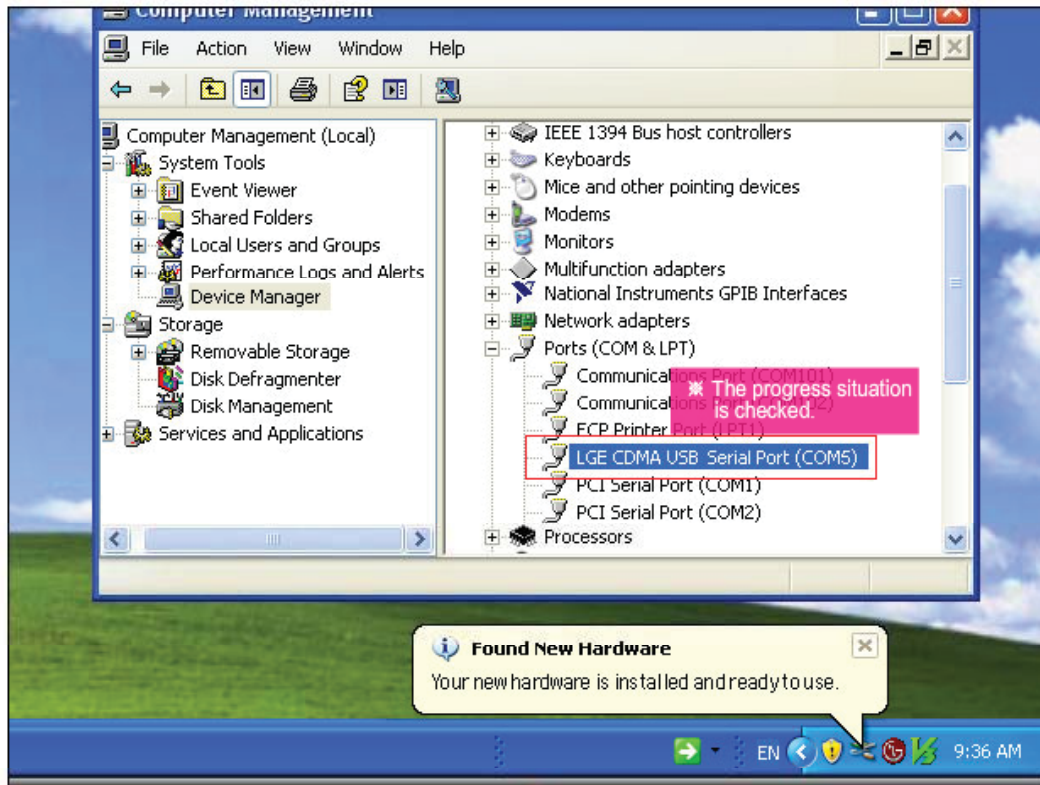


## 5. DOWNLOAD



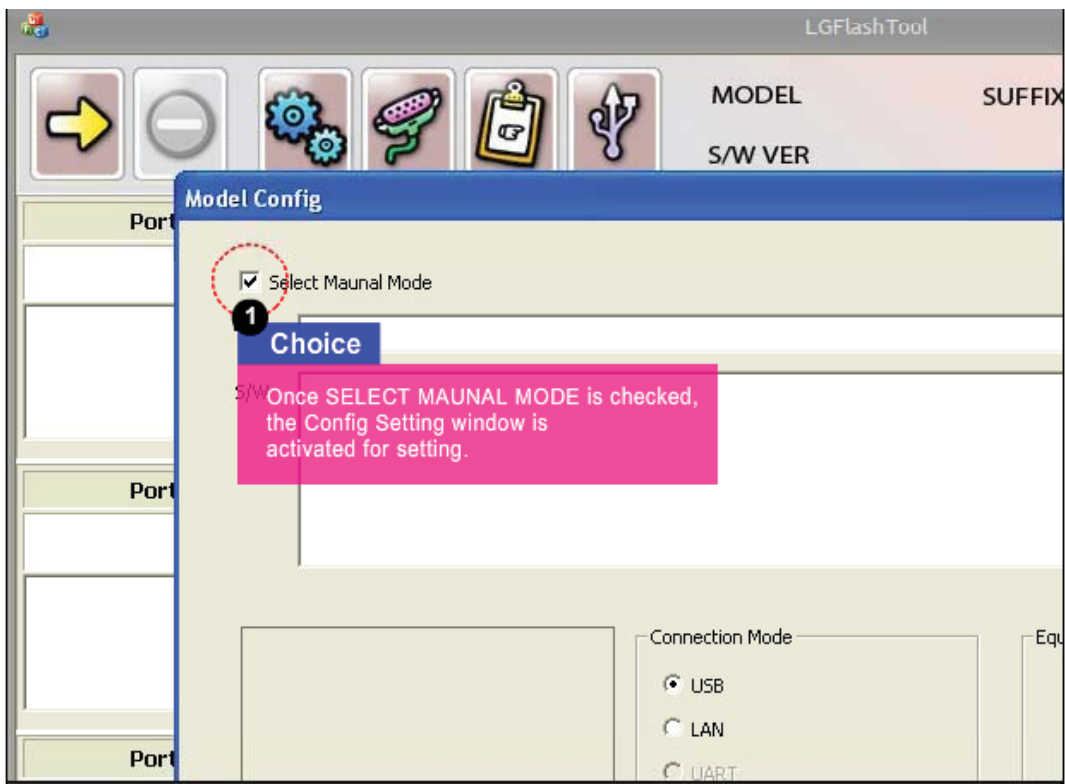
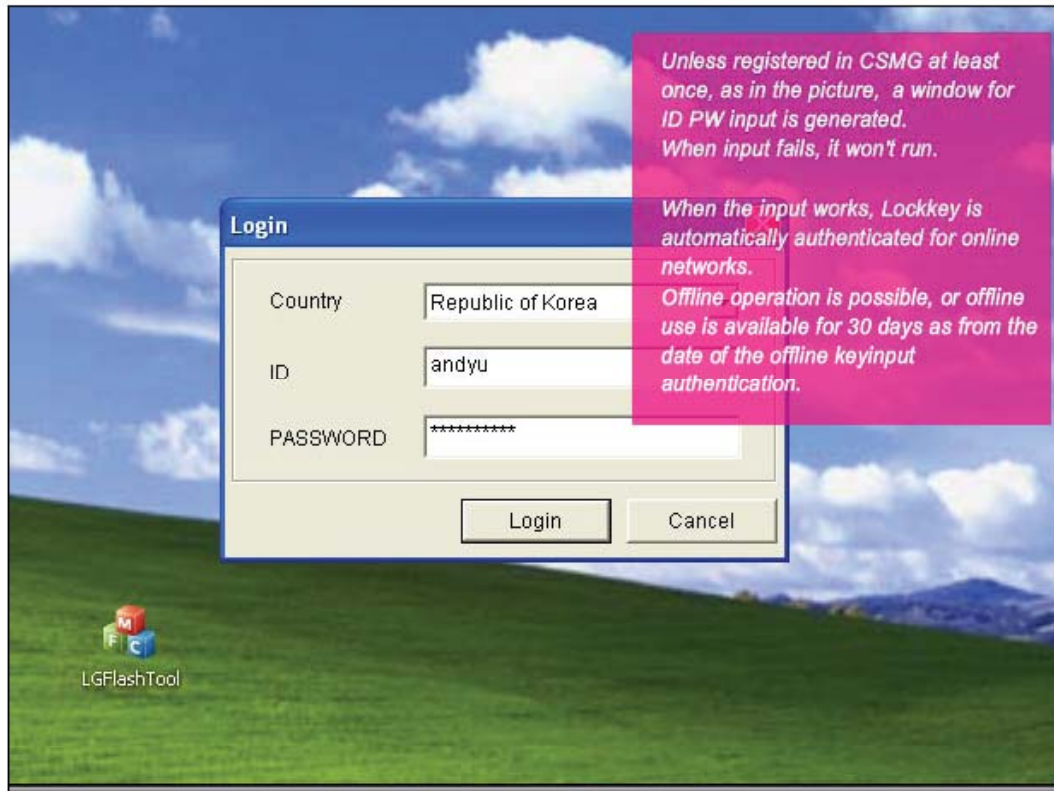


## 5. DOWNLOAD

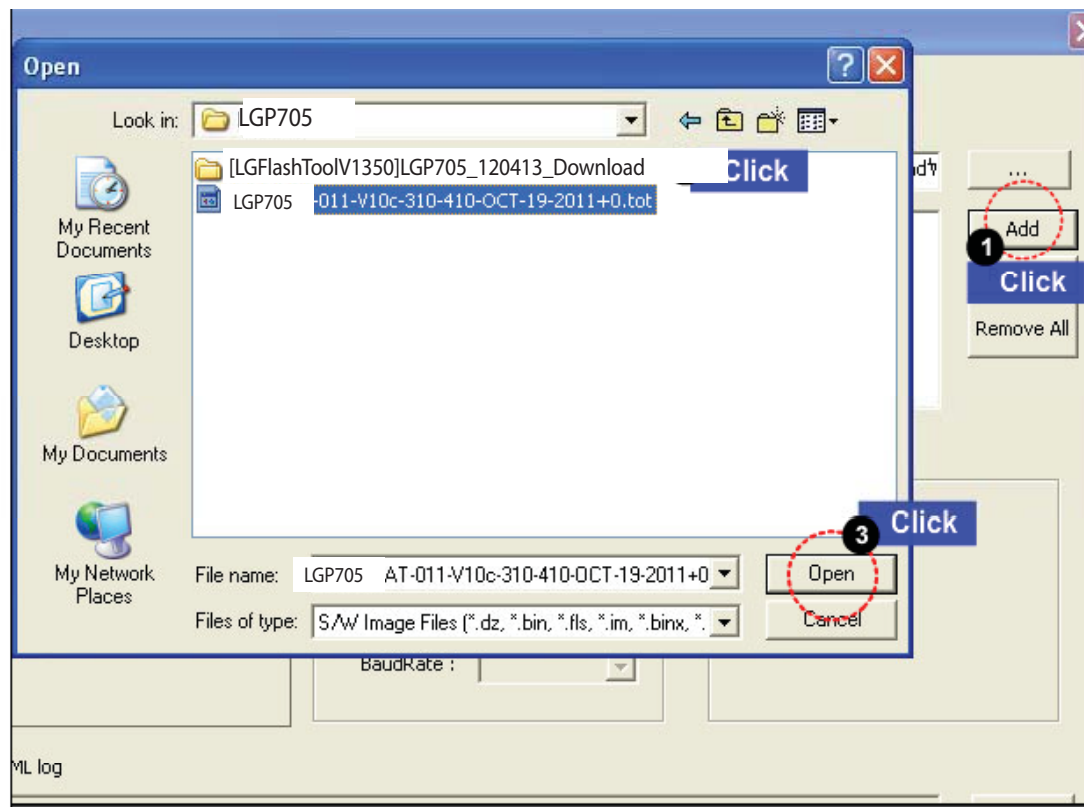
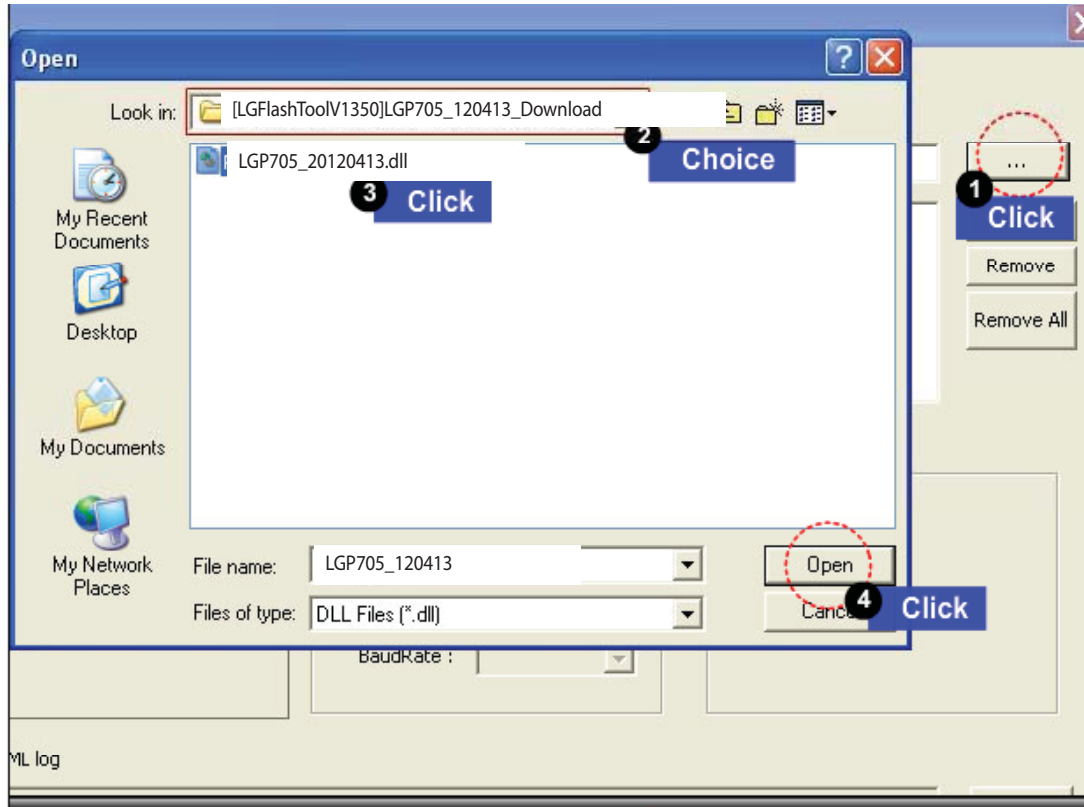




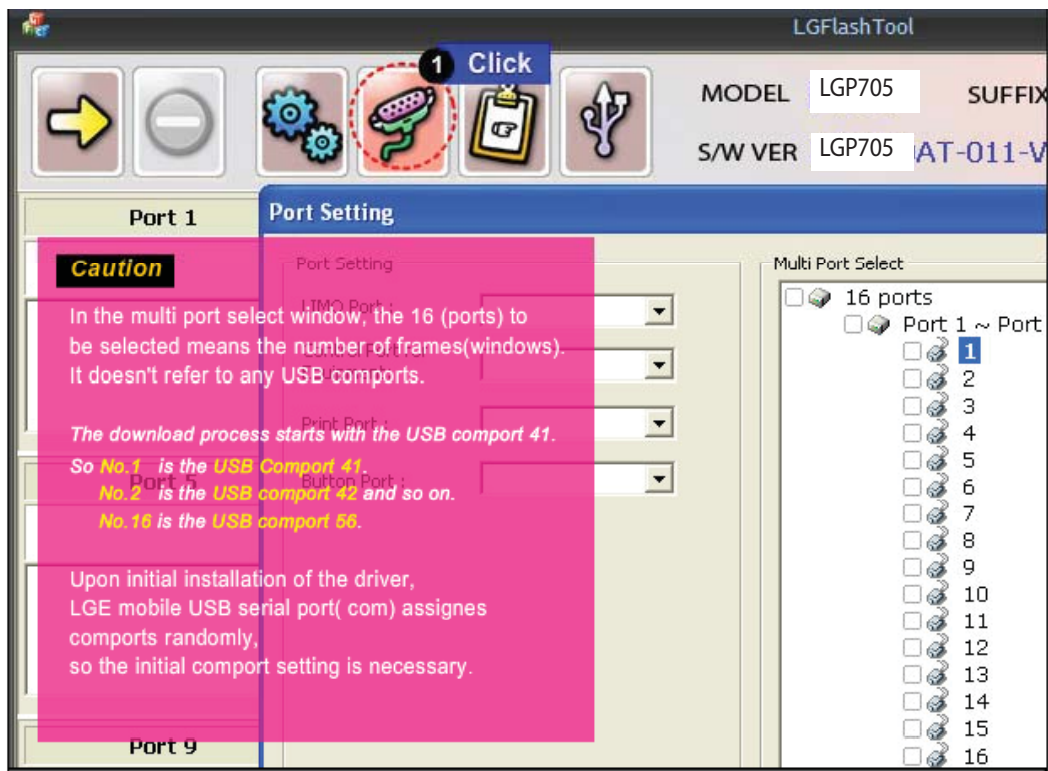
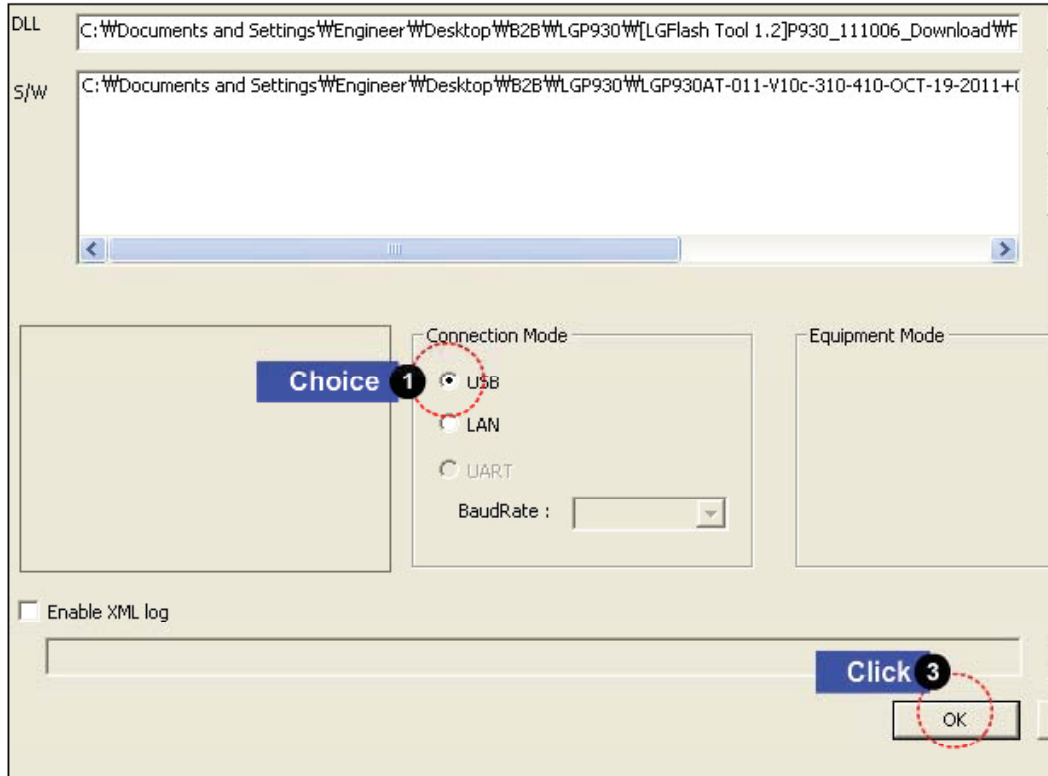
## 5. DOWNLOAD



## 5. DOWNLOAD

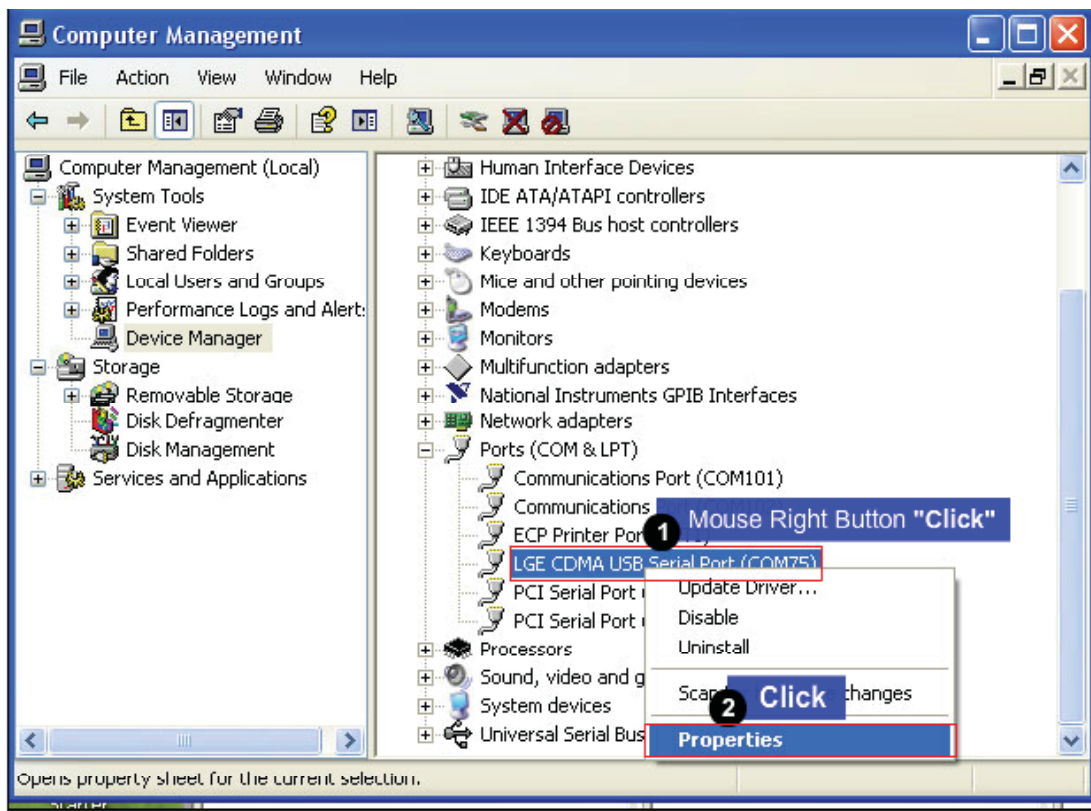
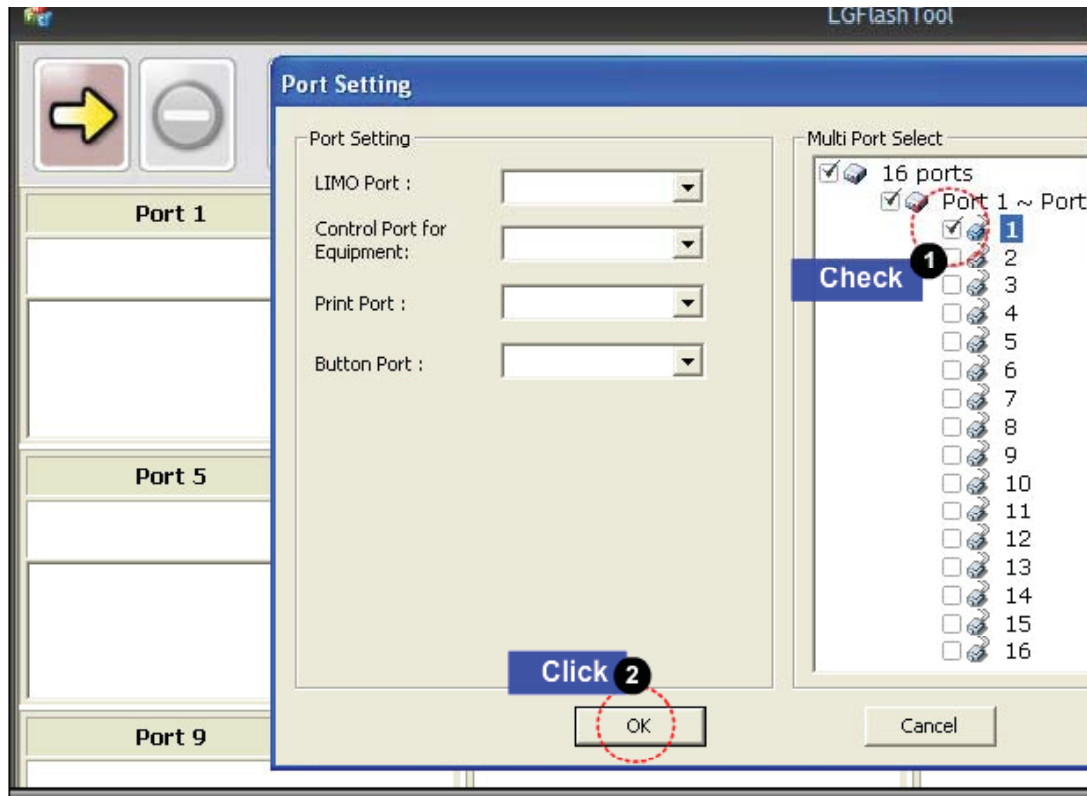


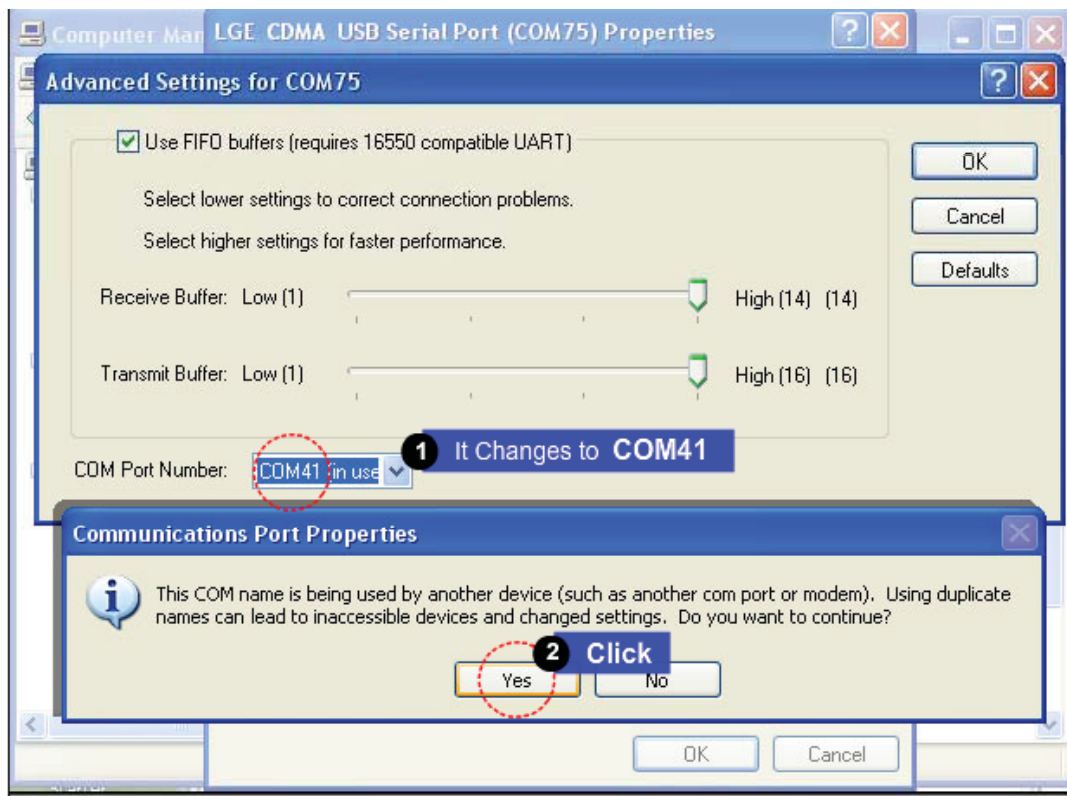
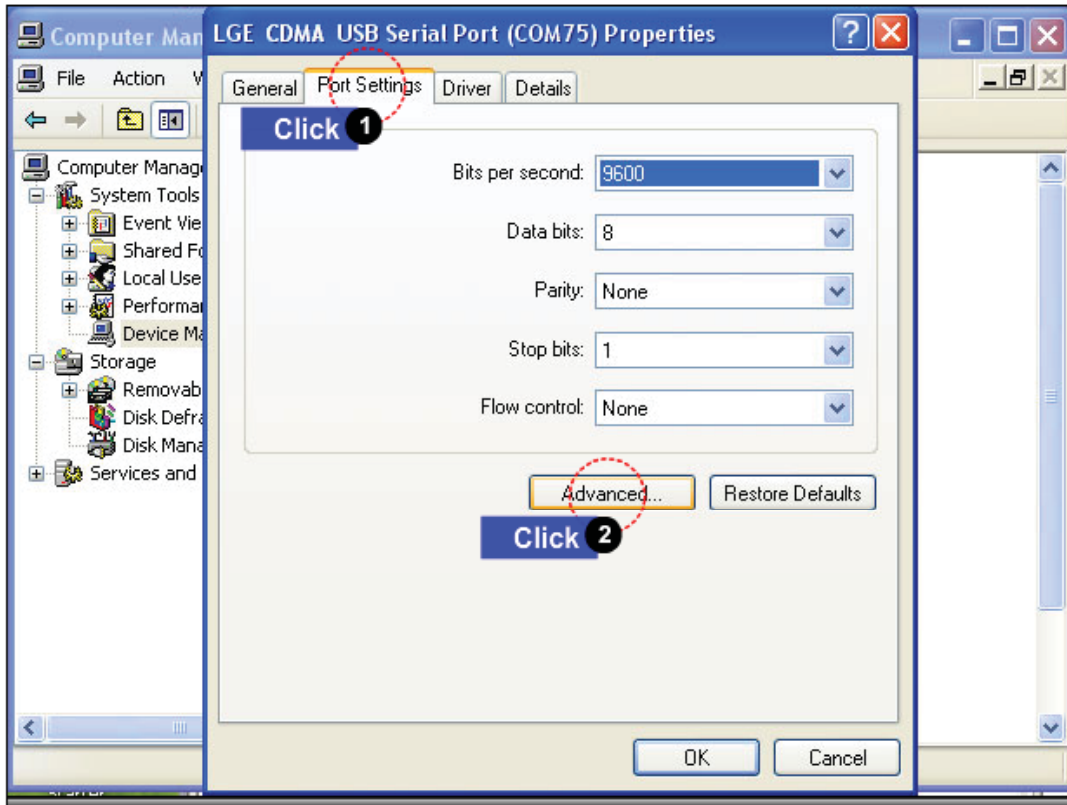
## 5. DOWNLOAD



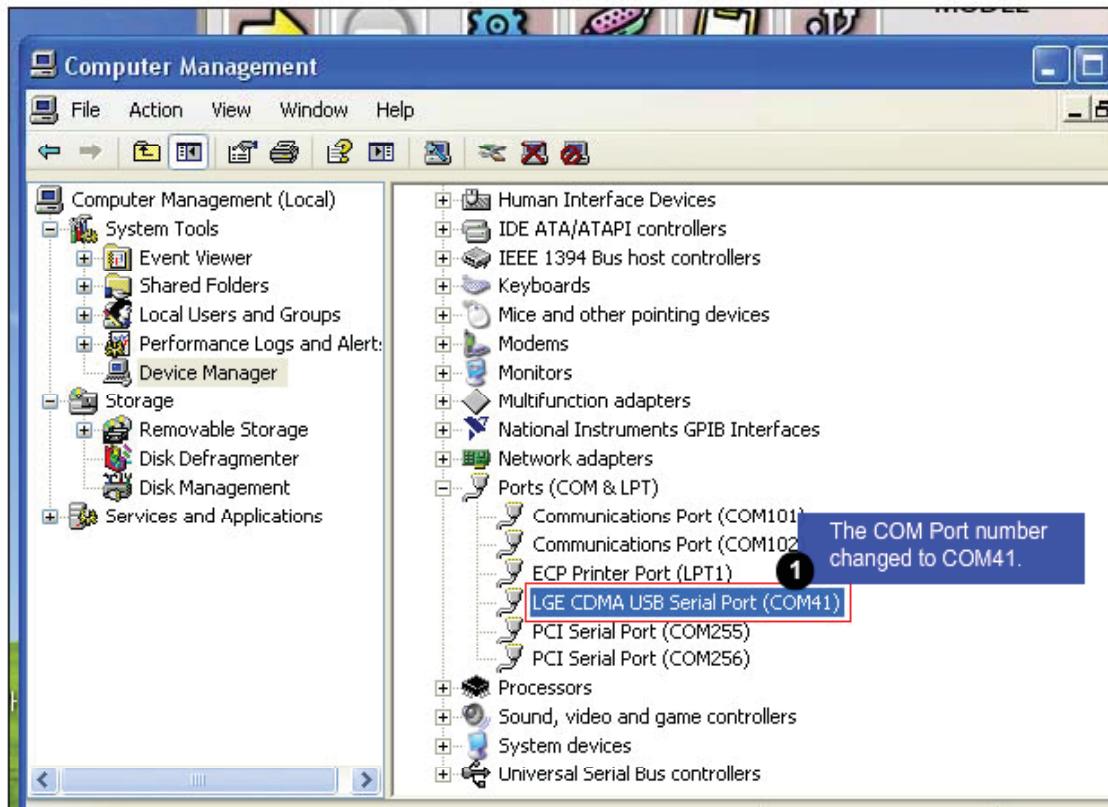
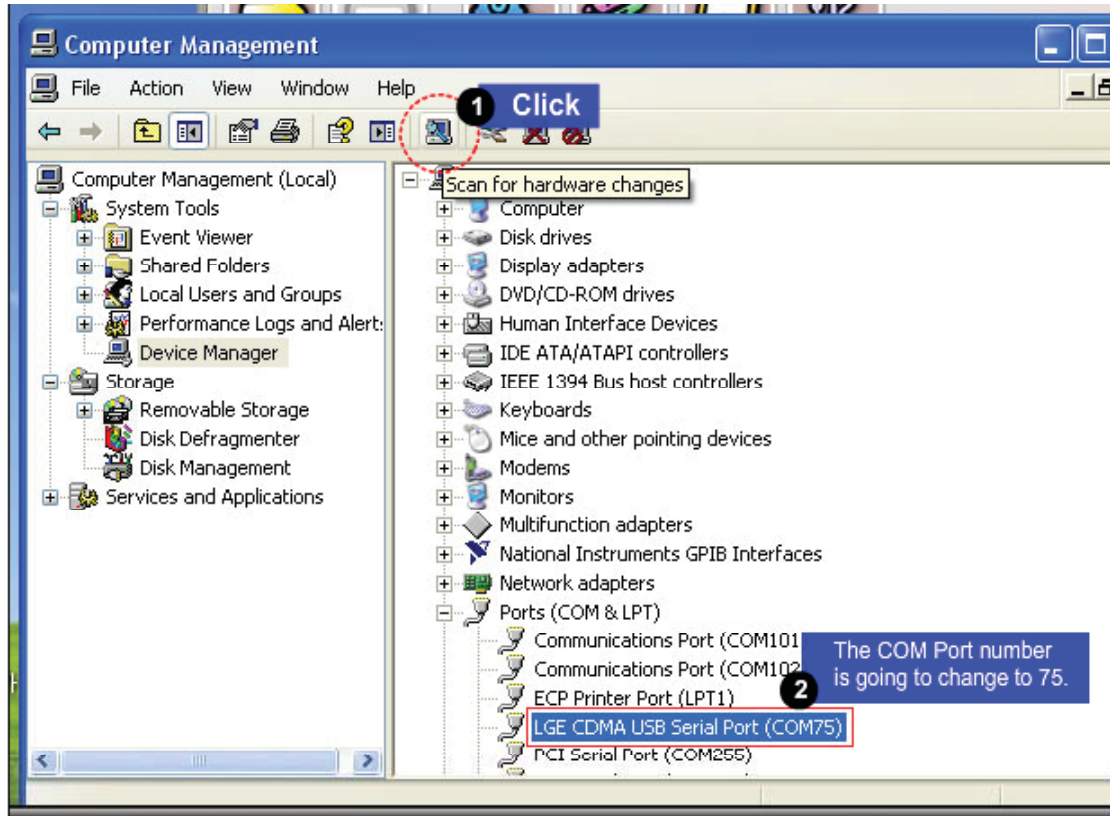


## 5. DOWNLOAD

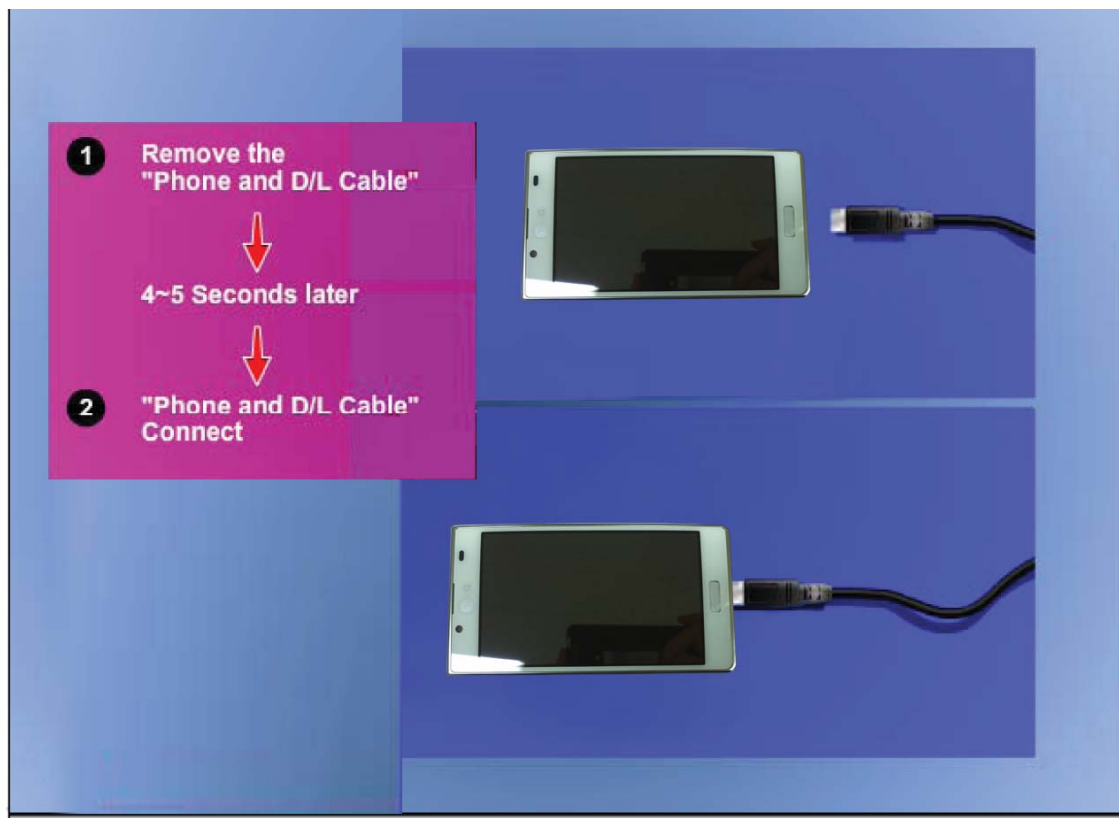




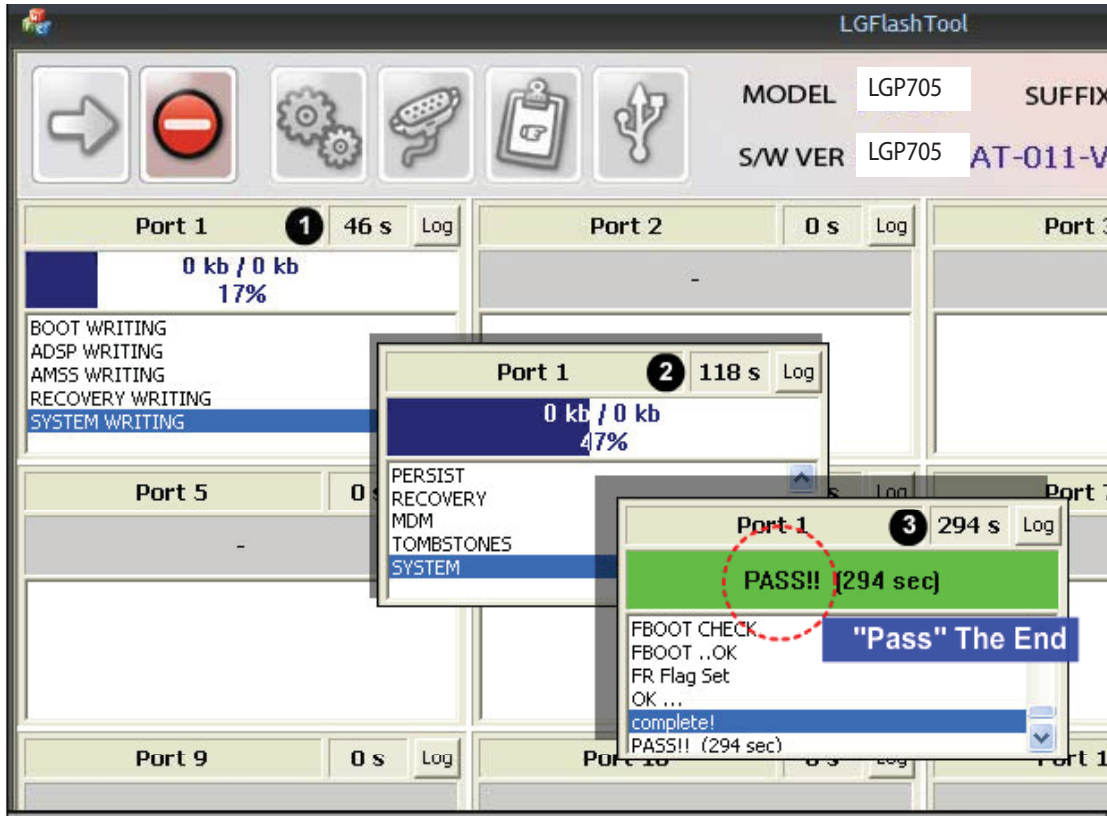
## 5. DOWNLOAD



## 5. DOWNLOAD

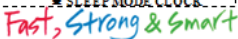


## 5. DOWNLOAD



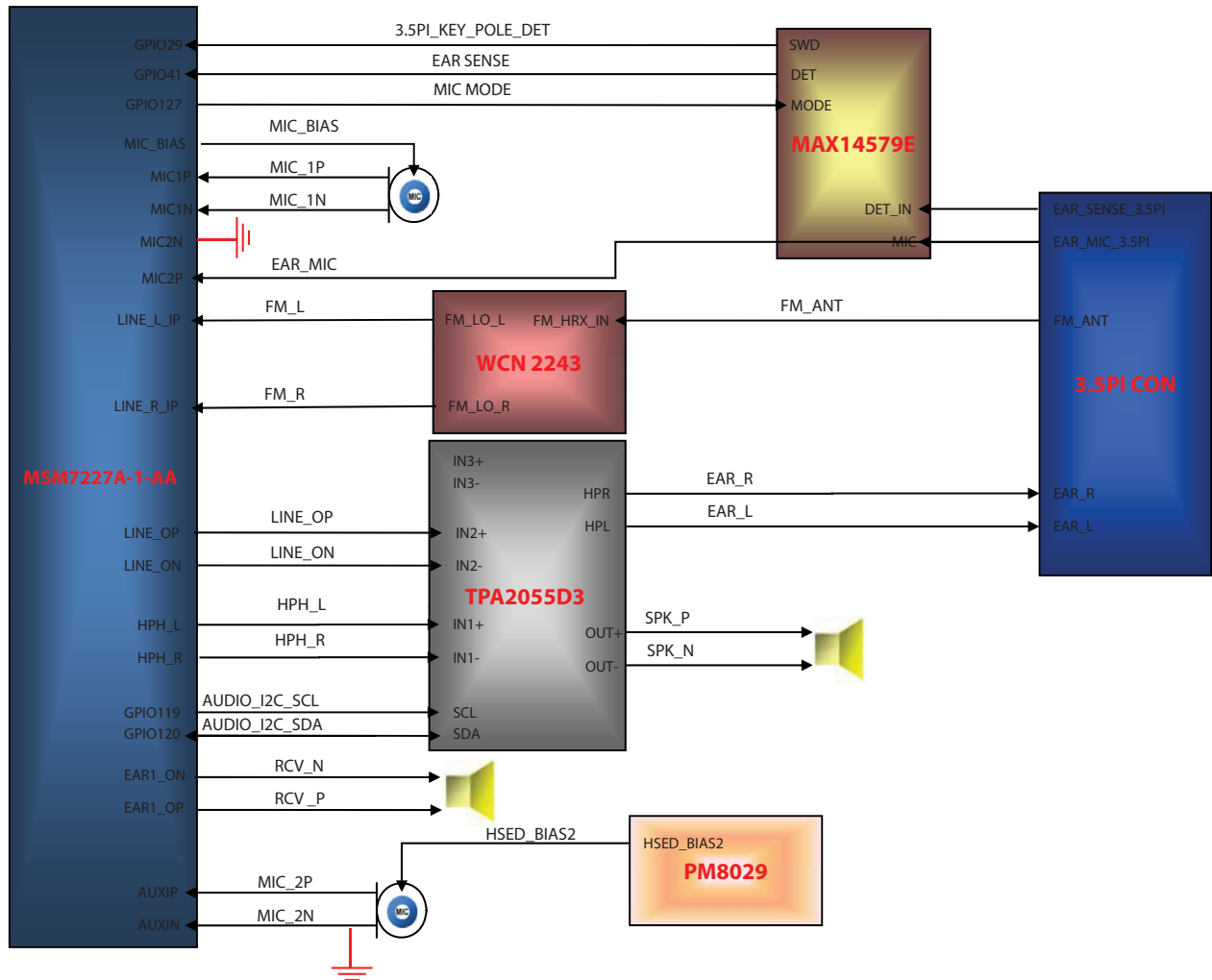


### Block Diagram \_TOTAL



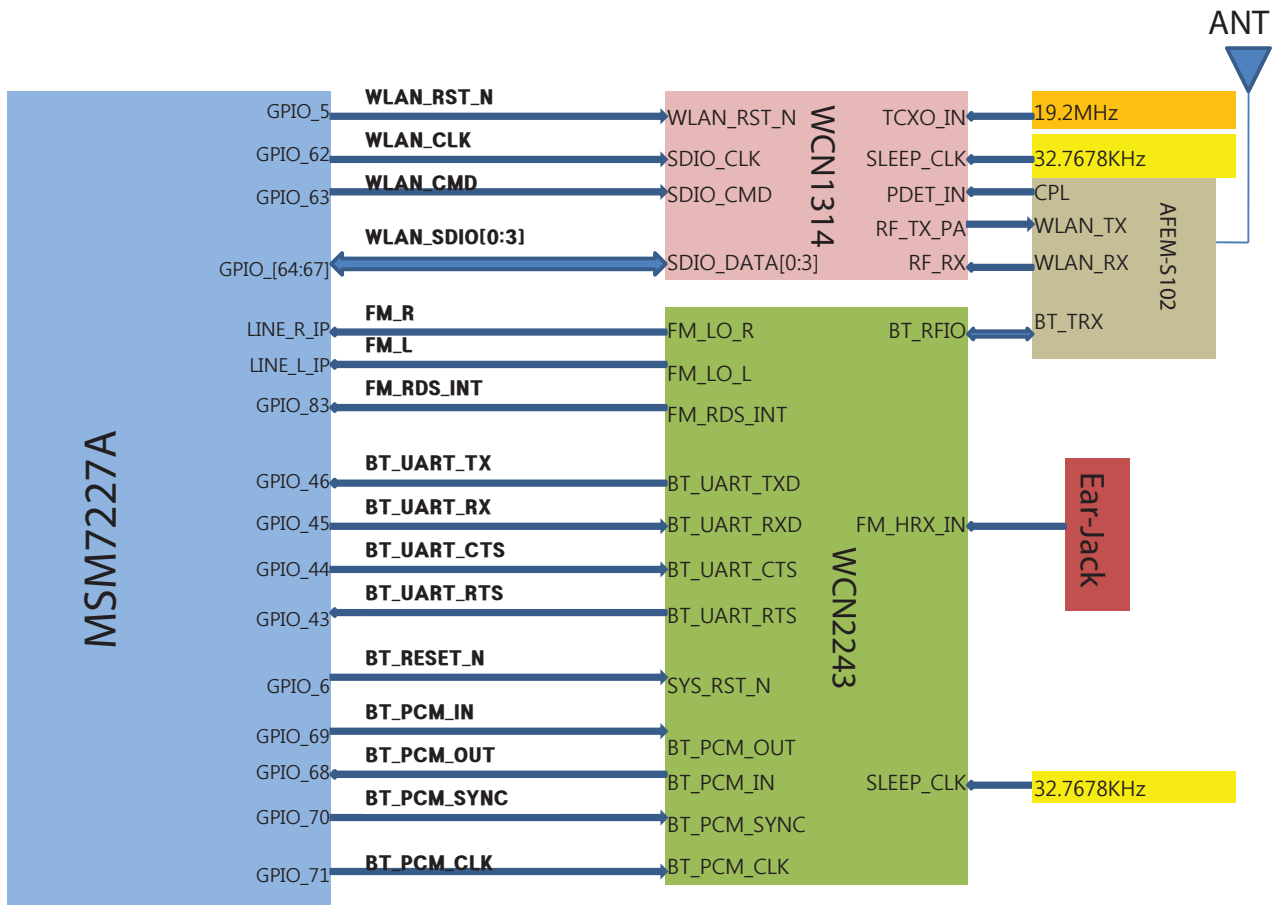


### Block Diagram \_ AUDIO

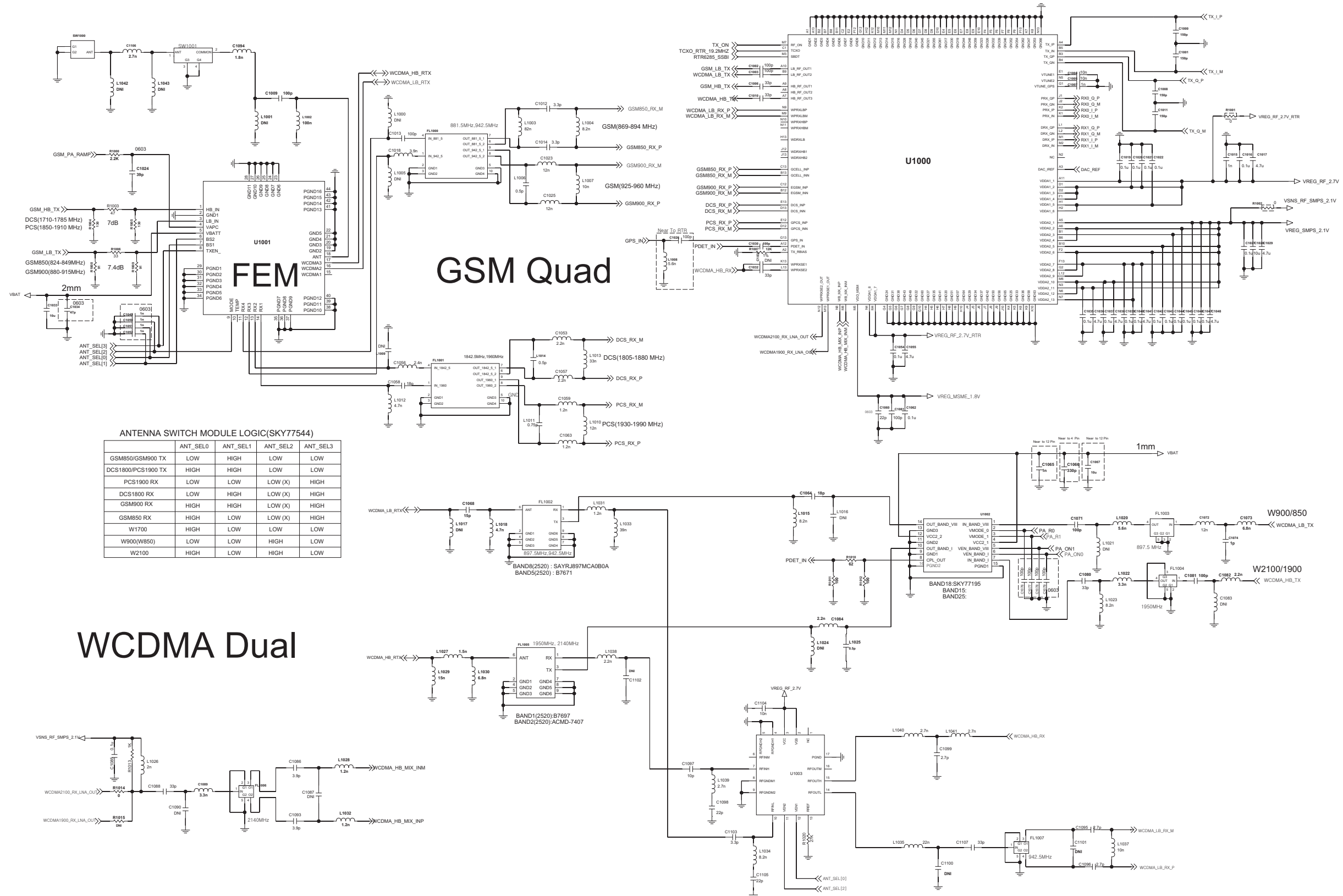


## 6. BLOCK DIAGRAM

Block Diagram \_ BTWIFIM



## 7. CIRCUIT DIAGRAM





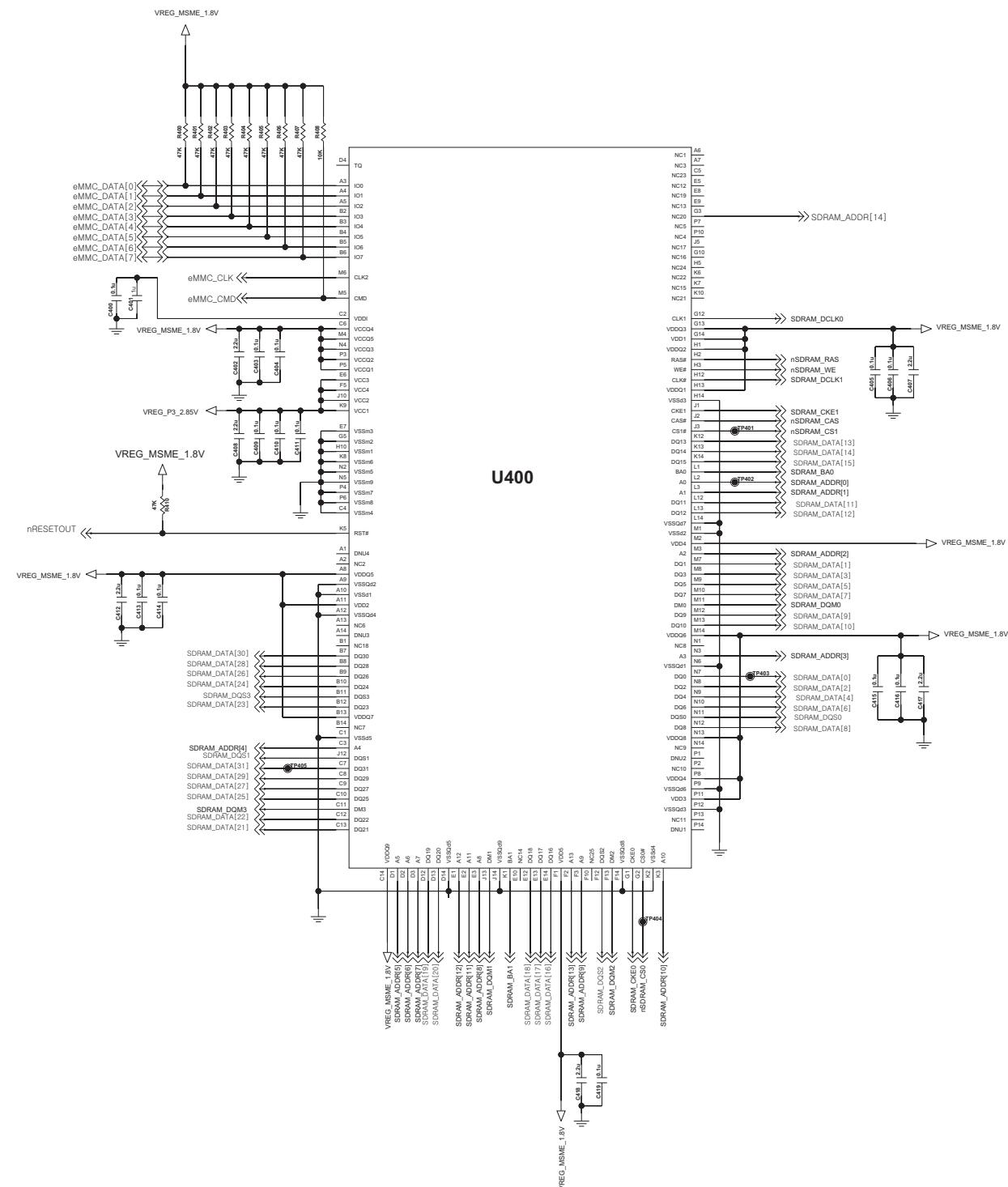
# CAN CLIP

The diagram illustrates a CAN bus system architecture. It features a main horizontal bus line at the top, which branches into several vertical segments. Each segment contains a series of components, each represented by a square box with a circle inside and a label below it. The components are connected to the bus line via vertical lines. The components are labeled as follows:

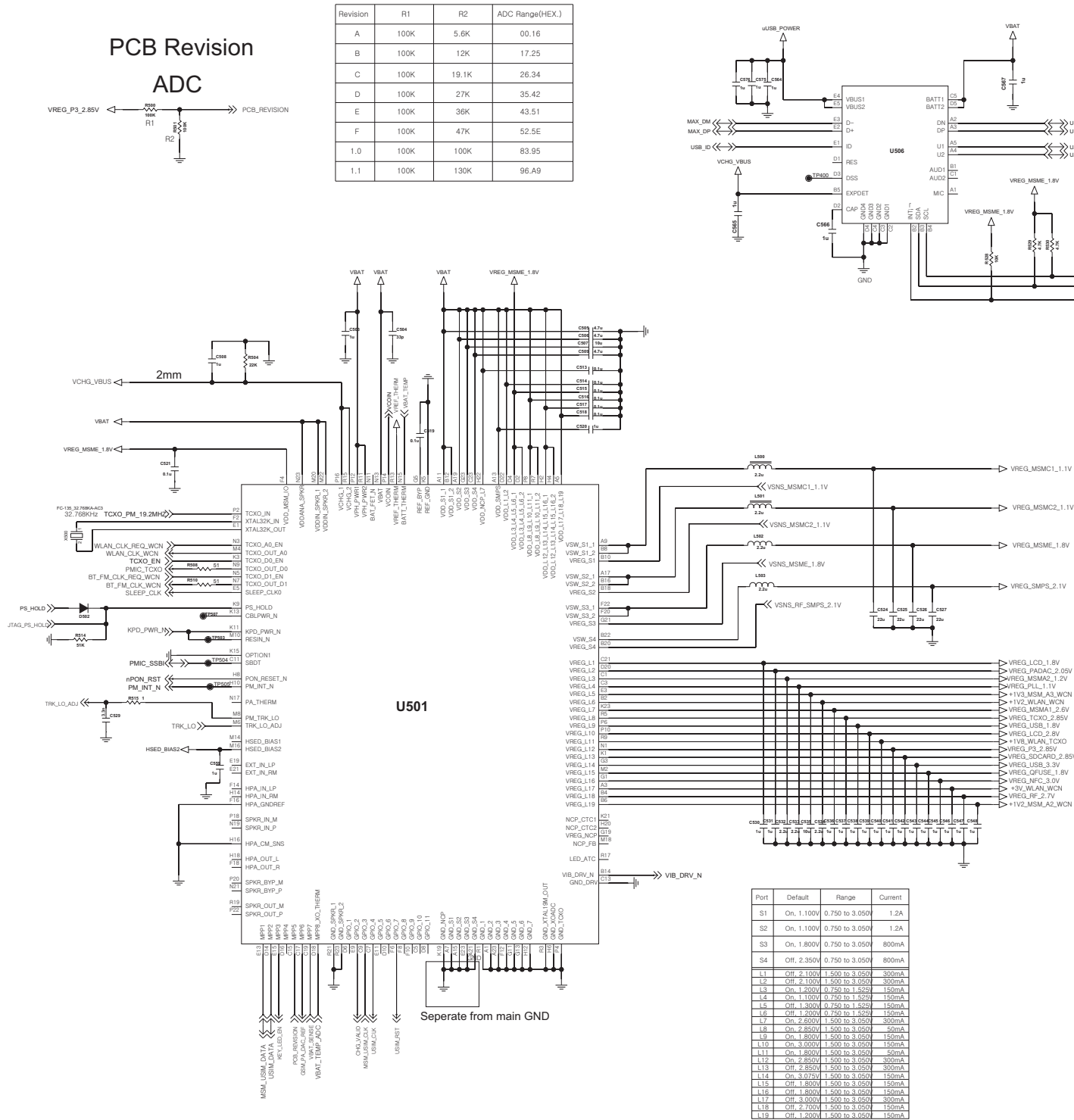
- SC300, SC301, SC303, SC304 (top row)
- SC306, SC316, SC317, SC307 (second row)
- SC309, SC319, SC311 (third row)
- SC312, SC313, SC314, SC315 (fourth row)
- SC321, SC318, SC319, SC320 (fifth row)
- SC322, SC323, SC324 (bottom row)

A common ground symbol is located at the bottom right of the diagram, connected to the bottom of the main bus line.

## MCP (4GB eMMC +4Gb LPDDR1)

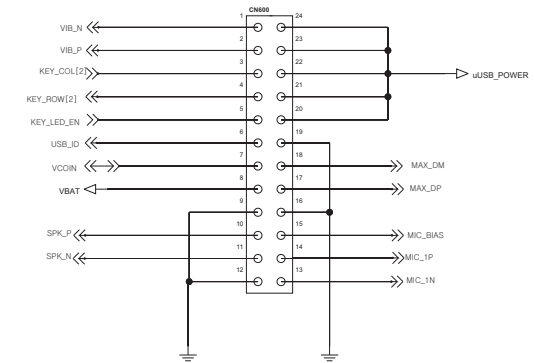




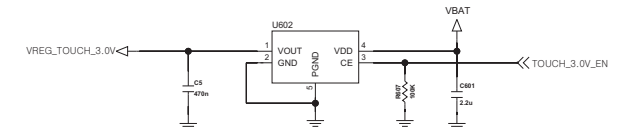


## MAIN-TO-lowerFPCB CONNECTOR

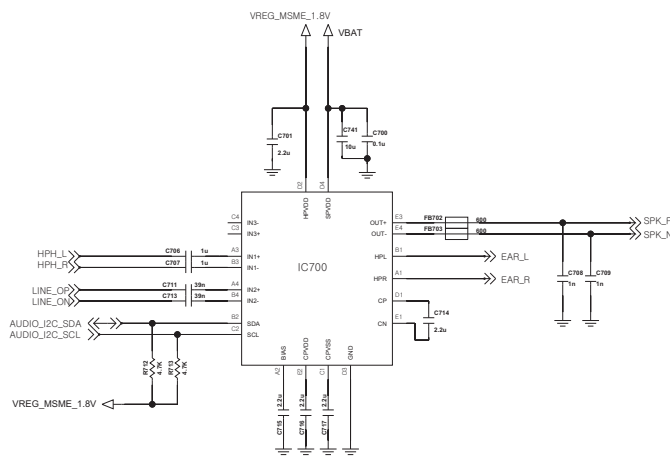
24pin 0.4mm pitch, 0.9T Narrow Type



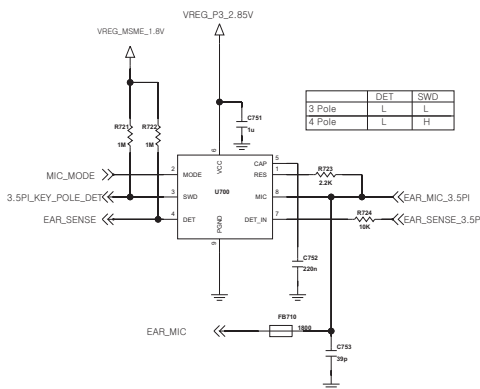
## MAIN-TO-upperFPCB CONNECTOR

[illegible]

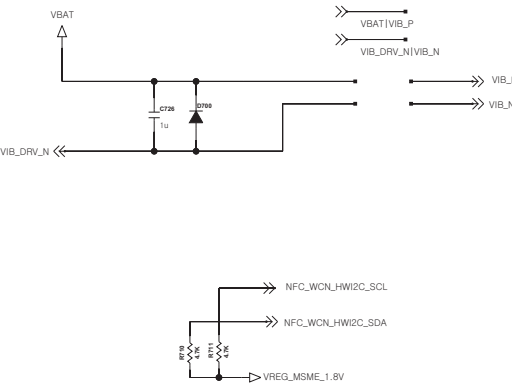
Audio Sub System



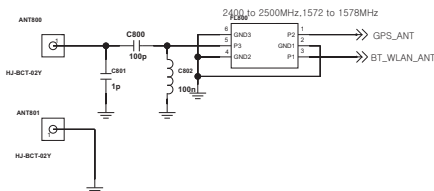
HEADSET\_DETECT



MOTOR

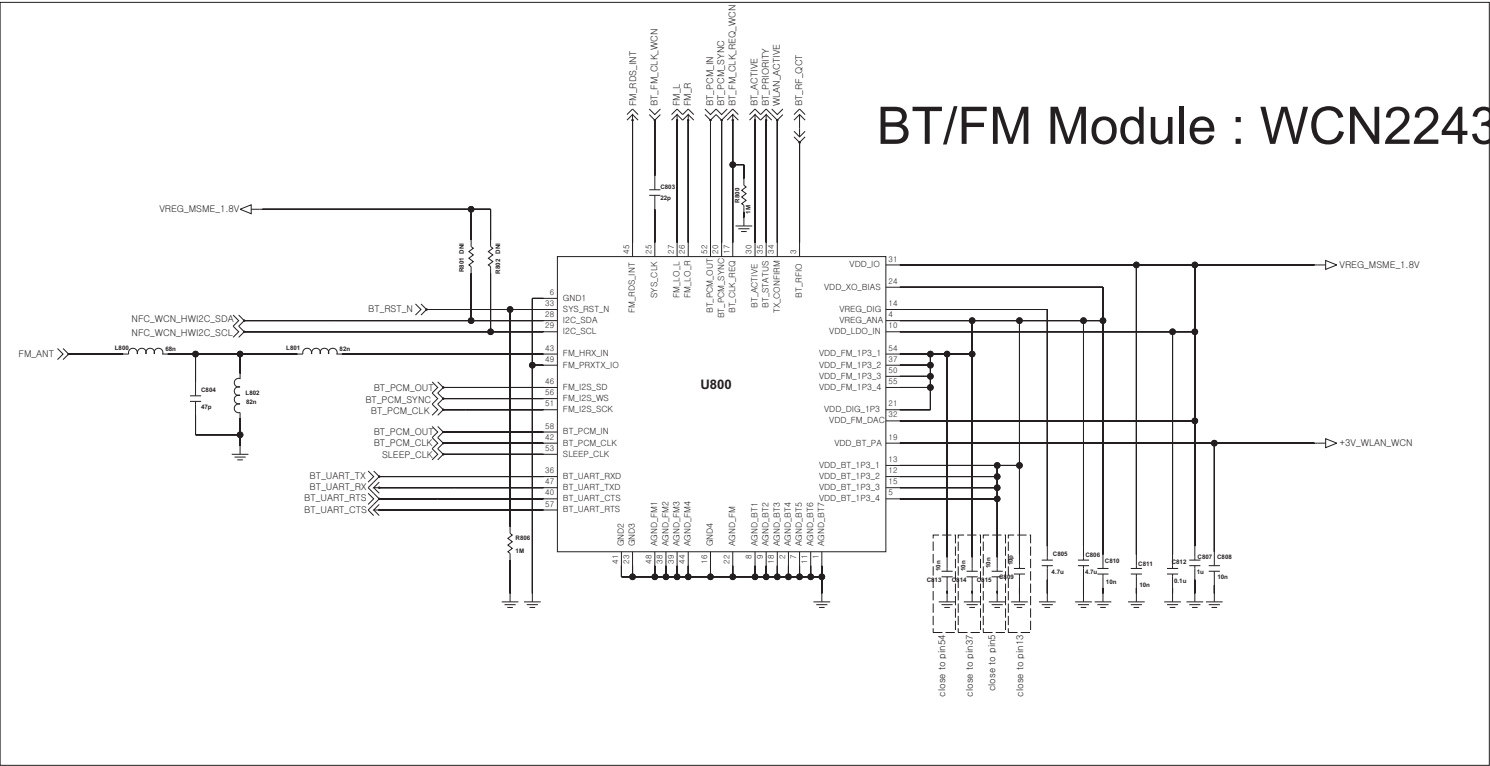
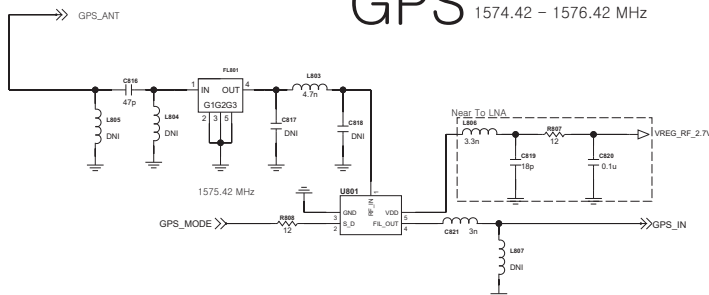


# BT/GPS Di-plexer



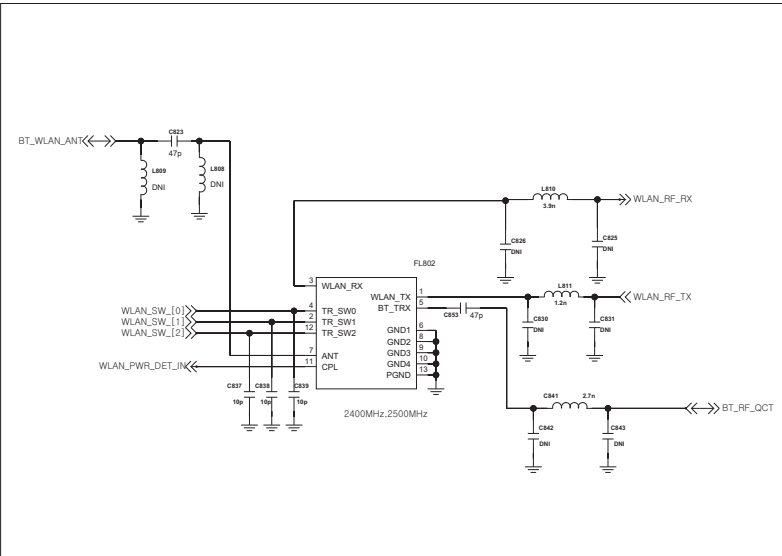
# GPS 1574.42 – 1576.42 MHz

The schematic diagram illustrates the GPS receiver circuit. It features a GPS\_ANT input connected to a matching network consisting of inductor L805 and capacitors C816 (47pF) and C804. This network feeds the IN pin of the G1G2G3 chip. The chip's OUT pin is connected to a matching network with inductor L803 and capacitors C817 and C818. The output of this network is connected to the input of a 'Noise To LNA' block, which contains a 3.3nH inductor and a 12pF capacitor. The output of the LNA is connected to the IN pin of the VREG\_RF\_2.7V block. The VREG\_RF\_2.7V block contains a 12pF capacitor and a 0.1uF capacitor. The output of the VREG\_RF\_2.7V block is connected to the GPS\_IN output. The GPS\_MODE input is connected to the S.D pin of the U801 chip, which is also connected to the FL\_OUT pin. The U801 chip is connected to ground at pins 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42, 43, 44, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 59, 60, 61, 62, 63, 64, 65, 66, 67, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 79, 80, 81, 82, 83, 84, 85, 86, 87, 88, 89, 90, 91, 92, 93, 94, 95, 96, 97, 98, 99, 100. The U801 chip is also connected to ground at pins 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, 16, 17, 18, 19, 20, 21, 22, 23, 24, 25, 26, 27, 28, 29, 30, 31, 32, 33, 34, 35, 36, 37, 38, 39, 40, 41, 42, 43, 44, 45, 46, 47, 48, 49, 50, 51, 52, 53, 54, 55, 56, 57, 58, 59, 60, 61, 62, 63, 64, 65, 66, 67, 68, 69, 70, 71, 72, 73, 74, 75, 76, 77, 78, 79, 80, 81, 82, 83, 84, 85, 86, 87, 88, 89, 90, 91, 92, 93, 94, 95, 96, 97, 98, 99, 100.



The schematic diagram illustrates the internal connections of the WLAN module. Key components and connections include:

- BT Interface:** The BT\_WLAN\_ANT pin is connected to a matching network consisting of capacitors C923 (47pF), L889, and L890, which are grounded.
- WLAN Control:**
  - WLAN\_SW\_[0], WLAN\_SW\_[1], and WLAN\_SW\_[2] are connected to pins 4, 2, and 12 of the FL802 chip.
  - WLAN\_PWR\_DET\_INK is connected to pin 7 of the FL802 chip.
  - Pin 11 of the FL802 chip is connected to three 100Ω resistors (CR37, CR38, CR39) which are grounded.
- RF Front-End:**
  - The FL802 chip has pins 3 (WLAN\_RX), 1 (WLAN\_TX), and 5 (BT\_TX) connected to the RF section.
  - Pin 6 of the FL802 chip is connected to a 47pF capacitor (CR35) and a 2400MHz/2500MHz filter.
  - Pin 8 (GNDS1) is connected to a 47pF capacitor (CR36) and ground.
  - Pin 9 (GNDS2) is connected to ground.
  - Pin 10 (GNDS3) is connected to ground.
  - Pin 12 (GNDS4) is connected to ground.
  - Pin 13 (PGND) is connected to ground.
- RF Output:**
  - The RF output path includes capacitors C828 (47pF) and C829 (47pF), inductor L819 (3.9nH), and capacitor C425 (47pF) connected to the WLAN\_RF\_RX pin.
  - Another path includes capacitor C830 (47pF), inductor L811 (1.5nH), and capacitor C431 (47pF) connected to the WLAN\_RF\_TX pin.
  - The BT output path includes capacitor C841 (47pF), inductor L841 (3.7nH), and capacitor C843 (47pF) connected to the BT\_RF\_QCT pin.
  - Capacitor C842 (47pF) is also connected to ground.

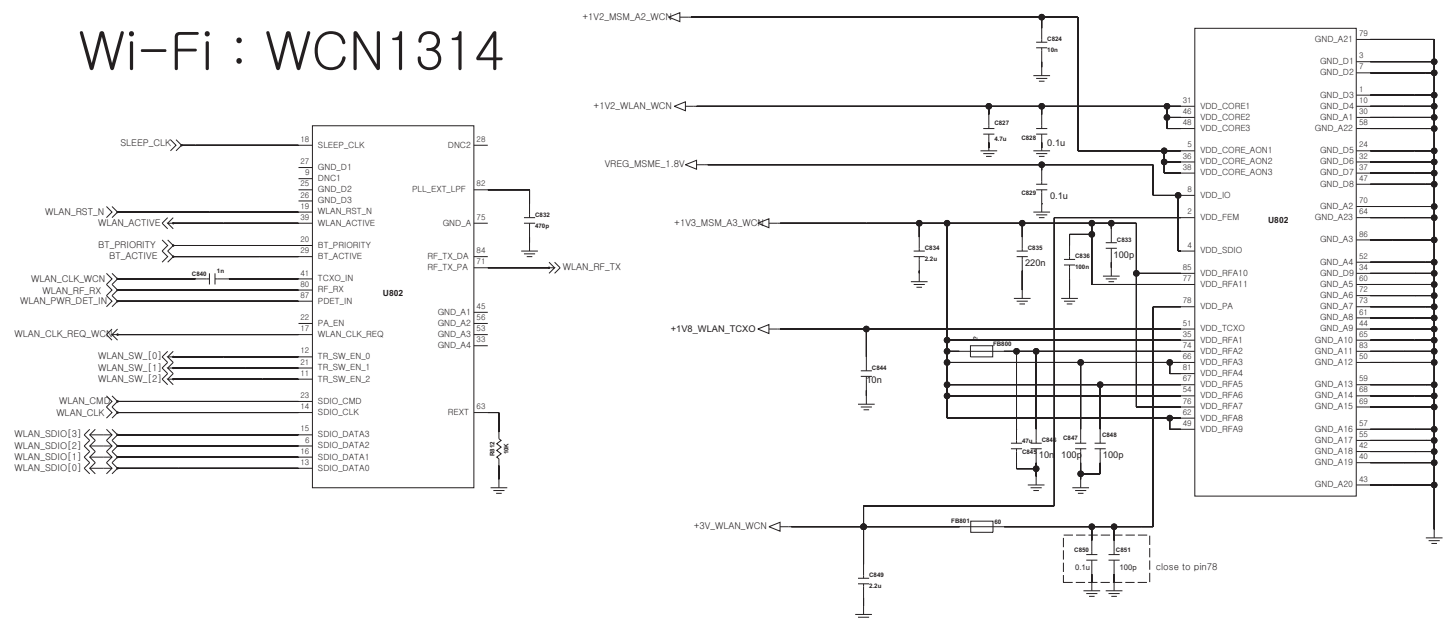


# Wi-Fi : WCN1314

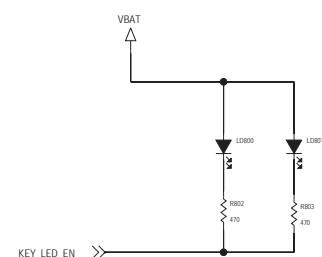
The diagram illustrates the electrical connections for the WCN1314 Wi-Fi module. It is divided into three main sections: Power and Grounding, Signal and Control, and RF/Interface Connections.

- Power and Grounding:**
  - Power:** +1V2\_WLAN\_WCN, +1V2\_MSMM\_A3\_WCN, +1V2\_WLAN\_TCXO, and +3V\_WLAN\_WCN are connected to specific pins on the module and the microcontroller.
  - Grounding:** Multiple GND pins (GND\_D1, GND\_D2, GND\_D3, GND\_A1, GND\_A2, GND\_A3, GND\_A4, GND\_A5, GND\_A7, GND\_A8, GND\_A10, GND\_A11, GND\_A12, GND\_A13, GND\_A14, GND\_A15, GND\_A17, GND\_A18, GND\_A19, GND\_A20, GND\_A21, GND\_D1, GND\_D2, GND\_D3, GND\_D4, GND\_D5, GND\_D6, GND\_D7, GND\_D8, GND\_D9, GND\_D10, GND\_D11, GND\_D12, GND\_D13, GND\_D14, GND\_D15, GND\_D16, GND\_D17, GND\_D18, GND\_D19, GND\_D20, GND\_D21, GND\_D22, GND\_D23, GND\_D24, GND\_D25, GND\_D26, GND\_D27, GND\_D28, GND\_D29, GND\_D30, GND\_D31, GND\_D32, GND\_D33, GND\_D34, GND\_D35, GND\_D36, GND\_D37, GND\_D38, GND\_D39, GND\_D40, GND\_D41, GND\_D42, GND\_D43, GND\_D44, GND\_D45, GND\_D46, GND\_D47, GND\_D48, GND\_D49, GND\_D50, GND\_D51, GND\_D52, GND\_D53, GND\_D54, GND\_D55, GND\_D56, GND\_D57, GND\_D58, GND\_D59, GND\_D60, GND\_D61, GND\_D62, GND\_D63, GND\_D64, GND\_D65, GND\_D66, GND\_D67, GND\_D68, GND\_D69, GND\_D70, GND\_D71, GND\_D72, GND\_D73, GND\_D74, GND\_D75, GND\_D76, GND\_D77, GND\_D78, GND\_D79, GND\_D80, GND\_D81, GND\_D82, GND\_D83, GND\_D84, GND\_D85, GND\_D86, GND\_D87, GND\_D88, GND\_D89, GND\_D90, GND\_D91, GND\_D92, GND\_D93, GND\_D94, GND\_D95, GND\_D96, GND\_D97, GND\_D98, GND\_D99, GND\_D100) are connected to the module and the microcontroller.
- Signal and Control:**
  - Control:** SLEEP\_CLK, WLAN\_RST\_N, BT\_PRIORITY, WLAN\_CLK\_WCN, WLAN\_PWR\_DET\_N, WLAN\_CLK\_REQ\_WCN, WLAN\_SW\_0, WLAN\_SW\_1, WLAN\_SW\_2, WLAN\_CMD, WLAN\_CLK, WLAN\_SIOI[3], WLAN\_SIOI[2], WLAN\_SIOI[1], WLAN\_SIOI[0] are connected to the module and the microcontroller.
  - RF/Interface:** RF\_TX\_D0, RF\_TX\_PA, RF\_RX, PDET\_IN, PA\_EN, WLAN\_CLK\_REQ, TRSW\_EN\_0, TRSW\_EN\_1, TRSW\_EN\_2, SIOI\_CMD, SIOI\_CLK, SIOI\_DATA2, SIOI\_DATA1, SIOI\_DATA0 are connected to the module and the microcontroller.
- RF/Interface Connections:**
  - RF:** RF\_TX\_D0, RF\_TX\_PA, RF\_RX, PDET\_IN, PA\_EN, WLAN\_CLK\_REQ, TRSW\_EN\_0, TRSW\_EN\_1, TRSW\_EN\_2, SIOI\_CMD, SIOI\_CLK, SIOI\_DATA2, SIOI\_DATA1, SIOI\_DATA0 are connected to the module and the microcontroller.
  - Interface:** VDD\_CORE1, VDD\_CORE2, VDD\_CORE3, VDD\_CORE\_AON1, VDD\_CORE\_AON2, VDD\_CORE\_AON3, VDD\_IO, VDD\_FEM, VDD\_SIOI, VDD\_RFA10, VDD\_RFA11, VDD\_PA, VDD\_TCXO, VDD\_RFA1, VDD\_RFA2, VDD\_RFA3, VDD\_RFA4, VDD\_RFA5, VDD\_RFA6, VDD\_RFA7, VDD\_RFA8, VDD\_RFA9 are connected to the module and the microcontroller.

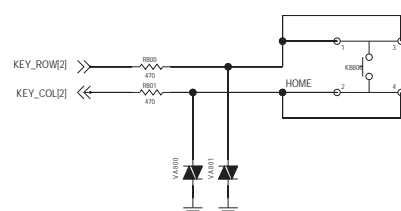
The diagram also shows various passive components like capacitors (C801, C802, C803, C804, C805, C806, C807, C808, C809, C810, C811, C812, C813, C814, C815, C816, C817, C818, C819, C820, C821, C822, C823, C824, C825, C826, C827, C828, C829, C830, C831, C832, C833, C834, C835, C836, C837, C838, C839, C840, C841, C842, C843, C844, C845, C846, C847, C848, C849, C850, C851, C852, C853, C854, C855, C856, C857, C858, C859, C860, C861, C862, C863, C864, C865, C866, C867, C868, C869, C870, C871, C872, C873, C874, C875, C876, C877, C878, C879, C880, C881, C882, C883, C884, C885, C886, C887, C888, C889, C890, C891, C892, C893, C894, C895, C896, C897, C898, C899, C900, C901, C902, C903, C904, C905, C906, C907, C908, C909, C910, C911, C912, C913, C914, C915, C916, C917, C918, C919, C920, C921, C922, C923, C924, C925, C926, C927, C928, C929, C930, C931, C932, C933, C934, C935, C936, C937, C938, C939, C940, C941, C942, C943, C944, C945, C946, C947, C948, C949, C950, C951, C952, C953, C954, C955, C956, C957, C958, C959, C960, C961, C962, C963, C964, C965, C966, C967, C968, C969, C970, C971, C972, C973, C974, C975, C976, C977, C978, C979, C980, C981, C982, C983, C984, C985, C986, C987, C988, C989, C990, C991, C992, C993, C994, C995, C996, C997, C998, C999, C1000) and inductors (L801, L802, L803, L804, L805, L806, L807, L808, L809, L810, L811, L812, L813, L814, L815, L816, L817, L818, L819, L820, L821, L822, L823, L824, L825, L826, L827, L828, L829, L830, L831, L832, L833, L834, L835, L836, L837, L838, L839, L840, L841, L842, L843, L844, L845, L846, L847, L848, L849, L850, L851, L852, L853, L854, L855, L856, L857, L858, L859, L860, L861, L862, L863, L864, L865, L866, L867, L868, L869, L870, L871, L872, L873, L874, L875, L876, L877, L878, L879, L880, L881, L882, L883, L884, L885, L886, L887, L888, L889, L890, L891, L892, L893, L894, L895, L896, L897, L898, L899, L900) used in the circuit.



## MAIN KEY LED

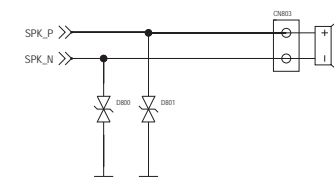


# Home KEY

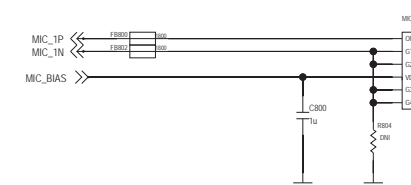


	COL[1]	COL[2]
ROW[0]	VOL_UP	
ROW[1]	VOL_DOWN	
ROW[2]		HOME

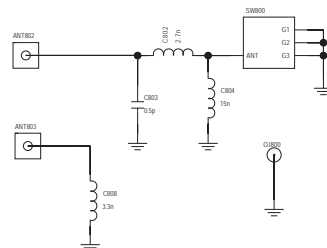
SPEAKER



## MAIN MIC



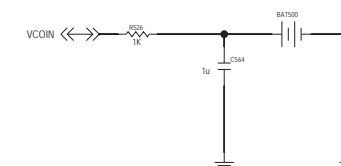
# MAIN ANT PAD



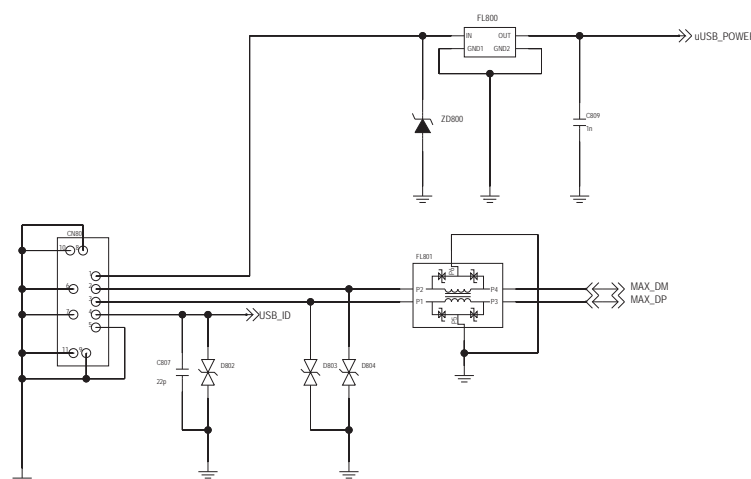
# LINEAR MOTOR



## Back\_up Capacitor

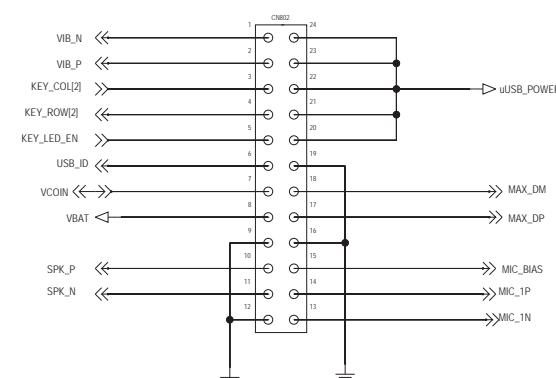


## MICRO USB IO

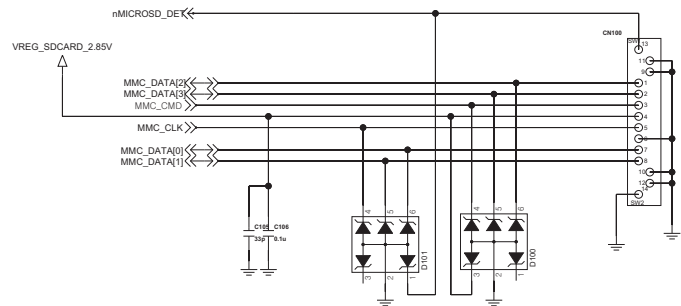


## FPCB2 TO MAIN

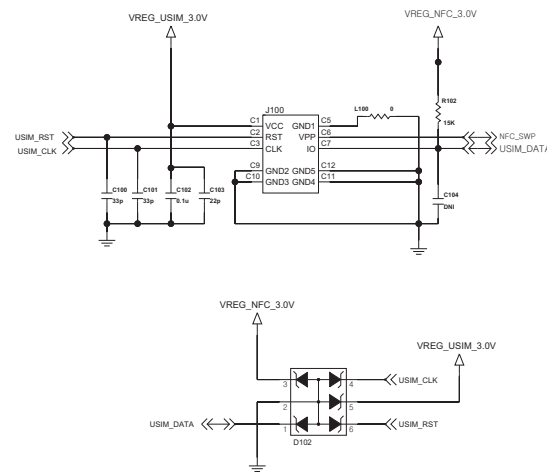
24pin 0.4mm pitch narrow Type



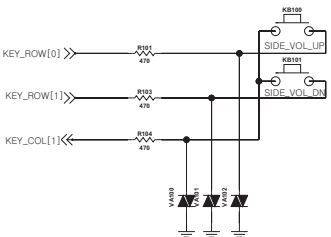
micro-SD SOCKET  
(Push-Pull Type w/ detect)



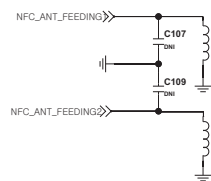
USIM (6pin Normal)



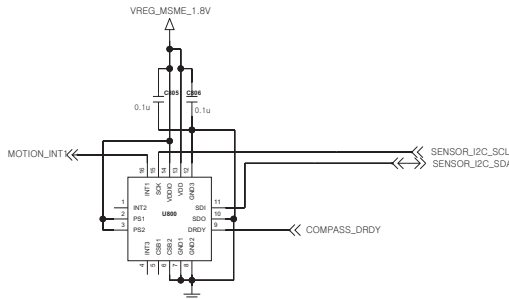
VOLUME KEY



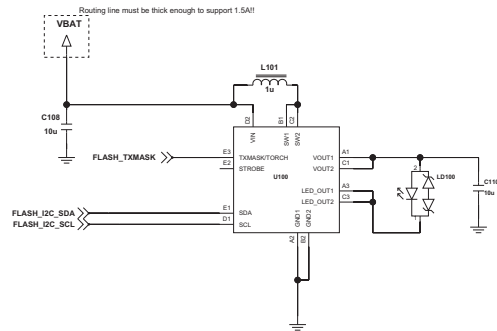
NFC ANT Matching Circuit



Digital Compass  
+ Accelerometer sensor

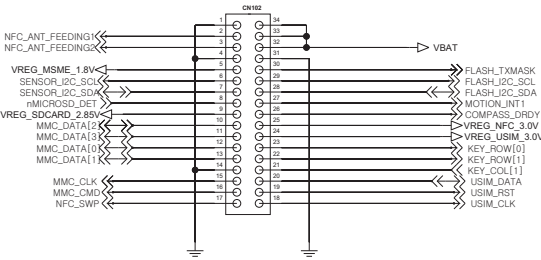


CAMERA FLASH LED DRIVER

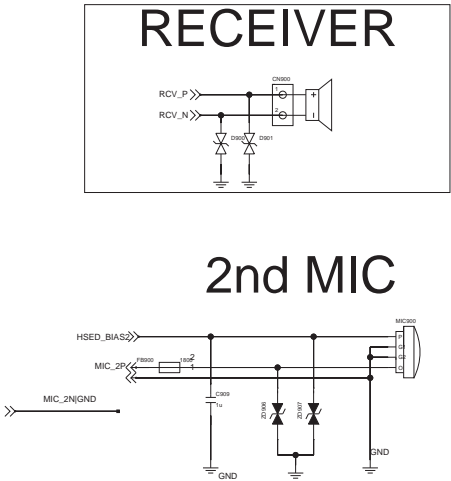
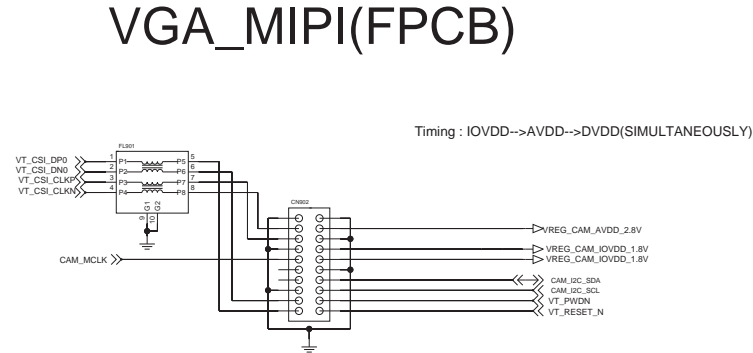
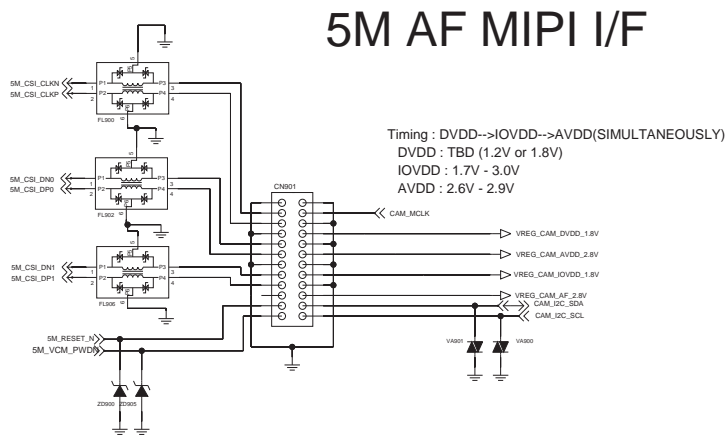


SUB-TO-MAIN CONNECTOR

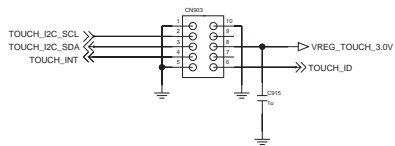
30pin socket NARROW TYPE 0.9t



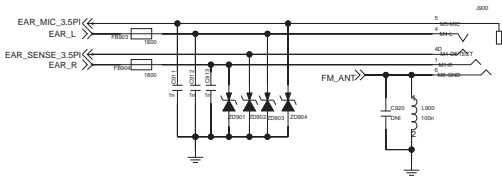




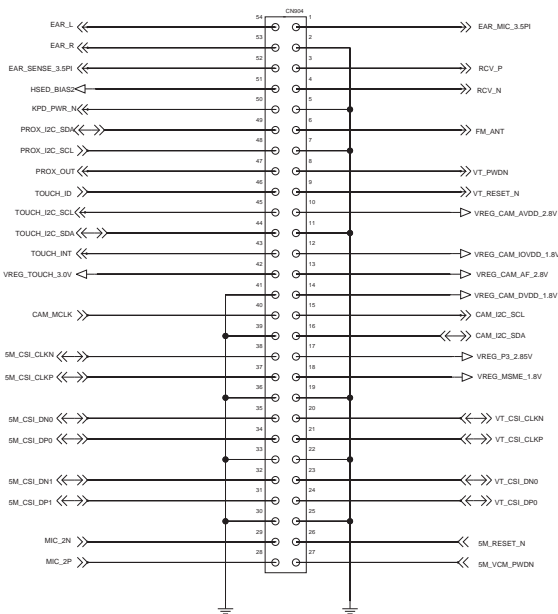
## TOUCH CONNECTOR



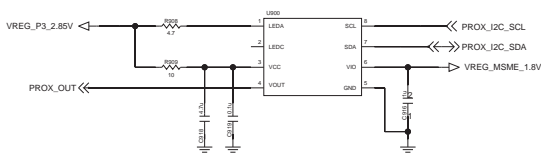
## 3.5pi Ear Jack Connector



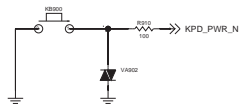
## MAIN-TO-upperFPCB CONNECTOR



## Proximity Sensor



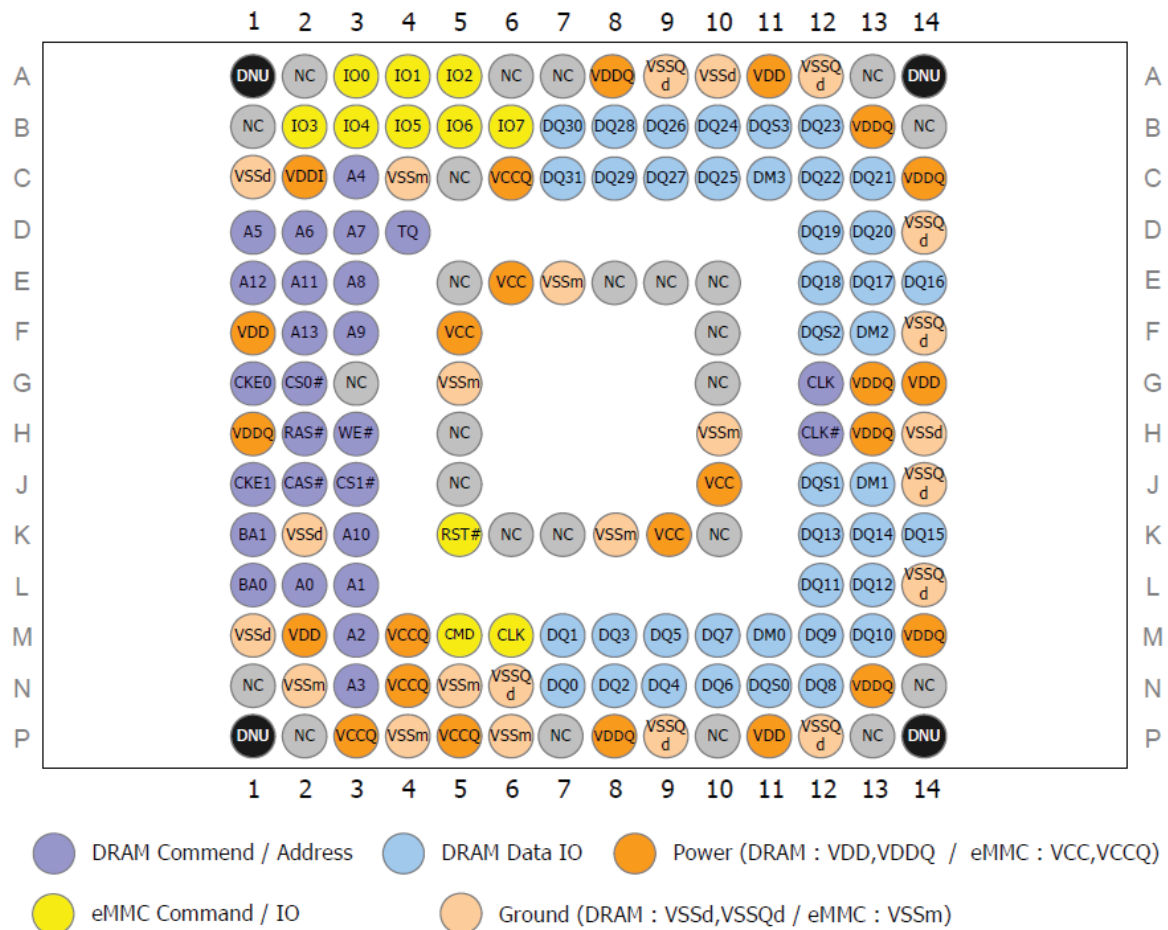
## POWER & LOCK KEY



## 8. BGA PIN MAP

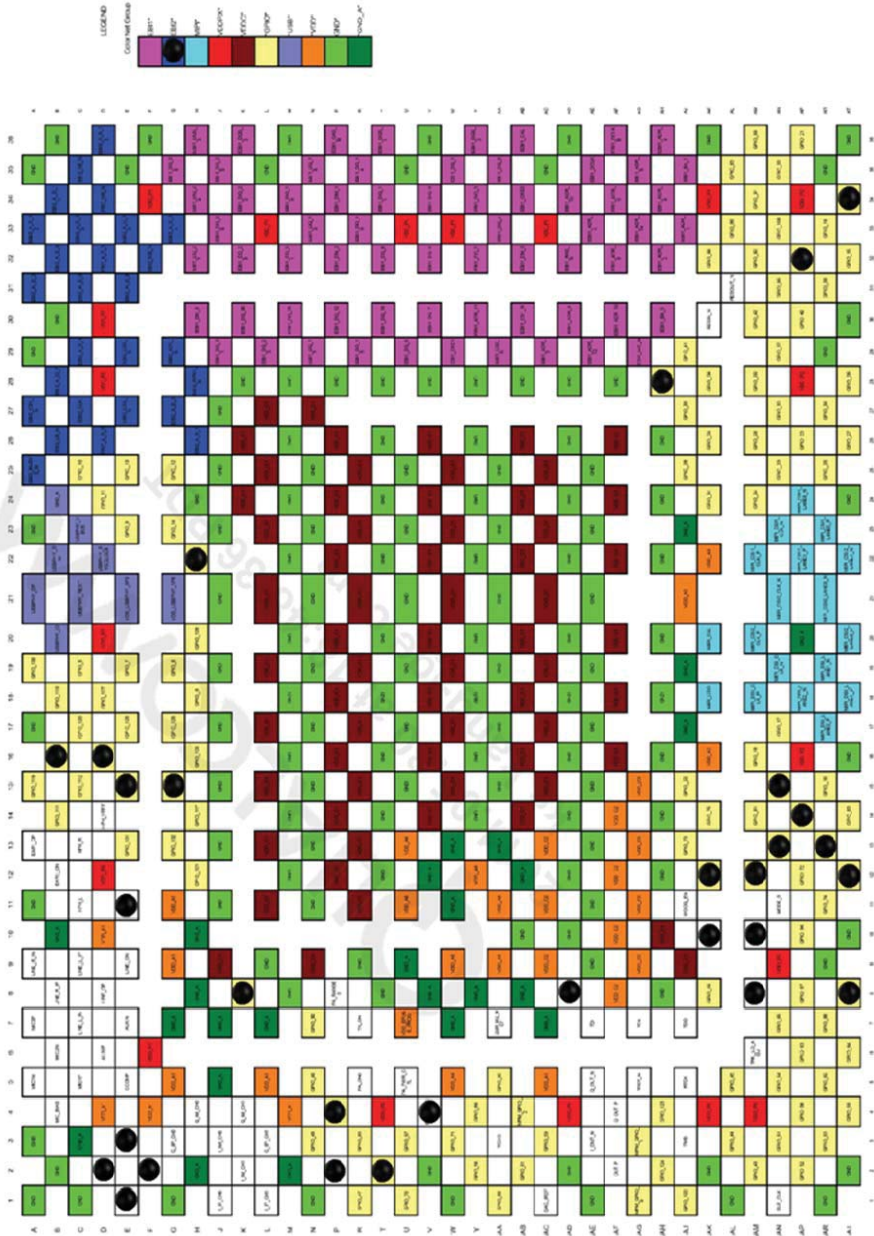
U400 - Memory MCP (Top View)

### 153Ball ASSIGNMENT - (4GB+4Gb / eMMC4.41 + x32 LPDDR, 2CS)



*Top View*

### U200 - MSM7227A(bottom view)



○ USE

● NOT IN USE

## 8. BGA PIN MAP

### U501 – PM8029

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24
A	NC	VREG_L17	NC	VDD_L17	NC	NC	NC	VREG_L11	NC	VDD_L11	NC	VDD	NC	NC	NC	VREG_L2	NC	VDD_L2	NC	NC	NC	NC	NC
B	NC	VREG_L18	NC	VREG_L18	NC	NC	VREG_L11	NC	VREG_L11	NC	VDD_L11	NC	VREG_L11	NC	NC	VREG_L2	NC	VREG_L2	NC	NC	NC	NC	NC
C	VREG_L13	NC	VREG_L14	NC	NC	NC	OP104	NC	OP103	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
D	NC	VDD_L13	NC	VDD_L13	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
E	XTAL12K_OUT	NC	VREG_L15	NC	SLBP_OUT	NC	NC	NC	OP107	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
F	NC	XTAL12K_IN	NC	VDD	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
G	VREG_L16	NC	VREG_L14	NC	REF_BYP	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
H	NC	VDD_L12	NC	VDD_L12	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
I	VREG_L13	NC	TOKO_IN	NC	REF_GND	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
J	NC	VREG_L18	NC	TOKO_OUT_A3	NC	TRK_LO_A3	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
K	VREG_L13	NC	TOKO_IN	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
L	NC	VREG_L18	NC	TOKO_IN	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
M	VREG_L13	NC	TOKO_IN	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
N	VREG_L13	NC	TOKO_IN	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	TOKO_OUT_A3	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
P	NC	TOKO_IN	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC
R	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC	NC

PM8029 IC pin assignments (bottom view)

○ USE  
● NOT IN USE

## 8. BGA PIN MAP

U1000 - RTR6285A (Top View)

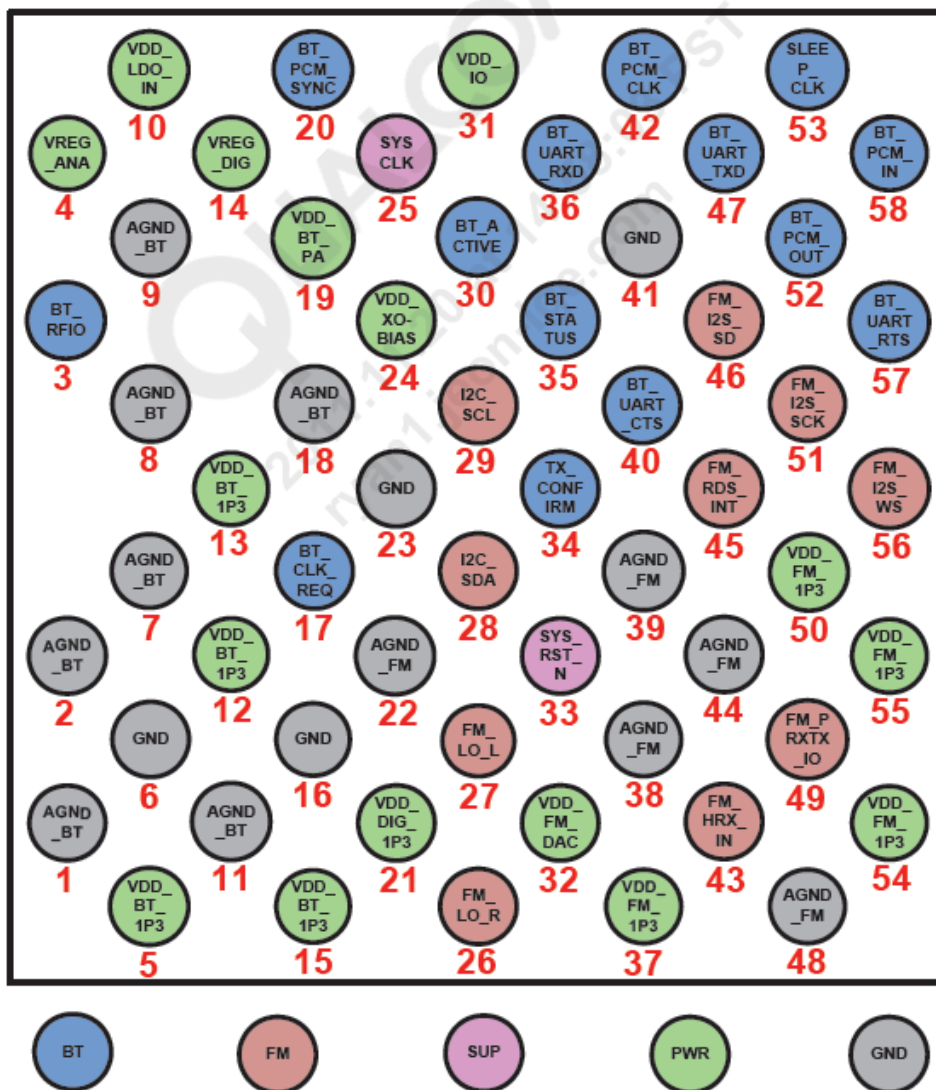
	1	2	3	4	5	6	7	8	9	10	11	12	13	
A	GND	TX_RB1AS	DAC_IREF	TX_IP	VDDA2	VDDA2	HB_RF_O UT3	HB_RF_O UT1	LB_RF_OU T1	VDDA1	PDET_IN	GND		
B	VDDA2	GND	TX_QP	TX_QN	TX_IN	VDDA2	GND	GND	LB_RF_OU T2	VDDA2	GND	EGSM_INN	GCELL_IN N	
C	TCXO	GND										EGSM_INP	GCELL_IN P	
D	VDDA1	VDDA1		GND	GND	GND	GND	GND	GND	GND		GPCS_INN	DCS_INN	
E	VTUNE1	GND		GND	GND	GND	GND	GND	GND	GND		GPCS_INP	DCS_INP	
F	VDDA1	VDDA2		GND	GND	GND	GND	GND	GND	GND		GND	VDDA2	
G	VTUNE_G PS	VDDA2		GND	GND	GND	GND	GND	GND	GND		GND	GPS_IN	
H	VDDA1	VDDA1		GND	GND	GND	GND	GND	GND	GND		GND	VDDA1	
J	PRX_QP	PRX_QN		GND	GND	GND	GND	GND	GND	GND		WPRXSE1	WPRXSE2	
K	PRX_IN	PRX_IP		GND	GND	GND	GND	GND	GND	GND		GND	WPRXSE1	
L	DRX_QP	DRX_QN										VDDA2	WPRXSE2	
M	DRX_IP	DRX_IN	SBOT	VDDA1	VDD_MSM	VDDA2	RF_ON	WB_MX_I NM	WPRXLBM	GND	GND	GND	WPRXSE1 _OUT	
N	GND	NC	VDDA2	VDDA1	VTUNE2	VDDA2	VDDA2	WB_MX_I NP	WPRXLBP	WPRXSE1	WPRXSE2	WPRXSE2 _OUT	GND	
	1	2	3	4	5	6	7	8	9	10	11	12	13	

○ USE

● NOT IN USE



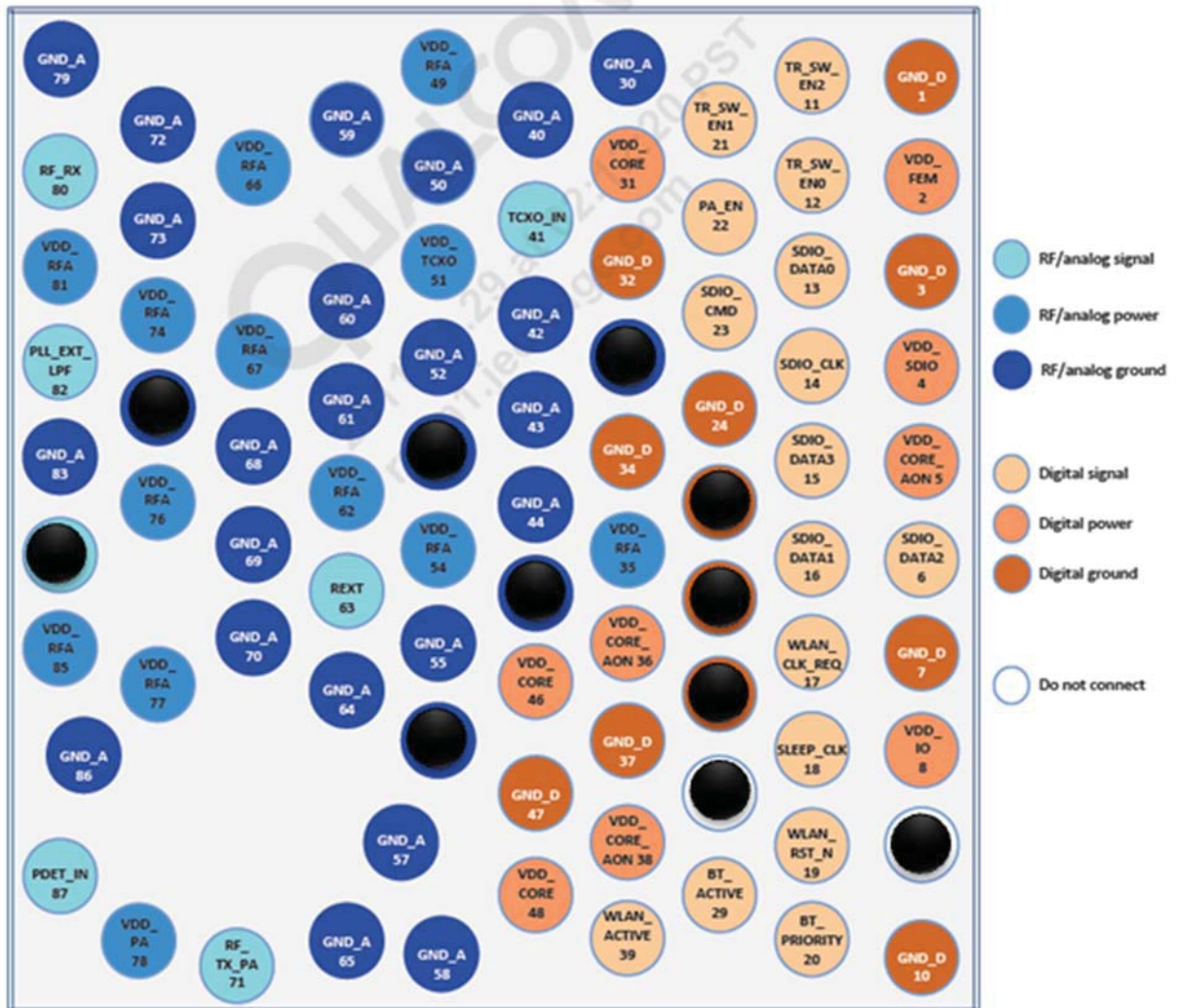
### U800 – WCN2243 (BT/FM) (Top View)



WCN2243 IC pin assignments, top view



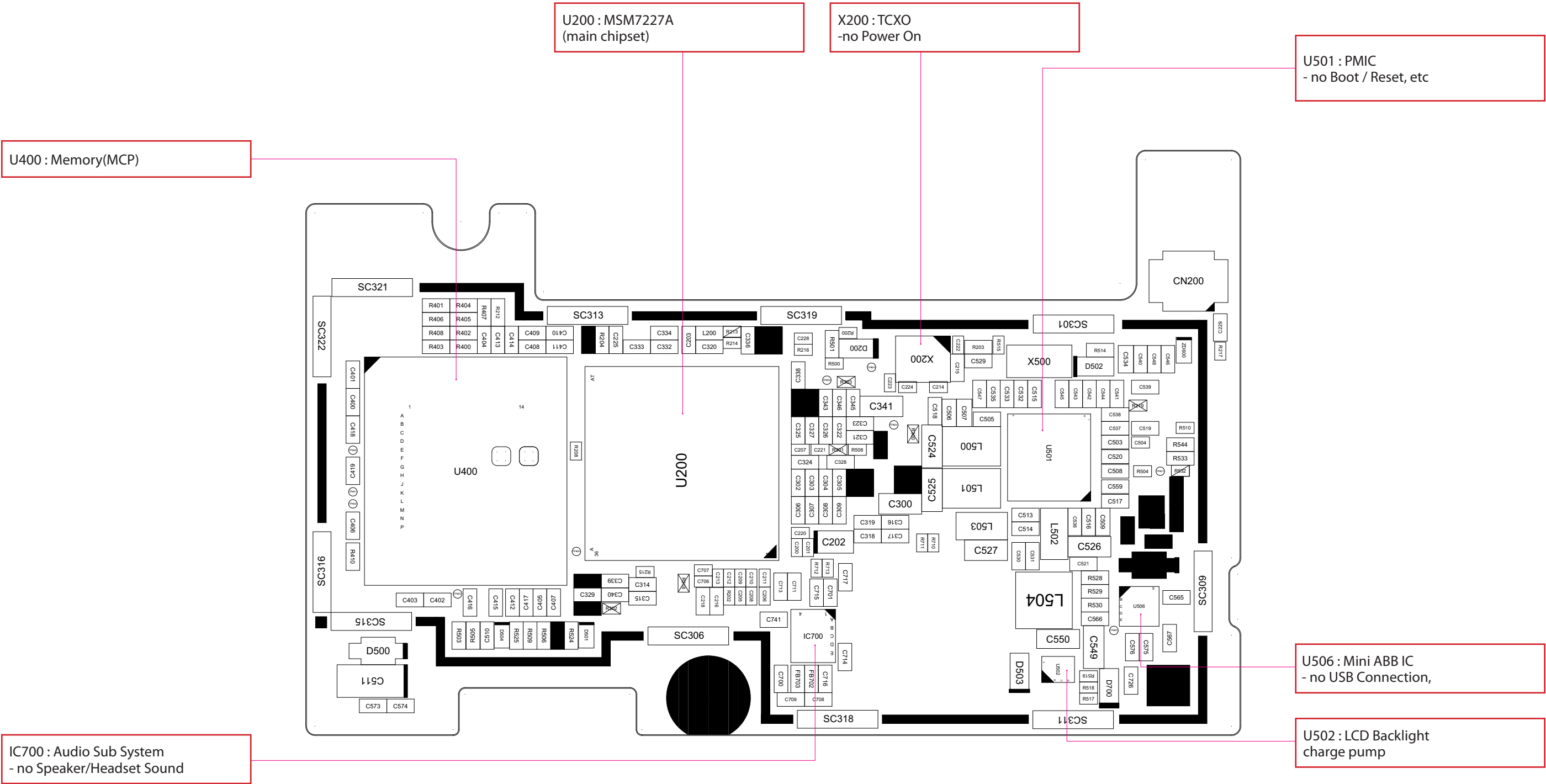
### U802– WCN1314 (WiFi) (Top View)



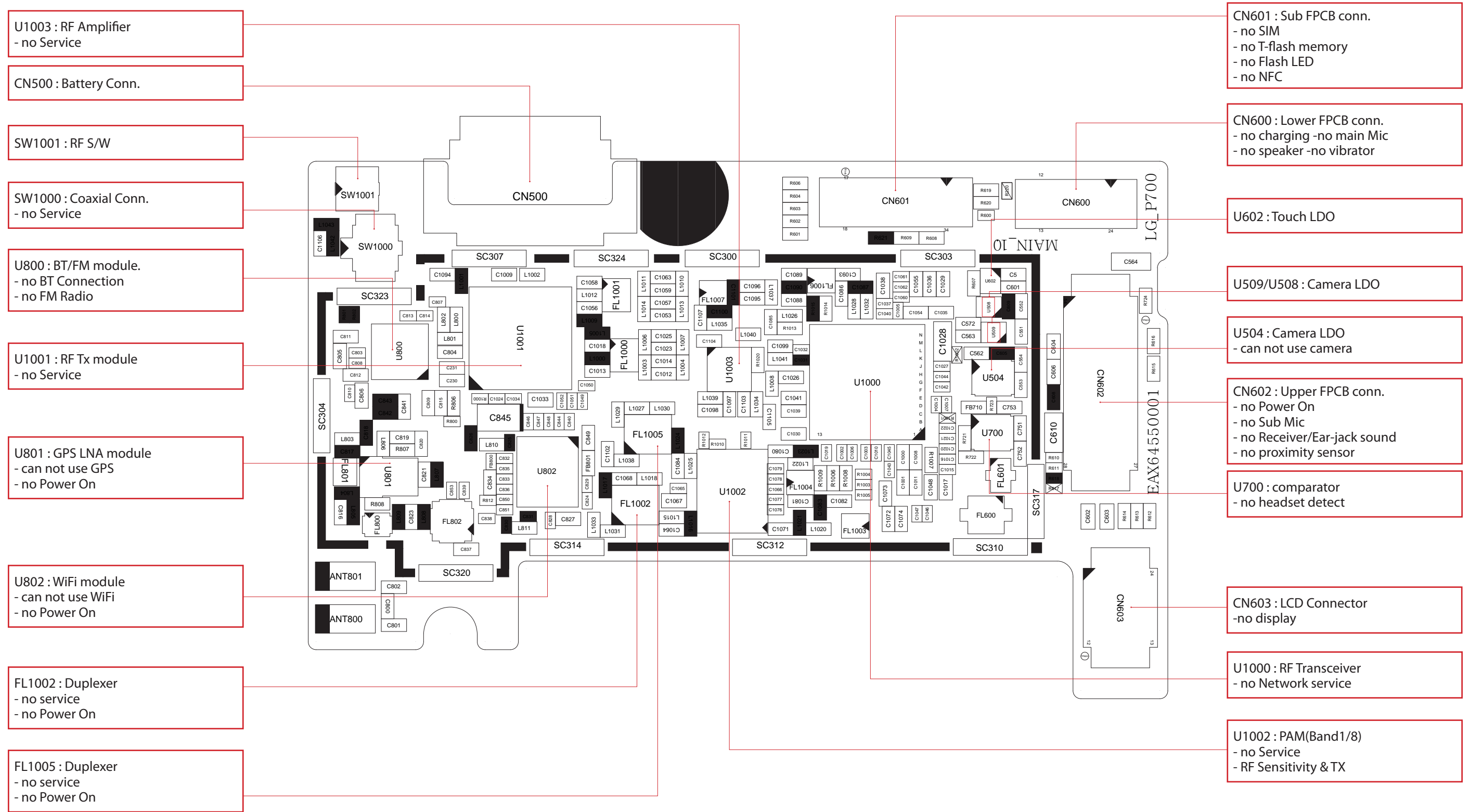
WCN1314 IC pin assignments (top view)

- USE  
● NOT IN USE

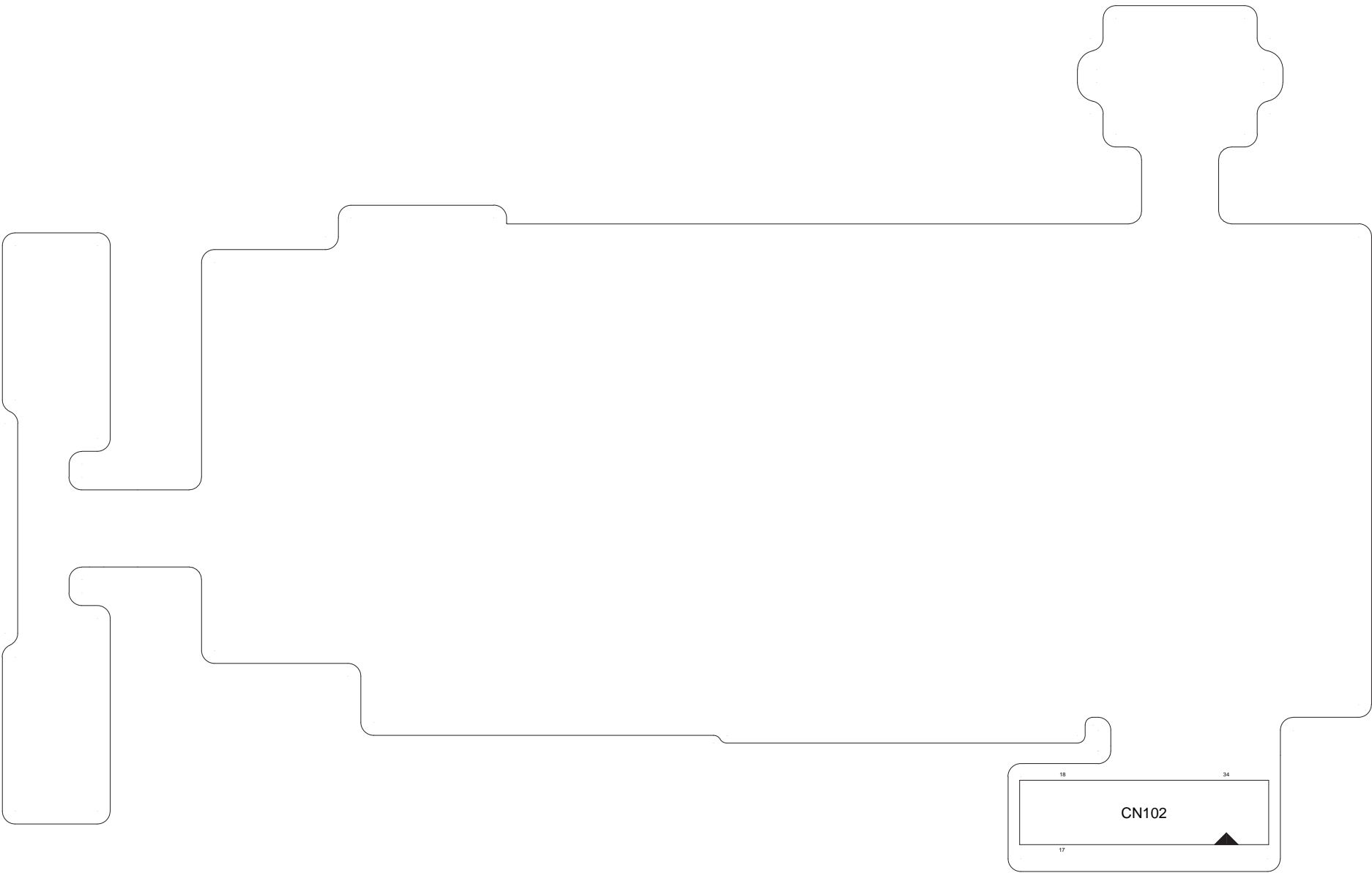
9. PCB LAYOUT



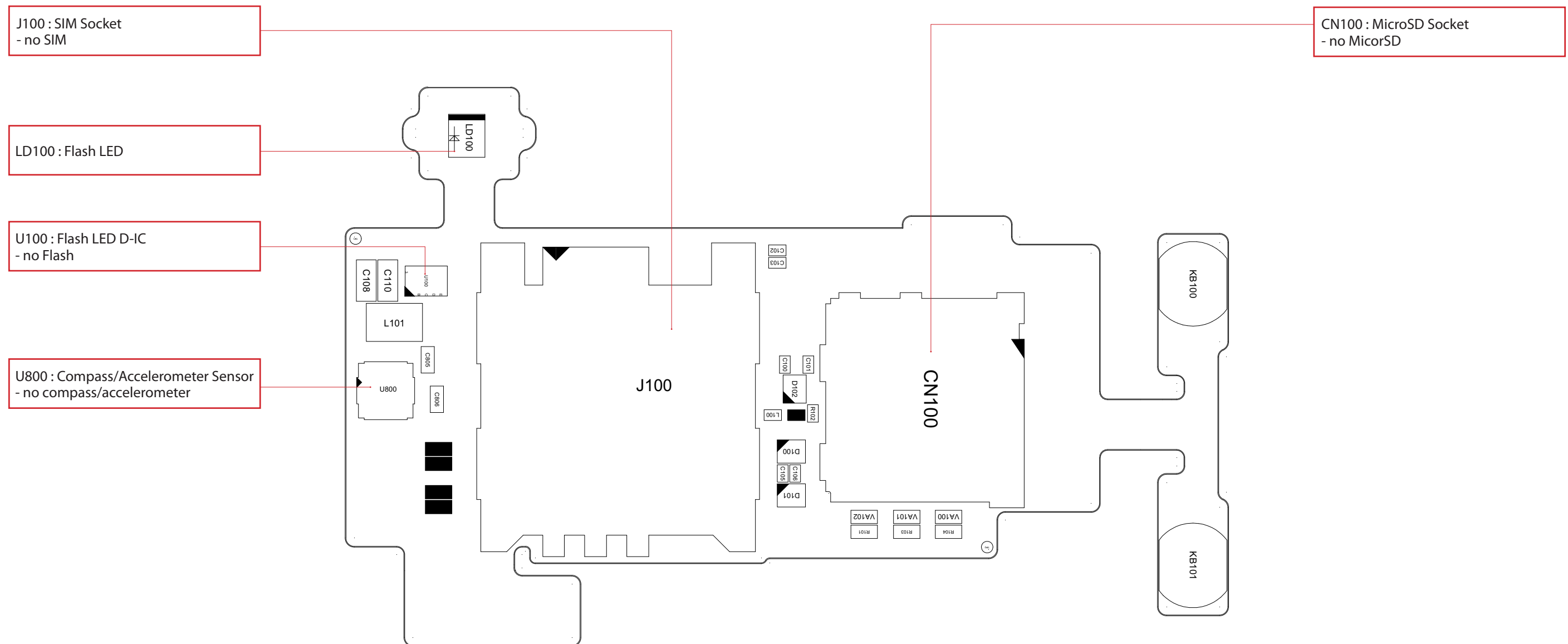
LG-P705\_MAIN\_EAX64550001-1.0-TOP



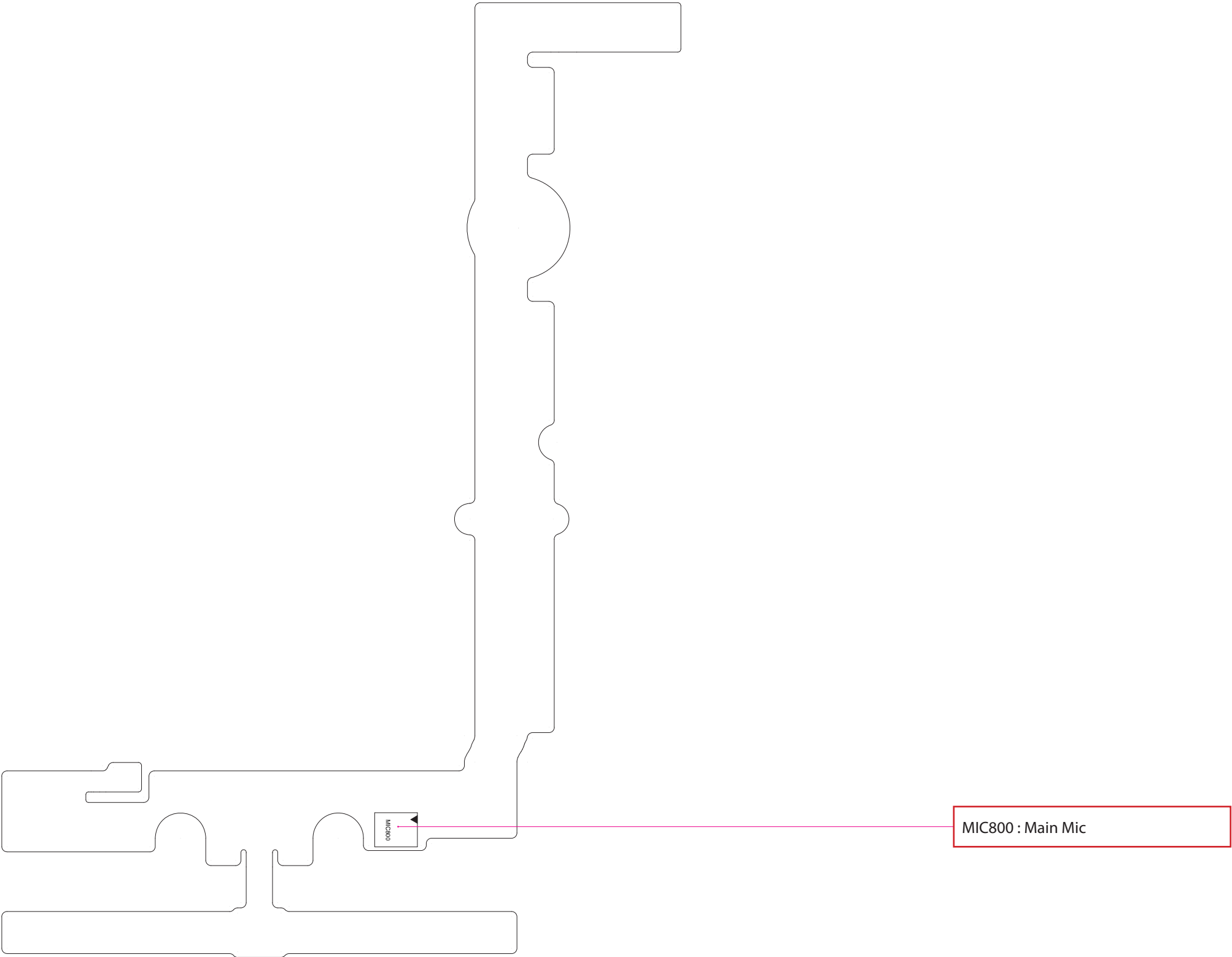
LG-P705\_MAIN\_EAX64550001-1.0\_BOT



LG-P705\_F\_SUB-1.1-TOP

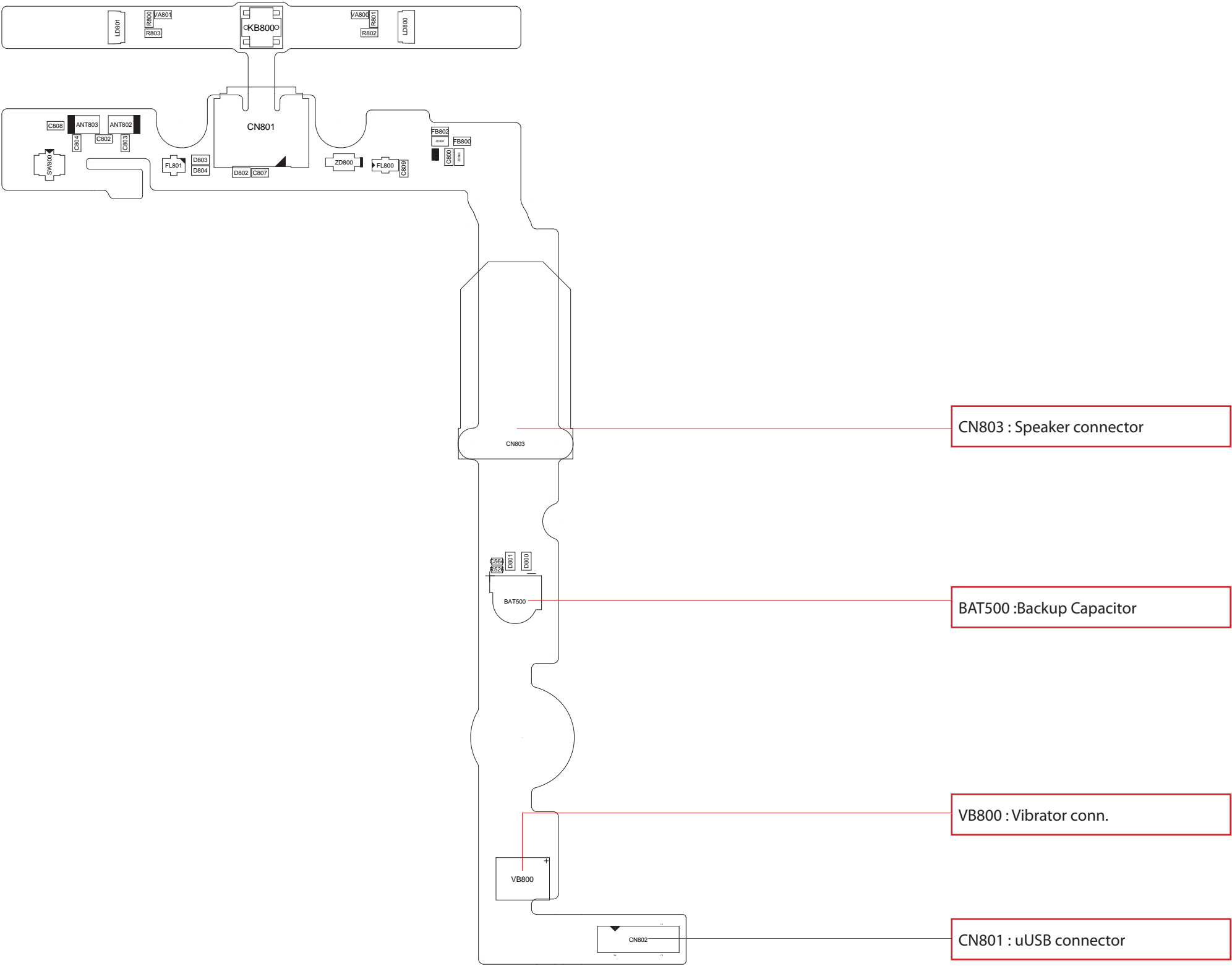


LG-P705\_F\_SUB-1.1-BOT

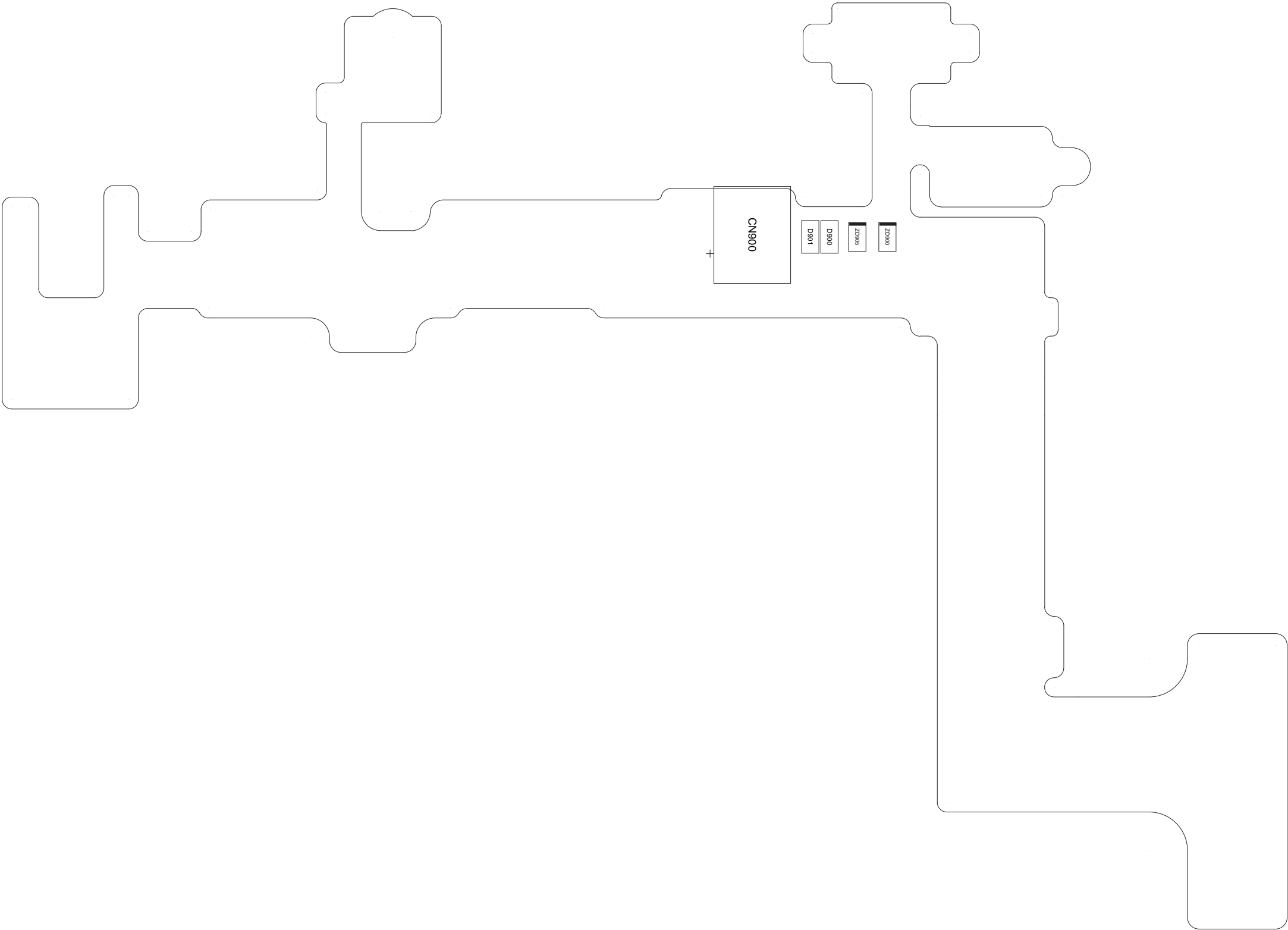


LG-P705\_F\_LOWER-1.0-TOP

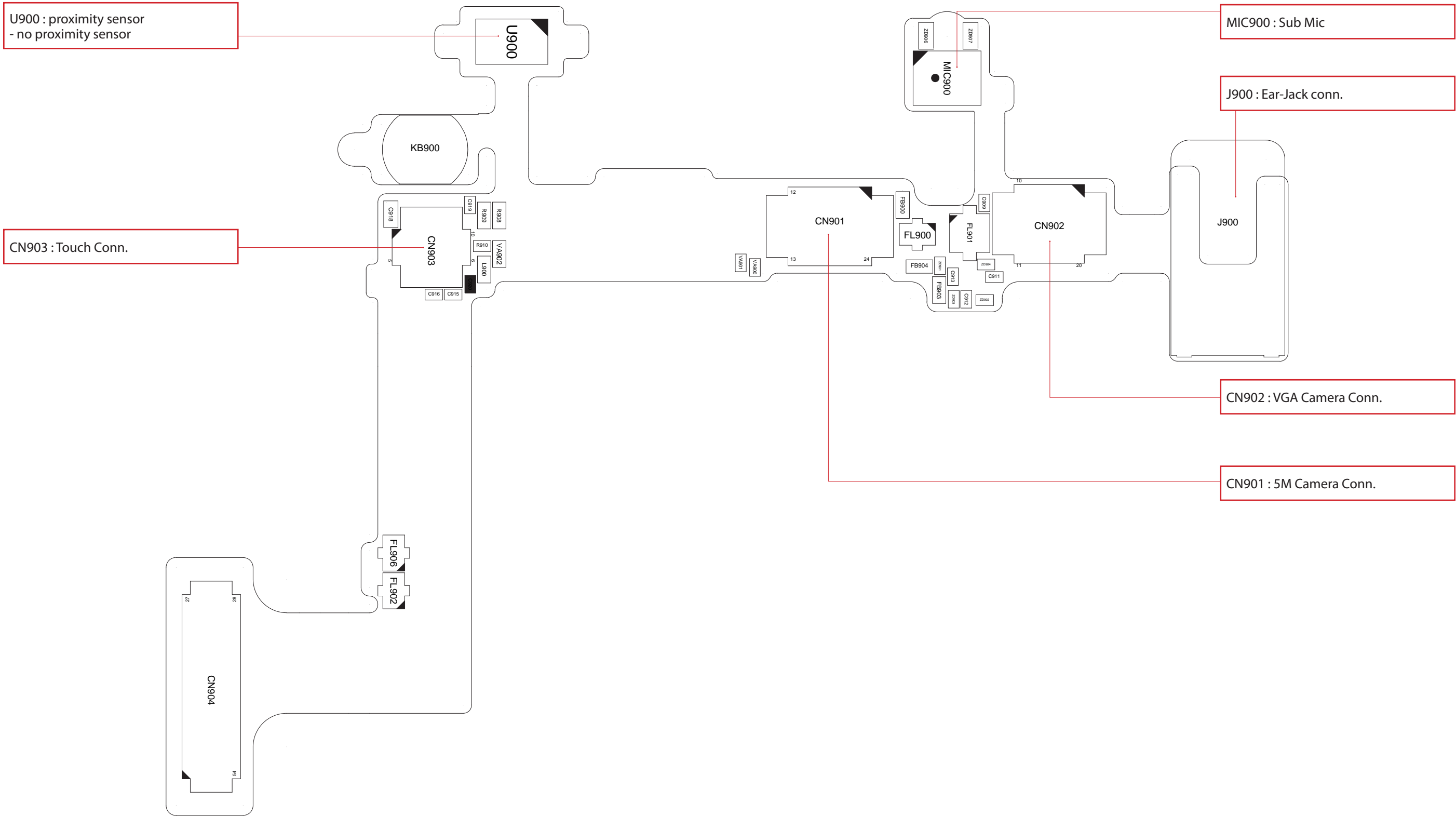




LG-P705\_F\_LOWER-1.0-BOT



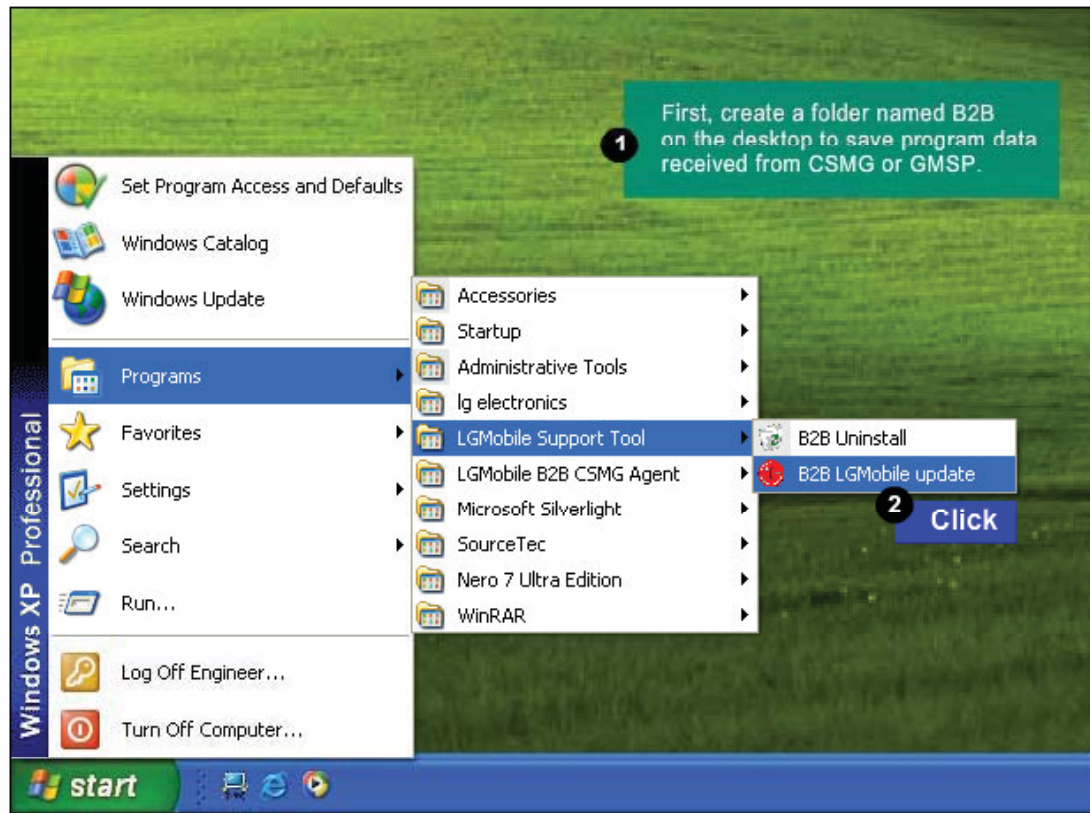
LG-P705\_F\_UPPER\_EAX64667901-1.1-TOP

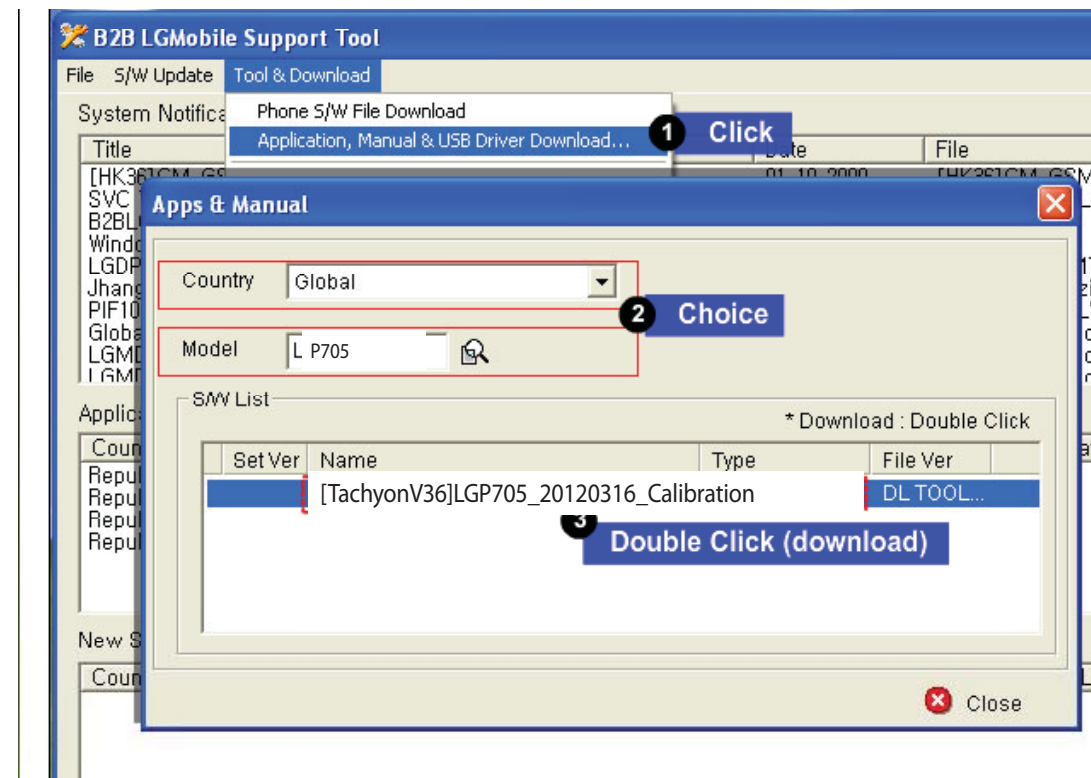
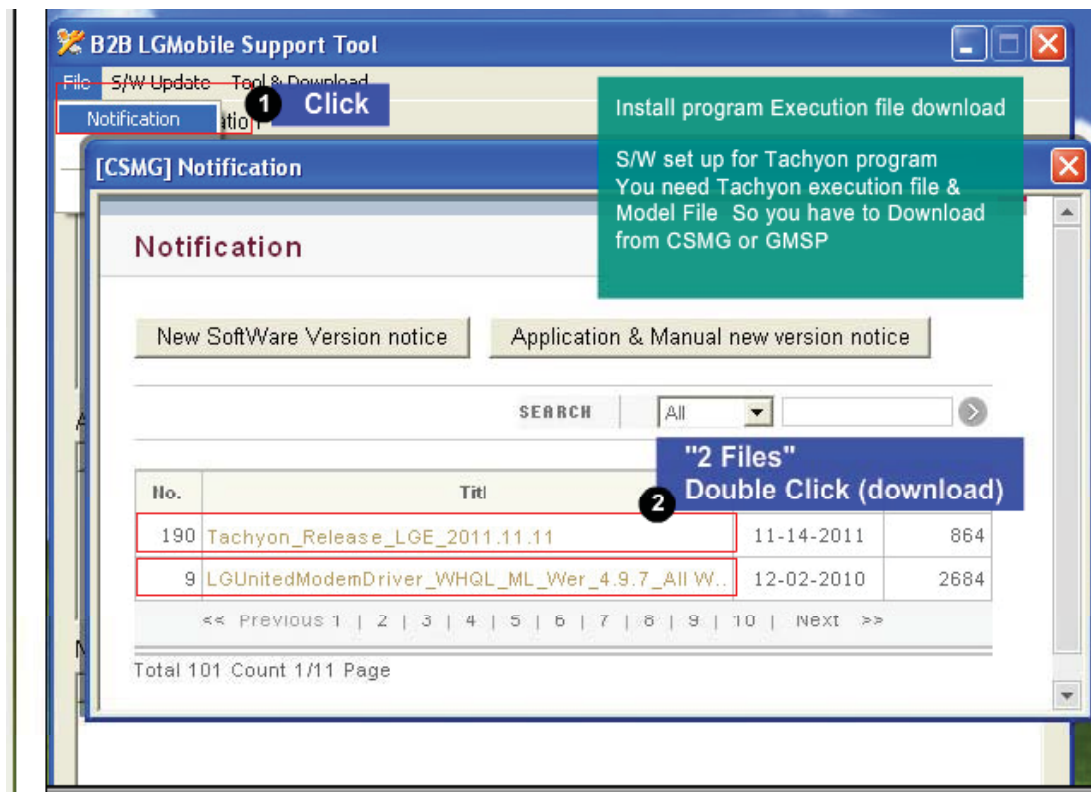


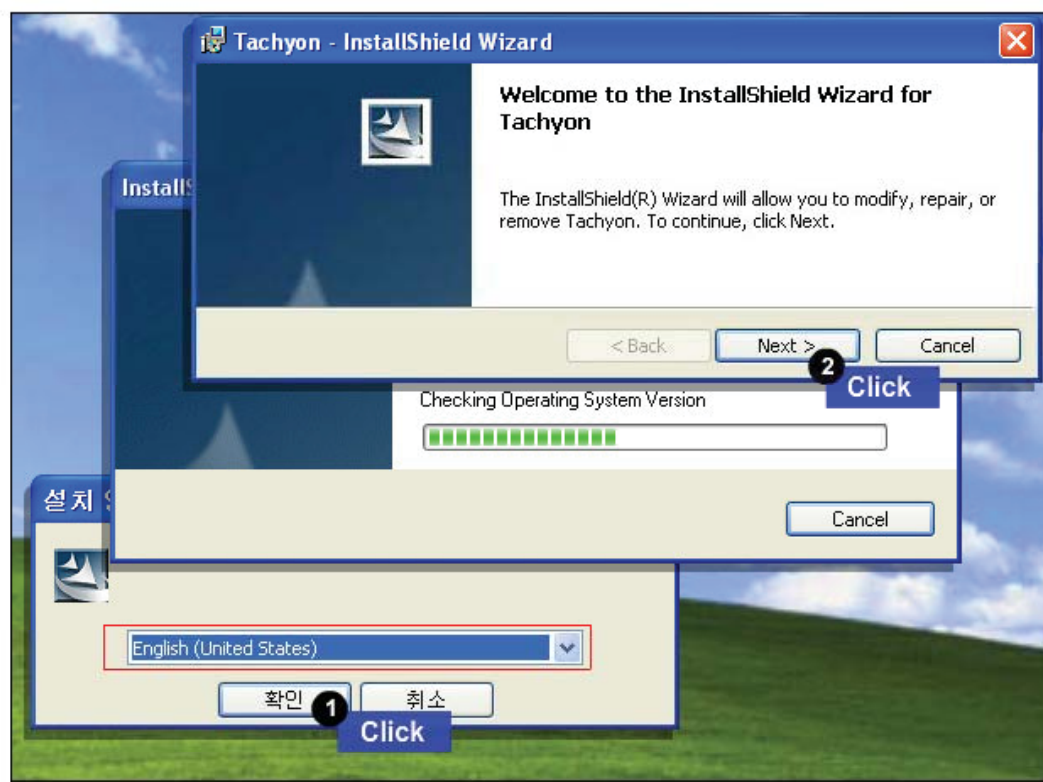
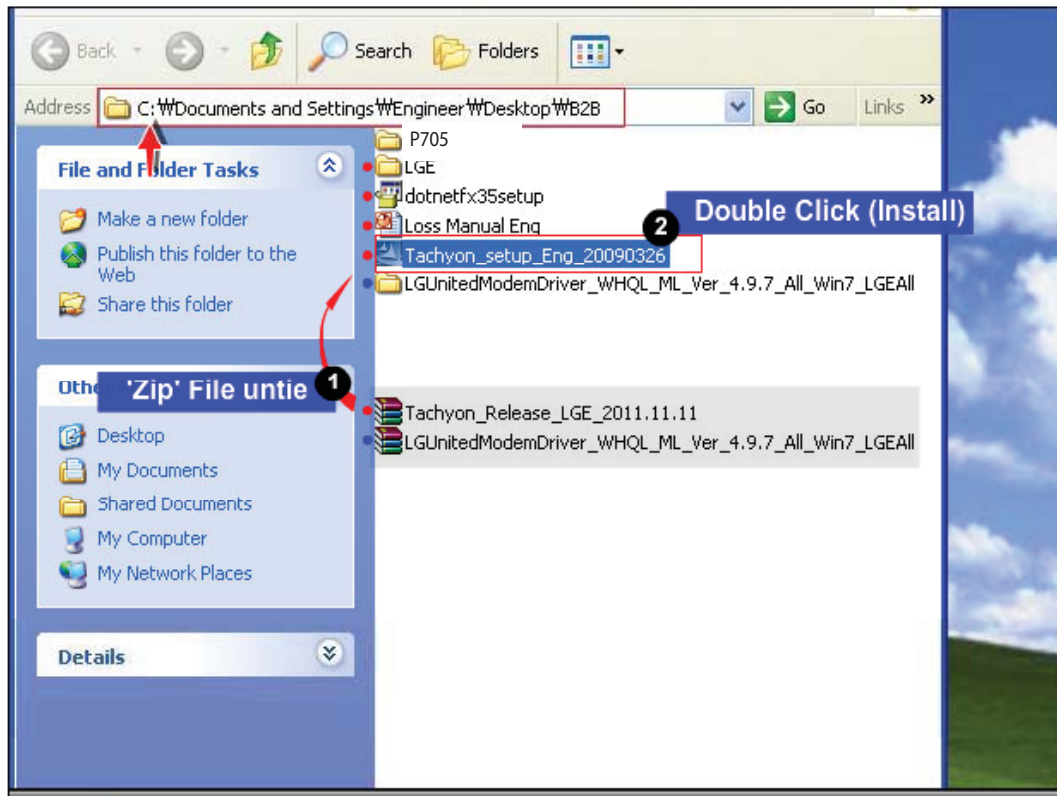
LG-P705\_F\_UPPER\_EAX64667901-1.1-BOT

## 10. CALIBRATION

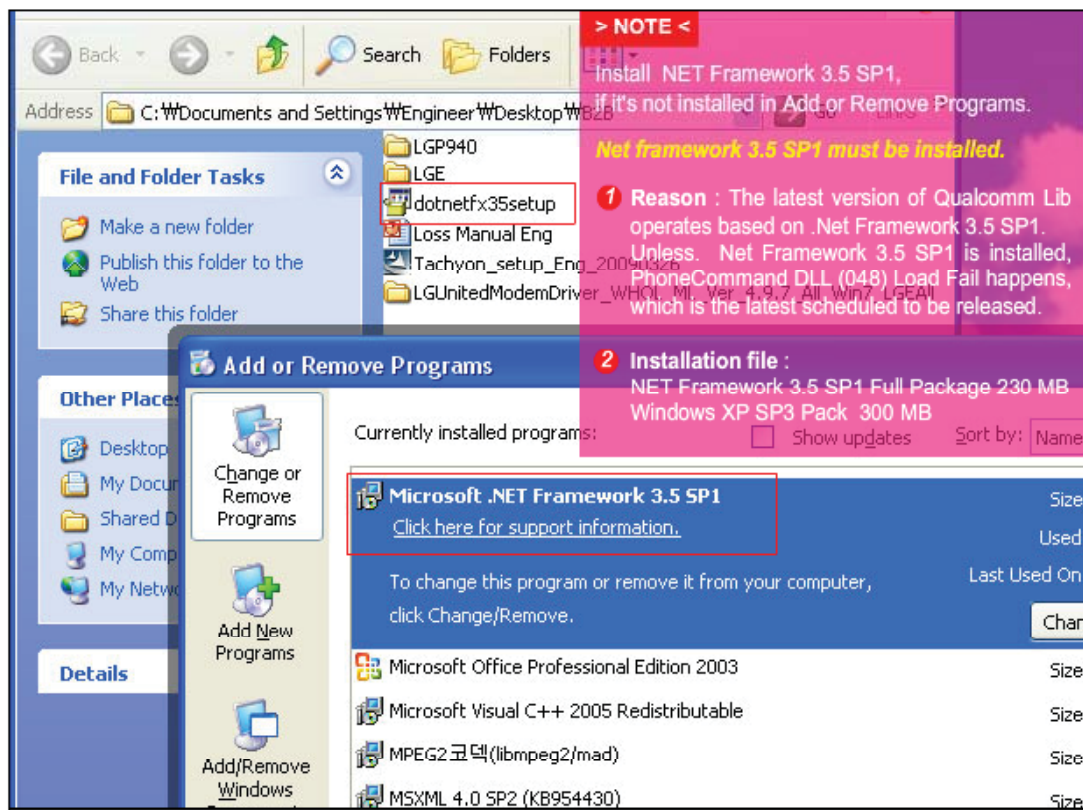
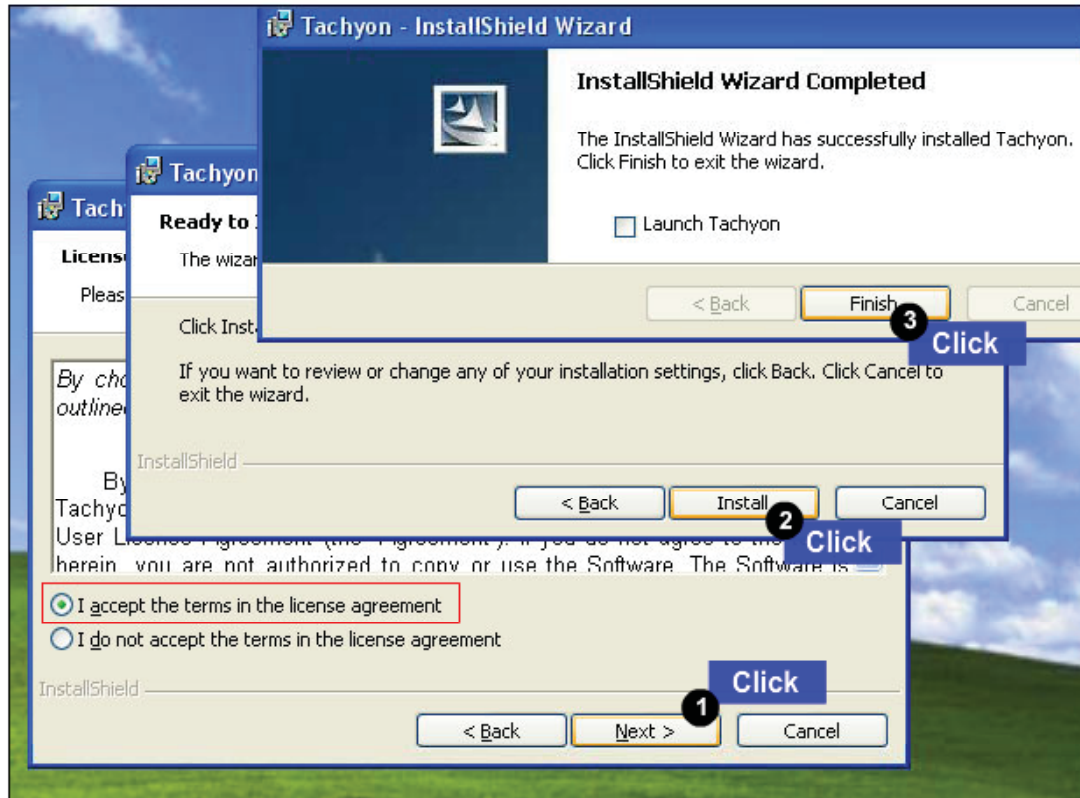
CAL INFORMATION		
S/W VERSION		
[TachyonV36]LGP705_20120316_Calibration		
Please check the final version to "B2B"		
H/W		
	Name	Part No.
PIF	PIF200(All Type)	BJAY0024021
USB Cable	USB Cable	RAD32247898
Power Cable	DC Power Cable	RAD32247878
I/O Cable	5P E-SATA_DC_Plug	RAD32167861
RF Cable_Main	MS-156C	BJAY0024004
Power Supply_PIF	Power Supply 5.3V	
Power Supply_Phone	Power Supply 5.0V	
RF Test Equipment	E5515C(8960)	

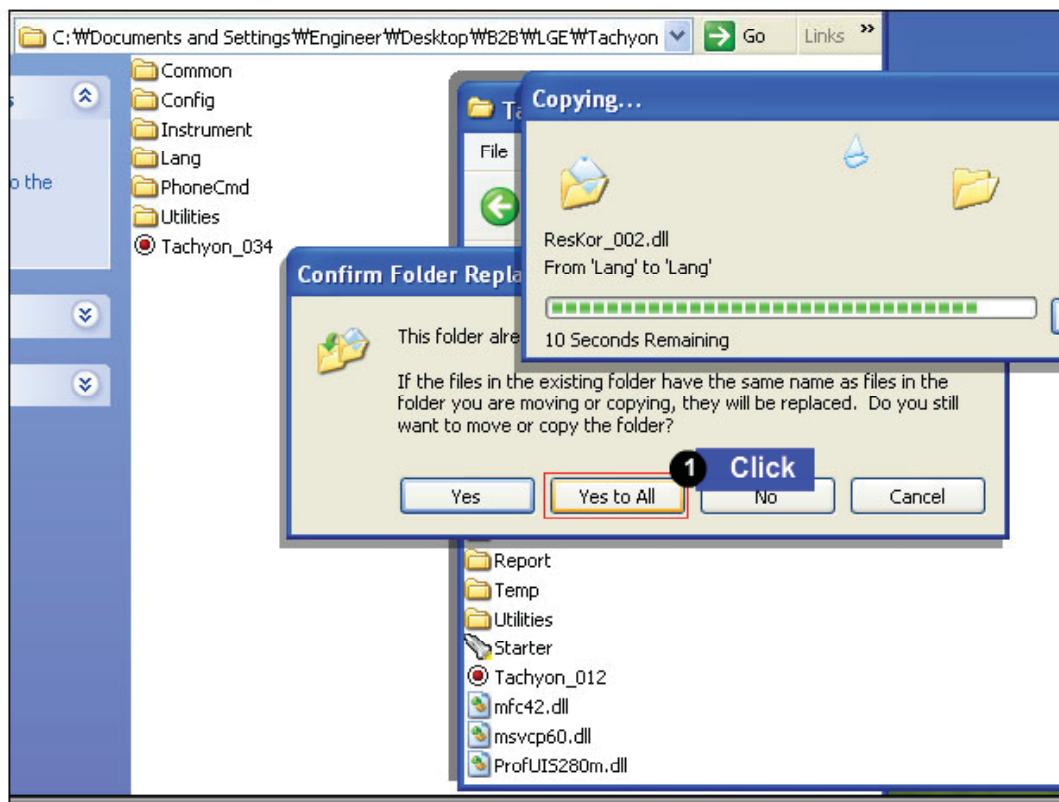
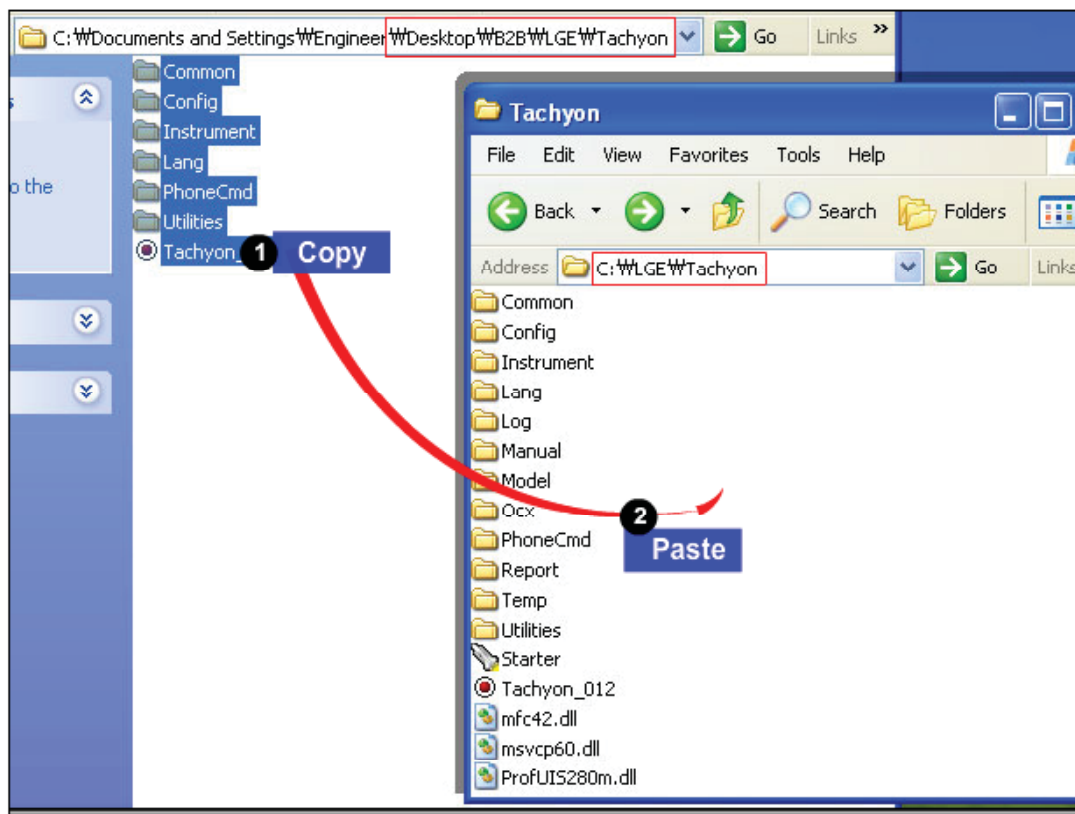


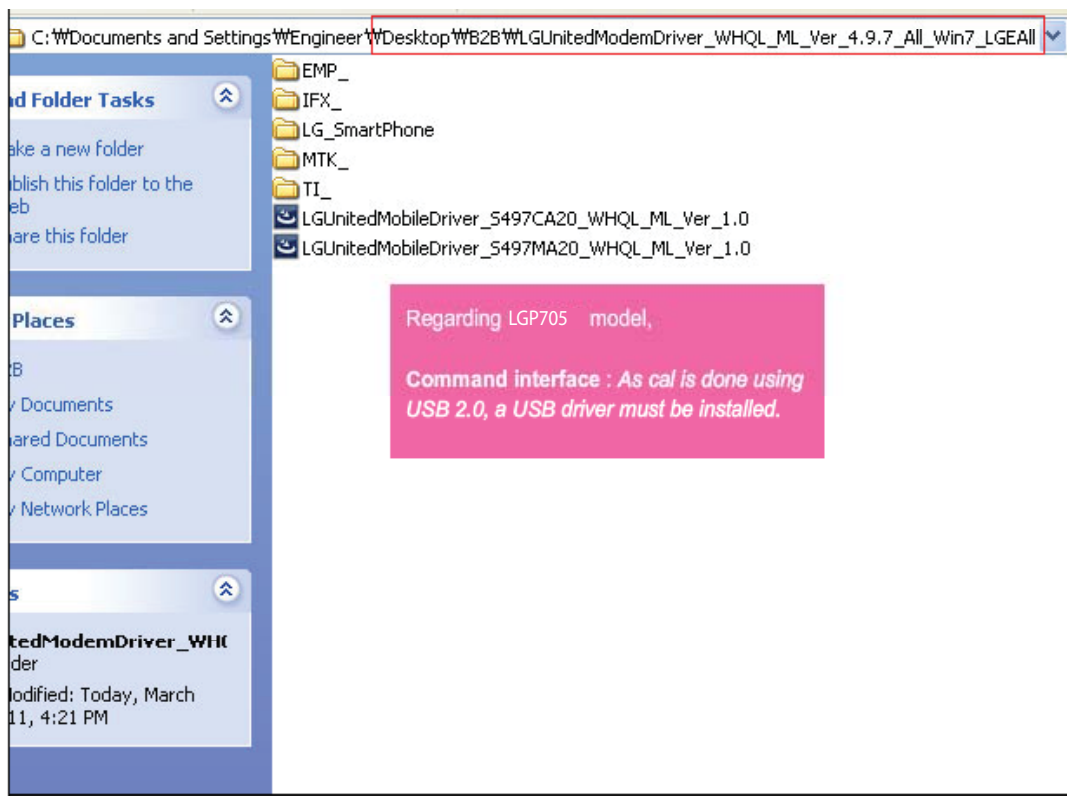
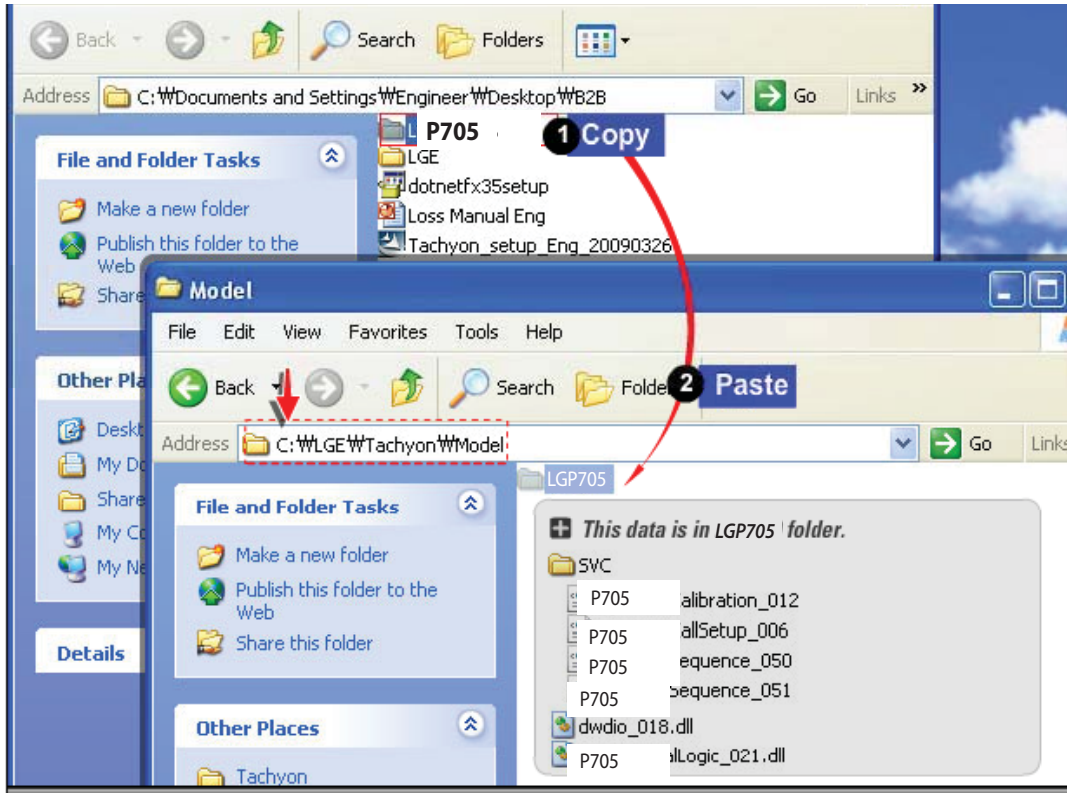


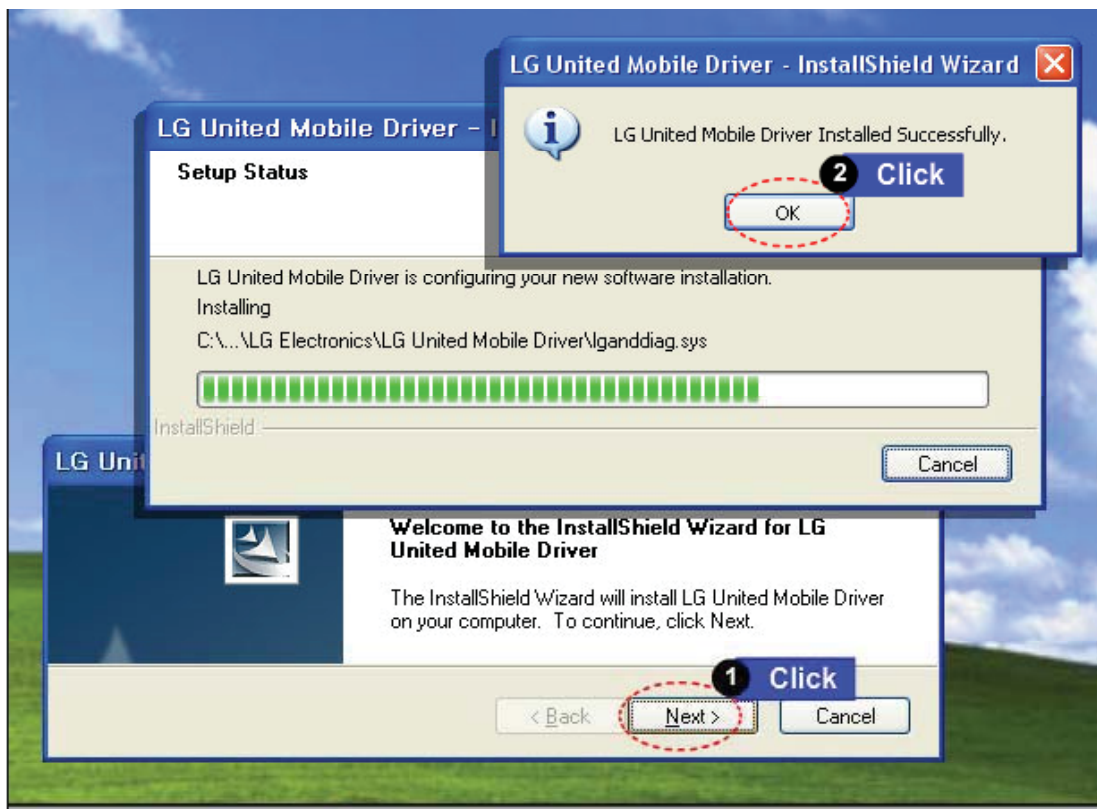
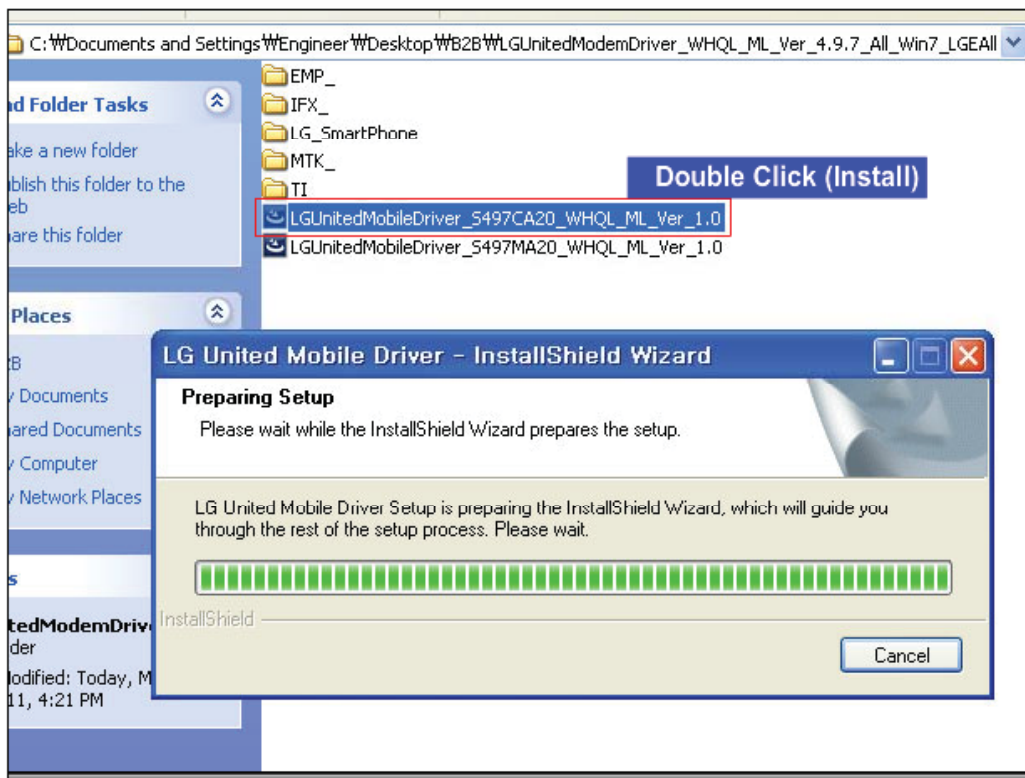




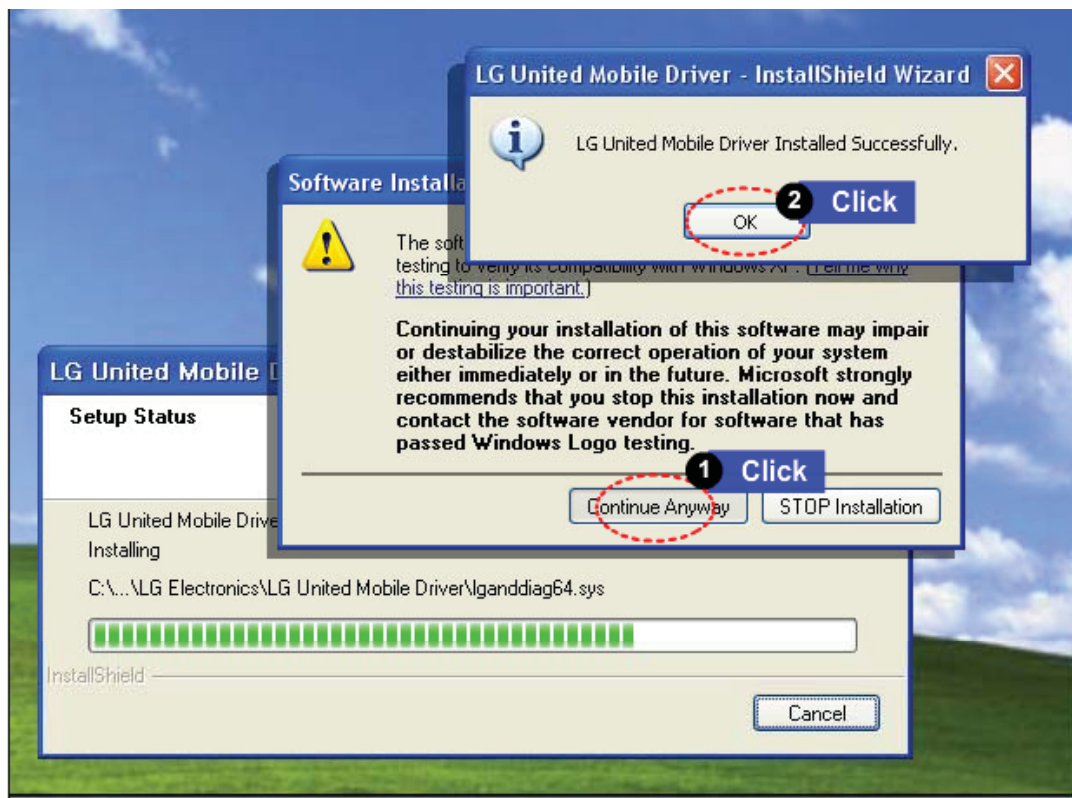
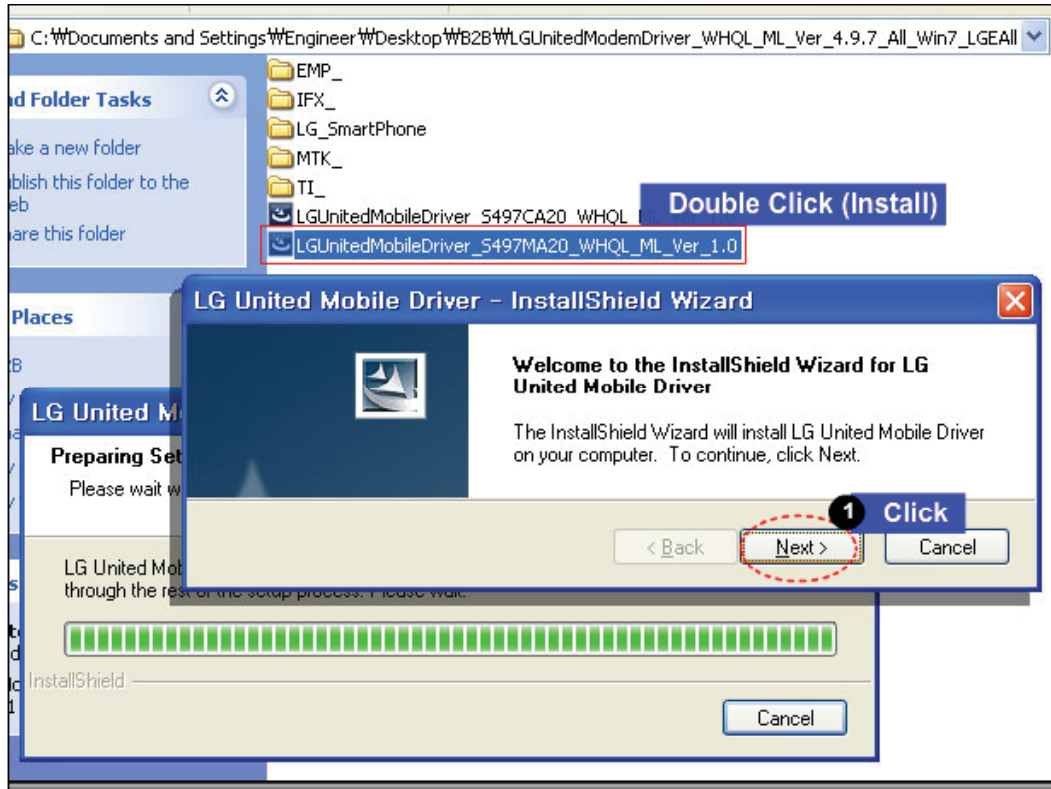




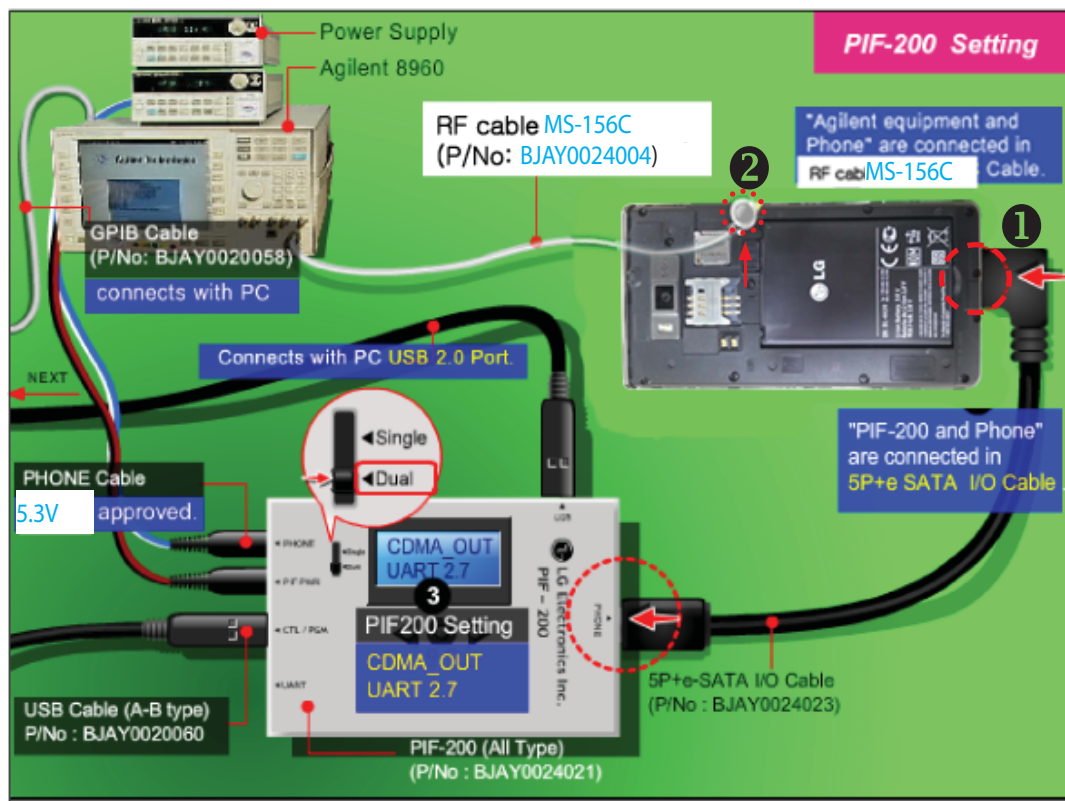
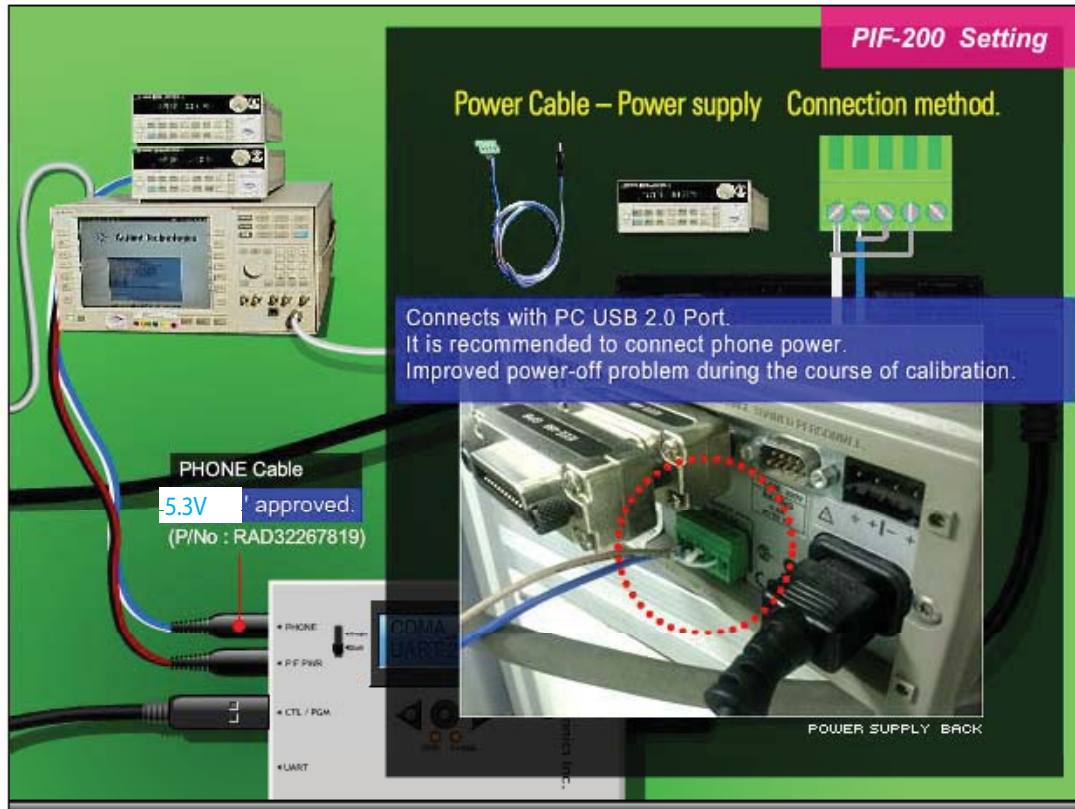




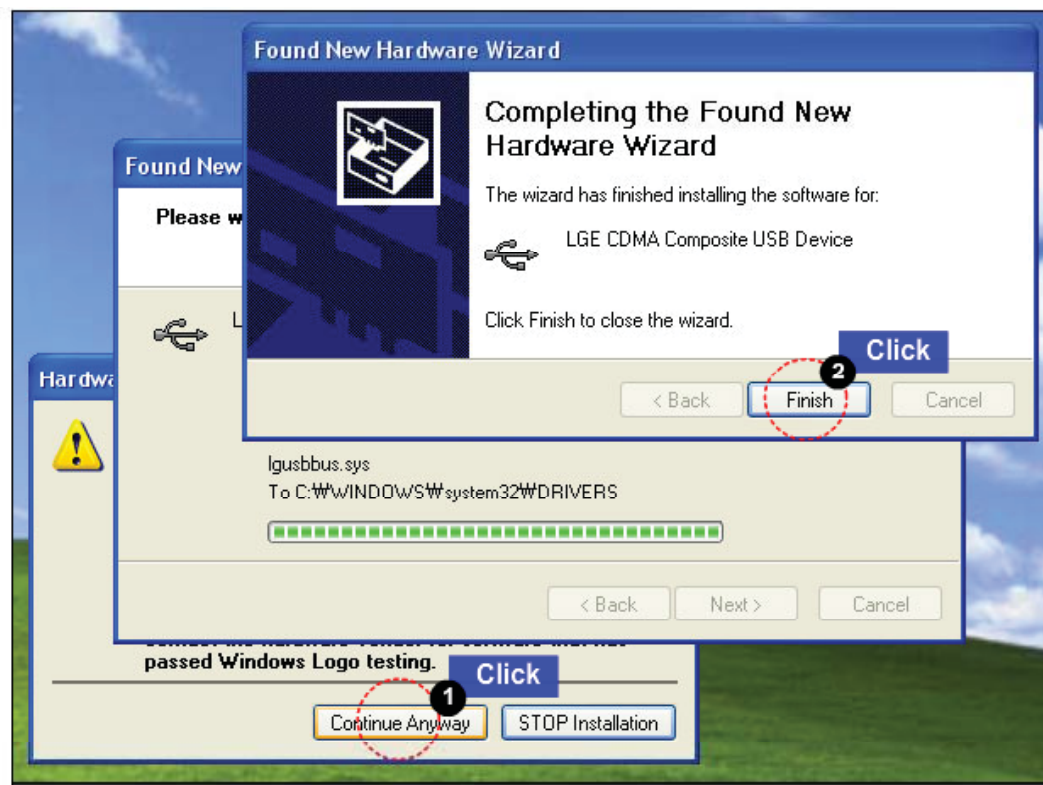
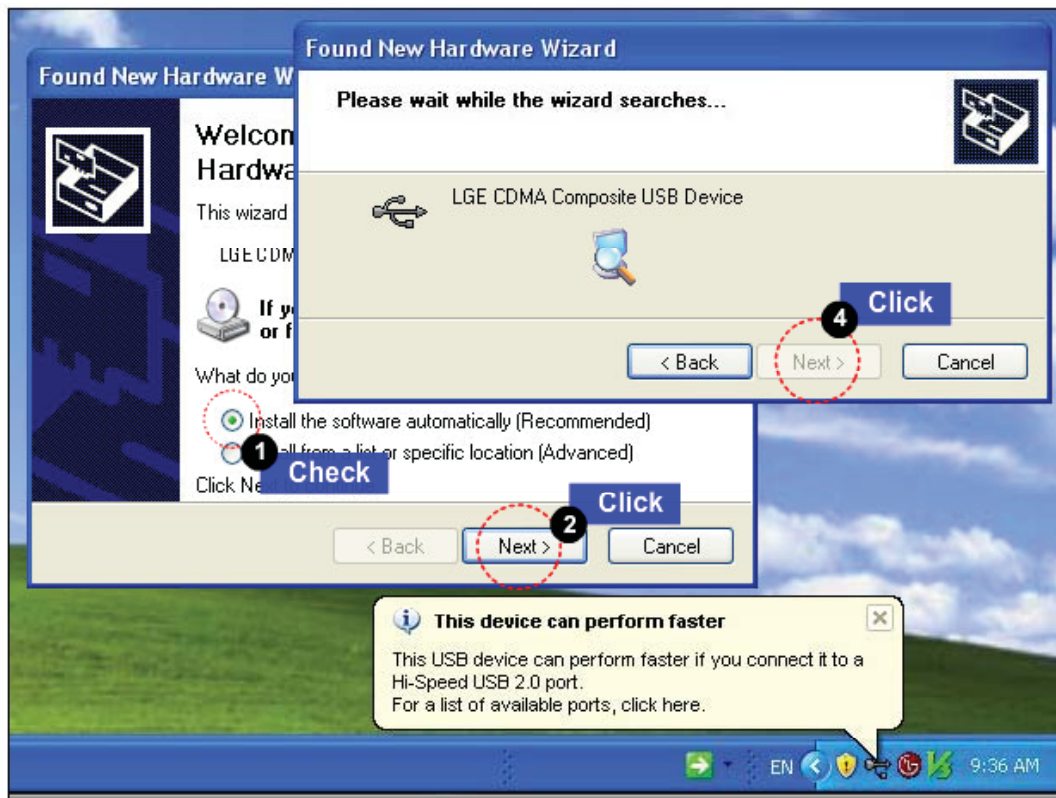


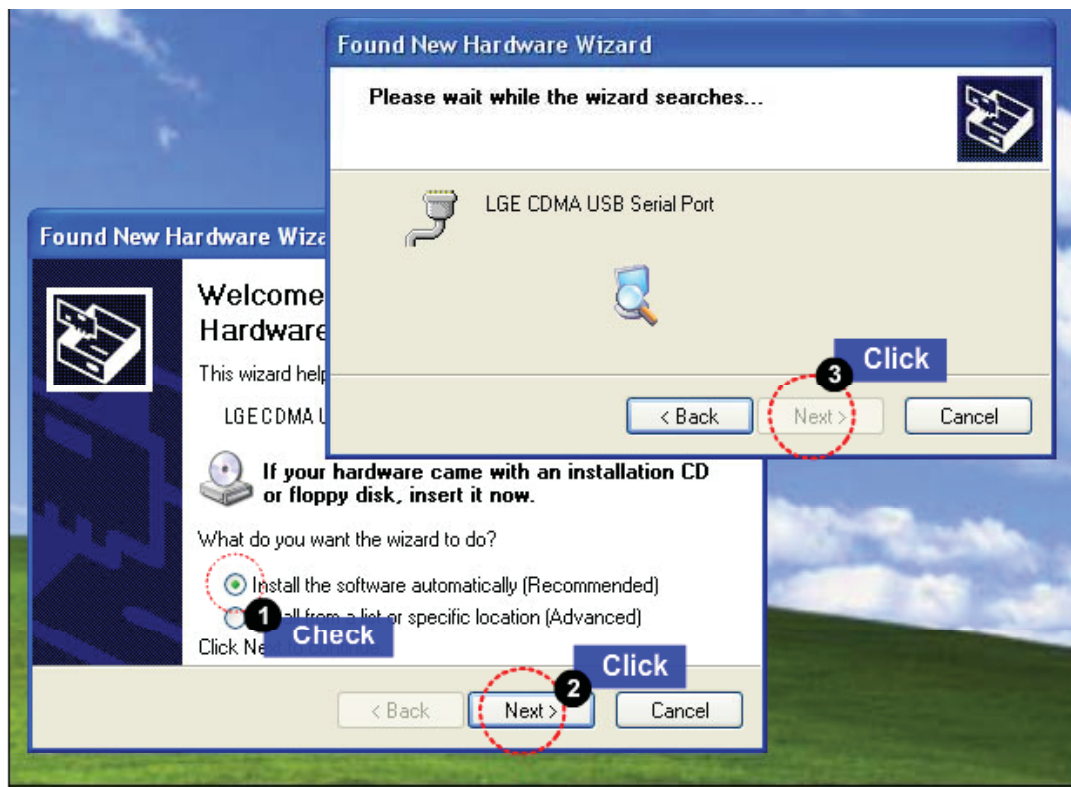
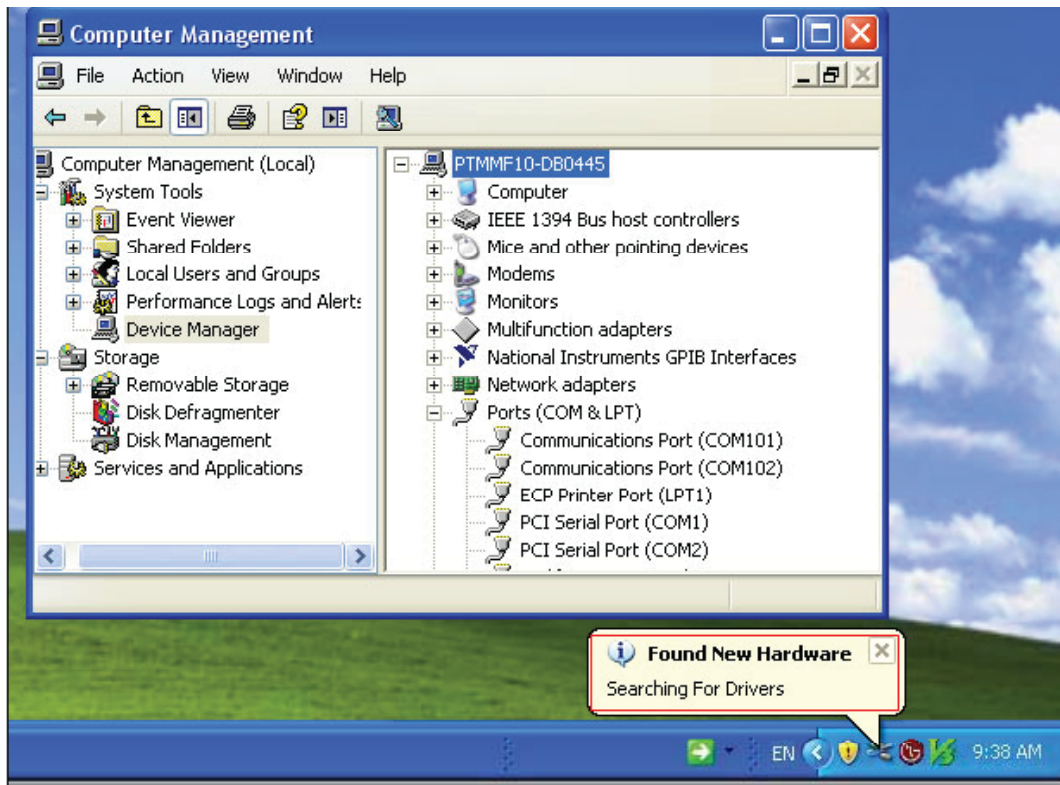


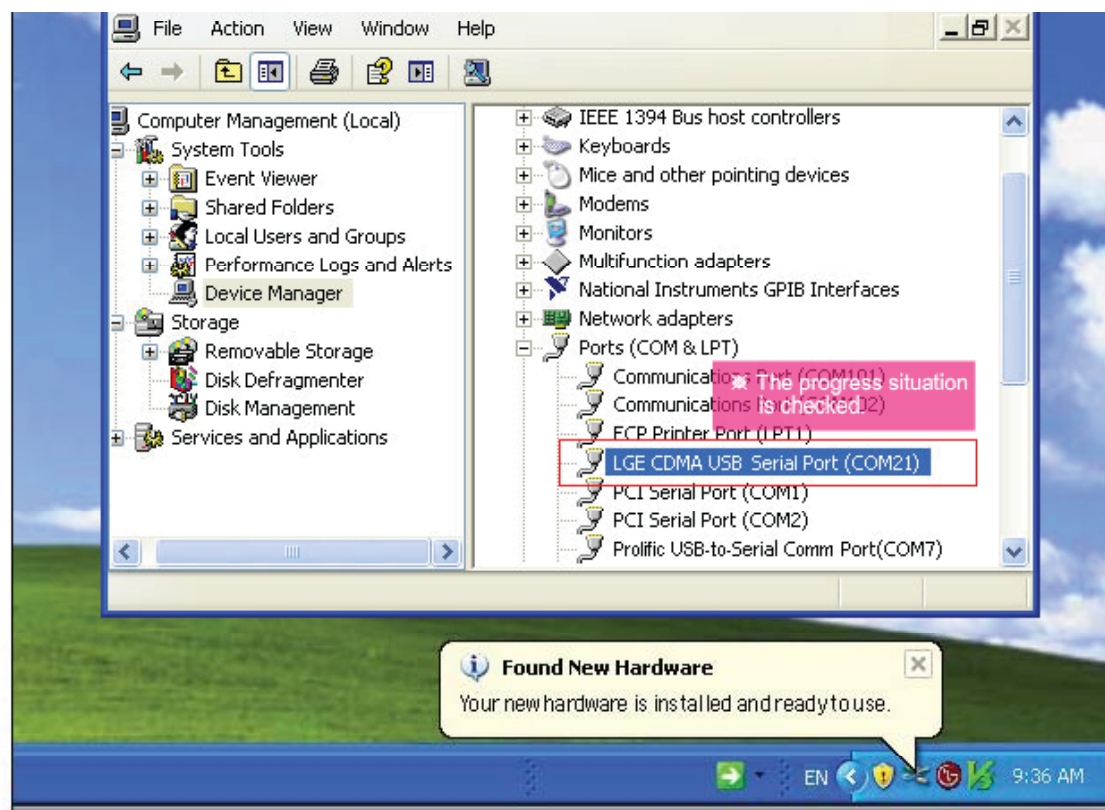
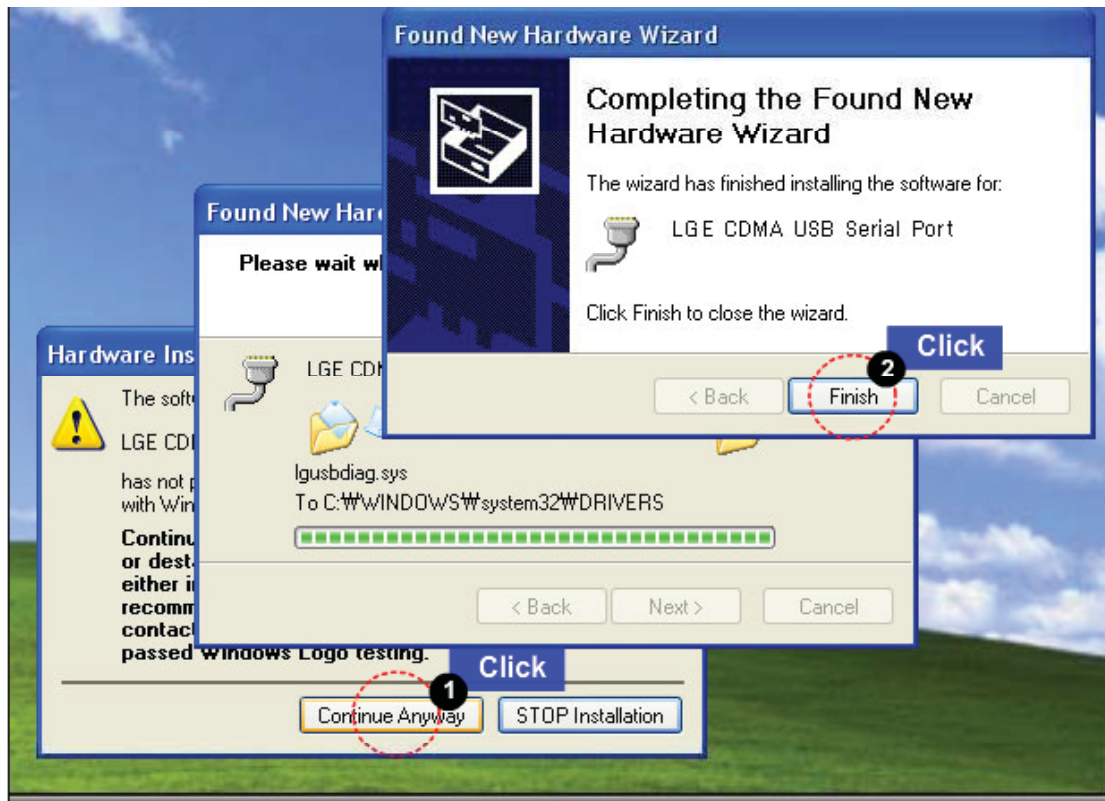
## 10. CALIBRATION





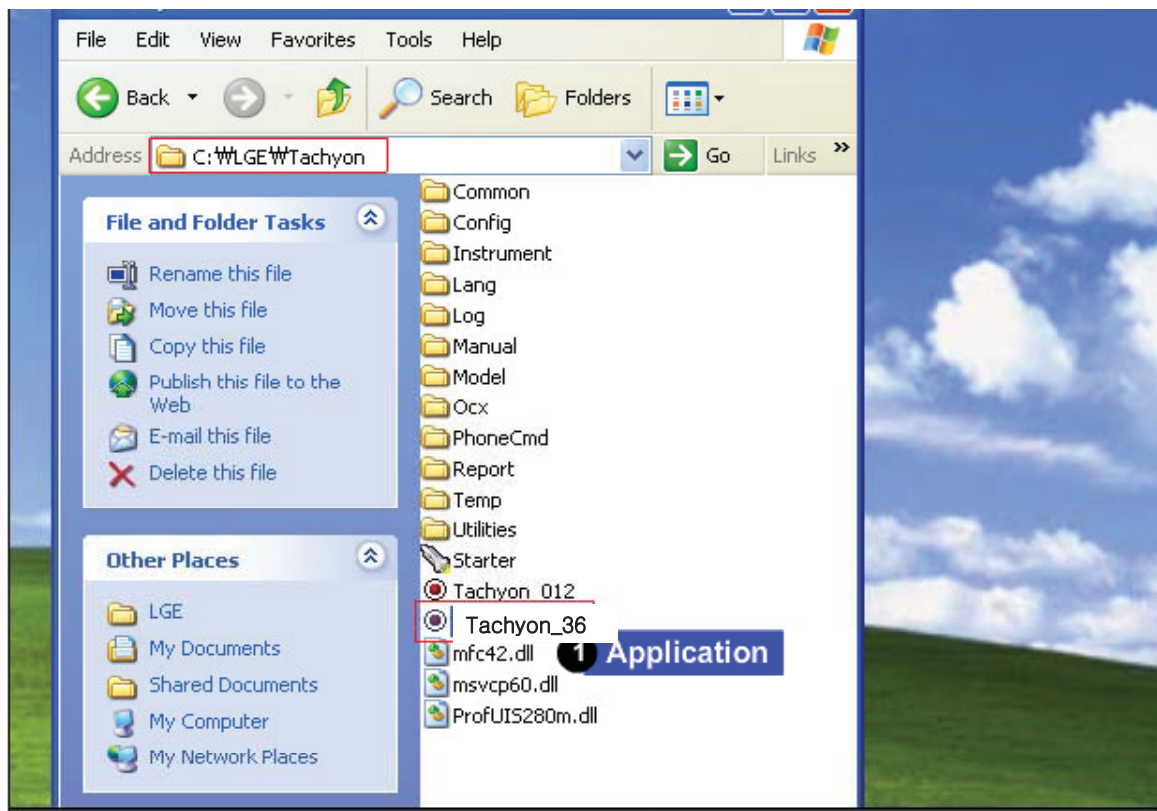
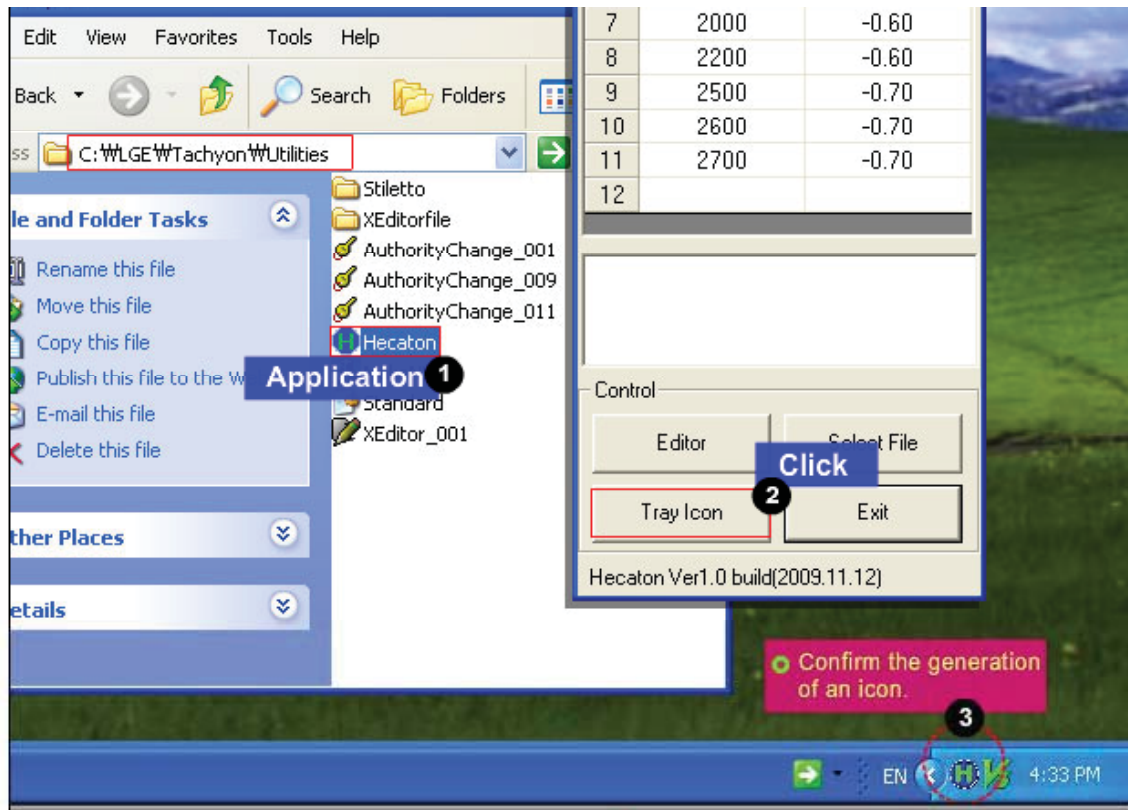




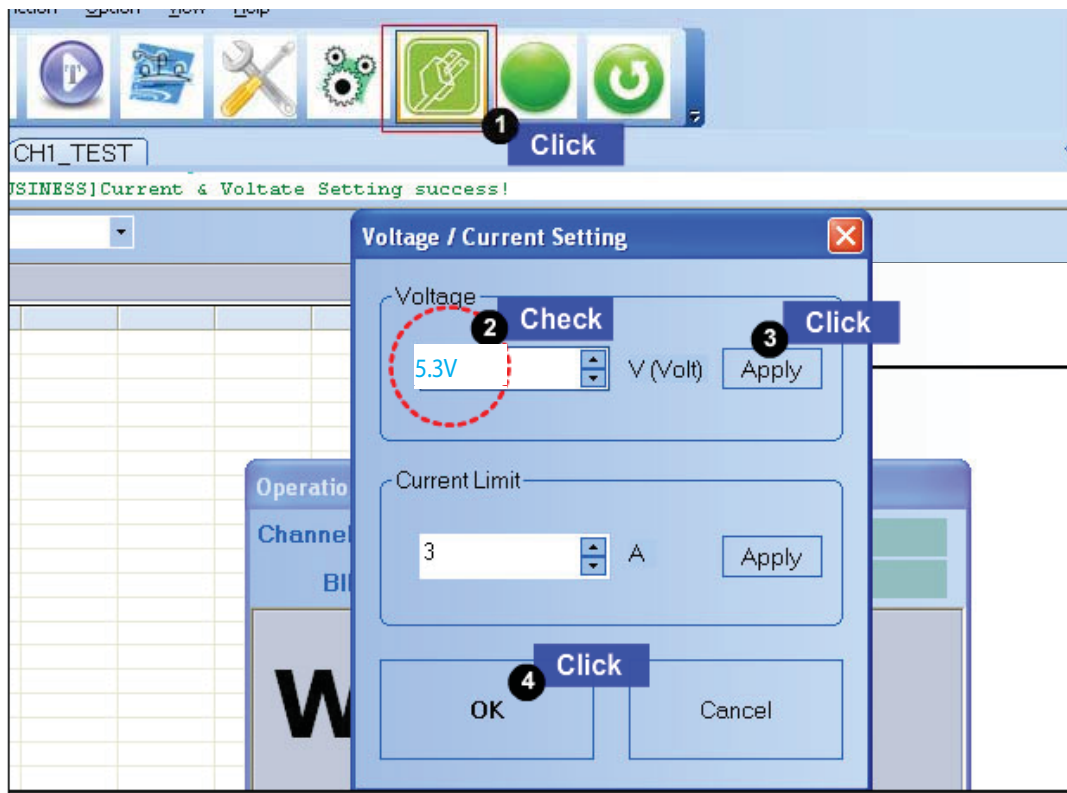
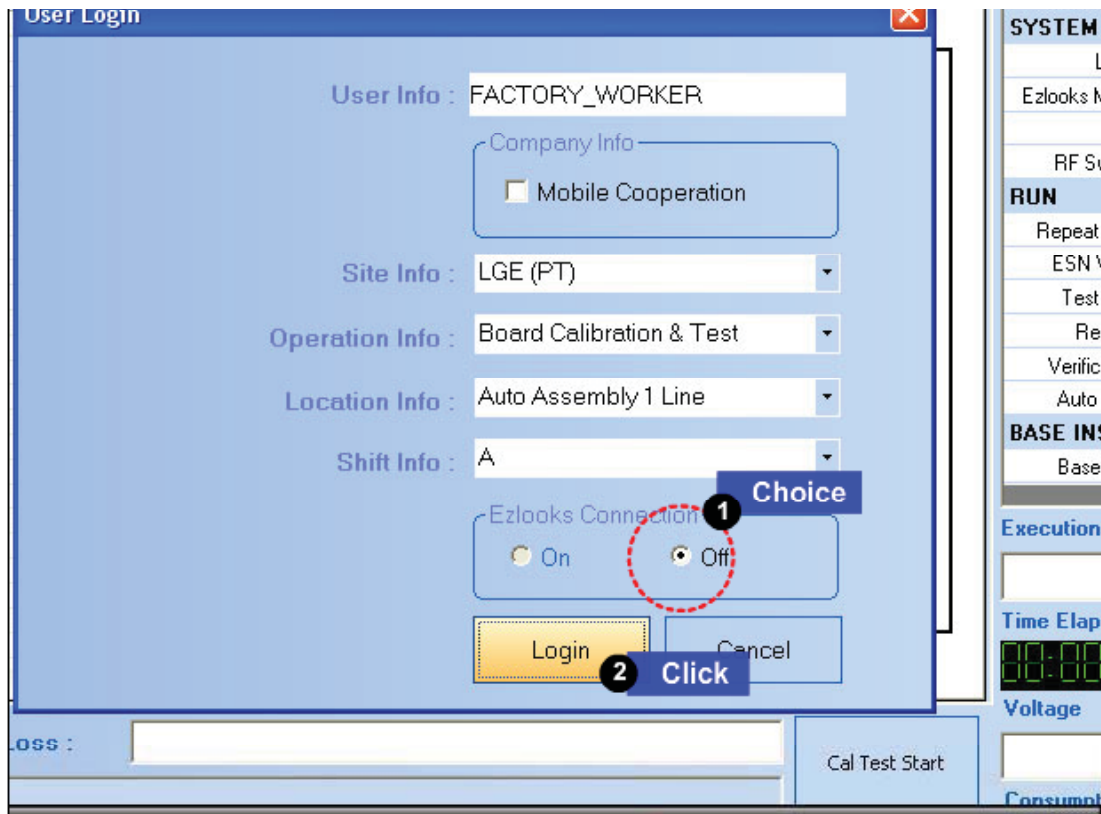




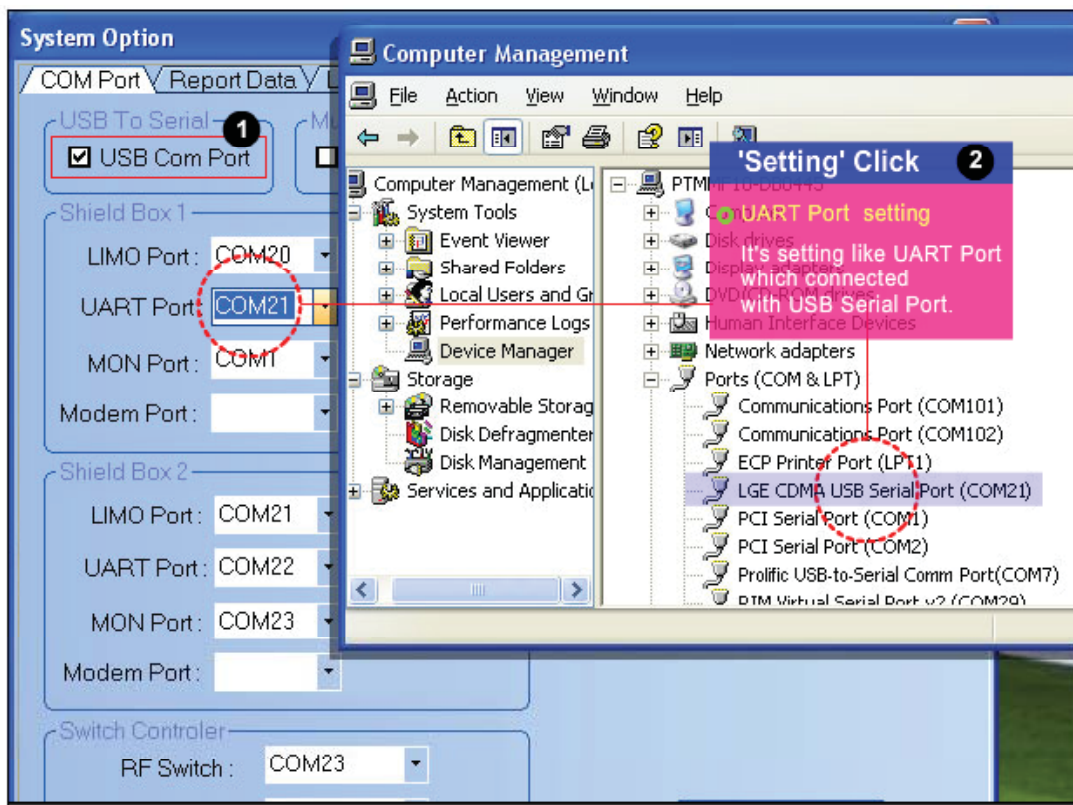
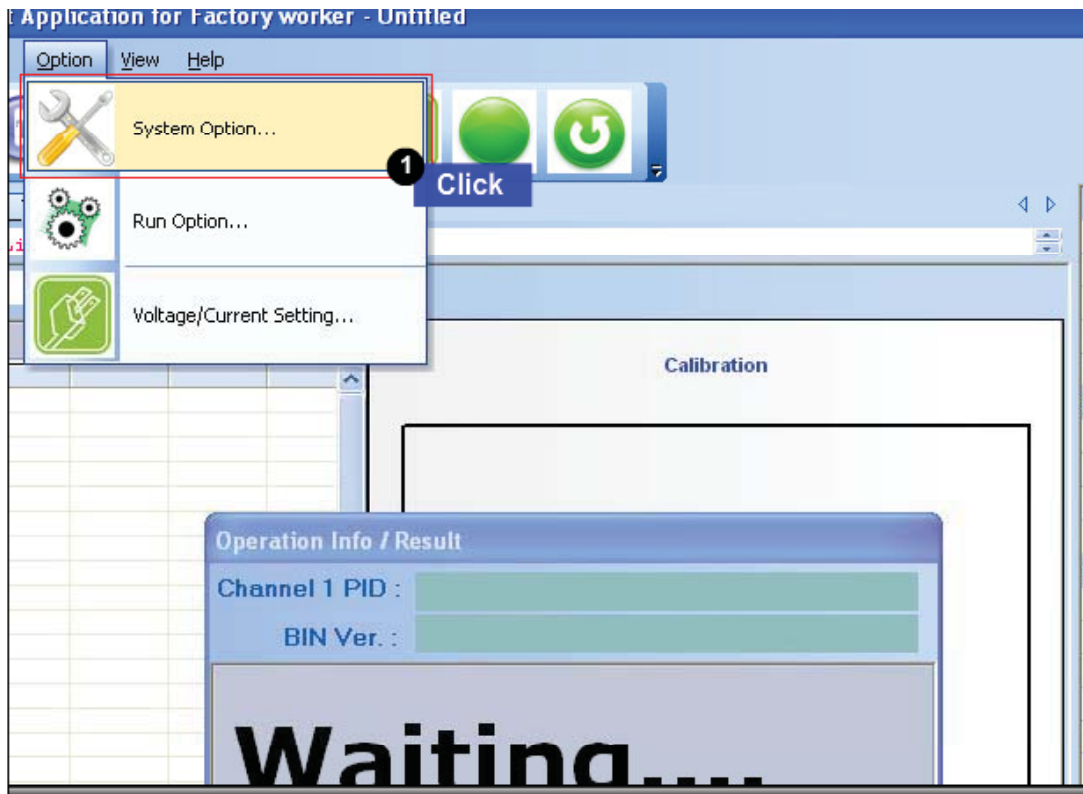
## 10. CALIBRATION



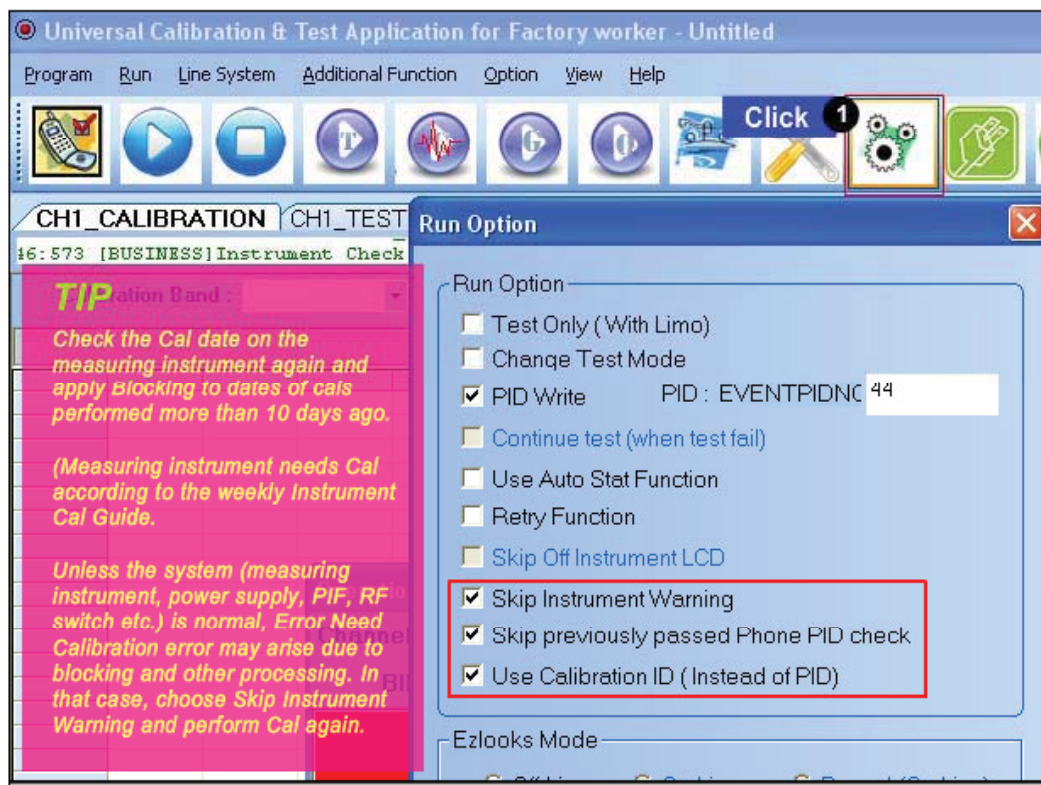
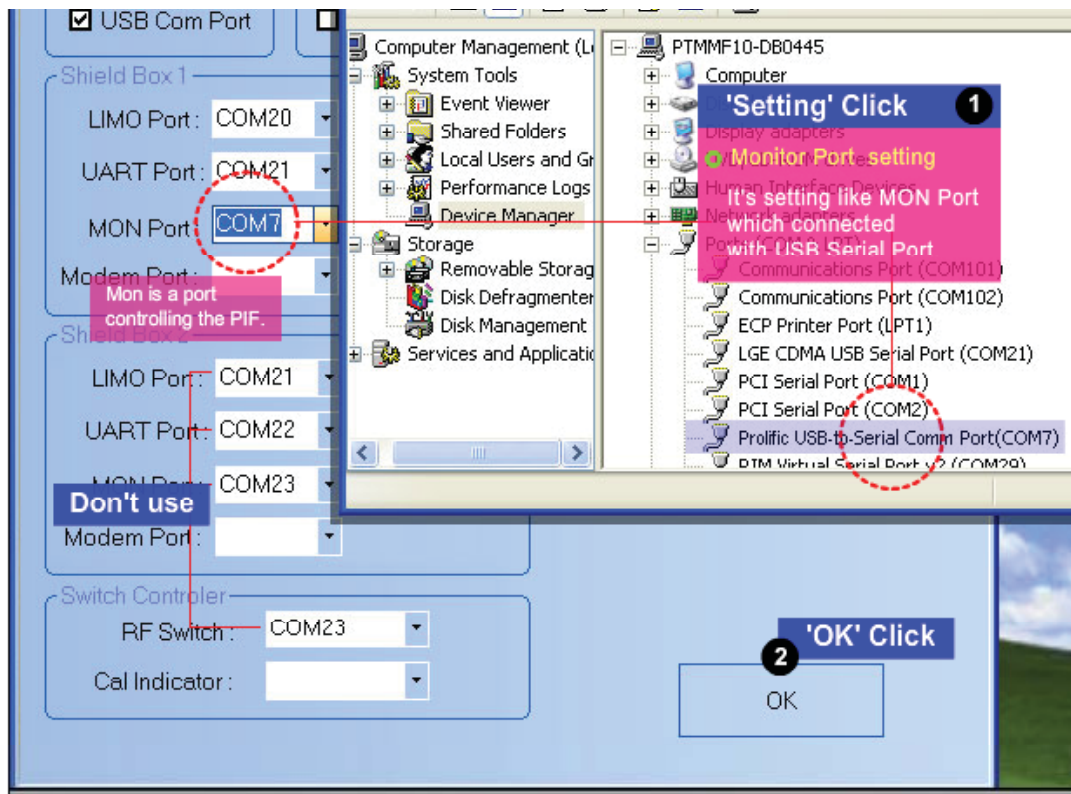
## 10. CALIBRATION

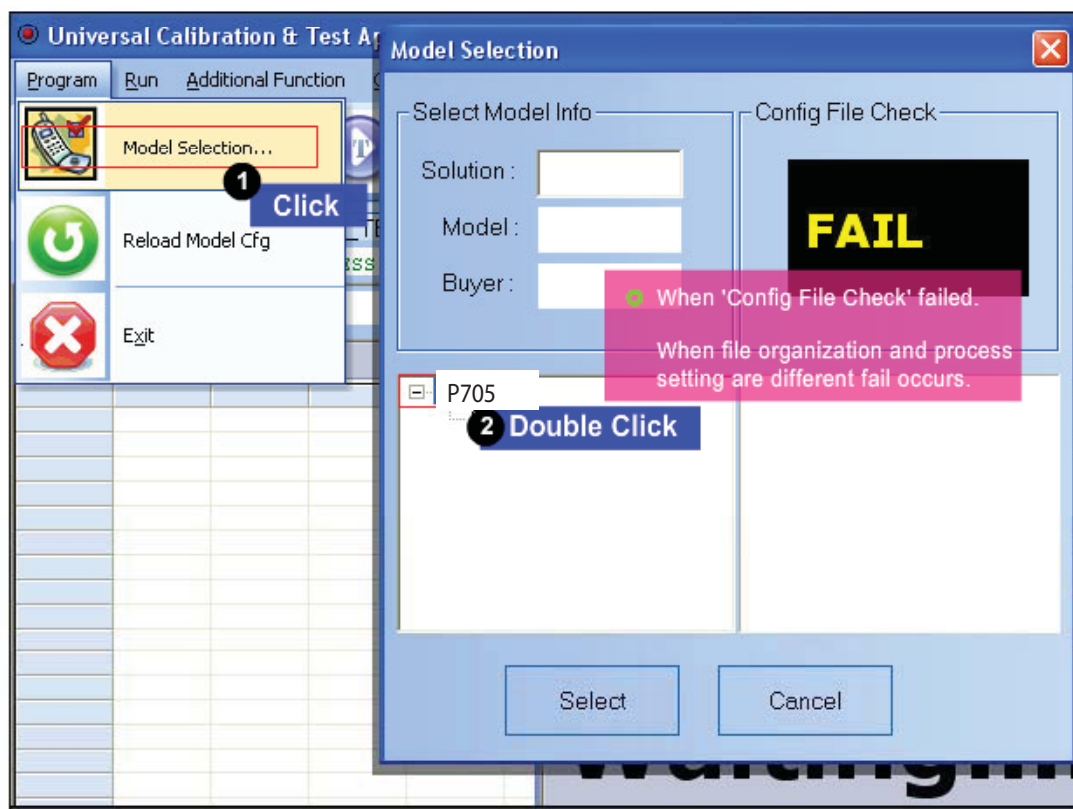
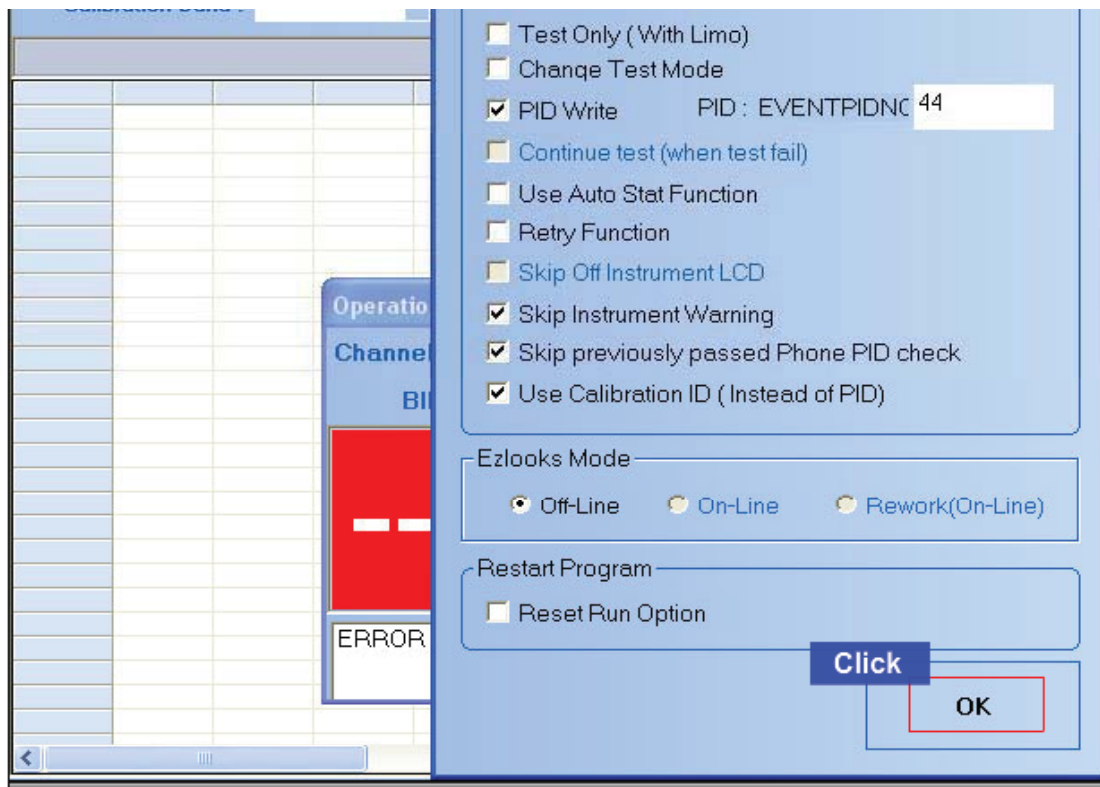


## 10. CALIBRATION

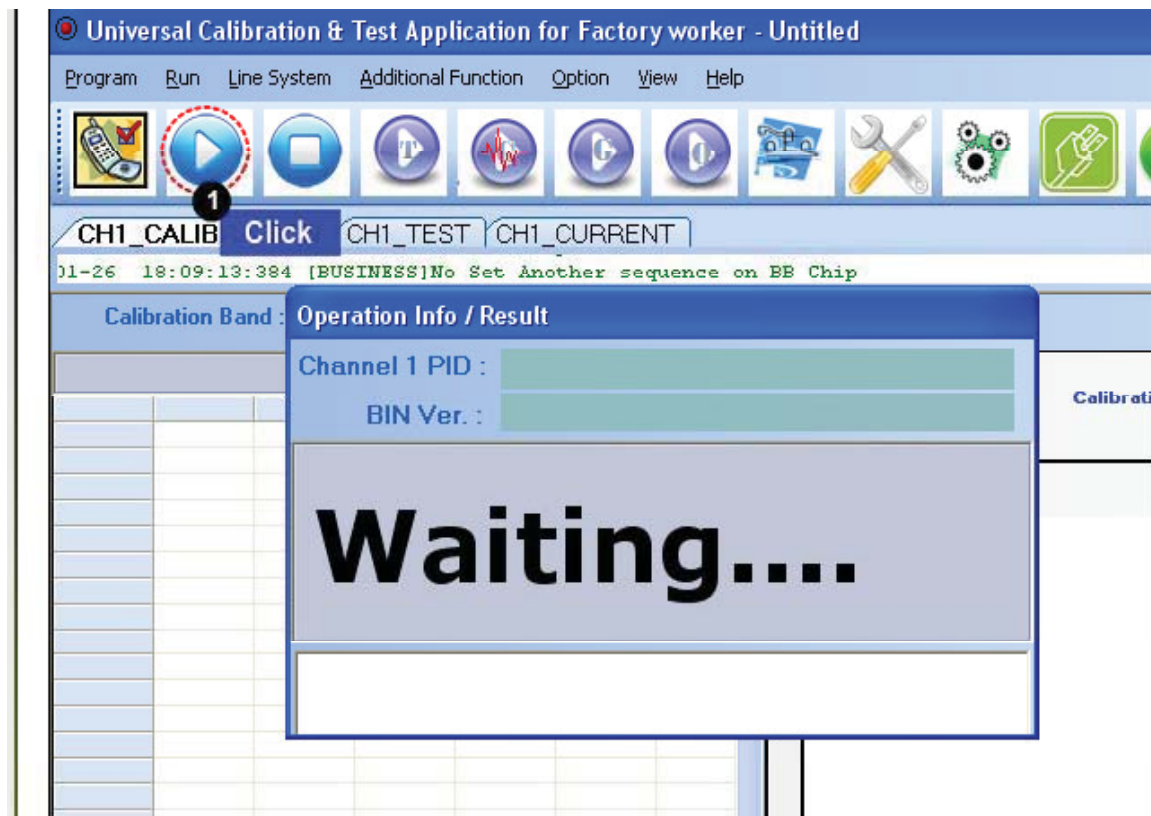
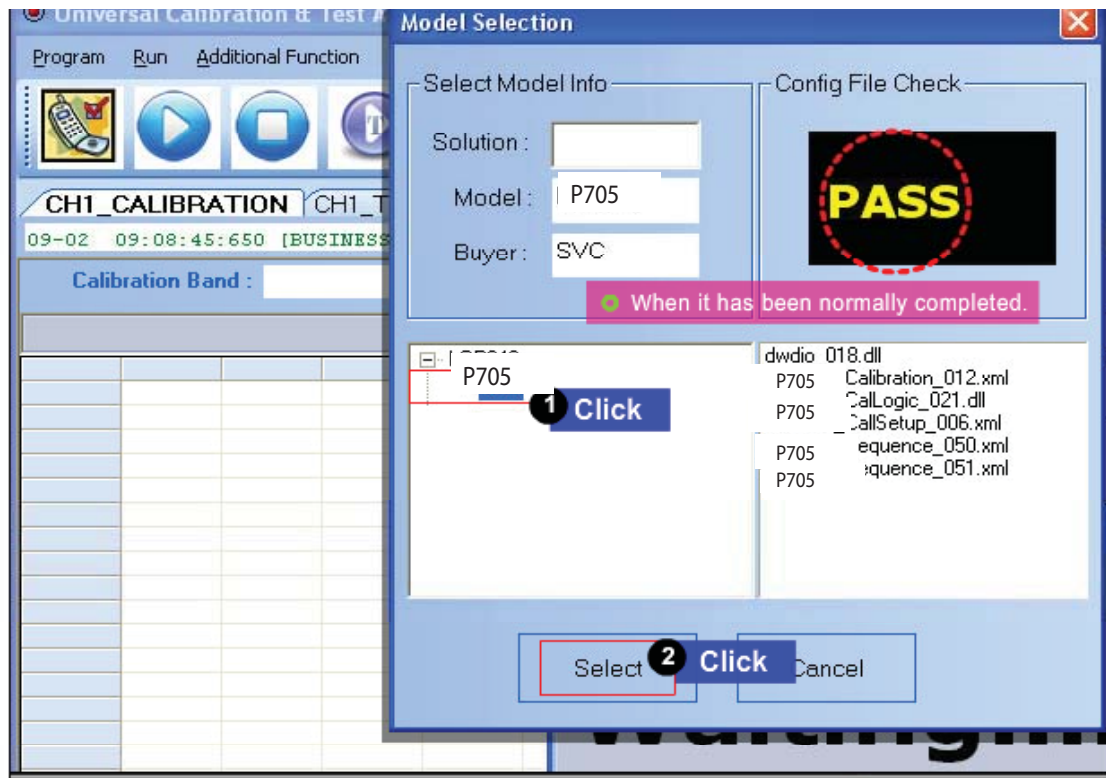


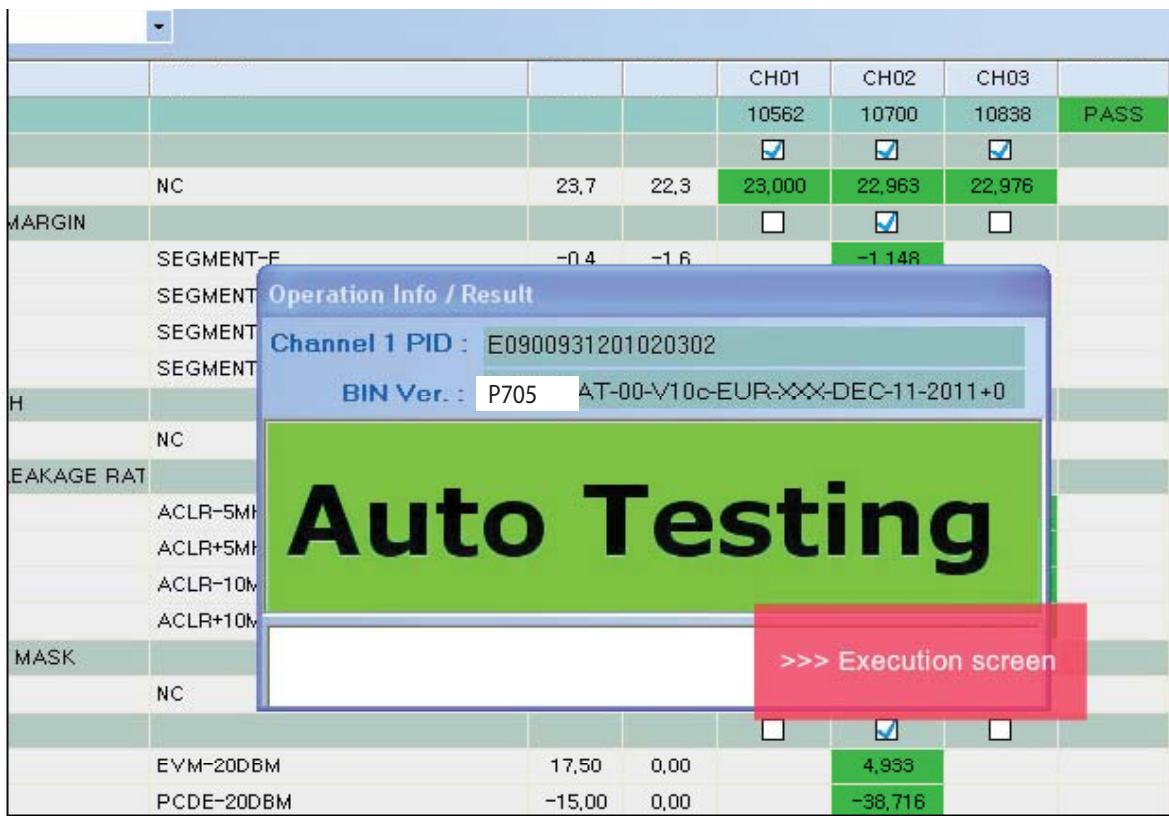
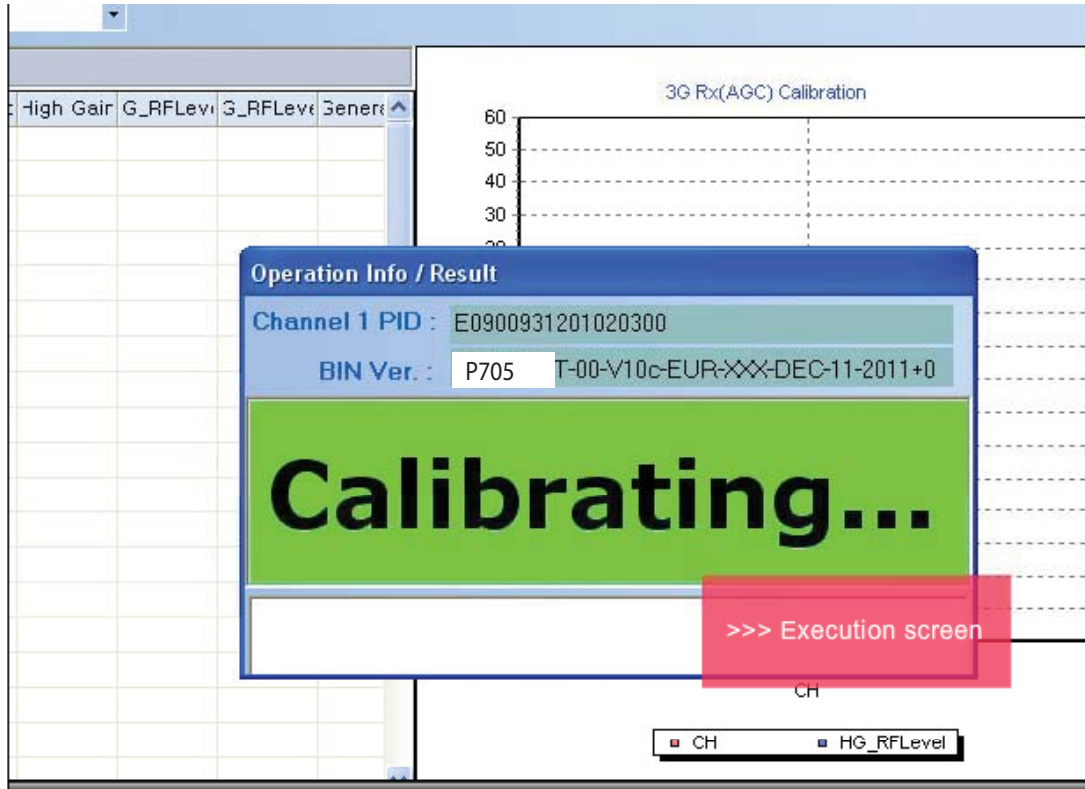






## 10. CALIBRATION




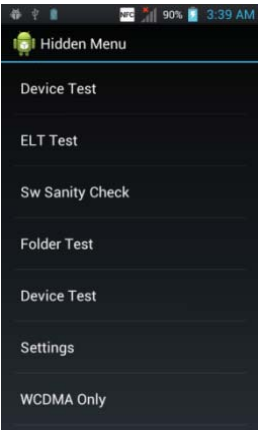





				10562	10700	10838	PASS
				<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	
	NC	23,7	22,3	23,065	22,983	23,013	
MARGIN				<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	
SEGMENT	<div> <div>Operation Info / Result</div> <div>Channel 1 PID : F09000931201020299</div> <div>BIN Ver. : P705 AT-00-V10c-EUR-XXX-DEC-11-2011+0</div> <div> <div>--- PASS ---</div> <div></div> </div> </div>						
SEGMENT							
SEGMENT							
SEGMENT							
OTH							
NC							
LEAKAGE RAT							
ACLR-5M							
ACLR+5M							
ACLR-10M							
ACLR+10M							
ON MASK							
NC		0,5	-0,5		11,1001		
Y							<input type="checkbox"/>
EVM-20DBM		17,50	0,00		4,720		
PCDE-20DBM		-15,00	0,00		-38,441		
<div>System Loss : MySystem(MS ).gms · RF900 6C.grf</div>							

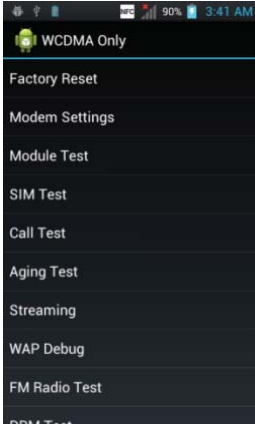
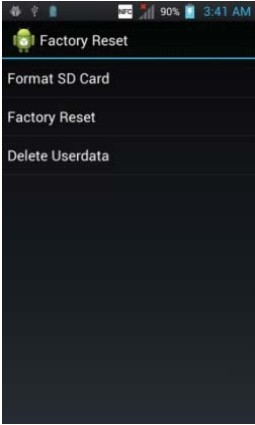
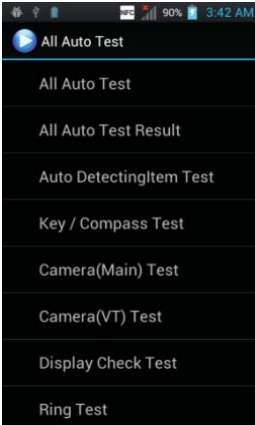
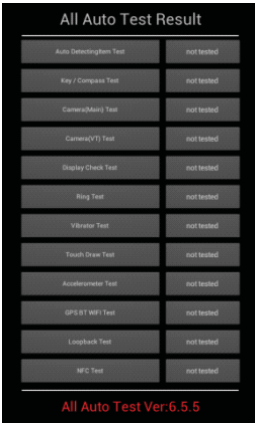
'PASS' The End

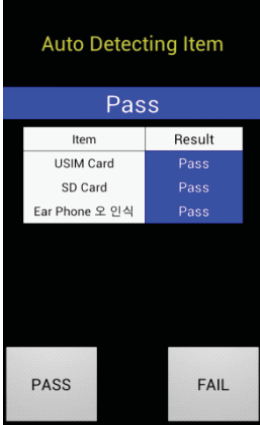
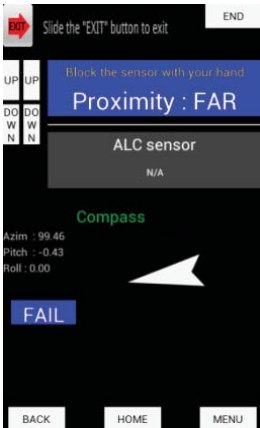

# 11. HIDDEN MENU

	<p><b>Hidden Menu Start</b></p> <p>Start shortcut keys: 3845#*705#</p>
	<p><b>Hidden Menu</b></p> <p>Start the desired menu: Menu, click</p>
	<p><b>Version Info</b></p> <p>Classified Information representation</p> <ul style="list-style-type: none"> <li>-&gt; Hidden Menu</li> <li>-&gt; Settings</li> <li>-&gt; Version Info</li> </ul>

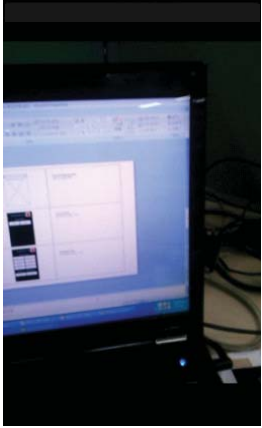

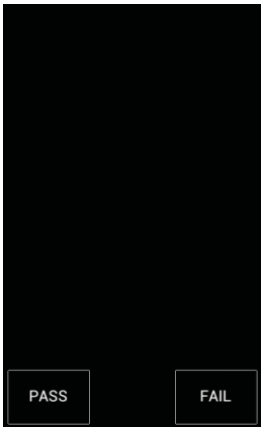


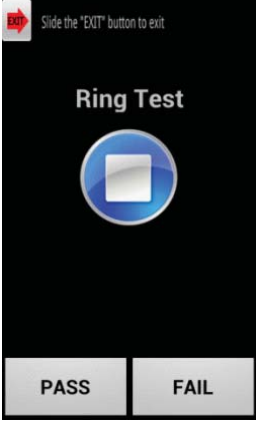
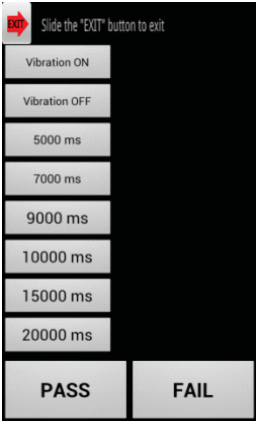
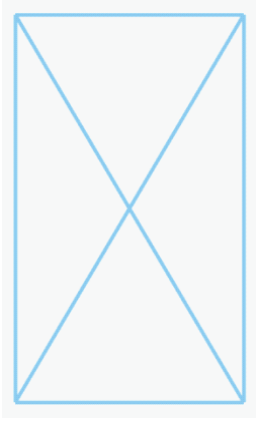
## 11. HIDDEN MENU

		<b>Factory Reset</b> Format SD Card : SD Card Data reset Factory Reset : Reset as default Factory Settings Delete Userdata : Disabled -> Hidden menu -> WCDMA-Only -> Factory Reset
	<b>AAT Device Test</b> Allauto Test : -> You can test all functions automatically	
	<b>Auto All Test Result</b> -> You can check Test Results	

	<p><b>Auto Detecting Item</b></p> <p>Check below Items</p> <p>USIM Card : connecting is PASS</p> <p>-&gt; SD Card : connecting is PASS</p> <p>-&gt; Ear Phone : <b>No</b> connecting is PASS</p> <p>-&gt; Charging Mode : connecting is PASS</p>
	<p><b>Key Press Test</b></p> <p>Check below Items</p> <p>Up/Down key : Hard Key</p> <p>Power key : Hard Key</p> <p>Menu key : Touch Key</p> <p>Home key : Hard Key</p> <p>Back key : Touch Key</p> <p>Compass Sensor : Check North</p> <p>Proximity Sensor : Block the Proximity sensor</p>
	<p><b>Camera Test – Snapshot</b></p> <p>Touch screen to capture</p>

## 11. HIDDEN MENU

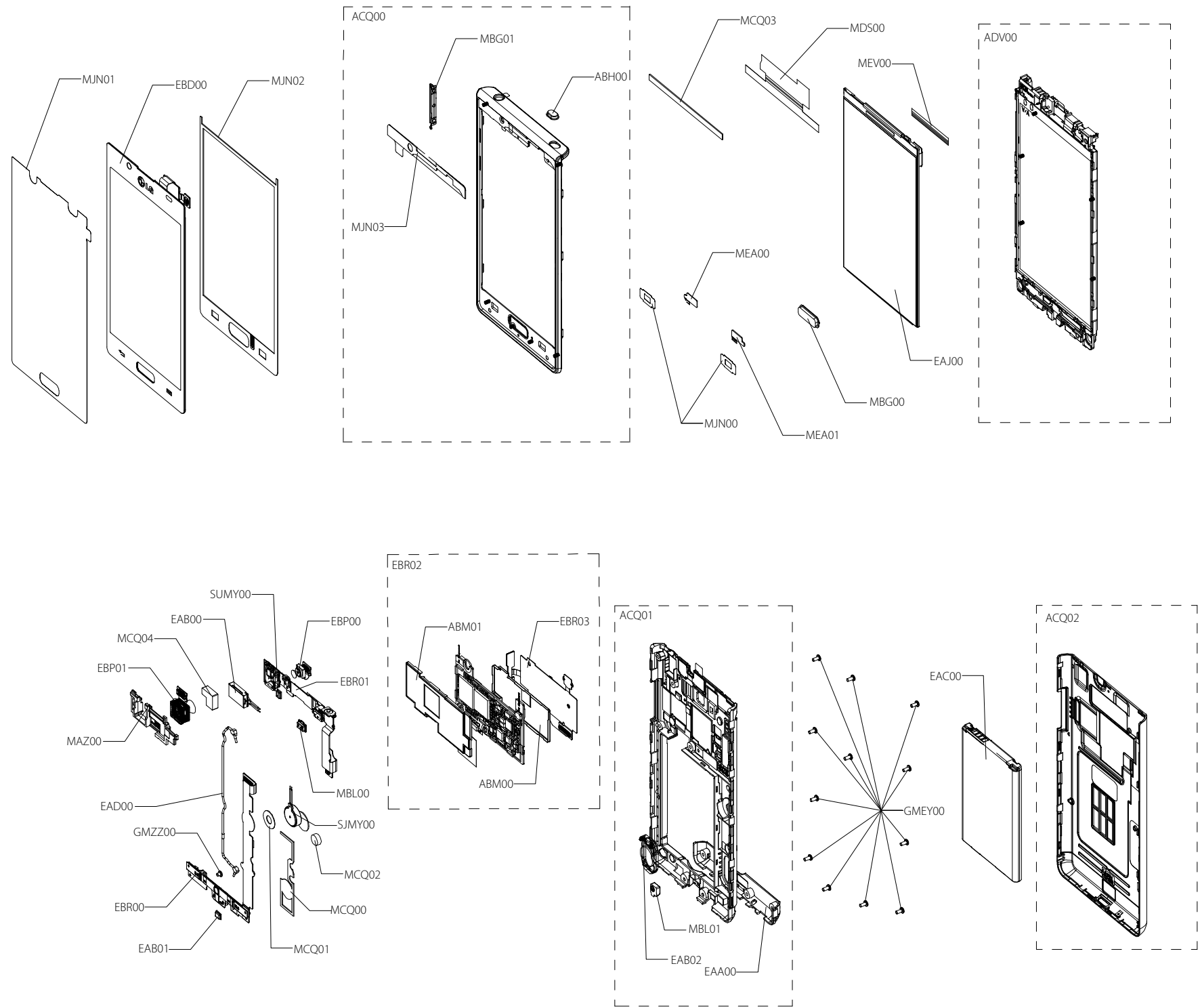
	<p><b>Camera Test - Camcoding</b> Camera is recoding for 5 seconds</p>
	<p><b>VT Camera Test</b> Show the VT Camera image</p>
	<p><b>2D LCD Display Test</b> Check Black &amp; White Color</p>

	<p><b>Sound Test</b> Touch the "Play" icon</p>
	<p><b>Vibrator Test</b> Touch the "Start" icon</p>
	<p><b>Touch Drawing Test</b> Draw a guide line</p>

	<p><b>Motion Sensor Test</b></p> <p>Check 3 positions</p> <ul style="list-style-type: none"> <li>-&gt; Position horizontally</li> <li>-&gt; Position Vertically</li> <li>-&gt; Position side</li> </ul>
	<p><b>GPS BT Wifi Test</b></p> <p>GPS(RF) test : CNO is some value : OK</p> <p>Bluetooth Scanning is PASS : OK</p> <p>WiFi Scanning is PASS : OK</p>
	<p><b>Sound Loopback Test</b></p> <p>"Look Back On" is test mode on</p> <p>"Look Back OFF" is test mode off</p>

12. EXPLODED VIEW & REPLACEMENT PART LIST

12.1 EXPLODED VIEW(SBOM)



Location	Description
EBR02	PCB Assembly,Main
ABM00	Can Assembly,Shield
ABM01	Can Assembly,Shield
EBR03	PCB Assembly,Flexible
EAB02	Speaker,Dual Mode
EAA00	PIFA Antenna,Multiple
ACQ01	Cover Assembly,Rear(SVC)
MBL01	Cap,Receptacle
GMEY00	Screw,Machine
EBR00	PCB Assembly,Flexible
SUMY00	Microphone,Condenser
EBR01	PCB Assembly,Flexible
EAB01	Microphone,Condenser
SJMY00	Motor,DC
MBG00	Button
ACQ00	Cover Assembly,Front
MJN03	Tape,Window
ABH00	Button Assembly (Power)
MBG01	Button,Side (Volume)
ADV00	Frame Assembly
GMZZ00	Screw,Machine
MJN01	Tape
MJN00	Tape
MAZ00	Bracket
MBL00	Cap
MCQ00	Damper,Speaker
MCQ01	Damper,Motor
MCQ02	Damper
MCQ03	Damper,LCD
MCQ04	Damper
MDS00	Gasket
MEA01	Guide
MEA00	Guide
MEV00	Insulator
MJN02	Tape,Window
EBP01	Camera Module
EBP00	Camera Module
EBD00	Touch Window Assembly
EAJ00	LCD,Module-TFT
EAB00	Receiver
EAD00	Cable,Assembly
EAC00	Rechargeable Battery,Lithium Ion
ACQ02	Cover Assembly,Battery



## 12. EXPLODED VIEW & REPLACEMENT PART LIST

### 12.2 ReplacementParts <Mechanic component>

**Note:** This Chapter is used for reference, Part order is ordered by SBOM standard on GCSC

Level	LocationNo.	Description	PartNumber	Spec	Remark
1	AGQ000000	Phone Assembly	AGQ86787201	LGP705.ACISWH WH:WHITE WHITE -	
2	MEZ002100	Label,Approval	MLAA0062319	COMPLEX GU280 OREBK ZZ:Without Color COMPLEX, (empty), , , ,	
2	ACQ100400	Cover Assembly,EMS	ACQ86034301	LGP705.ANGRBK BK:BLACK BLACK -	
6	SC301 SC306 SC309 SC311 SC313 SC315 SC316 SC318 SC319 SC321 SC322	Clip	MCGY0003801	COMPLEX LG-KH3900 KTF ZZ:Without Color -	
6	ANT800 ANT801	Contact	MCIZ0008501	COMPLEX LG-T310 VIVBK ZZ:Without Color PRESS, BeCu, , 3.5, 2.0, 1.5,	
6	SC301 SC306 SC309 SC311 SC313 SC315 SC316 SC318 SC319 SC321 SC322	Clip	MCGY0003801	COMPLEX LG-KH3900 KTF ZZ:Without Color -	
5	MEZ000000	Label	MLAZ0038301	COMPLEX LG-VX6000 ZZ:Without Color PID Label 4 Array PRINTING,	
5	ABM00	Can Assembly,Shield	ABM73816201	LGP700.AFRAWH ZZ:Without Color -	
6	MEV000000	Insulator	MEV64172001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MBK070300	Can,Shield	MBK63254501	PRESS STS 0.15 LGP700.AFRAWH ZZ:Without Color -	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	MCQ000000	Damper	MCQ67069001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	ABM01	Can Assembly,Shield	ABM73816101	LGP700.AFRAWH ZZ:Without Color -	
6	MJN000000	Tape	MJN68138801	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MCQ000002	Damper	MCQ67068901	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MCQ000001	Damper	MCQ67068801	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MCQ000000	Damper	MCQ67068701	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MHK000000	Sheet	MHK63801001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MEV000000	Insulator	MEV64171901	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MEV000001	Insulator	MEV64169101	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
6	MBK070300	Can,Shield	MBK63234101	PRESS STS 0.15 LGP700.AFRAWH ZZ:Without Color -	
6	MCQ000003	Damper	MCQ67006801	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
3	ACQ063300	Cover Assembly,Rear	ACQ86108601	LGP705.ACISWH BK:BLACK BLACK -	
4	ACQ01	Cover Assembly Rear(SVC)	ACQ86075501	LGP705.ACISWH BK:BLACK BLACK -	
5	MHK000002	Sheet	MHK63845101	COMPLEX LGP705.ANGRBK ZZ:Without Color -	
5	MJN020800	Tape,Decor	MJN68076901	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MJN089301	Tape,Window	MJN68077001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MJN000000	Tape	MJN68099401	COMPLEX LGP700.AFRAWH ZZ:Without Color -	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
5	MJN089300	Tape,Window	MJN68114401	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MKC009400	Window,Camera	MKC64340201	CUTTING ACRYL LGP700.AFRAWH ZZ:Without Color -	
5	MEZ000900	Label,After Service	MLAB0001102	COMPLEX C2000 CGRSV WA:White C2000 USASV DIA 4.0 PRINTING,	
5	MHK000001	Sheet	MHK63751401	COMPLEX LGP700.AFRAWH BK:Black -	
5	MHK000000	Sheet	MHK63792701	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MBL01	Cap,Receptacle	MBL65201301	MOLD PC LGP700.AFRAWH BK:Black -	
5	MCK063300	Cover,Rear	MCK67152401	MOLD PC LGP700.AFRAWH BK:Black -	
5	MCQ049800	Damper,Motor	MCQ66914901	COMPLEX LGP700.AFRAWH BK:Black -	
5	MCQ015700	Damper Connector	MCQ66915001	COMPLEX LGP700.AFRAWH BK:Black -	
5	MCQ000001	Damper	MCQ66919101	COMPLEX LGP700.AFRAWH BK:Black -	
5	MCQ074200	Damper,Speaker	MCQ66951401	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MCQ015701	Damper Connector	MCQ66959801	COMPLEX LGP700.AFRAWH BK:Black -	
5	MCQ000002	Damper	MCQ66959901	COMPLEX LGP700.AFRAWH BK:Black -	
5	MCQ009400	Damper,Camera	MCQ66970101	COMPLEX LGP700.AFRAWH BK:Black -	
5	MCQ000000	Damper	MCQ66995001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MCR000000	Decor	MCR64753401	PRESS STS ZZ LGP700.AFRAWH ZZ:Without Color -	
5	MCR000001	Decor	MCR64753501	COMPLEX LGP700.AFRAWH WH:WHITE WHITE -	
5	MDS000000	Gasket	MDS63981701	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MFB029600	Lens,Flash	MFB62793301	MOLD PC LGP700.AFRAWH ZZ:Without Color -	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
3	GMEY00	Screw,Machine	GMEY0011201	GMEY0011201 BH + 1.4mM 3mM MSWR FZB N N LG ELECTRONICS INC.	
3	ACQ003400	Cover Assembly,Bar	ACQ85950405	LGP700.AFAWH WH:WHITE WHITE -	
7	ANT802 ANT803	Contact	MCE62253601	COMPLEX LGLS685.ASPRZY ZZ:Without Color -	
4	MBG00	Button	MBG64528101	COMPLEX LGP700.AFAWH WH:WHITE WHITE -	
4	ACQ00	Cover Assembly,Front	ACQ85922101	LGP700.AFAWH WH:WHITE WHITE -	
5	MJN000000	Tape	MJN68098601	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	MEV000001	Insulator	MEV64161501	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	MJN020800	Tape,Decor	MJN68076701	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	MJN03	Tape,Window	MJN68076601	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	MEV000000	Insulator	MEV64080001	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	MDJ000000	Filter	MDJ63425801	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	MCR000000	Decor	MCR64792701	PRESS STS 0.2T LGP700.AFAWH WH:WHITE WHITE -	
5	MCR000001	Decor	MCR64792601	COMPLEX LGP700.AFAWH BK:Black -	
5	MCQ000000	Damper	MCQ66995501	COMPLEX LGP700.AFAWH BK:Black -	
5	MEV000002	Insulator	MEV64169401	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	MCQ000001	Damper	MCQ67104501	COMPLEX LGP700.AFAWH ZZ:Without Color -	
5	ABH00	Button Assembly (Power)	ABH74619701	LGP700.AFAWH ZZ:Without Color -	
6	MCQ000000	Damper	MCQ67105301	COMPLEX LGP700.AFAWH ZZ:Without Color -	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	MBG071300	Button,Side	MBG64528301	PRESS STS zz LGP700.AFRAWH ZZ:Without Color -	
5	MBG01	Button,Side (Volume)	MBG64584901	MOLD PC LGP700.AFRAWH WH:WHITE WHITE -	
5	MCK032700	Cover,Front	MCK67131801	MOLD PC LGP700.AFRAWH WH:WHITE WHITE -	
6	MET099500	INSERT,NUT	MICE0016903	MECH_COMMON ZY,ZZ,PRESS, STS, , , , ,	
6	MET099501	INSERT,NUT	MICE0016905	MECH_COMMON ZY,ZZ,PRESS, STS, , , , ,	
5	MCQ074200	Damper,Speaker	MCQ66970001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	ADV00	Frame Assembly	ADV74288301	LGP700.AFRAWH ZZ:Without Color -	
5	MCQ000001	Damper	MCQ66918401	COMPLEX LGP700.AFRAWH BK:Black -	
5	MCQ000000	Damper	MCQ66995601	COMPLEX LGP700.AFRAWH BK:Black -	
5	MDQ000000	Frame	MDQ63198001	CASTING PMP TPX MX-221M LGP700.AFRAWH ZZ:Without Color -	
6	MET099500	INSERT,NUT	MICE0016903	MECH_COMMON ZY,ZZ,PRESS, STS, , , , ,	
6	MDQ000000	Frame	MDQ63238601	MOLD PA LGP700.AFRAWH ZZ:Without Color -	
5	MJN000000	Tape	MJN68077101	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MJN000003	Tape	MJN68169601	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MJN000001	Tape	MJN68133901	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MDS000000	Gasket	MDS63979701	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MDS000001	Gasket	MDS64030201	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
5	MJN000002	Tape	MJN68098301	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	GMZZ00	Screw,Machine	GMZZ0019003	GMZZ0019003 FH + 1.4mM 1.5mM MSWR FZB N - SERVEONE CO., LTD.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
4	MJN01	Tape	MJN68123501	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MJN00	Tape	MJN68227201	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MEZ000000	Label	MLAZ0038303	COMPLEX LG-LC3200 WA:White PRINTING, PPRI PRINTING	
4	MAZ00	Bracket	MAZ63410101	MOLD PA LGP700.AFRAWH ZZ:Without Color -	
4	MBL00	Cap	MBL65280101	MOLD PC LGP700.AFRAWH BK:Black -	
4	MCQ00	Damper,Speaker	MCQ66917201	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MCQ01	Damper,Motor	MCQ66951301	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MCQ02	Damper	MCQ67068501	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MCQ03	Damper,LCD	MCQ67068601	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MCQ04	Damper	MCQ67069101	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MDS00	Gasket	MDS64000801	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MEA01	Guide	MEA62991001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MEA00	Guide	MEA63050001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MEV000000	Insulator	MEV64174801	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MEV00	Insulator	MEV64176901	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MJN061100	Tape,Protect	MJN68106501	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
4	MJN02	Tape,Window	MJN68114301	COMPLEX LGP700.AFRAWH ZZ:Without Color -	



## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
1	AAD000000	Addition Assembly	AAD86056501	LGP705.ACISWH WH:WHITE WHITE -	
2	MEZ002101	Label,Approval	MEZ64570001	CUTTING LAMI LGP940.ACISBK WA:White -	
2	MEZ002100	Label,Approval	MEZ64188201	COMPLEX LGA190.ACISBK ZZ:Without Color -	
2	AFN053800	Manual Assembly Operation	AFN75754701	LGP705.ACISBK ZZ:Without Color Manual assy for LGP705 CIS	
2	ACQ02	Cover Assembly,Battery	ACQ86009201	LGP700.AFRAWH WH:WHITE WHITE -	
3	MCK004100	Cover,Battery	MCK67152501	MOLD PC LGP700.AFRAWH WH:WHITE WHITE -	
3	MEZ000000	Sheet	MHK63800001	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
3	MEV000000	Insulator	MEV64212401	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
3	MCR000000	Decor	MCR64808601	COMPLEX LGP700.AFRAWH ZZ:Without Color -	
1	AGF000000	Package Assembly	AGF76485603	LGP705.ACISWH ZZ:Without Color LGP705 CIS( S6T/CIS UB/CIS LB_CH) 480ea/Pallet	
2	MEZ000000	Label	MLAZ0050901	COMPLEX KU990.AGBRBK ZZ:Without Color Battery Warning Label (Lithium ion Battery Label)	
2	MAY084000	Box,Unit	MAY65535504	PRINTING LGP705.ACISWH ZZ:Without Color LGP705 CIS Unit Box(S6T)	
2	AGJ000000	Pallet Assembly	AGJ73458304	LGE510.ACISBK ZZ:Without Color S6T Type_CIS Body+Cap+AL(1200x800x800)_480EA	
3	MCQ000000	Damper	MCQ66486911	COMPLEX LGE730.ACISBK ZZ:Without Color S6T-CIS Dead Space Sleeve(480EA/1200*800)	
3	MBL007000	Cap,Box	MCCL0002604	COMPLEX LGE730.ANLDKT ZZ:Without Color S6T-STD Cap(800EA/1200*800)	
3	MAY010800	Box,Carton	MBEC0004405	COMPLEX LGE730.ACISBK ZZ:Without Color S6T-CIS Body(480EA/h:800 under/1200*800)	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
3	MGA000000	Pallet	MPCY0012403	COMPLEX KG800 FRABK DB:DARK BLUE -	
2	MEZ084100	Label,Unit Box	MLAQ0018301	PRINTING GS200 CISBK ZZ:Without Color Unit Box Label(CIS USE-LGE-Peel-90*40) CIS only_China_Peel_unit box label_90x40	
2	MEZ047200	Label,Master Box	MLAJ0004402	PRINTING CG300 CGR DG ZZ:Without Color LABEL MASTER BOX(for CGR TDR 2VER. mbox_label) GSM standard_master box label	
2	MAY047100	Box,Master	MBEE0061004	COMPLEX LGE730.ANLDKT ZZ:Without Color S6T_STD Master Box(10EA)	
2	MAF086500	Bag,Vinyl	MBAD0005204	COMPLEX LG-LX260 SPRAG ZZ:Without Color -	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

### 12.2 Replacement Parts <Main component>

**Note:** This Chapter is used for reference, Part order is ordered by SBOM standard on GCSC

Level	LocationNo.	Description	PartNumber	Spec	Remark
3	EBR02	PCB Assembly, Main	EBR75418001	LGP705.ACISWH 1.0 Main	
4	EBR071800	PCB Assembly Main, SMT	EBR75440701	LGP705.ANGRBK 1.0 Main	
5	SAD010000	Software, Mobile	SAD33443301	Base V09i - EUROPE QCT -	
5	EBR071700	PCB Assembly Main, SMT Top	EBR75440901	LGP705.ANGRBK 1.0 Main	
6	R212	Resistor, Chip	ERHZ0000406	MCR01MZIP5J104 100KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R400 R401 R402 R403 R404 R405 R406 R407 R410	Resistor, Chip	ERHZ0000486	MCR01MZIP5J473 47KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R514	Resistor, Chip	ERHZ0000493	MCR01MZIP5J513 51KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R505	Resistor, Chip	ERHZ0000537	MCR01MZIP5F6803 680KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	R525	Resistor, Chip	ERHZ0003001	MCR01MZIP5F3002 30KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	IC700	IC, Audio Sub System	EUSY0420001	TPA2055D3 1.6~5.5V 0W WLCSP R/TP 20P - TEXAS INSTRUMENTS INCO.	
6	FB702 FB703	Filter, Bead	SFBH0008101	BLM15AG601SN1D 600 ohm 1.0X0.5X0.5 25% 0.6 ohm 0.3A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	X500	Crystal	EAW61843401	Q13FC1350000200 32.768KHZ 20PPM 0.000000000007F NONE SMD R/TP EPSON TOYOCOM CORP	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C511	Capacitor,TA,Confo rmal	ECTH0002703	TCTAL1A107M8R-V2 100uF 20% 10V 50UA - 55TO+125C 2.5OHM 3.2X1.6X1.1MM NONE SMD R/TP 1.2T max. ROHM CO.,LTD.	
6	R710 R711 R712 R713	Resistor,Chip	ERHY0009526	MCR006YZPJ472 4.7KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	R213 R532	PCB ASSY,MAIN PAD OPEN	SAFO0000401	AX3100 ATL SV_SHIPBACK,MAIN,A,0OHM DNI	
6	R218 R219 R300 R301 R302 R303	PCB ASSY,MAIN,PAD SHORT	SAFP0000401	LG-LU3000 LGTBK,MAIN,A,	
6	C507 C534 C741	Capacitor Ceramic,Chip	EAE62502901	CL05A106MP5NUNC 10uF 20% 10V X5R - 55TO+85C 1005 R/TP 0.55T max. SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C550	Capacitor Ceramic,Chip	EAE62505701	CL10A105KB8NNNC 1uF 10% 50V X5R - 55TO+85C 1608 R/TP 0.9T max. SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C505 C506 C509	Capacitor Ceramic,Chip	EAE62506501	CL05A475MP5NRNC 4.7uF 20% 10V X5R - 55TO+85C 1005 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	C575 C576	Capacitor Ceramic,Chip	EAE62685301	CL05A105KA5NQNC 1uF 10% 25V X5R - 55TO+85C 1005 R/TP 0.6T max. SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	D200 D700	Diode,Switching	EAH61532901	BA891_ 1V 35V - - 0SEC 715mW SOD523 R/TP 2P 1 NXP Semiconductors	
6	D500	Diode,TVS	EAH61872601	PESD12VS1UA 12V 13.3V min. 19V 22.5A 360mW SOD323 R/TP 2P 1 NXP Semiconductors	
6	U501	IC,PMIC	EAN62090501	PM8029 3 to 4.4V adj 1.3W NSP R/TP 140P - QUALCOMM INCORPORATED.	
6	U400	IC,MCP,eMMC	EAN62171901	H9DP32A4JJCGR-KEM NAND/4G SDRAM/4G(2G*2/ 32bit) 1.7VTO1.95V,2.7VTO3.6V,1.7VTO1.95V 11.5x13.0x0.9 TR 153P NAND+DDR SDRAM FBGA 4GB eMMC v4.41+4Gb LPDDR1 200MHz x32 2CS (27nm 32Gb MLC NAND+44nm 2Gb LPDDR1) HYNIX SEMICONDUCTOR	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	U502	IC,DC,DC Converter	EAN62186901	LM3530TMX-40 NOPB 2.7 to 5.5V adj 0W CSP R/TP 12P - NATIONAL SEMICONDUCTOR CORPORATION.	
6	U506	IC,Mini ABB	EAN62339701	LP8727- B MUIC with Charger IC CSP R/TP 25P TEXAS INSTRUMENTS KOREA LTD, HONGKONG BRANCH.	
6	U200	IC,Digital Baseband Processor,3G	EAN62408201	MSM7227A-1-AA 576NSP,ARMv7(1GHz),HSPA7.2Mbps,FWVGA30fps,8M,MIPI CSI_DSI NSP R/TP 576P QUALCOMM INCORPORATED.	
6	L504	Inductor,Wire Wound,Chip	EAP61747901	VLS3010ET-100M 10UH 20% - 560mA 0.56 0.8 0.468OHM - - SHIELD 3.0X3.0X1.0 MM NONE R/TP TDK KOREA COOPERATION	
6	X200	Oscillator VCTCXO	EAW61563401	KT2520F19200DCW28RAK 19.2MHZ 2PPM 2.8V 2.5x2.0x0.8MM ; SMD R/TP KYOCERA CORP.	
6	EAX010000	PCB,Main	EAX64550001	LGP700.AFRABK 1.0 FR-4 Stack via 10 1.0 Main	
6	R515	Resistor,Chip	EBC62035901	RC0201FR-071RL 1OHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	C573	Capacitor Ceramic,Chip	ECCH0000115	MCH155A220JK 22pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C708 C709	Capacitor, Ceramic,Chip	ECCH0000143	MCH155CN102KK 1nF 10% 50V X7R -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C529	Capacitor Ceramic,Chip	ECCH0000149	MCH155CN332KK 3.3nF 10% 50V X7R - 55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C510	Capacitor Ceramic,Chip	ECCH0000161	MCH153CN333KK 33nF 10% 16V X7R - 55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C215 C229 C328 C513 C514 C515 C516 C517 C518 C519 C521 C700	Capacitor Ceramic,Chip	ECCH0000182	GRM155R61A104K 0.1uF 10% 10V X5R - 55TO+85C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C203 C402 C407 C408 C412 C417 C418 C532 C533 C535 C701 C714 C715 C716 C717	Capacitor Ceramic,Chip	ECCH0000198	CL05A225MQ5NSNC 2.2uF 20% 6.3V X5R - 55TO+85C 1005 R/TP . SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	C216 C218 C400 C403 C404 C405 C406 C409 C410 C411 C413 C414 C415 C416 C419	Capacitor Ceramic,Chip	ECCH0002001	C1005JB0J104KT000F 0.1uF 10% 6.3V Y5P - 30TO+85C 1005 R/TP - TDK CORPORATION	
6	C401	Capacitor Ceramic,Chip	ECCH0004904	GRM155R60J105K 1uF 10% 6.3V X5R -55TO+85C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C549	Capacitor Ceramic,Chip	ECCH0007803	CL10A106MP8NNNC 10uF 20% 10V X5R - 55TO+85C 1608 R/TP 0.8MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	



## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C201 C208 C209 C210 C211 C212 C213 C220 C221	Capacitor Ceramic,Chip	ECCH0009101	C0603X5R0J104KT00NN 0.1uF 10% 6.3V X5R - 55TO+85C 0603 R/TP - TDK CORPORATION	
6	C222	Capacitor Ceramic,Chip	ECCH0009106	C0603X7R1C103KT 10nF 10% 10V X7R - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	C207	Capacitor Ceramic,Chip	ECCH0009107	GRM033R71C222K 2.2nF 10% 16V X7R - 55TO+125C 0603 R/TP - KOREA MURATA ELECTRONICS CO. LTD.	
6	C223	Capacitor Ceramic,Chip	ECCH0009506	MCH032A270JK 27pF 5% 25V NP0 -55TO+125C 0603 R/TP - ROHM.	
6	C225	Capacitor Ceramic,Chip	ECCH0010501	GRM1555C1H7R5D 7.5pF 0.5PF 50V C0G - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C706 C707	Capacitor Ceramic,Chip	ECCH0017301	CL03A105MQ3CSNH 0.000001F 20% 6.3V X5R - 45TO+85C 0603 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
6	C300 C341 C524 C525 C526 C527	Capacitor Ceramic,Chip	ECCH0017501	CL10A226MQ8NRNE 22uF 20% 6.3V X5R - 55TO+85C 1608 R/TP 0.8MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C202	Capacitor TA,Conformal	ECTH0001903	F980J226MMA 22uF 20% 6.3V 1.4UA -55TO+125C 80HM 1.6X0.85X0.8MM NONE SMD R/TP 0.9T max. NICHICON CORPORATION, EAST JAPAN SALES OFFICE	
6	C574	Capacitor Ceramic,Chip	ECZH0000813	C1005C0G1H101JT 100pF 5% 50V C0G - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C503 C508 C520 C530 C531 C536 C537 C538 C539 C540 C541 C542 C543 C544 C545 C546 C547 C548 C559 C565 C566 C567 C726	Capacitor Ceramic,Chip	ECZH0001215	C1005X5R1A105KT000F 1uF 10% 10V X5R - 55TO+85C 1005 R/TP - TDK KOREA COOPERATION	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C302 C303 C304 C305 C306 C307 C308 C309 C314 C315 C316 C317 C318 C319 C320 C321 C322 C323 C324 C325 C326 C327 C329 C332 C333 C334 C336 C338 C339 C340 C343 C345 C346	Capacitor Ceramic,Chip	ECZH0001217	GRM155R60J474K 470nF 10% 6.3V X5R - 25TO+70C 1005 BK-DUP - MURATA MANUFACTURING CO.,LTD.	
6	C711 C713	Capacitor Ceramic,Chip	ECZH0003126	GRM155R71A393K 39nF 10% 10V X7R - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C205 C206 C504	Capacitor Ceramic,Chip	ECZH0025916	GRM0335C1E330J 33pF 5% 25V NP0 - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C200 C228	Capacitor Ceramic,Chip	ECZH0025917	GRM0335C1E470J 47pF 5% 25V NP0 - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C214 C224	Capacitor Ceramic,Chip	ECZH0025920	GRM033R71C102K 1nF 10% 16V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	D502	Diode,Switching	EDSY0011901	SDB310Q 340mV 30V 200mA 1A 0SEC 150mW EMD2 R/TP 2P 1 AUK CORP	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	D503	Diode,Switching	EDSY0018601	SDS511Q 1.2V 85V 100mA 2A 4NSEC 150mW SOD523 R/TP 2P 1 AUK CORP	
6	ZD600	Diode,TVS	EDTY0012101	PESD5V0F1BL 5.5V 6V min 11V 2.5A - SOD-882 R/TP 2P 1 STC CORP.	
6	D501 D504	Diode,TVS	EDTY0012102	PESD5V0V1BL 5V 5.8V min. 12.5V 4.8A 45W SOD-882 R/TP 2P 1 STC CORP.	
6	L200	Inductor Multilayer,Chip	ELCH0010401	LK1005 2R2K-T 2.2UH 10% - 20mA - - 1.7OHM 40MHZ 20 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	L502 L503	Inductor,Wire Wound,Chip	ELCP0008013	MIPSZ2012D2R2 2.2UH 30% - 700mA 0.77 0.7 0.23OHM - - SHIELD 2.0X1.2X1.0 MM NONE R/TP FDK CORPORATION.	
6	L500 L501	Inductor,Wire Wound,Chip	ELCP0014201	1239AS-H-2R2N=P2 2.2UH 30% - 1.6A 2.2 1.6 0.108OHM - - SHIELD 2.5X2.0X1.2MM NONE R/TP TOKO, INC.	
6	R506 R529 R530	Resistor,Chip	ERHY0000254	MCR01MZP5J472 4.7KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R203	Resistor,Chip	ERHY0003301	MCR01MZP5J101 100OHM 5% 1/16W 1005 R/TP - ROHM.	
6	R517 R518 R519	Resistor,Chip	ERHY0009303	MCR006YZPF1002 10KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	R216 R508 R510	Resistor,Chip	ERHY0009311	MCR006YZPF51R0 51OHM 1% 1/20W 0603 R/TP - ROHM.	
6	R200 R214 R217	Resistor,Chip	ERHY0009505	MCR006YZPJ103 10KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	R504	Resistor,Chip	ERHY0009517	MCR006YZPJ223 22KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	R500	Resistor,Chip	ERHY0009536	MCR006YZPF1003 100KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	R202	Resistor,Chip	ERHY0009586	MCR006YZPF2201 2.2KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	R215	Resistor,Chip	ERHY0042405	RC0201FR-074K02L 4.02KOHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R208	Resistor,Chip	ERHY0042409	RC0201FR-0749R9L 49.9OHM 1% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	R524	Resistor,Chip	ERHZ0000201	MCR01MZP5F1000 100OHM 1% 1/16W 1005 R/TP - ROHM.	
6	R544	Resistor,Chip	ERHZ0000203	MCR01MZP5F1002 10KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	R501	Resistor,Chip	ERHZ0000204	MCR01MZP5F1003 100KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	R204	Resistor,Chip	ERHZ0000206	MCR01MZP5F10R0 10OHM 1% 1/16W 1005 R/TP - ROHM.	
6	R503	Resistor,Chip	ERHZ0000288	MCR01MZP5F4703 470KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	R533	Resistor,Chip	ERHZ0000318	MCR01MZP5F8062 80.6KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	R509	Resistor,Chip	ERHZ0000323	MCR01MZP5F9102 91KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	R408 R528	Resistor,Chip	ERHZ0000405	MCR01MZP5J103 10KOHM 5% 1/16W 1005 R/TP - ROHM.	
5	EBR071600	PCB Assembly Main,SMT Bottom	EBR75440801	LGP705.ANGRBK 1.0 Main	
6	C836	Capacitor Ceramic,Chip	EAE62286801	CL03A104KP3NNNC 0.0000001F 10% 10V X5R - 55TO+85C 0603 R/TP 0.3 SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C507 C534 C741	Capacitor Ceramic,Chip	EAE62502901	CL05A106MP5NUNC 10uF 20% 10V X5R - 55TO+85C 1005 R/TP 0.55T max. SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C550	Capacitor Ceramic,Chip	EAE62505701	CL10A105KB8NNNC 1uF 10% 50V X5R - 55TO+85C 1608 R/TP 0.9T max. SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	L1011	Capacitor Ceramic,Chip	EAE62621801	C1005NPO758CGTQ 0.75pF 0.25PF 50V C0G - 55TO+125C 1005 R/TP 0.55MM DARFON ELECTRONICS CORP.	
6	C845	Capacitor Ceramic,Chip	EAE62767201	CL21A476MQ9LRNB 47uF -20TO20% 6.3V X5R - 55TO+85C 2012 R/TP 0.9T SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	FB801	Filter,Bead	EAM62150301	CIM05J600NC 60 ohm 1.0X0.5X0.5 25% 0.2 ohm 0.65A SMD R/TP 2P 0 SAMSUNG ELECTRO-MECHANICS CO., LTD.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	FB800	Filter,Bead	EAM62471001	BLM03AX241SN1D 240 ohm 0.6X0.3X0.33 25% 0.38 ohm 0.35A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	U800	IC,Bluetooth	EAN61966101	WCN-2243-0-58BWLNSP-S/TR-05 17VTO2.7V,2.2VTO3V,1.7VTO1.9V 120mW 58P - WLCSP R/TP-T 58P QUALCOMM INCORPORATED.	
6	U700	IC,Comparator	EAN62065901	MAX14579E 2.5~5.5V 2uA COMPARATOR TDFN R/TP 8P Headset Jack Detection IC with LDO, 15kV ESD MAXIM INTEGRATED PRODUCTS INC.	
6	U1000	IC,RF Transceiver,3G	EAN62090401	RTR6285A GSM/EDGE/3G Quad with MSM7227A CSP R/TP 137P QUALCOMM INCORPORATED.	
6	U802	IC,WiFi	EAN62416201	WCN1314-0-87WLNSP-TR-0D WCN1314 Revision version, WiFi(11bgn) single band, 3.95x4.16x0.63, 0.4pitch, 65nm, WLCSP R/TP 87P QUALCOMM INCORPORATED.	
6	U1001	Module,Tx Module	EAT61674101	SKY77544-52 0DBM 0DB 0% 0A 0A 0DB 0DBM 0DBM 28P 6.0x6.0x0.9MM WGP RS TxM Quad Tx, Quad Rx, SP9T, Triple WCDMA Port, 28pin, 6*6*0.9 SKYWOKS SOLUTIONS INC.	
6	C1097 C809 C837	Capacitor Ceramic,Chip	ECCH0000110	MCH155A100D 10pF 0.5PF 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C1068	Capacitor Ceramic,Chip	ECCH0000112	MCH155C150J 15pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C1058 C1064 C819	Capacitor Ceramic,Chip	ECCH0000113	MCH155A180J 18pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C573	Capacitor Ceramic,Chip	ECCH0000115	MCH155A220JK 22pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C753	Capacitor Ceramic,Chip	ECCH0000120	MCH155A390J 39pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C804 C816 C823	Capacitor Ceramic,Chip	ECCH0000122	MCH155A470JK 47pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	



## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C1104 C811 C815	Capacitor Ceramic,Chip	ECCH0000155	MCH153CN103KK 10nF 10% 16V X7R - 55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
6	C1095 C1096 C1099	Capacitor Ceramic,Chip	ECCH0000175	GRM1555C1H2R7B 2.7pF 0.1PF 50V NP0 - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C1012 C1014 C1103	Capacitor Ceramic,Chip	ECCH0000180	GRM1555C1H3R3C 3.3pF 0.25PF 50V NP0 - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C1000 C1001 C1008 C1011	Capacitor Ceramic,Chip	ECCH0000187	GRM1555C1H151J 150pF 5% 50V NP0 - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C1086 C1093	Capacitor Ceramic,Chip	ECCH0000195	GRM1555C1H3R9C 3.9pF 0.25PF 50V NP0 - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C401	Capacitor Ceramic,Chip	ECCH0004904	GRM155R60J105K 1uF 10% 6.3V X5R -55TO+85C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C1028 C610	Capacitor Ceramic,Chip	ECCH0005604	GRM188R60J106M 10000000 pF,6.3V,M,X5R,TC,1608,R/TP,0.8 mm MURATA MANUFACTURING CO.,LTD.	
6	C601 C834 C849	Capacitor Ceramic,Chip	ECCH0007804	CL05A225MP5NSNC 2.2uF 20% 10V X5R - 55TO+85C 1005 R/TP 0.5MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C201 C208 C209 C210 C211 C212 C213 C220 C221	Capacitor Ceramic,Chip	ECCH0009101	C0603X5R0J104KT00NN 0.1uF 10% 6.3V X5R - 55TO+85C 0603 R/TP - TDK CORPORATION	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C1002 C1003 C1061 C1076 C1077 C1078 C1079 C833 C847 C848 C851	Capacitor Ceramic,Chip	ECCH0009103	C0603C0G1H101JT00NN 100pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	C1006 C1010 C1032	Capacitor Ceramic,Chip	ECCH0009104	C0603C0G1H330JT00NN 33pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	C222	Capacitor Ceramic,Chip	ECCH0009106	C0603X7R1C103KT 10nF 10% 10V X7R - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	C1066	Capacitor Ceramic,Chip	ECCH0009109	C0603X7R1H331KT00NN 330pF 10% 50V X7R - 55TO+125C 0603 R/TP - TDK CORPORATION	
6	C1060 C803	Capacitor Ceramic,Chip	ECCH0009216	GRM0335C1E220J 22pF 5% 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C1024	Capacitor Ceramic,Chip	ECCH0009226	GRM0335C1E390J 39pF 5% 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C832	Capacitor Ceramic,Chip	ECCH0009231	GRM033R71C471K 470pF 10% 16V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C838 C839	Capacitor Ceramic,Chip	ECCH0009514	MCH032A(AN)100DK 10pF 0.5PF 25V X7R - 55TO+125C 0603 R/TP - ROHM.	
6	C706 C707	Capacitor Ceramic,Chip	ECCH0017301	CL03A105MQ3CSNH 0.000001F 20% 6.3V X5R - 45TO+85C 0603 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C1017 C1029 C1036 C1038 C1041 C1048 C1055 C604 C606 C805 C806 C827	Capacitor Ceramic,Chip	ECCH0017601	CL05A475MQ5NRNC 4.7uF 20% 6.3V X5R - 55TO+85C 1005 R/TP 0.5MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
6	C835	Capacitor Ceramic,Chip	ECCH0032801	GRM033R60J224M 0.00000022F 20% 6.3V X5R - 55TO+85C 0603 R/TP 0.3MM MURATA MANUFACTURING CO.,LTD.	
6	C574	Capacitor Ceramic,Chip	ECZH0000813	C1005C0G1H101JT 100pF 5% 50V C0G - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	C1080 C1088 C1107	Capacitor Ceramic,Chip	ECZH0000830	C1005C0G1H330JT000F 33pF 5% 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	L1006 L1014 L1025	Capacitor Ceramic,Chip	ECZH0001002	C1005CH1H0R5BT000F 0.5pF 0.1PF 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	C503 C508 C520 C530 C531 C536 C537 C538 C539 C540 C541 C542 C543 C544 C545 C546 C547 C548 C559 C565 C566 C567 C726	Capacitor Ceramic,Chip	ECZH0001215	C1005X5R1A105KT000F 1uF 10% 10V X5R - 55TO+85C 1005 R/TP - TDK KOREA COOPERATION	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	C752	Capacitor Ceramic,Chip	ECZH0001216	C1005X5R1A224KT000E 220nF 10% 10V X5R - 55TO+85C 1005 R/TP - TDK KOREA COOPERATION	
6	C302 C303 C304 C305 C306 C307 C308 C309 C314 C315 C316 C317 C318 C319 C320 C321 C322 C323 C324 C325 C326 C327 C329 C332 C333 C334 C336 C338 C339 C340 C343 C345 C346	Capacitor Ceramic,Chip	ECZH0001217	GRM155R60J474K 470nF 10% 6.3V X5R - 25TO+70C 1005 BK-DUP - MURATA MANUFACTURING CO.,LTD.	
6	C1035 C1039 C1054 C1085 C812 C820	Capacitor Ceramic,Chip	ECZH0003103	GRM36X7R104K10PT 100nF 10% 10V X7R - 55TO+125C 1005 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C200 C228	Capacitor Ceramic,Chip	ECZH0025917	GRM0335C1E470J 47pF 5% 25V NP0 - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
6	C214 C224	Capacitor Ceramic,Chip	ECZH0025920	GRM033R71C102K 1nF 10% 16V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	L803	Inductor Multilayer,Chip	ELCH0001035	HK1005 4N7S-T 4.7NH 0.3NH - 300mA 0.21OHM 4GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	L810	Inductor Multilayer,Chip	ELCH0001040	HK1005 3N9S-T 3.9NH 0.3NH - 300mA 0.21OHM 4GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	L1007 L1037	Inductor Multilayer,Chip	ELCH0001048	1005GC2T10NJLF 10NH 5% - 250mA 0.42OHM 2.5GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	C1073 L1030	Inductor Multilayer,Chip	ELCH0001049	1005GC2T6N8JLF 6.8NH 5% - 250mA 0.32OHM 3GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1020	Inductor Multilayer,Chip	ELCH0001054	1005GC2T5N6SLF 5.6NH 0.3NH - 300mA 0.27OHM 3.2GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1039 L1040 L1041	Inductor Multilayer,Chip	ELCH0001056	1005GC2T2N7SLF 2.7NH 0.3NH - 300mA 0.17OHM 5.5GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	C1018	Inductor Multilayer,Chip	ELCH0001057	1005GC2T3N9SLF 3.9NH 0.3NH - 300mA 0.22OHM 4GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1027	Inductor Multilayer,Chip	ELCH0001404	LL1005-FHL1N5S 1.5NH 0.3NH - 400mA 0.13OHM 15GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	L1012 L1018	Inductor Multilayer,Chip	ELCH0001406	LL1005-FHL4N7S 4.7NH 0.3NH - 300mA 0.2OHM 7GHZ 9 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	L1028 L1032 L811	Inductor Multilayer,Chip	ELCH0001411	LL1005-FHL1N2S 1.2NH 0.3NH - 400mA 0.1OHM 16GHZ 7 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	C1094	Inductor Multilayer,Chip	ELCH0001412	LL1005-FHL1N8S 1.8NH 0.3NH - 400mA 0.14OHM 15GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	L1035	Inductor Multilayer,Chip	ELCH0001413	LL1005-FHL22NJ 22NH 5% - 300mA 0.7OHM 2.5GHZ 10 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	L1003 L801 L802	Inductor Multilayer,Chip	ELCH0001425	LL1005-FHL82NJ 82NH 5% - 150mA 1.9OHM 1.15GHZ 10 SHIELD NONE 1.0X0.5X0.5MM R/TP TOKO, INC.	
6	C1106 C841	Inductor Multilayer,Chip	ELCH0003815	LQG15HS2N7S02D 2.7NH 0.3NH - 300mA 0.15OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C1072 L1010	Inductor Multilayer,Chip	ELCH0003819	LQG15HS12NJ02D 12NH 5% - 300mA - - 0.28OHM 3GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C821	Inductor Multilayer,Chip	ELCH0003820	LQG15HS3N0S02D 3NH 0.3NH - 300mA 0.17OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C1056	Inductor Multilayer,Chip	ELCH0003828	LQG15HS2N4S02D 2.4NH 0.3NH - 300mA 0.15OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C1084	Inductor Multilayer,Chip	ELCH0003832	LQG15HS2N2S02D 2.2NH 0.3NH - 300mA - - 0.12OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C802	Inductor Multilayer,Chip	ELCH0003842	LQG15HSR10J02D 100NH 5% - 150mA - - 1.25OHM 600MHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	C1023 C1025	Inductor Multilayer,Chip	ELCH0004701	1005GC2T12NJLF 12NH 5% - 250mA 0.48OHM 2.1GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1004 L1015 L1023 L1034	Inductor Multilayer,Chip	ELCH0004705	1005GC2T8N2JLF 8.2NH 5% - 250mA 0.37OHM 2.8GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	C1089 L1022 L806	Inductor Multilayer,Chip	ELCH0004709	1005GC2T3N3SLF 3.3NH 0.3NH - 300mA 0.19OHM 4.5GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	



## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	L1029	Inductor Multilayer,Chip	ELCH0004710	1005GC2T15NJLF 15NH 5% - 250mA 0.53OHM 2GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1033	Inductor Multilayer,Chip	ELCH0004716	1005GC2T39NJLF 39NH 5% - 200mA 1.2OHM 1.2GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1008	Inductor Multilayer,Chip	ELCH0004718	1005GC2T5N6SLF 5.6NH 0.3NH - 300mA 0.27OHM 3.2GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	C1059 C1063 L1031	Inductor Multilayer,Chip	ELCH0004720	1005GC2T1N2SLF 1.2NH 0.3NH - 300mA - - 0.12OHM 9GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	C1053 C1057 C1082 L1038	Inductor Multilayer,Chip	ELCH0004721	1005GC2T2N2SLF 2.2NH 0.3NH - 300mA - - 0.16OHM 6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1002	Inductor Multilayer,Chip	ELCH0004727	1005GC2TR10JLF 100NH 5% - 100mA 2.3OHM 600MHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L1013	Inductor Multilayer,Chip	ELCH0004730	1005GC2T33NJLF 33NH 5% - 200mA 1OHM 1.3GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
6	L800	Inductor Multilayer,Chip	ELCH0005019	HK1005 68NJ 68NH 5% - 180mA 1.2OHM 750MHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP TAIYO YUDEN CO.,LTD	
6	L1026	Inductor Multilayer,Chip	ELCH0012508	LQP15MN2N0B02D 2NH 0.1NH - 220mA 0.3OHM 6GHZ 13 SHIELD NONE 1.0X0.5X0.35MM R/TP MURATA MANUFACTURING CO.,LTD.	
6	CN603	Connector,BtoB	ENBY0034201	GB042-24S-H10-E3000 24P 0.40MM STRAIGHT SOCKET SMD R/TP 1M - LS Mtron Ltd.	
6	CN602	Connector,BtoB	ENBY0042701	GB042-54S-H10 54P 0.4MM STRAIGHT SOCKET SMD R/TP 1M - LS Mtron Ltd.	
6	CN600	Connector,BtoB	ENBY0056901	24-5804-024-000-829+ 24P 0.40MM STRAIGHT FEMALE SMD R/TP 900mM - KYOCERA ELCO KOREA SALES CO.,LTD.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	CN601	Connector,BtoB	ENBY0057501	24-5804-034-000-829+ 34,0.4mm,STRAIGHT,gold,34,0.40MM,STRAIGHT,FEMALE,SMD,0.9T, KYOCERA ELCO KOREA SALES CO.,LTD.	
6	SW1000	Connector,RF	ENWY0005501	20279-001E-01 NONE STRAIGHT SOCKET SMD R/TP AU 50OHM 400mDB I-PEX CO., LTD	
6	SW1001	Connector,RF	ENWY0008701	MS-156C NONE STRAIGHT SOCKET SMD T/REEL AU 50OHM 400mDB HIROSE KOREA CO.,LTD	
6	CN500	Connector Terminal Block	ENZY0030301	04-9254-004-032-868+ 4P 2.50MM ANGLE SMD R/TP - KYOCERA ELCO KOREA SALES CO.,LTD.	
6	R1020	Resistor,Chip	ERHY0000137	MCR01MZP5F2702 27KOHM 1% 1/16W 1005 R/TP - ROHM.	
6	R506 R529 R530	Resistor,Chip	ERHY0000254	MCR01MZP5J472 4.7KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R517 R518 R519	Resistor,Chip	ERHY0009303	MCR006YZPF1002 10KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	R1011 R1012	Resistor,Chip	ERHY0009503	MCR006YZPJ101 100OHM 5% 1/20W 0603 R/TP - ROHM.	
6	R600 R800	Resistor,Chip	ERHY0009507	MCR006YZPJ105 1MOHM 5% 1/20W 0603 R/TP - ROHM.	
6	R723	Resistor,Chip	ERHY0009516	MCR006YZPJ222 2.2KOHM 5% 1/20W 0603 R/TP - ROHM.	
6	R1003	Resistor,Chip	ERHY0009524	MCR006YZPJ470 47OHM 5% 1/20W 0603 R/TP - ROHM.	
6	R1010	Resistor,Chip	ERHY0009531	MCR006YZPJ620 62OHM 5% 1/20W 0603 R/TP - ROHM.	
6	R202	Resistor,Chip	ERHY0009586	MCR006YZPF2201 2.2KOHM 1% 1/20W 0603 R/TP - ROHM.	
6	R1004 R1005	Resistor,Chip	ERHY0042403	RC0201JR-07130RL 130OHM 5% 1/20W 0603 R/TP - YAGEO CORPORATION	
6	R1007	Resistor,Chip	ERHZ0000212	MCR01MZP5F1202 12KOHM 1% 1/16W 1005 R/TP - ROHM.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	R807 R808	Resistor,Chip	ERHZ0000348	MCR01MZP5F12R0 12OHM 1% 1/16W 1005 R/TP - ROHM.	
6	R1014 R621	Resistor,Chip	ERHZ0000401	MCR01MZSJ000 0OHM 5% 1/16W 1005 R/TP - ROHM.	
6	R1013	Resistor,Chip	ERHZ0000404	MCR01MZP5J102 1KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R408 R528	Resistor,Chip	ERHZ0000405	MCR01MZP5J103 10KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R212	Resistor,Chip	ERHZ0000406	MCR01MZP5J104 100KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R721 R722 R806	Resistor,Chip	ERHZ0000407	MCR01MZP5J105 1MOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R1006	Resistor,Chip	ERHZ0000463	MCR01MZP5J330 33OHM 5% 1/16W 1005 R/TP - ROHM.	
6	R514	Resistor,Chip	ERHZ0000493	MCR01MZP5J513 51KOHM 5% 1/16W 1005 R/TP - ROHM.	
6	R1008 R1009	Resistor,Chip	ERHZ0000517	MCR01MZP5J910 91OHM 5% 1/16W 1005 R/TP - ROHM.	
6	U1003	IC,RF Amplifier	EUSY0365001	BGA735 -0.3~3.6 2.7-3.0 NA 0W 0W NA 0 TSLP R/TP 16P - INFINEON TECHNOLOGIES (ASIA PACIFIC) PTE LTD.	
6	U602	IC,LDO Voltage Regulator	EUSY0373901	RP103K301D-TR RP103K301D-TR RP103K301D-TR,PLP1010 ,4 ,R/TP ,150mA, 3.0V Single LDO RICOH COMPANY, LTD. RICOH COMPANY, LTD.	
6	U509	IC,LDO Voltage Regulator	EUSY0407101	BU28TD4WNVX SSON004,4,R/TP,2.8V 150mA Single LDO,IC,LDO Voltage RegulatorIC,LDO Voltage Regulator ROHM.	
6	U504	IC,LDO Voltage Regulator	EUSY0407401	RT9032 WDFN8L,8,R/TP,Programmable Dual LDO,IC,LDO Voltage RegulatorIC,LDO Voltage Regulator RICHTEK TECHNOLOGY CORP.	
6	U508	IC,LDO Voltage Regulator	EUSY0407501	BU18TD4WNVX SSON004,4,R/TP,1.8V 150mA Single LDO,IC,LDO Voltage RegulatorIC,LDO Voltage Regulator ROHM.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	FL1005	Filter,Duplexer,IMT	SDMY0003001	B7697 2140000000 2112.4 to 2167.6 1950000000 1922.4 to 1977.6 2.2 1.8 2.5x2.0x0.89 DUAL SMD R/TP - EPCOS PTE LTD.	
6	FL1002	Filter,Duplexer,IMT	SDMY0003701	B7675 942500000 925 to 960 897500000 880 to 915 3.5 3.1 2.5*2.0*0.68 DUAL SMD R/TP - EPCOS PTE LTD.	
6	FL800	Filter,Separator	SFAY0012401	LFD181G57DPFC087 0.6 22 - 2400 to 2500,1572 to 1578,0.6 dB,0.4 dB,22 dB,13 dB,1608,diplexer,GPS/WiFi, MURATA MANUFACTURING CO.,LTD.	
6	FL802	Filter Separator,FEM	SFAY0015501	AFEM-S102 2.1 25 0 connectivity for WCN1314 AVAGO TECHNOLOGIES INTERNATIONAL SALES PTE. LIMITED	
6	FB710	Filter,Bead	SFBH0008102	BLM15HD182SN1D 1800 ohm 1.0X0.5X0.5 25% 2.2 ohm 0.2A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
6	FL600	Filter,EMI/Power	SFEY0015901	ICMEF214P101MFR ICMEF214P101MFR ICMEF214P101MFR,SMD ,ESD Common mode Filter INNOCHIPS TECHNOLOGY INNOCHIPS TECHNOLOGY	
6	FL601	Filter,EMI/Power	SFEY0016301	ICMEF112P900M COMMON MODE NOISE FILTER 0HZ 0F 0H SMD R/TP INNOCHIPS TECHNOLOGY	
6	FL1000	Filter,Saw,Dual	SFSB0001802	SAWEN881MCN0F00 881.5MHz, 1960MHz 1.8*1.4*0.5 SMD R/TP 10P MURATA MANUFACTURING CO.,LTD.	
6	FL1001	Filter,Saw,Dual	SFSB0001902	SAWEN1G84CN0F00 1842.5MHz, 1960MHz 1.8*1.4*0.5 SMD R/TP 10P MURATA MANUFACTURING CO.,LTD.	
6	FL1007	Filter,Saw	SFSY0024301	SAFE8942MFL0F00 942.5 1.4*1.1*0.6 SMD R/TP 5P MURATA MANUFACTURING CO.,LTD.	
6	FL1004	Filter,Saw	SFSY0028101	SAFE81G95KA0F00 1950 1.4*1.1*0.6 SMD R/TP 5P MURATA MANUFACTURING CO.,LTD.	
6	FL1006	Filter,Saw	SFSY0028201	SAFE82G14FB0F00 - - - - 2P MURATA MANUFACTURING CO.,LTD.	
6	FL1003	Filter,Saw	SFSY0037501	SAFE8897MAM0F00 897.5MHz 1.4*1.1*0.6 SMD R/TP 5P MURATA MANUFACTURING CO.,LTD.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	FL801	Filter,Saw	SFSY0038901	SAFEB1G57KB0F00 SAFEB1G57KB0F00 SAFEB1G57KB0F00,1575.42 MHz,1.4*1.1*0.6 ,SMD ,1574.22M~1576.62M, IL 0.8, 5pin, U-U, 50-50, GPS LOW LOSS MURATA MANUFACTURING CO.,LTD. MURATA MANUFACTURING CO.,LTD.	
6	U1002	IC,Power Amplifier	SMPY0020001	SKY77195 SKY77195,28 dBm,%,A,dBc,dB,4x5,SMD,3G Dual PAM Band 1+8. CPL integrated SKYWORKS SOLUTIONS INC.	
6	U801	IC,RF Amplifier	SMZY0025501	RF2815 3.3*2.1*1.0,FILTER+GPS LNA+FILTER MODULE,GPS, RF MICRO DEVICES INC	
6	C1074 C801	Capacitor Ceramic,Chip	ECZH0000802	C1005C0G1H010CT 1pF 0.25PF 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
6	R213 R532	PCB ASSY,MAIN PAD OPEN	SAFO0000401	AX3100 ATL SV_SHIPBACK,MAIN,A,00HM DNI	
6	R218 R219 R300 R301 R302 R303	PCB ASSY MAIN,PAD SHORT	SAFP0000401	LG-LU3000 LGTBK,MAIN,A,	
4	EBR071500	PCB Assembly Main,Insert	EBR74616902	LGP700.AFRAWH 1.0 Main	
5	RAA050100	Resin,PC	BRAH0001301	UF2040 or 3075BHF . . NONE	
5	EBR03	PCB Assembly Flexible	EBR75100102	LGP700.AFRABK 1.0 Flexible	
6	EBR070400	PCB Assembly Flexible,SMT	EBR75100202	LGP700.AFRABK 1.0 Flexible	
7	EAX010700	PCB,Flexible	EAX64658001	LGP700.AFRABK 1.0 POLYI Multi 2 0.15 Flexible	
7	EBR070200	PCB Assembly Flexible,SMT Bottom	EBR75036002	LGP700.AFRABK 1.0 Flexible	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
8	C1006 C1010 C1032	Capacitor Ceramic,Chip	ECCH0009104	C0603C0G1H330JT00NN 33pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	
8	R101 R103 R104	Resistor,Chip	ERHZ0000285	MCR01MZP5F4700 470OHM 1% 1/16W 1005 R/TP - ROHM.	
8	VA100 VA101 VA102	Varistor	SEVY0003601	ICVL0505101V150FR 5.6V 0% 100pF 1.0*0.5*0.55 NONE SMD R/TP INNOCHIPS TECHNOLOGY	
8	CN100	Socket,Card	EAG62830201	104031-0811 SD 8P ANGLE SMD R/TP 11.95x11.40x1.42t, Push-pull type MOLEX	
8	D100 D101 D102	Diode,TVS	EAH61794301	ESD5205P6T6G 5V 5.5V min. 10V 2UA 0W SOT-963 R/TP 6P 5 ON SEMICONDUCTOR	
8	C216 C218 C400 C403 C404 C405 C406 C409 C410 C411 C413 C414 C415 C416 C419	Capacitor Ceramic,Chip	ECCH0002001	C1005JB0J104KT000F 0.1uF 10% 6.3V Y5P - 30TO+85C 1005 R/TP - TDK CORPORATION	
8	L101	Inductor,Wire Wound,Chip	ELCP0014301	1239AS-H-1R0N=P2 1UH 30% - 2.3A 3.0 2.3 0.059OHM - - SHIELD 2.5X2.0X1.2MM NONE R/TP TOKO, INC.	
8	C549	Capacitor Ceramic,Chip	ECCH0007803	CL10A106MP8NNNC 10uF 20% 10V X5R - 55TO+85C 1608 R/TP 0.8MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
8	J100	Socket DIMM/SIMM	EAG63215801	5000-6P-1.5L-A1 6P STRAIGHT STANDARD SMD T/REEL - HYUPJIN I&C CO.,LTD.	



## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
8	C201 C208 C209 C210 C211 C212 C213 C220 C221	Capacitor Ceramic,Chip	ECCH0009101	C0603X5R0J104KT00NN 0.1uF 10% 6.3V X5R - 55TO+85C 0603 R/TP - TDK CORPORATION	
8	R102	Resistor,Chip	ERHY0042402	RC0201JR-0715KL 15KOHM 5% 1/20W 0603 R/TP - YAGEO CORPORATION	
8	L100	Resistor,Chip	ERHY0009501	MCR006YZPJ000 0OHM 5% 1/20W 0603 R/TP - ROHM.	
8	U100	IC,DC,DC Converter	EAN62410701	AS3647 2.7 to 4.4V adj 0W WLCSP R/TP 13P - AUSTRIAMICROSYSTEMS AG	
8	U800	IC,Acceleration Sensor	EAN62222201	BMC050 Accelerometer with Geomagnetic Sensor 3X3X1 QFN R/TP 16P Accelerometer with Geomagnetic Sensor BOSCH SENSORTEC GMBH	
8	LD100	LED,Chip	EDLM0009701	EHP-C04/NT01A-P01/TR(LM) WHITE 3.35~4.15 1A 100~140lm x, y 6.6W - R/TP 2P - EVERLIGHT ELECTRONICS CO., LTD.	
8	C1060 C803	Capacitor Ceramic,Chip	ECCH0009216	GRM0335C1E220J 22pF 5% 25V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
7	EBR070300	PCB Assembly Flexible,SMT Top	EBR75035902	LGP700.AFRABK 1.0 Flexible	
8	CN102	Connector,BtoB	ENBY0057401	14-5804-034-000-829+ 34,0.4 mm,STRAIGHT,gold,34,0.40MM,STRAIGHT,MALE, SMD,0.9T, KYOCERA ELCO KOREA SALES CO.,LTD.	
4	EAB02	Speaker,Dual Mode	EAB62653301	1810-8T-08PP Fe-Ne-B 700mW 8OHM 90DB 750HZ 18.0 X 10.0 X 3 SPRING KIRYN TELECOM CO., LTD	
4	EAA00	PIFA Antenna,Multiple	EAA62747901	LG3369-16-000-C MULTI -2DB 5 LDS Type - SHANGHAI AMPHENOL AIRWAVE	
5	EAA030100	PIFA Antenna,Multiple	EAA62807201	ATC-P700-F-1109 DUAL -2DB 5 FPCB Type - AT&C CO.,LTD	
4	EBR00	PCB Assembly,Flexible	EBR75035501	LGP700.AFRABK 1.0 Flexible	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
5	EBR070400	PCB Assembly Flexible,SMT	EBR75099901	LGP700.AFRABK 1.0 Flexible	
6	EAX010700	PCB,Flexible	EAX64658101	LGP700.AFRABK 1.0 POLYI SBL 4 0.3 Flexible	
6	EBR070300	PCB Assembly Flexible,SMT Top	EBR75100001	LGP700.AFRABK 1.0 Flexible	
7	SUMY00	Microphone Condenser	SUMY0010616	SUMY0010616 FPCB,dB,1.1TO10V, KNOWLES ACOUSTICS	
6	EBR070200	PCB Assembly Flexible,SMT Bottom	EBR75035701	LGP700.AFRABK 1.0 Flexible	
7	C574	Capacitor Ceramic,Chip	ECZH0000813	C1005C0G1H101JT 100pF 5% 50V C0G - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
7	C1074 C801	Capacitor Ceramic,Chip	ECZH0000802	C1005C0G1H010CT 1pF 0.25PF 50V NP0 - 55TO+125C 1005 R/TP - TDK KOREA COOPERATION	
7	C1068	Capacitor Ceramic,Chip	ECCH0000112	MCH155C150J 15pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
7	R804	Diode,TVS	EAH61693001	uClamp0541Z 5V 6V min 12V 2A 30W SLP0603P2X3 R/TP 2P 1 SEMTECH INTERNATIONAL AG	
7	D803 D804	Diode,TVS	EAH61533301	RCLAMP0521PA.TCT 5V 6V min. / 9.3V typ. / 11V max. 15V 4A - SLP1006P2 R/TP 2P 1 SEMTECH INTERNATIONAL AG	
7	LD800 LD801	LED,Chip	EDLH0015202	99-216UTC/TR8-1 WHITE 2.95~3.3 30mA 1440~1720mcd x, y 110mW - R/TP 2P - EVERLIGHT ELECTRONICS CO., LTD.	
7	KB800	Switch,Tact	ESCY0008701	SKRWAME030 1C1P 12VDC 0.05A HORIZONTAL 1.57GF R/TP-T - ALPS ELECTRIC CO.,LTD.	
7	R101 R103 R104	Resistor,Chip	ERHZ0000285	MCR01MZP5F4700 470OHM 1% 1/16W 1005 R/TP - ROHM.	
7	D800 D801 D802	Diode,TVS	EDTY0008606	PRSB6.8C 4.7V 5.7 11.5V 1A 10W DFN-2 R/TP 2P 1 PROTEK DEVICES INC.	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	ZD801 ZD802	Diode,TVS	EDTY0012501	UCLAMP3311T.TCT 3.3V 3.5V min. 6.5V 5A - SLP1006P2T R/TP 2P 1 SEMTECH CORPORATION	
7	C803	Inductor Multilayer,Chip	ELCH0001052	1005GC2T18NJLF 18NH 5% - 200mA 0.65OHM 1.6GHZ 8 SHIELD NONE 1.0X0.5X0.5MM R/TP PILKOR ELECTRONICS LTD.	
7	R802 R803	Resistor,Chip	ERHY0008207	RC1005F470CS 47OHM 1% 1/16W 1005 R/TP - SAMSUNG ELECTRO-MECHANICS CO., LTD.	
7	FB710	Filter,Bead	SFBH0008102	BLM15HD182SN1D 1800 ohm 1.0X0.5X0.5 25% 2.2 ohm 0.2A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
7	FL601	Filter,EMI/Power	SFEY0016301	ICMEF112P900M COMMON MODE NOISE FILTER 0HZ 0F 0H SMD R/TP INNOCHIPS TECHNOLOGY	
7	C708 C709	Capacitor Ceramic,Chip	ECCH0000143	MCH155CN102KK 1nF 10% 50V X7R -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
7	CN801	Connector,I/O	EAG63090001	04-5161-005-100-868 7P 0.90MM ANGLE RECEPTACLE DIP R/TP Normal New IO Connector KYOCERA ELCO KOREA SALES CO.,LTD.	
7	BAT500	Capacitor Assembly	SMZY0023501	PAS311HR-VG1 3.8 Backup Capacitor 0.03F,Module Assembly, KOREA TAIYO YUDEN.CO., LTD.	
7	C706 C707	Capacitor Ceramic,Chip	ECCH0017301	CL03A105MQ3CSNH 0.000001F 20% 6.3V X5R - 45TO+85C 0603 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
7	SW800	Connector,RF	ENWY0005601	20369-001E NONE STRAIGHT SOCKET SMD R/TP AU 50OHM 400mDB I-PEX CO., LTD	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	C503 C508 C520 C530 C531 C536 C537 C538 C539 C540 C541 C542 C543 C544 C545 C546 C547 C548 C559 C565 C566 C567 C726	Capacitor Ceramic,Chip	ECZH0001215	C1005X5R1A105KT000F 1uF 10% 10V X5R - 55TO+85C 1005 R/TP - TDK KOREA COOPERATION	
7	CN802	Connector,BtoB	ENBY0056801	14-5804-024-000-829+ 24P 0.40MM STRAIGHT MALE SMD R/TP 900mM - KYOCERA ELCO KOREA SALES CO.,LTD.	
7	ZD800	Diode,TVS	EDTY0008602	PSD12-LF 12V 13.3 25.9V 21A 500W SOD323 R/TP 2P 1 PROTEK DEVICES INC.	
7	FL800	Filter,EMI/Power	SFEY0015301	NFM18PC104R1C3 ESD/EMI 0HZ 0.1uF 0H SMD R/TP MURATA MANUFACTURING CO.,LTD.	
7	C573	Capacitor Ceramic,Chip	ECCH0000115	MCH155A220JK 22pF 5% 50V NP0 -55TO+125C 1005 R/TP - ROHM Semiconductor KOREA CORPORATION	
7	R526	Resistor,Chip	ERHY0009504	MCR006YZPJ102 1KOHM 5% 1/20W 0603 R/TP - ROHM.	
7	VA100 VA101 VA102	Varistor	SEVY0003601	ICVL0505101V150FR 5.6V 0% 100pF 1.0*0.5*0.55 NONE SMD R/TP INNOCHIPS TECHNOLOGY	
4	EBR01	PCB Assembly Flexible	EBR75099401	LGP700.AFRABK 1.0 Flexible	
5	EBR070400	PCB Assembly Flexible,SMT	EBR75099501	LGP700.AFRABK 1.0 Flexible	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
6	EAX010700	PCB,Flexible	EAX64667901	LGP700.AFRABK 1.1 FR-4 SBL 4 0.4 Flexible	
6	EBR070300	PCB Assembly Flexible,SMT Top	EBR75099601	LGP700.AFRABK 1.0 Flexible	
7	ZD600	Diode,TVS	EDTY0012101	PESD5V0F1BL 5.5V 6V min 11V 2.5A - SOD-882 R/TP 2P 1 STC CORP.	
7	D800 D801 D802	Diode,TVS	EDTY0008606	PRSB6.8C 4.7V 5.7 11.5V 1A 10W DFN-2 R/TP 2P 1 PROTEK DEVICES INC.	
6	EBR070200	PCB Assembly Flexible,SMT Bottom	EBR75099701	LGP700.AFRABK 1.0 Flexible	
7	C1002 C1003 C1061 C1076 C1077 C1078 C1079 C833 C847 C848 C851	Capacitor Ceramic,Chip	ECCH0009103	C0603C0G1H101JT00NN 100pF 5% 50V C0G - 55TO+125C 0603 R/TP - TDK CORPORATION	
7	C912 C913	Capacitor Ceramic,Chip	ECCH0009228	GRM033R61A472K 4700pF 10% 10V X5R - 55TO+85C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
7	CN903	Connector,BtoB	ENBY0051001	GB042-10S-H10-E3000 10P 0.4MM STRAIGHT FEMALE SMD R/TP 1M - LS Mtron Ltd.	
7	FB710	Filter,Bead	SFBH0008102	BLM15HD182SN1D 1800 ohm 1.0X0.5X0.5 25% 2.2 ohm 0.2A SMD R/TP 2P 0 MURATA MANUFACTURING CO.,LTD.	
7	C706 C707	Capacitor Ceramic,Chip	ECCH0017301	CL03A105MQ3CSNH 0.000001F 20% 6.3V X5R - 45TO+85C 0603 R/TP - SAMSUNG ELECTRO- MECHANICS CO., LTD.	
7	FL601	Filter,EMI/Power	SFEY0016301	ICMEF112P900M COMMON MODE NOISE FILTER 0HZ 0F 0H SMD R/TP INNOCHIPS TECHNOLOGY	
7	ZD801 ZD802	Diode,TVS	EDTY0012501	UCLAMP3311T.TCT 3.3V 3.5V min. 6.5V 5A - SLP1006P2T R/TP 2P 1 SEMTECH CORPORATION	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	J900	Jack,Phone	EAG63070601	KJA-PH-4-0176 5P 2P ANGLE R/TP 3.5M BLACK 5P - KSD CO., LTD	
7	VA100 VA101 VA102	Varistor	SEVY0003601	ICVL0505101V150FR 5.6V 0% 100pF 1.0*0.5*0.55 NONE SMD R/TP INNOCHIPS TECHNOLOGY	
7	C1017 C1029 C1036 C1038 C1041 C1048 C1055 C604 C606 C805 C806 C827	Capacitor Ceramic,Chip	ECCH0017601	CL05A475MQ5NRNC 4.7uF 20% 6.3V X5R - 55TO+85C 1005 R/TP 0.5MM SAMSUNG ELECTRO-MECHANICS CO., LTD.	
7	U900	IC,Proximity	EUSY0376201	GP2AP002S00F GP2AP002S00F GP2AP002S00F,,8 ,R/TP , SHARP CORPORATION. SHARP CORPORATION.	
7	CN603	Connector,BtoB	ENBY0034201	GB042-24S-H10-E3000 24P 0.40MM STRAIGHT SOCKET SMD R/TP 1M - LS Mtron Ltd.	
7	R804	Diode,TVS	EAH61693001	uClamp0541Z 5V 6V min 12V 2A 30W SLP0603P2X3 R/TP 2P 1 SEMTECH INTERNATIONAL AG	
7	C214 C224	Capacitor Ceramic,Chip	ECZH0025920	GRM033R71C102K 1nF 10% 16V X7R - 55TO+125C 0603 R/TP - MURATA MANUFACTURING CO.,LTD.	
7	FL600	Filter,EMI/Power	SFEY0015901	ICMEF214P101MFR ICMEF214P101MFR ICMEF214P101MFR,SMD ,ESD Common mode Filter INNOCHIPS TECHNOLOGY INNOCHIPS TECHNOLOGY	
7	R204	Resistor,Chip	ERHZ0000206	MCR01MZP5F10R0 100OHM 1% 1/16W 1005 R/TP - ROHM.	
7	CN902	Connector,BtoB	ENBY0039601	GB042-20S-H10-E3000 20P 0.4MM STRAIGHT SOCKET SMD R/TP 1M - LS Mtron Ltd.	
7	EAB01	Microphone Condenser	EAB62429201	SO8OT423-09 -42DB 100OHM OMNI 1.5 TO 3.6V 3.76x2.95x1.1 SMD GoerTek Inc.	



## 12. EXPLODED VIEW & REPLACEMENT PART LIST

Level	LocationNo.	Description	PartNumber	Spec	Remark
7	CN904	Connector,BtoB	ENBY0042601	GB042-54P-H10 54P 0.40MM STRAIGHT MALE SMD R/TP 1M - LS Mtron Ltd.	
7	R908	Resistor,Chip	ERHZ0000488	MCR01MZP5J4R7 4.7OHM 5% 1/16W 1005 R/TP - ROHM.	
7	L900	Inductor Multilayer,Chip	ELCH0001444	0402AF-101XJEW 100NH 5% - 900mA 0.16OHM 1.4GHZ 8 NON SHIELD NONE 1.12X0.66X0.66MM R/TP COILCRAFT SINGAPORE PTE LTD.	
7	R1011 R1012	Resistor,Chip	ERHY0009503	MCR006YZPJ101 100OHM 5% 1/20W 0603 R/TP - ROHM.	
7	C201 C208 C209 C210 C211 C212 C213 C220 C221	Capacitor Ceramic,Chip	ECCH0009101	C0603X5R0J104KT00NN 0.1uF 10% 6.3V X5R - 55TO+85C 0603 R/TP - TDK CORPORATION	
4	SJMY00	Motor,DC	SJMY0007108	WHVM-1030B10 WHVM-1030B10 WHVM- 1030B10,3 V,80 mA,10*3.0 ,12mm SEOUNGHYUN SMT SEOUNGHYUN SMT	
4	EBP01	Camera Module	EBP61582101	C5AA-H429A C5AA-H429A 5M AF, Hynix(1/4") CIS, 8.5x8.5x4.95t, MIPI, 0deg, FPCB LG INNOTEK CO., LTD	
4	EBP00	Camera Module	EBP61561901	CW0361 CW0361 VGA Aptina 1/11" MIPI, FPCB 5mm, 0deg. COWELL ELECTRONICS CO.,LTD	
4	EBD00	Touch Window Assembly	EBD61346201	TSMC-G434A CAPACITIVE TOUCH GFF Melfas MMS136 4.3" B to B White color LG INNOTEK.,LTD.	
4	EAJ00	LCD,Module-TFT	EAJ62069801	LH430WV1-SD04 WVGA 4.3INCH 800X480 450CD COLOR 70% 15/9 800:1 60Hz Inverter N LED 3D(Non-Glasses) - LG Display Co. Ltd.	
4	EAB00	Receiver	EAB62491301	KR-1207-WB1P 30mW 32OHM 106DB 300HZTO7KHZ WIRE dualize EM tech RCV 1207x2.7T wideband RCV SURY0015202 , SPL improvement 106dB KIRYN TELECOM CO., LTD	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

---

Level	LocationNo.	Description	PartNumber	Spec	Remark
4	EAD00	Cable,Assembly	EAD62064601	80421-202B-92L-01 UFL-LP-066 UFL-LP-066 0.09M 2 BLACK N N I-PEX CO., LTD	

## 12. EXPLODED VIEW & REPLACEMENT PART LIST

### 12.3 Accessory

**Note:** This Chapter is used for reference, Part order is ordered by SBOM standard on GCSC

Level	LocationNo.	Description	PartNumber	Spec	Remark
2	EAC00	Rechargeable Battery Lithium Ion	EAC61839001	BL-44JH_LGC_UPPER PRISMATIC 3.8V 1.65AH 330mAh 61.0x44.0x4.4 65.0x44.0x4.8Max BLACK Top cap Assembly - LG Chem,LTD.	
2	MFL053800	Manual,Operation	MFL67528301	PRINTING LGP705.ACISWH ZZ:Without Color Web manual for LGP705 CIS	
3	MBM062600	Card,Quick Reference	MBM63736701	PRINTING LGP705.ACISBK ZZ:Without Color Simple manual for LGP705 CIS	
3	MBM087200	Card,Warranty	MCDF0011303	COMPLEX GD350 CISBK ZZ:Without Color -	
2	EAY060000	Adapters	SSAD0038301	100-240V,5060 Hz,5.1 V,700 mA,CE,AC-DC Adaptor,90Vac~264Vac,5.1V,700mA,5060,WALL 2P,USB,	
2	EBX000000	Accessory,Data Cable	SGDY0016701	KCA-ET-8-0020 KCA-ET-8-0020 Micro USB, 1.2M KSD CO., LTD	